# ENQUIRY DOCUMENT - TENDER

**(Document No : B957-TENDER_DOC-B957-300-16-43-MR-T-3001)**

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-TENDER_DOC-B957-300-16-43-MR-T-3001 | A | ENQUIRY DOCUMENT - TENDER | 23 |
| B957-300-16-43-MR-T-3001 | 0 | Mechanical Works - Ifor ECU | 1445 |
| B957-300-16-43-SOW-3001 | 1 | SCOPE OF WORK & SUPPLY (PIPING) MECHANICAL WORKS - I FOR ECU | 1469 |
| B957-300-80-46-SOW-3001 | 0 | SCOPE OF SUPPLY AND WORK | 1493 |
| B957-300-80-42-SOW-3001 | 0 | SCOPE OF WORK / SUPPLY FOR MECHANICAL TENDER (SMED) | 1499 |
| B957-300-80-42-SOW-3001 Annexure-A | 0 | SCOPE OF WORK AND SUPPLY (Static equipment) | 1500 |
| B957-300-80-42-SOW-3001-ANNEXURE B | A | SCOPE OF WORK/SUPPLYANNEXURE-B (SMED-ROTATING) | 1519 |
| Annexure-C B957-300-80-42-SOW-3001 | 0 | Annexure C for Scope of Work/Supply (SMED) | 1547 |
| B957-300-81-41-SOW-3001 | 1 | SCOPE OF SUPPLY & WORK | 1558 |
| B957-300-81-45-SOW-3001 | C | SCOPE OF SUPPLY & WORK | 1576 |
| B957-6-44-0022 | A | JOB SPECIFICATIONS FOR PRE- INSULATED SS TUBING AND FITTINGS | 1585 |
| B957-6-44-0016 | D | JOB SPEC FOR NON DESTRUCTIVE TESTING | 1590 |
| B957-300-16-43-00001 | 1 | Equipment Layout | 1614 |
| B957-300-16-43-00002 | 1 | EQUIPMENT LAYOUT | 1615 |
| B957-000-06-45-VL-02 | 0 | VENDOR LIST | 1616 |
| B957-000-06-45-TC-01 | A | TECHNICAL COMPLIANCE | 1625 |
| B957-300-06-45-CSP-01 | A | JOB SPECIFICATION - CP SYSTEM | 1627 |
| B957-300-06-45-VDR-3001 | B | VENDOR DATA REQUIRMENT | 1704 |
| B957-300-6-45-CPS-3001 | 0 | CP SYSTEM SPECIFICATION | 1708 |
| B957-000-06-42-PLS-01 | 2 | JOB SPECIFICATION FOR SURFACE PREPARATION AND PROTECTIVE COATING | 1784 |
| B957-000-06-42-CCS-001 | B | JOB SPECIFICATION FOR PRETREATMENT CUM ON-STREAM CLEANING OF RECIRCULATING FRESH COOLING WATER SYSTEM | 1869 |
| B957-000-06-42-CCS-003. Rev. B | B | JOB SPECIFICATION FOR DEGREASING OF CARBON STEEL PIPING VESSELS & EQUIPMENT IN AMINE SERVICE | 1877 |
| B957-000-06-42-CCS-004 | B | JOB SPECIFICATION FOR CHEMICAL CLEANING OF VHP/HP STEAM PIPING | 1881 |
| B957-000-06-42-CCS-005 | B | JOB SPECIFICATION FOR CHEMICAL CLEANING & PASSIVATION OF COMPRESSOR CIRCUITS | 1886 |
| B957-000-06-42-CCS-007 | B | JOB SPECIFICATION FOR CHEMICAL CLEANING OF HP/MP/LP STEAM GENERATORS | 1899 |
| B957-000-06-42-CCS-008 | B | JOB SPECIFICATION FOR ALKALI BOILOUT CHEMICAL CLEANING OF BOILERS | 1904 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-000-06-42-CCS-011 | B | JOB SPECIFICATION FOR EXTERNAL CHEMICAL CLEANING OF SS WELDS | 1909 |
| B957-000-06-42-PLS-04 Rev.0 | 0 | JOB SPECIFICATION FOR EXTERNAL COATING OF BURIED PIPING AND FITTINGS | 1912 |
| B957-000-06-42-PLS-10 | 0 | TECHNICAL SPECIFICATION FOR COATING OF UNDERGROUND STAINLESS STEEL/ ALLOY STEEL PIPING | 1920 |
| B957-000-06-42-SPC-ECU | 0 | B957-000-06-42-SPC-ECU_Mark up | 1930 |
| B957-300-16-50-VR-3001 | A | VENDOR DATA REQUIREMENTS - MECH. TENDER-1-ECU | 2048 |
| B957-000-16-50-DS-4040 | B | DATA SHEET - Electrical tracing | 2051 |
| B957-000-16-50-DS-5102 | B | MV CABLE | 2054 |
| B957-000-16-50-DS-5201 | A | COMMUNICATION & FA CABLES | 2056 |
| B957-300-16-50-01012 | A | Cable layout ECU unit | 2058 |
| B957-300-16-50-SP-9503 | B | JOB SPECIFICATION - EHT SYSTEM-MECH. TENDER-ECU | 2059 |
| B957-300-16-50-VL-3001 | B | VENDOR LIST - MECH. TENDER-1-ECU | 2070 |
| 6-14-0017 | 5 | General specification for wire mesh demisters | 2099 |
| 6-12-0001 | 7 | General specification for pressure vessels | 2105 |
| 6-12-0002 | 9 | Supplementary specification for carbon steel vessels | 2119 |
| 6-12-0003 | 6 | Supplementary specification for low alloy steel vessels | 2125 |
| 6-12-0006 | 7 | Supplementary specification for austenitic stainless steel vessels | 2131 |
| 6-12-0007 | 6 | Supplementary specification for clad vessels | 2137 |
| 6-12-0011 | 9 | Standard specification for boiler quality carbon steel plates. | 2147 |
| 6-12-0014 | 7 | Standard specification for weldable structural quality steel plates for storage tanks and vessels | 2154 |
| 6-12-0015 | 6 | Standard specification for clad plates | 2159 |
| 6-12-0017 | 6 | Standard specification for 1% Cr-¿ % Mo and 1¿ % Cr-¿ % Mo steel plates | 2164 |
| 6-12-0020 | 9 | Standard specification for stainless steel plates | 2170 |
| 6-14-0011 | 6 | Standard specification for filling the packing inside the column | 2175 |
| 6-15-0091 | 5 | Standard specification for hardness requirement of static equipment | 2182 |
| 6-44-0007 | 6 | Standard specification for steam tracing | 2187 |
| 6-44-0007-A1 | 5 | Annexure-1 Steam tracing-site fabricated manifolds (Typical diagrams) | 2196 |
| 6-44-0007-A2 | 4 | Annexure-2 steam tracing-bought out manifolds (typical diagrams) | 2201 |
| 6-44-0012 | 6 | Standard specification for fabrication and erection of piping | 2207 |
| 6-44-0013 | 6 | Standard specification for inspection, flushing and testing of piping systems | 2222 |
| 6-45-0030 | 1 | Specification for cathodic protection system for tank bottom plate | 2231 |
| 6-45-0032 | 1 | Specification for cathodic protection system for underground vessels | 2241 |
| 6-45-0051 | 0 | Specification for installation, pre-commissioning, testing and commissioning of cathodic protection system for tanks | 2251 |
| 6-45-0060 | 0 | Specification for installation, pre-commissioning, testing and commissioning of cathodic protection system for vessels | 2267 |
| 6-51-0007 | 0 | Specification for flameproof power distribution boards | 2283 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| 6-51-0051 | 9 | Specification for medium and high voltage cables & accessories | 2292 |
| 6-51-0052 | 7 | Specification for communication and fire alarm cables. | 2302 |
| 6-51-0081 | 5 | Specification for electrical equipment installation. | 2313 |
| 6-51-0082 | 6 | Specification for Cable Installation | 2329 |
| 6-51-0084 | 5 | Specifications for earthing installation. | 2341 |
| 6-51-0087 | 4 | Specification for field inspection, testing and commissioning of electrical installations | 2349 |
| 6-51-0093 | 6 | Specification for electrics of package equipment | 2357 |
| 6-51-0095 | 5 | Specification for electric surface heating system. | 2367 |
| 6-51-0099 | 7 | Design philosophy for electrical facilities. | 2380 |
| 6-61-0015 | 6 | Standard specification for chain pulley block | 2412 |
| 6-65-0006 | 4 | Standard specification for earthwork for underground piping. | 2418 |
| 6-65-0019 | 4 | Standard specification for concrete pavement. | 2425 |
| 6-65-0027 | 6 | Standard specification for underground & above ground galvanized steel piping (water services) | 2435 |
| 6-65-0030 | 6 | Standard specification for fabrication and laying of underground piping | 2440 |
| 6-66-0004 | 1 | Standard specification for portable fire extinguisher | 2451 |
| 6-66-0012 | 5 | Standard specification for stand post type fire hydrant with normal type lading valve | 2456 |
| 6-66-0018 | 5 | Standard specification for first aid hose reel | 2464 |
| 6-66-0021 | 4 | Standard specification for stand post type water monitor | 2469 |
| 6-66-0027 | 5 | Standard specification for water cum foam monitor single barrel type (fixed & variable flow) | 2475 |
| 6-66-0038 | 5 | Standard specification for safety shower and eye wash. | 2481 |
| 6-66-0042 | 3 | Standard specification for remote operated foam / water monitor tower / grade mounted | 2486 |
| 6-66-0047 | 4 | Standard specification for hose cabinet. | 2494 |
| 6-66-0048 | 4 | Standard specification for deluge valve skid | 2499 |
| 6-66-0061 | 4 | Standard specification for 50 kg. & 75 kg. capacity dry chemical powder extinguisher. | 2510 |
| 6-68-0001 | 6 | Standard specification civil and structural works general scope | 2515 |
| 6-68-0002 | 7 | Standard specification civil & structural works materials | 2519 |
| 6-68-0003 | 6 | Standard Specification Civil & Structural Works Earthwork. | 2536 |
| 6-68-0004 | 8 | Standard specification civil & structural works plain and reinforced cement concrete | 2550 |
| 6-68-0005 | 7 | Standard specification civil and structural works reinforced cement concrete for structure retaining aqueous liquids | 2581 |
| 6-68-0006 | 8 | Standard specification civil & structural works structural steel works | 2589 |
| 6-68-0007 | 8 | Standard specification civil & structural works structural steel works (tubular/hollow sections) | 2614 |
| 6-68-0008 | 9 | Standard specification civil and structural works miscellaneous steel works | 2630 |
| 6-68-0009 | 6 | Standard specification civil & structural works brick masonry | 2644 |
| 6-68-0012 | 6 | Standard specification civil & structural works demolition and dismantling | 2653 |
| 6-68-0013 | 6 | Standard specifications civil & structural works miscellaneous items | 2660 |
| 6-68-0017 | 2 | Standard specification civil & structural works bipolar concrete penetrating corrosion inhibiting admixture | 2670 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| 6-68-0054 | 5 | Standard specification - civil & structural works - epoxy resin injection system. | 2690 |
| 6-68-0056 | 5 | Standard specification civil & structural works bonding fresh concrete to old concrete by EPOXY resin bonding system | 2698 |
| 6-68-0063 | 2 | Standard specification civil & structural works design of scaffolding (for RCC beam and slab) | 2704 |
| 6-76-0001 | 4 | Standard specification for erection of equipment & machinery | 2715 |
| 6-76-0002 | 3 | Standard specification for application of torque and hydraulic bolt tension for flange joints | 2737 |
| 6-77-0001 | 5 | Welding specification for fabrication of piping | 2772 |
| 6-78-0001 | 3 | Specification for quality management system requirements from bidders / suppliers / contractors | 2818 |
| 6-78-0002 | 3 | Specification for documentation requirements from contractors | 2825 |
| 6-78-0003 | 3 | Specification for documentation requirements from suppliers | 2836 |
| 6-79-0027 | 1 | Standard specification for cold insulation of vessels, piping and equipment | 2847 |
| 6-79-0040 | 0 | Standard specification for rockwool insulation | 2900 |
| 6-81-0001 | 4 | Standard specification for positive material identification (PMI) at supplier's works | 2909 |
| 6-81-0002 | 6 | ITP for welded pipes | 2917 |
| 6-81-0007 | 5 | ITP For Bolting Material | 2923 |
| 6-81-0035 | 4 | ITP for chain pulley block/winch | 2930 |
| 6-81-0035 | 5 | Inspection and test plan for chain pulley block / winch | 2935 |
| 6-81-1008 | 4 | Inspection and test plan for flameproof lighting and power panels | 2940 |
| 6-81-1051 | 4 | ITP for MV & HV cables & accessories | 2945 |
| 6-81-1052 | 4 | ITP for communication & fire alarm cables | 2951 |
| 6-81-1061 | 4 | ITP for hazardous area lighting fixture & junction boxes | 2958 |
| 6-81-1097 | 1 | Inspection and test plan for electrical heat tracers | 2963 |
| 6-82-0001 | 2 | Standard specification for health, safety & environmental management at construction sites | 2969 |
| 6-82-0002 | 5 | Standard specification for positive material identification at construction sites | 3074 |
| 6-82-0003 | 4 | Standard specification for colour coding of piping material | 3084 |
| 6-82-3100 | 2 | Inspection & test plan (ITP) for civil, structural & architectural works (item rate contracts-with categorization) | 3096 |
| 6-82-3200 | 2 | Inspection & test plan (ITP) for mechanical works (item rate contracts - with categorization) | 3161 |
| 6-82-3300 | 2 | Inspection & test plan (ITP) for general works (item rate contracts with categorisation) | 3270 |
| 6-82-6100 | 4 | Standard quality assurance plan (for item rate contracts) | 3286 |
| 7-12-0001 | 7 | Vessel tolerances | 3299 |
| 7-12-0002 | 7 | Support for horizontal vessel | 3301 |
| 7-12-0003 | 7 | Wooden pillows for saddle support | 3302 |
| 7-12-0004 | 8 | Skirt base details | 3303 |
| 7-12-0005 | 7 | Skirt opening details | 3304 |
| 7-12-0006 | 7 | Angle leg support | 3306 |
| 7-12-0007 | 7 | Pipe leg support | 3308 |
| 7-12-0008 | 7 | Bracket support for vertical vessel | 3309 |
| 7-12-0009 | 8 | Manhole with hinged cover | 3310 |
| 7-12-0010 | 8 | Manhole with davit | 3312 |
| 7-12-0011 | 7 | Ladder rungs for manhole/demister | 3314 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| 7-12-0012 | 7 | Retaining plate | 3315 |
| 7-12-0013 | 8 | Nozzle reinforcement and projection | 3316 |
| 7-12-0014 | 7 | Pad nozzles for vessels | 3318 |
| 7-12-0015 | 7 | Standard bolt hole orientation | 3319 |
| 7-12-0016 | 7 | Alloy liner details | 3320 |
| 7-12-0018 | 7 | Internal flanges | 3322 |
| 7-12-0019 | 7 | Vortex breakers | 3323 |
| 7-12-0020 | 7 | Inlet deflector baffle | 3324 |
| 7-12-0021 | 7 | Support ring & bolting bar | 3325 |
| 7-12-0022 | 7 | Support ring sizes for packed tower¿s internals | 3326 |
| 7-12-0023 | 8 | Pipe davit | 3327 |
| 7-12-0024 | 9 | Lifting lug top head type (for vertical vessels / columns) | 3330 |
| 7-12-0025 | 7 | Fire proofing & insulation suppor | 3331 |
| 7-12-0026 | 7 | Earthing lug | 3333 |
| 7-12-0027 | 7 | Name plate | 3334 |
| 7-12-0028 | 7 | Manufacturer name plate | 3335 |
| 7-12-0029 | 7 | Bracket for name plate | 3336 |
| 7-12-0030 | 6 | Name plate for small equipment | 3337 |
| 7-12-0031 | 6 | Details of forged nozzles | 3338 |
| 7-12-0032 | 6 | Supports for internal feed pipe | 3339 |
| 7-12-0033 | 6 | Hot insulation supports for horizontal vessel | 3341 |
| 7-12-0034 | 6 | Pipe davit support detail for cold insulated vessels | 3342 |
| 7-12-0036 | 6 | Typical detail of wiremesh demister and its supports (for vessels and columns) | 3343 |
| 7-12-0037 | 5 | S.R. nozzle neck | 3347 |
| 7-12-0038 | 2 | Allowable nozzle loads | 3348 |
| 7-12-0039 | 0 | Still well for level transmitter (radar type) for buried vessel | 3352 |
| 7-14-0001 | 5 | Construction tolerances for welded supports for trays/tower internals | 3353 |
| 7-15-0001 | 6 | Part details (shell & tube exchangers) | 3354 |
| 7-44-0003 | 6 | Symbols of piping elements on drawings | 3356 |
| 7-44-0033 | 7 | Details of mitered elbow | 3360 |
| 7-44-0050 | 6 | Chain operation attachment for valves (150#, 300#, 600#) | 3362 |
| 7-44-0162 | 6 | Standard for spacers and blinds > 26¿ (150#, 300# and 600# FF to B 16.47 series B) | 3363 |
| 7-44-0164 | 2 | Standard for spacers and blinds > 26¿ (for AWWA flanges) | 3366 |
| 7-44-0310 | 6 | Sample cooler - type 1 (non-congealing services) | 3368 |
| 7-44-0311 | 4 | Sample cooler - type 2 (congealing services) | 3369 |
| 7-44-0350 | 6 | Vents and drains (on lines 1" and below) | 3370 |
| 7-44-0351 | 6 | Vents and drains (on lines 2" and above). | 3371 |
| 7-44-0352 | 6 | Orientation of orifice taps (class 600 & below) | 3372 |
| 7-44-0353 | 6 | Wells installation 1 1/2" dia taps (up to class 600). | 3374 |
| 7-44-0354 | 6 | Pressure tappings (PA, PG, PC, PT, PIC etc) | 3376 |
| 7-44-0400 | 7 | Steam trap assembly STA-1 (closed system) | 3377 |
| 7-44-0401 | 6 | Utility hose station | 3381 |
| 7-44-0403 | 7 | DRIP leg for steam lines | 3382 |
| 7-44-0404 | 6 | Pipe sleeve details for insulated lines under roads and dykes | 3383 |
| 7-44-0476 | 6 | Welding of pipe with different thickness | 3384 |
| 7-44-0477 | 6 | Butt welding end preparation | 3385 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| 7-44-0478 | 6 | Fillet weld details | 3386 |
| 7-44-0479 | 6 | Welding detail for branch connections (not breaking into) | 3387 |
| 7-44-0480 | 6 | Butt weld details (dimensions) | 3388 |
| 7-44-0481 | 6 | Butt weld details (sequence of welds) | 3389 |
| 7-44-0482 | 6 | Welding detail for branch connections (stub in) | 3390 |
| 7-44-0483 | 6 | Branch connection (breaking into) | 3391 |
| 7-44-0484 | 6 | Branch connections (not breaking into) | 3392 |
| 7-44-0485 | 6 | Method of cutting and dimensions of field manufactured concentric reducers | 3393 |
| 7-44-0486 | 6 | Tolerances for fabrication | 3394 |
| 7-44-0487 | 7 | Method of cutting and dimensions of field manufactured ECC. reducers | 3395 |
| 7-44-0504 | 5 | Clearance requirements for orifice flange instrument piping | 3396 |
| 7-51-0103 | 7 | Typical earth plate and fixing details. | 3399 |
| 7-51-0112 | 6 | Earthing / bonding of pipes and pipe racks (in hazardous area). | 3400 |
| 7-51-0116 | 9 | Equipment earthing schedule | 3402 |
| 7-51-0225 | 6 | Typical installation of flame proof lighting / power panel | 3404 |
| 7-51-0303 | 7 | Typical section of RCC cable trench | 3405 |
| 7-51-0332 | 4 | Safety measures for electrical installations during construction | 3406 |
| 7-51-0333 | 4 | Details for hot dip galvanized ladder type cable trays | 3408 |
| 7-65-0001 | 5 | Abbreviation legends and eqpt. Symbols | 3411 |
| 7-65-0272 | 6 | United drainage details (rectangular ditch details) | 3415 |
| 7-65-0404 | 5 | RCC pavement details | 3416 |
| 7-65-0420 | 5 | Installation details of fire water dydrant | 3417 |
| 7-65-0421 | 4 | Installation details of water or water cum foam monitor long range foam / water monitor | 3418 |
| 7-67-0008 | 8 | Pedestal For Stair/Ladder. | 3419 |
| 7-67-0010 | 7 | Foundation for sliding supports for pipes on grade | 3420 |
| 7-67-0012 | 5 | Short sliding pipe supports on existing R.C.C. pavements | 3423 |
| 7-68-0051 | 7 | Standard lifting hooks in precast slabs and cheq. plates | 3425 |
| 7-68-0052 | 8 | Details for M.S. rungs for conc. structures | 3426 |
| 7-68-0056 | 8 | Metal insert plates | 3427 |
| 7-68-0060 | 1 | Handrail - Tube and Ball Type | 3434 |
| 7-68-0062 | 7 | Typical cranking detail of rebar at beam and col. junctions | 3436 |
| 7-68-0101 | 7 | Standard re-bar shapes and cut length computation | 3437 |
| 7-68-0102 | 6 | Adjustment of stirrups at beam crossing | 3442 |
| 7-68-0103 | 7 | Reinforcement details at circular cut-out in slab | 3443 |
| 7-68-0104 | 7 | Reinforcement details at SQ./RECT. cut-out in slab | 3444 |
| 7-68-0106 | 8 | Standard lap length for rebars | 3445 |
| 7-68-0201 | 7 | Standard lugs | 3446 |
| 7-68-0202 | 8 | Typical grating support | 3447 |
| 7-68-0203 | 8 | Typical chequered plate support | 3448 |
| 7-68-0207 | 6 | Welded column splice (unequal ISMB section) | 3449 |
| 7-68-0208 | 7 | Splicing detail for rolled sections | 3451 |
| 7-68-0211 | 6 | Beam To Beam And Beam To Column Connection Details. | 3460 |
| 7-68-0213 | 7 | Base plate for channels | 3461 |
| 7-68-0214 | 7 | Base plate for angles | 3462 |
| 7-68-0215 | 8 | Base plate for joists | 3463 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| 7-68-0224 | 0 | Bolted bracing connection details of angles, channels & square hollow sections | 3464 |
| 7-68-0250 | 1 | List of equivalent structural steel sections for substitution | 3472 |
| 7-68-0251 | 7 | Welding symbols | 3474 |
| 7-68-0355 | 4 | Instrumentation cable duct / tray supporting arrangement | 3480 |
| 7-68-0417 | 9 | M.S. anchor bolt assemblies | 3482 |
| 7-68-0506 | 8 | Steel stairs | 3490 |
| 7-68-0507 | 9 | Details of steel ladder | 3496 |
| 7-68-0509 | 8 | Steel ladder joint details | 3499 |
| 7-68-0562 | 6 | Small operating platforms on grade / RCC elevated structure | 3503 |
| 7-68-0563 | 5 | Pipe sleeper crossover | 3506 |
| 7-68-0626 | 6 | Cable trench outside the buildings (for hydra movement) | 3510 |
| 7-68-0627 | 2 | Precast cable trench and joint detail | 3527 |
| 7-68-0631 | 7 | Liquid retaining structure concrete joints | 3529 |
| 7-68-0655 | 6 | Cable trench for class-aa tracked / 70R-wheeled vehicle (crane approach) | 3534 |
| 7-68-0658 | 1 | Bolted shear connection details for beam to beam | 3540 |
| 7-68-0659 | 0 | Bolted Shear Connection Details for Beam with Column | 3551 |
| 7-68-0683 | 5 | Monorail fixing detail with steel members | 3553 |
| 7-68-0684 | 5 | Monorail fixing detail with R.C.C. beam | 3561 |
| 7-68-0686 | 1 | Welded Shear Connection Details for Parallel Flange Beam with Parallel Flange Beam | 3564 |
| 7-68-0688 | 1 | Welded shear connection details for parallel flange beam with parallel flange column | 3566 |
| 7-68-0689 | 4 | Shear connections welded type - beam to beam | 3568 |
| 7-68-0690 | 0 | Bolted moment connection detail | 3572 |
| 7-68-0691 | 4 | Detail of sliding T-support | 3575 |
| 7-68-0692 | 3 | Detail of sliding T-support using hollow sections | 3577 |
| 7-68-0695 | 4 | Electrical cable tray supporting structure | 3580 |
| 7-68-0697 | 6 | Electroforged grating type-I & type-II | 3589 |
| 7-68-0699 | 2 | Saddle supports for equipments on tech. structures | 3597 |
| 6-14-0003 | 7 | Installation procedure for trays and tower internals | 3605 |
| 6-14-0016 | 6 | Standard specification for review of site installation of column internals | 3623 |
| 6-51-0008 | 7 | Specification for flameproof lighting and power panels | 3638 |
| 6-51-0061 | 7 | Specification for hazardous area light fixtures and junction boxes | 3646 |
| 6-68-0014 | 2 | Standard specification civil & structural works precast concrete | 3654 |
| 6-79-0026 | 1 | Standard specification for HOT insulation of vessels, piping and equipment | 3661 |
| 6-81-0011 | 5 | Inspection and test plan for pressure vessels / columns carbon steel | 3733 |
| 6-81-0015 | 4 | Inspection and test plan for trays and tower internals | 3741 |
| 6-81-0016 | 4 | Inspection and test plan for tower packings | 3747 |
| 6-81-0017 | 4 | Inspection and test plan for un-engineered trays and tower internals | 3752 |
| 6-81-0061 | 5 | Inspection and test plan for ejectors | 3758 |
| 7-68-0206 | 2 | Detail of welded column splice (unequal parallel flange section) | 3764 |
| 7-68-0501 | 9 | Handrails | 3766 |
| 7-68-0503 | 2 | Arrangements for access from grade to spiral staircase of steel tanks | 3774 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| 7-68-0653 | 5 | Typical detail of weld length for angle members | 3778 |
| 7-68-0654 | 5 | Detail of moment connection for MC [ ] col. to [ ] beam | 3779 |
| 7-68-0660 | 4 | Typ. det. of moment connection with MB col. / MC box col. to MB beam | 3781 |
| 7-68-0687 | 2 | Detail of moment connection for parallel flange beams with parallel flange columns | 3785 |
| 7-68-0696 | 4 | Detail of lacing connections | 3787 |
| B857-000-16-54-DB-0001 | 0 | SITE SPECIFIC SEISMIC SPECTRA, BPREP, BPCL BINA | 3791 |
| B857-000-16-54-DB-0002 | 1 | DESIGN BASIS FOR WIND LOAD ON PIPING, BPREP, BPCL BINA | 3795 |
| B857-000-16-54-DB-0003 | 0 | SEISMIC DESIGN REQUIREMENTS FOR PIPING, BPREP, BPCL BINA | 3798 |
| B957-300-81-45-AD-3001 | A | ADDENDUM TO  STANDARD SPECIFICATION | 3801 |
| B957-999-81-45-00001 | J | Overall Plot Plan BPREP, BPCL-Bina | 3807 |
| B957-999-81-45-DS-8003 | 0 | Data Steet of Hydrant | 3808 |
| B957-999-81-45-DS-8004 | 0 | Data Steet of Hose Box | 3810 |
| B957-999-81-45-DS-8005 | 0 | Data Steet of Monitor | 3811 |
| B957-999-81-45-DS-8006 | B | Data Steet of ROLRM | 3813 |
| B957-999-81-45-DS-8007 | 0 | Data Steet of Nozzle | 3815 |
| B957-999-81-45-DS-8010 | 0 | Data Steet of QBD | 3816 |
| B957-999-81-45-DS-8011 | 0 | Data Steet of DV | 3817 |
| B957-999-81-45-DS-8017 | 0 | Data SheetAir Release Valve | 3818 |
| B957-999-81-45-DS-8018 | 0 | Data SheetLANDING VALVE | 3819 |
| B957-999-81-45-DS-8019 | 0 | Data SheetHOSE REEL | 3821 |
| B957-999-81-45-DS-8020 | 0 | Data Sheet of LRM(Manual W.O Foam Induc.) | 3822 |
| B957-999-81-45-DS-8021 | 0 | Data Sheet of LRM(Manual with Foam Induc.) | 3824 |
| B957-999-81-45-DS-8024 | 0 | Data Sheet of Sand Bucket | 3826 |
| B957-999-81-45-DS-8026 | 0 | DATA SHEET FOR FIRST AIDHOSE REEL (STAND MOUNTING | 3827 |
| B957-000-81-45-LL-8003 | A | APPROVED VENDOR LIST | 3828 |
| B957-300-81-45-00442 | 1 | Layout of FireWater System | 3841 |
| B957-80-46-SOW-3001 | 0 | SCOPE OF WORK AND SUPPLY for Mechanical works-I/II Part A/ Part B | 3843 |
| B957-999-06-41-WSC-0001.. | 6 | WELDING SPECIFICATION CHARTS FOR PIPING CLASSES | 3857 |
| B957-999-06-41-WSP-0001. | 1 | WELDING SPECIFICATION FOR FABRICATION OF PIPING ( EIL Specification 6-77-0001 Rev.5) | 3905 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-999-06-43-IF01 | A | JOB SPECIFICATION FOR PASSIVE FIREPROOFING BY EPOXY INTUMESCENT COATING | 3910 |
| B957-300-80-42-VDR-3001 | A | VENDOR DATA REQUIREMENT (STATIC & MACHINERY EQUIPMENT) | 3923 |
| B957-300-80-42-DS-3006 | C | MDS-HP Depropanizer (300-CC-00-2201) | 3925 |
| B957-300-80-42-DS-3006S2 | C | COLUMNS MECHANICAL DATASHEET | 3926 |
| B957-300-80-42-DS-3006S3 | C | COLUMNS MECHANICAL DATASHEET | 3927 |
| B957-300-80-42-DS-3006S4 | C | COLUMNS MECHANICAL DATASHEET | 3928 |
| B957-300-80-42-DS-3006S5 | C | COLUMNS MECHANICAL DATASHEET | 3929 |
| B957-300-80-42-DS-3007 | B | MDS-LP Depropanizer (300-CC-00-2202) | 3930 |
| B957-300-80-42-DS-3007S2 | B | COLUMNS MECHANICAL DATASHEET | 3931 |
| B957-300-80-42-DS-3007S3 | B | COLUMNS MECHANICAL DATASHEET | 3932 |
| B957-300-80-42-DS-3009 | A | MDS-Deethanizer (300-CC-00-4001) | 3933 |
| B957-300-80-42-DS-3009S2 | A | MECHANICAL DATASHEETS | 3934 |
| B957-300-80-42-DS-3009S3 | A | MECHANICAL DATASHEETS | 3935 |
| B957-300-80-42-DS-3010 | 1 | Ethylene Fractionator (300-CC-00-4002) | 3936 |
| B957-300-80-42-DS-3010S2 | 1 | MECHANICAL DATASHEETS | 3937 |
| B957-300-80-42-DS-3010S3 | 1 | MECHANICAL DATASHEETS | 3938 |
| B957-300-80-42-DS-3012 | 0 | MDS-Propylene Fractionator No.2 (300-CC-00-4102) | 3939 |
| B957-300-80-42-DS-3012S2 | 0 | COLUMNS MECHANICAL DATASHEET | 3940 |
| B957-300-80-42-DS-3012S3 | 0 | COLUMNS MECHANICAL DATASHEET | 3941 |
| B957-300-80-42-DS-3013 | B | MDS-Debutanizer (300-CC-00-4201) | 3942 |
| B957-300-80-42-DS-3013S2 | B | MECHANICAL DATASHEETS | 3943 |
| B957-300-80-42-DS-3013S3 | B | MECHANICAL DATASHEETS | 3944 |
| B957-300-80-42-DS-3013S2 | B | MECHANICAL DATASHEETS | 3945 |
| B957-300-80-42-DS-3130 | B | HP DEPROPANIZER REFLUX DRUM (300-VV-VW-2201) | 3946 |
| B957-300-80-42-DS-3130S2 | B | MECHANICAL DATASHEETS | 3947 |
| B957-300-80-42-DS-3130S3 | B | MECHANICAL DATASHEETS | 3948 |
| B957-300-80-42-DS-3131 | A | LP Depropanizer RefluxDrum (300-VV-HW-2202) | 3949 |
| B957-300-80-42-DS-3131S2 | A | MECHANICAL DATASHEETS FOR VESSELS/COLUMNS/REACTORS | 3950 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-300-80-42-DS-3132 | A | Cond. Pot for 300-EE-00-2208 (300-VV-VW-2203) | 3951 |
| B957-300-80-42-DS-3132S2 | A | VESSELS MECHANICAL DATASHEET | 3952 |
| B957-300-80-42-DS-3133 | B | Cond. Pot for 300-EE-00-2201A/B (300-VV-VW-2204) | 3953 |
| B957-300-80-42-DS-3133S2 | B | MECHANICAL DATASHEETS | 3954 |
| B957-300-80-42-DS-3134 | A | Cond. Pot for 300-EE-00-2204A/B (300-VV-VW-2205) | 3955 |
| B957-300-80-42-DS-3134S2 | A | MECHANICAL DATASHEETS | 3956 |
| B957-300-80-42-DS-3135 | B | MDS:Regeneration Gas K.O.Drum (300-VV-VI-2301) | 3957 |
| B957-300-80-42-DS-3135S2 | B | VESSELS MECHANICAL DATASHEET | 3958 |
| B957-300-80-42-DS-3136 | A | Cond. Pot for 300-EE-00-2203 (300-VV-VW-2302) | 3959 |
| B957-300-80-42-DS-3136S2 | A | MECHANICAL DATASHEETS | 3960 |
| B957-300-80-42-DS-3137 | A | Cond. Pot for 300-EE-00-2204 (300-VV-VW-2303) | 3961 |
| B957-300-80-42-DS-3137S2 | A | MECHANICAL DATASHEETS | 3962 |
| B957-300-80-42-DS-3154 | A | MDS:Deethanizer Reflux Drum (300-VV-VW-4001) | 3963 |
| B957-300-80-42-DS-3154S2 | A | VESSELS MECHANICAL DATASHEET | 3964 |
| B957-300-80-42-DS-3155 | B | MDS:Ethylene Fract. Reflux Drum (300-VV-HW-4002) | 3965 |
| B957-300-80-42-DS-3155S2 | B | MECHANICAL DATASHEETS | 3966 |
| B957-300-80-42-DS-3156 | A | MDS:Propylene Fract. Reflux Drum (300-VV-HW-4101) | 3967 |
| B957-300-80-42-DS-3156S2 | A | VESSELS MECHANICAL DATASHEET | 3968 |
| B957-300-80-42-DS-3157 | A | MDS:Debutanizer Reflux Drrum (300-VV-HW-4202) | 3969 |
| B957-300-80-42-DS-3157S2 | A | MECHANICAL DATASHEETS | 3970 |
| B957-300-80-42-DS-3158 | A | Cond. Pot for 300-EE-00-4201A/B (300-VV-VW-4203) | 3971 |
| B957-300-80-42-DS-3158S2 | A | MECHANICAL DATASHEETS | 3972 |
| B957-300-80-42-DS-3159 | A | Debutanizer Area HC Drum Drum (300-VV-HW-4210) | 3973 |
| B957-300-80-42-DS-3159S2 | A | VESSELS MECHANICAL DATASHEET | 3974 |
| B957-300-80-42-DS-3159S3 | A | VESSELS MECHANICAL DATASHEET | 3975 |
| B957-300-80-42-DS-3165 | D | Liq Propy Accu for 300-EE-00-3012 (300-VV-VW-5006) | 3976 |
| B957-300-80-42-DS-3165S2 | D | VESSELS MECHANICAL DATASHEET | 3977 |
| B957-300-80-42-DS-3166 | C | Liq Propy Accu 300-EE-00-4003A-D (300-VV-VW-5007) | 3978 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-300-80-42-DS-3166S2 | C | VESSELS MECHANICAL DATASHEET | 3979 |
| B957-300-80-42-DS-3168 | B | Liquid Propylene Accumulator for 300-LZ-00-3001-EP-00-18 (300-VV-VI-5009) | 3980 |
| B957-300-80-42-DS-3168S2 | B | MECHANICAL DATASHEETS | 3981 |
| B957-300-80-42-DS-3201 | B | Acetylene Converter (300-RB-00-2201A-C) | 3982 |
| B957-300-80-42-DS-3201S2 | B | MECHANICAL DATASHEETS | 3983 |
| B957-300-80-42-DS-3201S3 | B | MECHANICAL DATASHEETS | 3984 |
| B957-300-80-42-DS-3203 | C | MAPD Converter (300-RB-00-4101A/B) | 3985 |
| B957-300-80-42-DS-3203S2 | C | MECHANICAL DATASHEETS | 3986 |
| B957-300-80-42-DS-3203S3 | C | MECHANICAL DATASHEETS | 3987 |
| B957-300-80-42-DS-3301 | B | CHARGE GAS DRYERS(300-VD-00-2001A/B/C) | 3988 |
| B957-300-80-42-DS-3301S2 | B | MECHANICAL DATASHEETS | 3989 |
| B957-300-80-42-DS-3301S3 | B | MECHANICAL DATASHEETS | 3990 |
| B957-300-80-42-DS-3303 | 0 | MDS: Acetylene Converter Dryer (300-VD-00-2201) | 3991 |
| B957-300-80-42-DS-3303S2 | 0 | MECHANICAL DATASHEETS | 3992 |
| B957-300-80-42-DS-3303S3 | 0 | MECHANICAL DATASHEETS | 3993 |
| B957-300-80-42-SP-1001 | 0 | PERLITE TECHNICAL SPECIFICATION | 3994 |
| B957-301-80-42-DS-3101 | A | C4 Feed Surge Drum (301-VV-HW-1601) | 3995 |
| B957-301-80-42-DS-3101S2 | A | MECHANICAL DATASHEETS | 3996 |
| B957-301-80-42-DS-3102 | B | C4 HP Flash Drum (301-VV-HW-1602) | 3997 |
| B957-301-80-42-DS-3102S2 | B | MECHANICAL DATASHEETS | 3998 |
| B957-301-80-42-DS-3102S3 | B | MECHANICAL DATASHEETS | 3999 |
| B957-301-80-42-DS-3103 | A | Cond. Pot for 301-EE-00-1604 (301-VV-VW-1603) | 4000 |
| B957-301-80-42-DS-3103S2 | A | VESSELS MECHANICAL DATASHEET | 4001 |
| B957-301-80-42-DS-3201 | B | C4 Hydrogenation Reactor (301-RB-00-1601A/B) | 4002 |
| B957-301-80-42-DS-3201S2 | B | MECHANICAL DATASHEETS | 4003 |
| B957-301-80-42-DS-3201S3 | B | MECHANICAL DATASHEETS | 4004 |
| B957-301-80-42-DS-3201S4 | B | MECHANICAL DATASHEETS | 4005 |
| B957-302-80-42-DS-3001 | B | MDS-Depentanizer(302-CC-00-2601) | 4006 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-302-80-42-DS-3001S2 | B | COLUMNS MECHANICAL DATASHEET | 4007 |
| B957-302-80-42-DS-3001S3 | B | COLUMNS MECHANICAL DATASHEET | 4008 |
| B957-302-80-42-DS-3002 | C | MDS-Rerun Tower (302-CC-00-2602) | 4009 |
| B957-302-80-42-DS-3002S2 | C | MECHANICAL DATASHEETS | 4010 |
| B957-302-80-42-DS-3004 | B | MDS-BTX Tower (302-CC-00-2702) | 4011 |
| B957-302-80-42-DS-3004S2 | B | MECHANICAL DATASHEETS | 4012 |
| B957-302-80-42-DS-3101 | A | MDS:PGH Feed Surge Drum (302-VV-HW-2602) | 4013 |
| B957-302-80-42-DS-3101s2 | A | VESSELS MECHANICAL DATASHEET | 4014 |
| B957-302-80-42-DS-3103 | A | Cond Pot for 302-EE-00-2602 (302-VV-VW-2604) | 4015 |
| B957-302-80-42-DS-3103S2 | A | VESSELS MECHANICAL DATASHEET | 4016 |
| B957-302-80-42-DS-3104 | B | MDS:PGH 1st Stage LP Flash Drum (302-VV-VW-2605) | 4017 |
| B957-302-80-42-DS-3104S2 | B | VESSELS MECHANICAL DATASHEET | 4018 |
| B957-302-80-42-DS-3105 | A | MDS:Depentanizer Reflux Drum (302-VV-HW-2606) | 4019 |
| B957-302-80-42-DS-3105S2 | A | VESSELS MECHANICAL DATASHEET | 4020 |
| B957-302-80-42-DS-3106 | A | Cond Pot for 302-EE-00-2604 (302-VV-VW-2607) | 4021 |
| B957-302-80-42-DS-3106S2 | A | VESSELS MECHANICAL DATASHEET | 4022 |
| B957-302-80-42-DS-3107 | A | Rerun Tower Reflux Drum (302-VV-HW-2608) | 4023 |
| B957-302-80-42-DS-3107S2 | A | VESSELS MECHANICAL DATASHEET | 4024 |
| B957-302-80-42-DS-3108 | A | Condensate Pot for 302-EE-00-2607 (302-VV-VW-2609) | 4025 |
| B957-302-80-42-DS-3108S2 | A | VESSELS MECHANICAL DATASHEET | 4026 |
| B957-302-80-42-DS-3109 | A | PGH 2nd Stage HP Flash Drum (302-VV-VW-2701) | 4027 |
| B957-302-80-42-DS-3109S2 | A | MECHANICAL DATASHEETS | 4028 |
| B957-302-80-42-DS-3110 | B | PGH Recycle Comp. SuctionDrum (302-VV-VI-2702) | 4029 |
| B957-302-80-42-DS-3110S2 | B | VESSELS MECHANICAL DATASHEET | 4030 |
| B957-302-80-42-DS-3111 | A | H2S Stripper Reflux Drum (302-VV-HW-2703) | 4031 |
| B957-302-80-42-DS-3111S2 | A | VESSELS MECHANICAL DATASHEET | 4032 |
| B957-302-80-42-DS-3112 | A | Condensate Pot for 302-EE-00-2705 (302-VV-VW-2704) | 4033 |
| B957-302-80-42-DS-3112S2 | A | VESSELS MECHANICAL DATASHEET | 4034 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-302-80-42-DS-3113 | A | BTX Tower Reflux Drum (302-VV-HW-2706) | 4035 |
| B957-302-80-42-DS-3113S2 | A | VESSELS MECHANICAL DATASHEET | 4036 |
| B957-302-80-42-DS-3114 | A | Condensate Pot for 302-EE-00-2708 (302-VV-VW-2708) | 4037 |
| B957-302-80-42-DS-3114S2 | A | VESSELS MECHANICAL DATASHEET | 4038 |
| B957-302-80-42-DS-3115 | A | PGH Area HC Drain Drum (302-VV-HW-2712) | 4039 |
| B957-302-80-42-DS-3115S2 | A | VESSELS MECHANICAL DATASHEET | 4040 |
| B957-302-80-42-DS-3115S3 | A | VESSELS MECHANICAL DATASHEET | 4041 |
| B957-302-80-42-DS-3201 | A | PGH 1st Stage Reactor (302-RB-00-2601A/B) | 4042 |
| B957-302-80-42-DS-3201S2 | A | REACTOR MECHANICAL DATASHEET | 4043 |
| B957-302-80-42-DS-3202 | 0 | PGH 2nd Stage Reactor (302-RB-00-2701A/B) | 4044 |
| B957-302-80-42-DS-3202S2 | 0 | MECHANICAL DATASHEETS | 4045 |
| B957-302-80-42-DS-3202S3 | 0 | MECHANICAL DATASHEETS | 4046 |
| B957-303-80-42-DS-3001 | 0 | Extractive Distillation Column (EDC) (303-CC-00-3501) | 4047 |
| B957-303-80-42-DS-3001S2 | 0 | MECHANICAL DATASHEETS | 4048 |
| B957-303-80-42-DS-3001S3 | 0 | MECHANICAL DATASHEETS | 4049 |
| B957-303-80-42-DS-3002 | B | MDS-Solvent Recovery Column (SRC) (303-CC-00-3502) | 4050 |
| B957-303-80-42-DS-3002S2 | B | MECHANICAL DATASHEETS | 4051 |
| B957-303-80-42-DS-3002S3 | B | MECHANICAL DATASHEETS | 4052 |
| B957-303-80-42-DS-3004 | 0 | MDS-Clay Tower (303-CC-00-3601A/B) | 4053 |
| B957-303-80-42-DS-3004S2 | 0 | MECHANICAL DATASHEETS | 4054 |
| B957-303-80-42-DS-3005 | C | MDS-Benzene Column (303-CC-00-3602) | 4055 |
| B957-303-80-42-DS-3005S2 | C | MECHANICAL DATASHEETS | 4056 |
| B957-303-80-42-DS-3006 | B | TOLUENE COLUMN (303-CC-00-3603) | 4057 |
| B957-303-80-42-DS-3006S2 | B | COLUMNS MECHANICAL DATASHEET | 4058 |
| B957-303-80-42-DS-3007 | B | XYLENE COLUMN (303-CC-00-3604) | 4059 |
| B957-303-80-42-DS-3007S2 | B | COLUMNS MECHANICAL DATASHEET | 4060 |
| B957-303-80-42-DS-3007S3 | B | COLUMNS MECHANICAL DATASHEET | 4061 |
| B957-303-80-42-DS-3102 | B | EDC OVHD RECEIVER (303-VV-HI-3502) | 4062 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-303-80-42-DS-3102S2 | B | VESSELS MECHANICAL DATASHEET | 4063 |
| B957-303-80-42-DS-3103 | A | EDC REBOILER CONDENSATE POT (303-VV-VW-3503) | 4064 |
| B957-303-80-42-DS-3103S2 | A | VESSELS MECHANICAL DATASHEET | 4065 |
| B957-303-80-42-DS-3105 | A | SRC REBOILER CONDENSATE POT (303-VV-VW-3505) | 4066 |
| B957-303-80-42-DS-3105S2 | A | VESSELS MECHANICAL DATASHEET | 4067 |
| B957-303-80-42-DS-3106 | A | SOLVENT REGENERATOR (303-VV-VI-3506) | 4068 |
| B957-303-80-42-DS-3106S2 | A | VESSELS MECHANICAL DATASHEET | 4069 |
| B957-303-80-42-DS-3106S3 | A | VESSELS MECHANICAL DATASHEET | 4070 |
| B957-303-80-42-DS-3107 | A | SOLVENT REG. REBOILER COND. POT(303-VV-VW-3507) | 4071 |
| B957-303-80-42-DS-3107S2 | A | VESSELS MECHANICAL DATASHEET | 4072 |
| B957-303-80-42-DS-3108 | B | WATER SURGE DRUM (303-VV-VW-3508) | 4073 |
| B957-303-80-42-DS-3108S2 | B | VESSELS MECHANICAL DATASHEET | 4074 |
| B957-303-80-42-DS-3111 | B | SOLVENT SUMP (303-VV-HW-3511) | 4075 |
| B957-303-80-42-DS-3111S2 | B | VESSELS MECHANICAL DATASHEET | 4076 |
| B957-303-80-42-DS-3111S3 | B | VESSELS MECHANICAL DATASHEET | 4077 |
| B957-303-80-42-DS-3112 | B | AROMATIC SUMP (303-VV-HW-3512) | 4078 |
| B957-303-80-42-DS-3112S2 | B | VESSELS MECHANICAL DATASHEET | 4079 |
| B957-303-80-42-DS-3112S3 | B | VESSELS MECHANICAL DATASHEET | 4080 |
| B957-303-80-42-DS-3113 | A | CLAY TOWER CHARGE DRUM (303-VV-HW-3601) | 4081 |
| B957-303-80-42-DS-3113S2 | A | MECHANICAL DATASHEETS | 4082 |
| B957-303-80-42-DS-3114 | A | CLAY TOWER CHARGE HEATER COND POT (303-VV-VW-3602) | 4083 |
| B957-303-80-42-DS-3114S2 | A | VESSELS MECHANICAL DATASHEET | 4084 |
| B957-303-80-42-DS-3115 | B | BENZENE COLUMN OVHD RECEIVER (303-VV-HW-3603) | 4085 |
| B957-303-80-42-DS-3115S2 | B | VESSELS MECHANICAL DATASHEET | 4086 |
| B957-303-80-42-DS-3116 | B | BENZENE COLUMN REBOILER II CO POT (303-VV-VW-3604) | 4087 |
| B957-303-80-42-DS-3116S2 | B | VESSELS MECHANICAL DATASHEET | 4088 |
| B957-303-80-42-DS-3118 | B | TOULENE COLUMN OVHD RECEIVER (303-VV-HW-3606) | 4089 |
| B957-303-80-42-DS-3118S2 | B | MECHANICAL DATASHEETS | 4090 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-303-80-42-DS-3119 | B | TOULENE COLUMN REBOILER COND POT(303-VV-VW-3607) | 4091 |
| B957-303-80-42-DS-3119S2 | B | VESSELS MECHANICAL DATASHEET | 4092 |
| B957-303-80-42-DS-3120 | B | XYLENE COLUMN OVHD RECEIVER (303-VV-HW-3608) | 4093 |
| B957-303-80-42-DS-3120S2 | B | MECHANICAL DATASHEETS | 4094 |
| B957-303-80-42-DS-3121 | B | XYLENE COLUMN REBOILER COND POT (303-VV-VW-3609) | 4095 |
| B957-303-80-42-DS-3121S2 | B | VESSELS MECHANICAL DATASHEET | 4096 |
| B957-303-80-42-DS-3122 | A | REGENERATION KO DRUM (303-VV-VI-3610) | 4097 |
| B957-303-80-42-DS-3122S2 | A | VESSELS MECHANICAL DATASHEET | 4098 |
| B997-300-80-42-DS-3001 | A | DATA SHEET FOR CHAIN PULLEY BLOCK | 4099 |
| B957-300-80-42-DS-3002 | B | MDS-Pyrolysis Fuel Oil Stripper (300-CC-00-1202) | 4101 |
| B957-300-80-42-DS-3002S2 | B | MECHANICAL DATASHEETS | 4102 |
| B957-300-80-42-DS-3004 | 1 | Process Water Stripper (300-CC-00-1401) | 4103 |
| B957-300-80-42-DS-3004S2 | 1 | MECHANICAL DATASHEETS | 4104 |
| B957-300-80-42-DS-3008 | 0 | MDS-Demethanizer (300-CC-00-3001) | 4105 |
| B957-300-80-42-DS-3008S2 | 0 | MECHANICAL DATASHEETS | 4106 |
| B957-300-80-42-DS-3008S3 | 0 | MECHANICAL DATASHEETS | 4107 |
| B957-300-80-42-DS-3011 | 1 | MDS-Propylene Fractionator No.1 (300-CC-00-4101) | 4108 |
| B957-300-80-42-DS-3011S2 | 1 | COLUMNS MECHANICAL DATASHEET | 4109 |
| B957-300-80-42-DS-3011S3 | 1 | COLUMNS MECHANICAL DATASHEET | 4110 |
| B957-300-80-42-DS-3014 | C | MDS-DCU Offgas Caustic/WWT (300-CC-00-2401) | 4111 |
| B957-300-80-42-DS-3014S2 | C | COLUMNS MECHANICAL DATASHEET | 4112 |
| B957-300-80-42-DS-3014S3 | C | COLUMNS MECHANICAL DATASHEET | 4113 |
| B957-300-80-42-DS-3100 | 0 | DATA SHEET FOR CHAIN PULLEY BLOCK | 4114 |
| B957-300-80-42-DS-3101 | 0 | LPG VAPORIZER DRUM (300-VV-VW-1001) | 4116 |
| B957-300-80-42-DS-3101S2 | 0 | MECHANICAL DATASHEETS | 4117 |
| B957-300-80-42-DS-3102 | 2 | KEROSENE FEED SURGE DRUM(300-VV-HW-1002) | 4118 |
| B957-300-80-42-DS-3102S2 | 2 | MECHANICAL DATASHEETS | 4119 |
| B957-300-80-42-DS-3103 | B | MDS:Naphtha Feed Surge Drum (300-VV-HW-1003) | 4120 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-300-80-42-DS-3103S2 | B | VESSELS MECHANICAL DATASHEET | 4121 |
| B957-300-80-42-DS-3104 | A | MDS:Cond. Pot for 300-EE-00-1003 (300-VV-VW-1004) | 4122 |
| B957-300-80-42-DS-3104S2 | A | MECHANICAL DATASHEETS | 4123 |
| B957-300-80-42-DS-3105 | A | MDS:Cond. Pot for 300-EE-00-1005 (300-VV-VW-1005) | 4124 |
| B957-300-80-42-DS-3105S2 | A | MECHANICAL DATASHEETS | 4125 |
| B957-300-80-42-DS-3106 | A | MDS:Cond. Pot for 300-EE-00-1007 (300-VV-VW-1006) | 4126 |
| B957-300-80-42-DS-3106S2 | A | MECHANICAL DATASHEETS | 4127 |
| B957-300-80-42-DS-3107 | A | MDS:Cond. Pot for 300-EE-00-1009 (300-VV-VW-1007) | 4128 |
| B957-300-80-42-DS-3107S2 | A | MECHANICAL DATASHEETS | 4129 |
| B957-300-80-42-DS-3110 | C | MDS:VHP Steam Cont. Blowdown Drum(300-VV-VW-1184) | 4130 |
| B957-300-80-42-DS-3110S2 | C | VESSELS MECHANICAL DATASHEET | 4131 |
| B957-300-80-42-DS-3112 | C | MDS:Quench Oil Drain Drum(300-VV-HW-1201) | 4132 |
| B957-300-80-42-DS-3112S2 | C | VESSELS MECHANICAL DATASHEET | 4133 |
| B957-300-80-42-DS-3112S3 | C | VESSELS MECHANICAL DATASHEET | 4134 |
| B957-300-80-42-DS-3113 | A | MDS:Quench Oil Drain DrumVSP (300-VV-VW-1202) | 4135 |
| B957-300-80-42-DS-3113S2 | A | MECHANICAL DATASHEETS | 4136 |
| B957-300-80-42-DS-3115 | A | MDS:Cond. Pot for 300-EE-00-1401 (300-VV-VW-1402) | 4137 |
| B957-300-80-42-DS-3115S2 | A | MECHANICAL DATASHEETS | 4138 |
| B957-300-80-42-DS-3116 | B | Cond. Pot for 300-EE-00-1402 A/B (300-VV-VW-1403) | 4139 |
| B957-300-80-42-DS-3116S2 | B | VESSELS MECHANICAL DATASHEET | 4140 |
| B957-300-80-42-DS-3119 | A | Charge Gas Comp.2nd StageDis.Drum (300-VV-VI-2004) | 4141 |
| B957-300-80-42-DS-3119S2 | A | VESSELS MECHANICAL DATASHEET | 4142 |
| B957-300-80-42-DS-3120 | A | Charge Gas Comp.3rd StageSuc.Drum (300-VV-VI-2005) | 4143 |
| B957-300-80-42-DS-3120S2 | A | VESSELS MECHANICAL DATASHEET | 4144 |
| B957-300-80-42-DS-3120S3 | A | VESSELS MECHANICAL DATASHEET | 4145 |
| B957-300-80-42-DS-3121 | A | Charge Gas Comp.3rd StageDis.Drum (300-VV-VI-2006) | 4146 |
| B957-300-80-42-DS-3121S2 | A | VESSELS MECHANICAL DATASHEET | 4147 |
| B957-300-80-42-DS-3121S3 | A | VESSELS MECHANICAL DATASHEET | 4148 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-300-80-42-DS-3122 | A | Charge Gas Comp.Casing Drain Drum (300-VV-HW-2007) | 4149 |
| B957-300-80-42-DS-3122S2 | A | MECHANICAL DATASHEETS | 4150 |
| B957-300-80-42-DS-3123 | B | MDS:Medium Gasoline FlashDrum (300-VV-VW-2008) | 4151 |
| B957-300-80-42-DS-3123S2 | B | MECHANICAL DATASHEETS | 4152 |
| B957-300-80-42-DS-3124 | A | Cond. Pot for 300-EE-00-2007A/B (300-VV-VW-2009) | 4153 |
| B957-300-80-42-DS-3124S2 | A | MECHANICAL DATASHEETS | 4154 |
| B957-300-80-42-DS-3125 | B | MDS:CGC Area Hydroc. Drain Drum (300-VV-HW-2010) | 4155 |
| B957-300-80-42-DS-3125S2 | B | VESSELS MECHANICAL DATASHEET | 4156 |
| B957-300-80-42-DS-3125S3 | B | VESSELS MECHANICAL DATASHEET | 4157 |
| B957-300-80-42-DS-3126 | A | MDS:Spent Caustic Coalescer (300-VV-HI-2101) | 4158 |
| B957-300-80-42-DS-3126S2 | A | VESSELS MECHANICAL DATASHEET | 4159 |
| B957-300-80-42-DS-3126S3 | A | VESSELS MECHANICAL DATASHEET | 4160 |
| B957-300-80-42-DS-3127 | A | MDS:Spent Gasoline Coales cer (300-VV-HI-2102) | 4161 |
| B957-300-80-42-DS-3127S2 | A | MECHANICAL DATASHEETS | 4162 |
| B957-300-80-42-DS-3127S3 | A | MECHANICAL DATASHEETS | 4163 |
| B957-300-80-42-DS-3128 | A | MDS:8% Caustic Surge Drum(300-VV-HW-2103) | 4164 |
| B957-300-80-42-DS-3128S2 | A | MECHANICAL DATASHEETS | 4165 |
| B957-300-80-42-DS-3129 | B | MDS:Caustic Drain Drum (300-VV-HW-2104) | 4166 |
| B957-300-80-42-DS-3129S2 | B | VESSELS MECHANICAL DATASHEET | 4167 |
| B957-300-80-42-DS-3129S3 | B | VESSELS MECHANICAL DATASHEET | 4168 |
| B957-300-80-42-DS-3138 | A | MDS:DCU Offgas Comp.Suc. Drum (300-VV-VI-2401) | 4169 |
| B957-300-80-42-DS-3138S2 | A | MECHANICAL DATASHEETS | 4170 |
| B957-300-80-42-DS-3139 | A | DCU Offgas Cau Tower Feed KO Drum (300-VV-VI-2402) | 4171 |
| B957-300-80-42-DS-3139S2 | A | MECHANICAL DATASHEETS | 4172 |
| B957-300-80-42-DS-3140 | A | DCU OG Dry/Tre Tower FeedKO Drum (300-VV-VI-2403) | 4173 |
| B957-300-80-42-DS-3140S2 | A | MECHANICAL DATASHEETS | 4174 |
| B957-300-80-42-DS-3142 | A | DCU Offgas Top Caus. FeedKO Drum (300-VV-VI-2405) | 4175 |
| B957-300-80-42-DS-3142S2 | A | MECHANICAL DATASHEETS | 4176 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-300-80-42-DS-3144 | A | Cond. Pot for 300-EE-00-2502 (300-VV-VW-2502) | 4177 |
| B957-300-80-42-DS-3144S2 | A | MECHANICAL DATASHEETS | 4178 |
| B957-300-80-42-DS-3146 | A | MDS:MEA Drain Drum (300-VV-HW-2505) | 4179 |
| B957-300-80-42-DS-3146S2 | A | VESSELS MECHANICAL DATASHEET | 4180 |
| B957-300-80-42-DS-3146S3 | A | VESSELS MECHANICAL DATASHEET | 4181 |
| B957-300-80-42-DS-3149 | 1 | MDS:Demethanizer Reflux Drum (300-VV-VW-3001) | 4182 |
| B957-300-80-42-DS-3149S2 | 1 | VESSELS MECHANICAL DATASHEET | 4183 |
| B957-300-80-42-DS-3150 | A | MDS:Fuel Gas KO Drum - Out Drum (300-VV-VI-3002) | 4184 |
| B957-300-80-42-DS-3150S2 | A | MECHANICAL DATASHEETS | 4185 |
| B957-300-80-42-DS-3151 | 0 | MDS:Demethanizer Feed Sep. No.1 (300-VV-VW-3004) | 4186 |
| B957-300-80-42-DS-3151S2 | 0 | MECHANICAL DATASHEETS | 4187 |
| B957-300-80-42-DS-3152 | 0 | MDS:Demethanizer Feed Sep. No.2 (300-VV-VW-3005) | 4188 |
| B957-300-80-42-DS-3152S2 | 0 | MECHANICAL DATASHEETS | 4189 |
| B957-300-80-42-DS-3153 | 0 | MDS:Demethanizer Feed Sep. No.3 (300-VV-VW-3006) | 4190 |
| B957-300-80-42-DS-3153S2 | 0 | MECHANICAL DATASHEETS | 4191 |
| B957-300-80-42-DS-3162 | B | Propy Refrig Comp 3rd St Suc Drum (300-VV-VI-5003) | 4192 |
| B957-300-80-42-DS-3162S2 | B | VESSELS MECHANICAL DATASHEET | 4193 |
| B957-300-80-42-DS-3164 | A | Propylene Refrigerant Accumulator (300-VV-HW-5005) | 4194 |
| B957-300-80-42-DS-3164S2 | A | VESSELS MECHANICAL DATASHEET | 4195 |
| B957-300-80-42-DS-3167 | 0 | LIQUID PROPYLENE ACCUMULATOR FOR 300-LZ-00-3001-EP-00-17 (300-VV-VI-5008) | 4196 |
| B957-300-80-42-DS-3167S2 | 0 | MECHANICAL DATASHEETS | 4197 |
| B957-300-80-42-DS-3169 | 0 | Binary Refrig Comp 1st StSuc Drum (300-VV-VI-6001) | 4198 |
| B957-300-80-42-DS-3169S2 | 0 | MECHANICAL DATASHEETS | 4199 |
| B957-300-80-42-DS-3169S3 | 0 | MECHANICAL DATASHEETS | 4200 |
| B957-300-80-42-DS-3170 | 0 | Binary Refrig Comp 2nd StSuc Drum (300-VV-VI-6002) | 4201 |
| B957-300-80-42-DS-3170S2 | 0 | MECHANICAL DATASHEETS | 4202 |
| B957-300-80-42-DS-3171 | 0 | Binary Refrig Comp 3rd StSuc Drum (300-VV-VI-6003) | 4203 |
| B957-300-80-42-DS-3171S2 | 0 | MECHANICAL DATASHEETS | 4204 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-300-80-42-DS-3172 | 1 | Binary Refrigeration Accumulator (300-VV-HW-6004) | 4205 |
| B957-300-80-42-DS-3172S2 | 1 | MECHANICAL DATASHEETS | 4206 |
| B957-300-80-42-DS-3172S3 | 1 | MECHANICAL DATASHEETS | 4207 |
| B957-300-80-42-DS-3173 | 0 | Binary Refrig Comp Suc Drum Blowc (300-VV-HW-6005) | 4208 |
| B957-300-80-42-DS-3173S2 | 0 | MECHANICAL DATASHEETS | 4209 |
| B957-300-80-42-DS-3174 | 0 | Binary Refriger. Retrograde Drum (300-VV-VW-6006) | 4210 |
| B957-300-80-42-DS-3174S2 | 0 | MECHANICAL DATASHEETS | 4211 |
| B957-300-80-42-DS-3175 | 1 | Binary Refrigerant Compressor Casing Drain Po (300-VV-HW-6007) | 4212 |
| B957-300-80-42-DS-3175S2 | 1 | MECHANICAL DATASHEETS | 4213 |
| B957-300-80-42-DS-3177 | 0 | Dry Flare Knock Out Drum (300-VV-HW-7002) | 4214 |
| B957-300-80-42-DS-3177S2 | 0 | MECHANICAL DATASHEETS | 4215 |
| B957-300-80-42-DS-3178 | B | LP Condensate Flash Drum (300-VV-HW-8001) | 4216 |
| B957-300-80-42-DS-3178S2 | B | VESSELS MECHANICAL DATASHEET | 4217 |
| B957-300-80-42-DS-3179 | B | MP Condensate Flash Drum (300-VV-VW-8002) | 4218 |
| B957-300-80-42-DS-3179S2 | B | VESSELS MECHANICAL DATASHEET | 4219 |
| B957-300-80-42-DS-3180 | A | Skimmed Yellow Oil Drum (300-VV-VW-9002) | 4220 |
| B957-300-80-42-DS-3180S2 | A | MECHANICAL DATASHEETS | 4221 |
| B957-300-80-42-DS-3181 | A | Quench Water Drain Drum (300-VV-HW-8010) | 4222 |
| B957-300-80-42-DS-3181S2 | A | VESSELS MECHANICAL DATASHEET | 4223 |
| B957-300-80-42-DS-3181S3 | A | VESSELS MECHANICAL DATASHEET | 4224 |
| B957-300-80-42-DS-3202 | A | DCU Offgas Oxygen Converter (300-RB-00-2401) | 4225 |
| B957-300-80-42-DS-3202S2 | A | MECHANICAL DATASHEETS | 4226 |
| B957-300-80-42-DS-3302 | 1 | MDS: Liquid Condensate Dryers (300-VD-00-2002 A/B) | 4227 |
| B957-300-80-42-DS-3302S2 | 1 | MECHANICAL DATASHEETS | 4228 |
| B957-300-80-42-DS-3302S3 | 1 | MECHANICAL DATASHEETS | 4229 |
| B957-300-80-42-DS-3304 | 0 | DCU OFF GAS DRYERS/TREATERS | 4230 |
| B957-300-80-42-DS-3304S2 | 0 | MECHANICAL DATASHEETS | 4231 |
| B957-300-80-42-DS-3305 | 0 | MDS: PG Propylene Treaters (300-VD-00-4101 A/B) | 4232 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-300-80-42-DS-3305S2 | 0 | MECHANICAL DATASHEETS | 4233 |
| B957-300-80-42-DS-3305S3 | 0 | MECHANICAL DATASHEETS | 4234 |
| B957-302-80-42-DS-3003 | 0 | H2S Stripper (302-CC-00-2701) | 4235 |
| B957-302-80-42-DS-3003S2 | 0 | MECHANICAL DATASHEETS | 4236 |
| B957-302-80-42-DS-3003s3 | 0 | MECHANICAL DATASHEETS | 4237 |
| B957-302-80-42-DS-3003S4 | 0 | MECHANICAL DATASHEETS | 4238 |
| B957-302-80-42-DS-3102 | 0 | MDS:PGH 1st Stage HP Flash Drum (302-VV-VW-2603) | 4239 |
| B957-302-80-42-DS-3102S2 | 0 | MECHANICAL DATASHEETS | 4240 |
| B957-302-80-42-DS-3111S2 | A | VESSELS MECHANICAL DATASHEET | 4241 |
| B957-303-80-42-DS-3003 | 1 | MDS-Water Stripper (Above HX) (303-CC-00-3503) | 4242 |
| B957-303-80-42-DS-3003S2 | 1 | MECHANICAL DATASHEETS | 4243 |
| B957-303-80-42-DS-3101 | B | EDC FEED SURGE DRUM (303-VV-HW-3501) | 4244 |
| B957-303-80-42-DS-3101S2 | B | VESSELS MECHANICAL DATASHEET | 4245 |
| B957-303-80-42-DS-3104 | B | SRC OVHD RECEIVER (303-VV-HI-3504) | 4246 |
| B957-303-80-42-DS-3104S2 | B | VESSELS MECHANICAL DATASHEET | 4247 |
| B957-303-80-42-DS-3109 | A | SOLVENT VENT DRUM (303-VV-VW-3509) | 4248 |
| B957-303-80-42-DS-3109S2 | A | MECHANICAL DATASHEETS | 4249 |
| B957-303-80-42-DS-3117 | A | MOISTURE GUARD BED (303-VV-VI-3605) | 4250 |
| B957-303-80-42-DS-3117S2 | A | MECHANICAL DATASHEETS | 4251 |
| B957-303-80-42-DS-3117S3 | A | MECHANICAL DATASHEETS | 4252 |
| B957-304-80-42-DS-3101 | A | WAO Separator (304-VV-VI-4501) | 4253 |
| B957-304-80-42-DS-3101S2 | A | VESSELS MECHANICAL DATASHEET | 4254 |
| B957-304-80-42-DS-3102 | A | WAO DRAIN SUMP (304-VV-HI-4502) | 4255 |
| B957-304-80-42-DS-3102S2 | A | VESSELS MECHANICAL DATASHEET | 4256 |
| B957-304-80-42-DS-3102S3 | A | VESSELS MECHANICAL DATASHEET | 4257 |
| B957-304-80-42-DS-3103 | A | WAO SULFURIC ACID TANK (304-VV-HW-4503) | 4258 |
| B957-304-80-42-DS-3103S2 | A | VESSELS MECHANICAL DATASHEET | 4259 |
| B957-304-80-42-DS-3104 | A | WAO ACID SUMP (304-VV-HI-4504) | 4260 |

*Click on the Document Title to go to that section of the document*

# Table of Contents


| Document Number | Rev. | Document Title | Page Number |
|---|---|---|---|
| B957-304-80-42-DS-3104S2 | A | VESSELS MECHANICAL DATASHEET | 4261 |
| B957-304-80-42-DS-3104S3 | A | VESSELS MECHANICAL DATASHEET | 4262 |
| B957-304-80-42-DS-3501 | 0 | WAO REACTOR 304-RB-00-4501 | 4263 |
| B957-304-80-42-DS-3501S2 | 0 | MECHANICAL DATASHEETS | 4264 |
| B957-80-42-EE-3001A | 0 | EQUIPMENT DETAILS FOR EQUIPMENT ERECTION | 4265 |
| B957-80-42-EE-3001B | 0 | EQUIPMENT DETAILS FOR EQUIPMENT ERECTION | 4286 |
| B957-80-42-EI-3001A | 0 | EQUIPMENT DETAILS FOR EQUIPMENT INSULATION | 4299 |
| B957-80-42-EI-3001B | 0 | EQUIPMENT DETAILS FOR EQUIPMENT INSULATION | 4315 |
| B957-300-81-41-LL-3001 | 1 | APPROVED VENDOR LIST | 4326 |
| B957-300-16-43-EHT LINES | A | LINE LIST FOR ELECTRICAL HEAT TRACING SYSTEM | 4332 |
| B957-000-92-41-OD-9801 | 0 | KPI List for BPREP Control Tower for Package Contracts | 4352 |
| B957-000-92-41-SP-9801 | 0 | SOW & JOB SPECIFICATIONS (Digital Technology Solutions) | 4356 |
| B957-BPCL Cybersecurity-Commercial Software | 0 | BPCL Security conditions in tender for purchasing Commercial software | 4373 |
| B957-BPCL-IS-GRC-2022-01 | 0 | Security Checklist for Cloud/ Third-party solutions | 4375 |
| BPCL IT Security Checklist-1 | 0 | IT Security Compliance Checklist-BPCL | 4378 |
| BPCL-Circular.IS.24-25-1 | 0 | Guideline for ensuring cyber security compliance of new IT initiatives- BPCL | 4386 |
| BPCL-Circular.IS.24-25-2 | 0 | Guidelines for BUs/ Entities on Cyber Security matters-BPCL | 4391 |

# BIDDING DOCUMENT

# FOR

# MECHANICAL WORKS FOR ETHYLENE CRACKER UNIT(ECU)

## (BIDDING DOCUMENT NO.: JP/B957-300-MR-T-3001/1030)

## PROJECT: BINA PETCHEM AND REFINERY EXPANSION PROJECT(BPREP) OF M/S BHARAT PETROLEUM CORPORATION LIMITED (BPCL)

**PREPARED & ISSUED BY:**

इंजीनियर्स इंडिया लिमिटेड
(भारत सरकार का उपक्रम)

ENGINEERS INDIA LIMITED
(A Govt. of India Undertaking)

# PART-I OF III : COMMERCIAL PART

# PART-II OF III : PRICED PART

# PART-III OF III: TECHNICAL PART

# BIDDING DOCUMENT

# FOR

# MECHANICAL WORKS FOR ETHYLENE CRACKER UNIT(ECU)

## (BIDDING DOCUMENT NO.: JP/B957-300-MR-T-3001/1030)

## PROJECT: BINA PETCHEM AND REFINERY EXPANSION PROJECT(BPREP) OF M/S BHARAT PETROLEUM CORPORATION LIMITED (BPCL)

## PART-I OF III : COMMERCIAL PART

इंजीनियर्स इंडिया लिमिटेड
(भारत सरकार का उपक्रम)

ENGINEERS INDIA LIMITED
(A Govt. of India Undertaking)

## PART – I – COMMERCIAL


| S. NO. | DESCRIPTION |
|---|---|
| **1.** | **TABLE OF CONTENT [ MASTER INDEX]** |
| **2.** | **INVITATION FOR BIDS (IFB)** |
| 2.1 | Appendix-**I** to IFB : FORMAT OF UNDERTAKING FOR AUTHENTICATION |
| 2.2 | Appendix-**II A** & **B** to IFB: DETAILS OF SPECIFIC EXPERIENCE FULFILLING QUALIFICATION CRITERIA / PAST EXPERIENCE IN SUPPORT OF BQC |
| 2.3 | Appendix-**III** to IFB : PROFORMA OF DECLARATION TOWARDS "CONFLICT OF INTEREST |
| 2.4 | DELETED |
| 2.5 | **Appendix -V** to IFB : LIST OF BANK FOR BG/E-BG/DD SUBMISSION |
| **3.** | **INSTRUCTION TO BIDDERS (ITB)** |
| a. | APPENDIX **I** : COMPLIANCE FOR RESTRICTIONS REGARDING PROCUREMENT FROM COUNTRIES WHICH SHARE LAND BORDER WITH INDIA. |
| b. | APPENDIX **II** : PUBLIC PROCUREMENT (PREFERENCE TO MAKE IN INDIA) (PPP-MII) & POLICY FOR PREFERENCE TO DOMESTICALLY MANUFACTURED ELECTRONIC & TELECOM |
| c. | APPENDIX **III** : INTEGRITY PACT |
| d. | APPENDIX **IV** : POLICY FOR PROVIDING PREFERENCE TO DOMESTICALLY MANUFACTURED IRON & STEEL PRODUCTS IN GOVERNMENT PROCUREMENT. |
| e. | APPENDIX **V** : POLICY OF HOLIDAY LISTING OF VENDORS IN BPCL |
| f. | APPENDIX **VI** : VERIFICATION OF MSE REGISTRATION CERTIFICATE BY CHARTERED ACCOUNTANT. |
| g. | APPENDIX **VII** : ACKNOWLEDGEMENT CUM CONSENT LETTER. |
| h. | APPENDIX **VIII** : E-PROCUREMENT GUIDELINES. |
| i. | APPENDIX-**IX** : PROVISIONS REGARDING ELIGIBLE BANKS FOR SUBMITTING EMD/ PBG AND LIST OF BANKS |
| **4.** | **BID DATA SHEET (BDS)** |
| **5.** | **BIDDING FORMS** |
| **6.** | **GENERAL CONDITIONS OF CONTRACT (GCC)** |
| **7.** | **SPECIAL CONDITIONS OF CONTRACT (SCC)** |
| **8.** | **ANNEXURES TO SCC** |
| a. | Appendix-**A**: TAXES AND DUTIES |
| b. | Annexure – **I**: Time for Completion |
| c. | Annexure – **II**: Terms of Payment |
| d. | Annexure – **III**: Measurement of Work |
| e. | Annexure – **IV**: Price Variation |

## PART – I – COMMERCIAL


| S. NO. | DESCRIPTION |
|---|---|
| f. | Annexure – **V:** Key Construction Manpower to be deployed by the Contractor during execution of Works |
| g. | Annexure – **VI**: Qualification & Experience Requirement of Key Construction Personnel and Penalty for Their Non-Mobilization |
| h. | Annexure – **VII**: Specification for Quality Management System requirements from Bidders |
| i. | Annexure – **VIII**: Key Construction Equipments to be mobilized by the Contractor during execution |
| j. | Annexure – **IX**: Calibration Requirements of Monitoring and Measuring Devices at Construction Site |
| k. | Annexure – **X**: Conditions for issue and reconciliation of materials |
| l. | Annexure – **XI**: Specification for Documentation requirements from Contractors |
| m. | Annexure – **XII**: Procurement of TMT Bars, Structural Steel and Cement By Contractor |
| n. | Annexure – **XIII**: Approval of Construction Sub-Contractor |
| o. | Annexure – **XIV**: Standard Specification for Health, Safety & Environmental Management at Construction Sites (doc no. 6-82-0001 Rev-2) & BPCL Safety Manual |
| p. | Annexure – **XV**: OISD 192 & OISD 207 |
| q. | Annexure – **XVI**: List of Eligible Banks for Submitting PBG/ABG etc |
| r. | Annexure – **XVII**: Energy Policy |
| s. | Annexure – **XVIII**: Discontinuation of Hydra Cranes within Refinery premises- |
| t. | Annexure – **XIX**: Labour Compliances |
| u. | Annexure – **XX**: Social Media Policy |
| v. | Annexure – **XXI**: Advisory on Environmental Criteria |
| w. | Annexure – **XXII**: Procedure for Vendor Invoice Processing |
| x. | Annexure-**XXIII** : Proforma of Advance Bank Guarantee |
| y. | Annexure-**XXIV :** Special Instructions to Contractors |


## PART – II – PRICE PART


| SR. NO. | DESCRIPTION |
|---|---|
| 1. | PREAMBLE TO SCHEDULE OF RATES |
| 2. | SCHEDULE OF RATES – FORM SP-0 |
| 3. | DETAILED SCHEDULE OF RATES (PRE-FILLED) (**FORM SP-1**) |
| 4. | DELETED |


## PART – III – TECHNICAL PART


| SR. NO. | DESCRIPTION |
|---|---|
| 1. | TECHNICAL SECTION (DOCUMENT No. : **B957-300-16-43-MR-T-3001** ) |

| | | |
|---|---|---|
| Bharat Petroleum | **INVITATION FOR BIDS (IFB)**<br>**FOR**<br>**MECHANICAL WORKS FOR ETHYLENE CRACKER UNIT(ECU) OF BINA PETCHEM AND REFINERY EXPANSION PROJECT(BPREP) OF M/S BHARAT PETROLEUM CORPORATION LIMITED (BPCL)**<br>**(DOMESTIC COMPETITIVE BIDDING)** | ई.आई.एल |
| **BIDDING DOCUMENT NO.: JP/B957-300-MR-T-3001/1030** | | |

## 1. INTRODUCTION:

**1.1.** M/s Bharat Petroleum Corporation Limited (BPCL) is setting up a Petrochemical Complex including a world scale Ethylene Cracker and Associated Units and Ethylene and Propylene based Petrochemical units for its diversification to Petrochemicals along with expansion of its BINA Refinery capacity to about 12 MMTPA located at Bina, Madhya Pradesh.

**1.2.** BPCL has appointed Engineers India Limited as the EPCM Consultant for the project.

**1.3.** EIL, on behalf of BPCL, Bina Refinery, invites e-Bids for **"MECHANICAL WORKS FOR ETHYLENE CRACKER UNIT(ECU)"** from competent contractors in the category of **Class-I Local Supplier** as defined in the PPP MII,2017 order enclosed elsewhere in the Bidding document, under **single stage two bid system** with sound commercial and financial capabilities meeting the Qualification Criteria stated in clause no. 5 below.

## 2. BRIEF SCOPE OF WORK:

**2.1.** Brief Scope of Work for the subject tender is as follows:

- Erection of all Rotating, Static, Packaged and Miscellaneous equipment along with their Ladder, platform and other accessories in all respect
- Installation of Equipment Internals in all respect
- Transportation of required piping materials including shop fabricated piping spools from Owner's storage to work site/shop, Shop & field fabrication, Erection of piping and prefabricated piping spools along with its branches and attached supports, alignment, cutting, beveling, fit up, welding, supporting, non-destructive examination, pressure testing, heat treatment, box up etc.
- Erection of all inline instruments
- Fabrication of piping specials like special radius bends, reducers, mitres, etc.
- Fabrication and erection of pipe supports
- Radiography, stress relieving, dye penetration test, magnetic particle test, Digital radiography and UT as per scope of work
- Fabrication and erection of small structures for pipe supports and valve operation / attending some instruments etc.
- Fabrication and Erection of Jacketed Piping, Fire water piping
- Insulation , Painting and Fire proofing
- Steam tracing and Electrical tracing works for piping and equipment
- Hydrotesting of loops, Flushing, Rotomol cleaning and testing of all piping
- Hydraulic bolt tensioning & torquing shall be performed on flange joints
- Loading of Chemical, Catalyst, Clay Inert Balls etc
- Pre-commissioning and Commissioning assistance

**2.2.** Bidder to refer the Technical section of the Bidding document for complete details of scope of work.

**3. TIME SCHEDULE FOR COMPLETION [For Part-A & Part-B]:**

**3.1** **Mechanical Completion [For Part-A & Part-B] :** Time for completion of works shall be **21 (Twenty One) Months** from the date of Letter of Acceptance (LOA)**.**

**3.2** **Pre-Commissioning/Commissioning Assistance [For Part-A & Part-B]: 3 (Three) Months** from Mechanical Completion.

**4. SALIENT FEATURES OF THE BIDDING DOCUMENT ARE AS FOLLOWS**:

**4.1. Salient Features**

| | | | |
|---|---|---|---|
| a) | Type of Enquiry | : | **DOMESTIC COMPETITIVE BIDDING**<br>**(E-BIDDING)**<br>**Under Two Bid System** |
| b) | Bidding Document availability on Website | : | **18.05.2026 to 08.06.2026**<br><br>Bidding Document/ Tender documents can be downloaded free of charge from GeM-CPP Portal website http://eprocure.gov.in/eprocure/app during the above period. |
| c) | Last date for submission of pre-bid queries | : | **27.05.2026** |
| d) | Date /Time of Pre-Bid Meeting # | : | **29.05.2026 at 1100 Hrs** |
| e) | Contact Details & Venue for Pre-Bid Meeting (Offline) /Site Visit | : | **Date of Site-Visit:**<br><br>**29.05.2026 at 1000 Hrs**<br><br>**Venue:**<br><br>Bharat Petroleum Corporation Limited,<br>Administrative Building, Refinery Complex,<br>Petro Chemical Unit,Post BORL residential complex-470124<br>Bina, District-Sagar, Madhya Pradesh, India.<br><br>**Contact Person from BPCL:**<br><br>1. **Mr. R H Panchal CGM-BPCL U&O (Project Manager)**<br>Mobile : +91 9819141449<br>Email: panchalrh@bharatpetroleum.in<br><br>2. **Mr. Manish Agrawal, GM BPREP**<br>Mobile : +91 9892517880<br>Email: agrawalmp@bharatpetroleum.in<br><br>**Contact Person from EIL:**<br><br>1. **Mr. K. Suresh, RCM, EIL**<br>Mob No.: +91 9869407762<br>Email: k.suresh@eil.co.in; |

| | | | |
|---|---|---|---|
| | | | **2. Mr. Akash Gupta, Sr. GM(Projects-EIL)**<br>Email: akash.gupta@eil.co.in<br><br>3. **Mr. Arun Singh Arya, AGM(Projects) EIL**<br>Mob No.: +91 9818800617<br>Email: arun.arya@eil.co.in<br><br>**Bidder to bring their own PPEs for Site visit during Pre-Bid meeting.** |
| f) | Address for Pre-Bid Meeting (Online) | : | **Pre-Bid Meeting shall be carried out through Physical Mode Only as per below details.**<br><br>➢ Date & Time: **29.05.2026 at 1100 Hrs**<br>➢ Venue for Physical meeting shall be as per (**e**) above |
| g) | Last Date and time for submission of e-Bids | : | **08.06.2026 at 1200 Hrs. (IST)** |
| h) | Cost of Bidding Document / Bidding Document Fee | : | Not Applicable. |
| i) | Bid Security / Earnest Money Deposit (EMD) | : | **INR 10,00,00,000/-** (Indian Rupees Ten Crore only)<br>**Also refer clause 6. of IFB below for details** |
| j) | Last date and time of submission of Earnest Money Deposit (EMD) /Bid Security ( In original hard copy ) | **:** | **Refer clause 6. of NIT/ IFB** |
| k) | Non-Disclosure Agreement (NDA) | : | Not Applicable. |
| l) | Opening of Techno-commercial (Un priced) Bids # | : | **09.06.2026 at 1200 Hrs. (IST)**<br>(On-line Opening shall be conducted) |
| m) | Integrity Pact Agreement | : | **Applicable** |
| n) | Bidding Document & subsequent Addendum/ Corrigendum (if any) available on Website for viewing & downloading | : | The Detailed Bidding Document along with Qualification Criteria, Integrity Pact and Bidding Document / Forms etc. can be viewed / downloaded from the Following website:<br><br>GeM-CPP Portal http://eprocure.gov.in/eprocure/app |
| o) | Mode of Submission | : | Offer must be uploaded on e-tender website GeM-CPP Portal http://eprocure.gov.in/eprocure/app before the last date & time of submission of tender.<br>Offer submitted using any other mode will not be accepted. |

| | | | |
|---|---|---|---|
| p) | Contact person for any query/ clarifications for this tender | : | **Queries to be addressed & forwarded to:**<br>Mr. Aritra De- AGM (SCM)/ Mr. Bapi Baidya- AGM (SCM) / Mr. Jaydip Purkayastha-GM (SCM)/ (Tel : +91 124 2891365/1307/1287)<br>(Mobile No.: Aritra De: +91 8130212692; Bapi Baidya: +91 9401708411)<br>E-mail: aritra.de@eil.co.in ; bapi.baidya@eil.co.in ;jaydip@eil.co.in; arun.arya@eil.co.in ) |
| q) | Opening of Priced Bids | : | The EIL/Owner will open price bids online. The bidder's who qualify pursuant to bid evaluation shall be able to view online the prices of all other bidder's who qualify pursuant to bid evaluation at their respective windows, after price bid opening by EIL / Owner. |

**4.2.** If the date indicated at Sl. No. **4.1 d), e) & l)** above happens to be a declared/closed holiday in EIL/BPCL BINA Refinery, the next working day shall be considered.

**4.3.** **All revisions, amendments, time extensions, clarifications, etc. to the IFB/NIT/Bidding Document shall be uploaded in the websites only and shall not be published in Newspapers. Bidders should regularly visit the above-mentioned website(s) to keep themselves updated and submit their Bids based on latest information/instructions hosted in website(s).**

**4.4.** Bidder shall submit all their requests for extension of Bid submission date (if unavoidable) and/or any queries prior to and/or during the pre-bid meeting. EIL/BPCL may at its sole discretion extend Bid submission due date on such written requests if the time schedule permits.

However, request for extension of Bid submission date or any queries received from any bidder with less than **Three (03)** working days prior to bid submission due date shall generally be ignored, since there will not be adequate time for proper communication with the other Bidders.

## 5. BIDDER QUALIFICATION CRITERIA (BQC):

The bidder shall be sole bidder.

Bidder shall fulfil the following qualification criteria in order to qualify for the work(s):

### 5.1. EXPERIENCE CRITERIA –COMMERCIAL:

**5.1.1.** The Bidder should have completed at least One or Two or Three Contracts of **"Similar Works"** (#) having Minimum Value(s) for the respective part(s) as indicated in **Table-1** below during last **10 (Ten) years**, reckoned from the last day of the month previous to the one in which enquiry was issued:

**Table-1**

| Description | PART-A | PART-B |
|---|---|---|
| *(Column-1)* | *(Column-2)* | *(Column-3)* |
| One contract of value not less than | **INR 176,83,19,000** ***[Indian Rupees One Hundred Seventy Six Crore Eighty Three Lakh Nineteen Thousand Only]*** | **INR 139,81,79,000** ***[Indian Rupees One Hundred Thirty Nine Crore Eighty One*** |

| Description | PART-A | PART-B |
|---|---|---|
| *(Column-1)* | *(Column-2)* | *(Column-3)* |
| | | ***Lakh Seventy Nine Thousand Only]*** |
| Two contracts each having value not less than | **INR 117,88,80,000** ***[Indian Rupees One Hundred Seventeen Crore Eighty Eight Lakh Eighty Thousand Only]*** | **INR 93,21,19,000** ***[Indian Rupees Ninety Three Crore Twenty One Lakh Nineteen Thousand Only]*** |
| Three contracts each having value not less than | **INR 94,31,04,000** ***[Indian Rupees Ninety Four Crore Thirty One Lakh Four Thousand Only]*** | **INR 74,56,96,000** ***[Indian Rupees Seventy Four Crore Fifty Six Lakh Ninety Six Thousand Only]*** |

**5.1.1.1** **(#) Definition of Similar works [For Part-A & Part-B]:**

*"Mechanical works involving fabrication & erection of Piping and Equipment erection in process unit/process units+ offsite of Hydrocarbon/Fertilizer/Chemicals Sector"*

**5.1.1.2** Bidder may quote either for Part-A or Part-B or for both parts. However, Part-A & Part-B shall be awarded to separate contractors on least cost combination basis as per Award Methodology mentioned at Clause No. **5.3** of IFB.

**5.1.1.3** If the Past Reference submitted by Bidder includes equipment Supply component more than 30% of Completed value, the equipment Supply portion of Past experience beyond 30% of Completed value shall not be considered for Bid Qualification purpose.

If the Past Reference submitted by Bidder includes equipment Supply component upto 30% of Completed value, the Completed value of Past experience shall be considered for Bid Qualification purpose.

Bidder shall be required to submit declaration with respect to component of equipment supply portion along with relevant documents in support of Bidders declaration for assessment of supply component.

**5.1.1.4** The value of Insulation AND / OR painting work, if part of work order, shall be considered as part of Mechanical Work for qualification purpose.

**5.1.1.5** For the purpose of Experience Criteria- Commercial as mentioned in clause No. **5.1**. of BQC, if the work order covers the activities beyond Mechanical Completion (i.e. Pre-commissioning and Commissioning/ Commissioning Assistance, PGTR), the value of these activities will be considered only if these activities are completed and bidder has to provide necessary documentation certified by Owner/PMC in this regard. However, value of Annual Maintenance Contracts shall not be considered for qualification purpose.

**5.1.1.6** If the work(s) executed is in combination of process unit & offsite, then cumulative value of such works shall be considered. However, exclusive experience of offsite work shall not be considered.

**5.1.2.** **For experience based on Composite Works**:

**5.1.2.1** In case the Bidder has executed composite work which includes the qualifying work(s) as per Clause No. **5.1.1** of BQC above, then the value of such qualifying works(s) out of the total value of Composite Work shall be considered for the purpose of qualification.

**5.1.2.2** The works carried out by Bidder for Mounded Bullets, Spheres, Storage Tanks and Cross-Country Pipeline Laying Works, shall not be considered as relevant experience to meet the experience criteria. However, such works shall be considered as Composite Works and the value of the qualifying work(s) {as per the definition of "Similar Work" (defined in Clause No. **5.1.1.1** above)} out of the total value of Composite Works shall be considered for the purpose of qualification.

**5.1.3.** Experience of only the Bidding entity shall be considered.

**5.1.4.** **For experience based on EPC/LSTK works**: In case bidder has executed EPC/LSTK/ multidisciplinary works which includes the similar work(s) as per Clause No. **5.1.1** of BQC above, then the value of such qualifying work(s) out of the total value of EPC/LSTK/multi-disciplinary works shall be considered for the purpose of qualification.

**5.1.5.** **Bidder's past experience as Consortium/JV:**

Bidder's past experience as a leader or member of a Consortium/JV shall be considered acceptable, provided his scope in that Consortium/JV meets the requirement stipulated in **Cl. No. 5.1.1** of BQC under evaluation.

In case, the PTR of Consortium/JV experience submitted by the Bidder meets the similar work(s) as per Clause No. **5.1.1.1.** of BQC above without indicating the division of scope of work in terms of specific activities and associated value of work between the Consortium/JV members, but only the division of scope in terms of percentage share is indicated, in such case the completed value shall be arrived at after considering percentage share of each member, for the purpose of qualification.

**5.1.6.** **Experience of Bidder as a Sub-Contractor:**

A job completed by a Bidder as a Sub-Contractor shall be considered for the purpose of meeting the experience criteria of BQC Clause No. **5.1.1** above, provided the appointment of sub-contractor was authorized and subject to submission of following documents in support of meeting the "Bidder's Qualification Criteria":

a) **Documentary evidence/Certificate issued by the end-User/Owner/PMC**, with regards to approval of Bidder/engaging Bidder/execution by the Bidder as a Sub-Contractor to the Main Contractor.

b) **Work order and Completion Certificates indicating the value of works and date of completion** issued by Main Contractor (including SOR/SOP, incase required for establishing scope of work). Completion certificate issued by PMC / Owner/ End-user shall also be acceptable.

**5.1.7.** **Experience of Own Projects**

Experience of only the Bidding entity shall be considered. A job executed by a Bidder for its own plant/projects shall not be considered as experience for the purpose of meeting the Qualification Criteria of the Enquiry document.

However, Jobs executed for Subsidiary/ Fellow subsidiary / Holding company shall be considered as experience for the purpose of meeting BQC Cl. No. **5.1.1.** above , subject to submission of additional document towards "tax paid invoice(s) duly certified by Statutory Auditor of the Bidder or consolidated statement issued by Statutory Auditor of the Bidder towards payments of statutory tax" in support of the job executed for Subsidiary/ Fellow subsidiary / Holding company.

In case referred Project falls under "No Tax Area" (like SEZ), Bidder can submit certificate from their Statutory Auditor to this effect in place of Tax paid invoice.

Chartered Accountant (CA) (in place of Statutory Auditor) is acceptable where audited accounts are not mandatory as per law for latest financial year. Also, CA shall not be an employee/ Director and not having any interest in the Bidder's company/Firm.

**5.1.8.** In case, Two separate Bidders submit reference of same work (wherein one was Main Contractor and the other was Sub-Contractor) for meeting Bidder Qualification Criteria, both Bidders' experience shall be considered for qualification subject to Bidder's meeting other qualification requirement.

**5.1.9.** In case a Bidder submits PTR having job awarded for multiple Parts in single Work Order having separate completion schedule for each Part, and the Bidder wants to get qualified based on the completion of One or more Parts (irrespective of whether all Parts under the same work order are completed or not), which meets the subject BQC value-wise and with respect to Qualifying work(s) as per clause of BQC Cl. No. **5.1.1** above, the same may be considered subject to the completion certificate with executed value of that/those Part(s) from the Owner/End User/PMC for that/those Part(s).

However, where multiple-parts work is awarded under different Work Order(s) having different Work Order reference number(s) with the same Enquiry Document No., cumulative value of such completed Work Orders meeting definition of Qualifying work(s) as per Clause No. **5.1.1** of BQC above, as submitted, shall be considered for the purpose of qualification.

**5.1.10.** The executed Contract Price as per the Completion Certificate shall be considered for meeting value based Experience Criteria of BQC.

However, if the completion certificate also indicates details of taxes & duties, then these values of taxes and duties shall be excluded for evaluation.

**5.1.11.** The **annual inflation** in the value of contract executed by the Bidder under the past experience shall not be considered.

**5.1.12.** In case currency indicated in the BQC related document (work order/completion certificate etc.) submitted by Bidder towards qualification of value-based experience criteria is other than in Indian Currency/specified foreign currency, the value of work shall be derived to Indian Currency/specified foreign currency considering "**RBI Reference Rate"** as on the **date of award of work**.

In case, the RBI Reference rate is not available as on the date of conversion as specified above for respective cases, the currency conversion rate shall be SBI TT Sell (Telegraphic Transfer). Further in absence of SBI TT Sell (Telegraphic Transfer), the conversion Rate shall be taken from the Internet, such as:

https://www.xe.com/currencyconverter
https://www.oanda.com/currency/converter
https://economictimes.indiatimes.com/markets/forex/currency-converter

## 5.2. FINANCIAL CRITERIA:

### 5.2.1. AVERAGE ANNUAL TURNOVER:

Bidder must have average annual turnover not less than values mentioned in Table-2 below during the immediate preceding three financial years.

**Table-2**

| PARTS | AVERAGE ANNUAL TURNOVER |
|---|---|
| For Part-A | INR 176,83,19,000 |

| PARTS | AVERAGE ANNUAL TURNOVER |
|---|---|
| | ***[Indian Rupees One Hundred Seventy Six Crore Eighty Three Lakh Nineteen Thousand Only]*** |
| **For Part-B** | **INR 139,81,79,000**<br>***[Indian Rupees One Hundred Thirty Nine Crore Eighty One Lakh Seventy Nine Thousand Only]*** |

**Note : Turnover** shall be taken as **Revenue from operation** as stated in Financial Statement of the Bidder, excluding other Income. GST, if applicable, shall be excluded.

**5.2.2. NET-WORTH:**

The financial net worth of the Bidder as per the latest audited annual report shall be **positive**.

**Net worth calculation: Net-worth means paid up share capital, Share Application Money pending allotment* and reserves# less accumulated losses and deferred expenditure to the extent not written off**. Net worth shall be calculated using the following formula:

# Reserves to be considered for the purpose of net-worth shall be all reserves created out of the profits and securities premium account but shall not include reserves created out of revaluation of assets, write back of depreciation and amalgamation.

*Share Application Money pending allotment will be considered only in respect of share to be allotted.

| Description | | Values (in INR) | Reference (Page no., Clause etc.) |
|---|---|---|---|
| Paid up share capital (A) | : | | |
| Add: Share Application Money pending allotment (B) | : | | |
| Add: Reserves (As defined Above) (C) | : | | |
| Less: Accumulated Losses (D) | : | | |
| Less: Deferred Revenue Expenditure to the extent not written off (E) | : | | |
| Net-worth (A+B+C-D-E) | : | | |

**5.2.3. Bidder should have completed 3 financial years of existence as on original due date of tender since date of commencement of business.**

**5.2.4.** The Financial statements shall be reviewed in respect of financial criteria under Bidder Qualification Criteria. However, in case any matter is referred in the notes to accounts and schedules referred in balance sheet and profit & loss account then, only quantified qualified/ adverse/ disclaimer opinion in the statutory auditor's reports, if any, having impact on financial criteria shall be considered for evaluation.

**5.3. PRICE OPENING, EVALUATION AND AWARD METHODOLOGY [ONE PART TO ONE CONTRACTOR]:**

a) Bidder quoting for Part-A / Part-B shall meet the **Experience Criteria (Commercial) and Financial Criteria** corresponding to that/those part(s) i.e., Part-A / Part-B.

b) Prices for all the parts shall be opened together.

c) **Work of only one part will be awarded to a bidder.**

d) Award shall be on **partwise L-1** basis.

e) In case a bidder happens to be L-1 in more than one part, the evaluation and award shall on **least cost combination basis** to BPCL.

## 5.4. DOCUMENTATION AND DATA REQUIRED WITH THE BID:

### 5.4.1. For Experience Criteria – Commercial as per clause no. 5.1 above:

a) The bidder shall, in his own interest, furnish complete documentary evidence to justify that the bidder meets the Qualification Criteria.

b) Bidder shall complete and submit the details of specific experience fulfilling qualification criteria, past experience in support of BQC in relevant forms provided under the Proposal Form/IFB of the Bidding Document (Along with supporting documents mentioned) to establish that the bidder meets the BQC as per Clause No**. 5.1.1** of BQC above.

c) Bidder shall submit the following documents in order to meet the Experience Criteria – Commercial of BQC as per Clause No. **5.1** above:

i. Work Order

ii. Completion Certificates (having co-relation with Work Order)

iii. Any other relevant documents, if required, to substantiate the executed value of Qualifying Works and to establish the Qualifying work(s) as per clause no. **5.1** of BQC **above**, co-relating the work order and/or Completion certificate, including but not limited to the certificate from Owner/End User/PMC, certified copy of invoice/final bill, SOR, Payment Terms etc.(as applicable)

d) **Documents to be submitted by Bidder in case of experience based on EPC/LSTK works**: In case of experience based on EPC/LSTK work, in the event the qualifying requirement of Qualifying work(s)/ experience criteria as per above clause no. **5.1.1** above cannot be ascertained from the work order/ completion certificate submitted by bidder, copy of relevant pages of Contract or Copy of relevant pages of final bill certified by Owner/Consultant or letter from their Owner/Consultant specifying the executed value(s) of Qualifying work(s) as per IFB, can be submitted for qualification to establish the value of similar work.

However, if the above document could not establish the value of Qualifying work(s), Billing Schedule/ Billing Break-up approved by Owner/ Consultant can also be considered for establishing the value of Qualifying work(s).

e) Any direct email communication from Bidder's Client/ PMC (from their domain server) [of whom Bidder has submitted the past experience] to EIL shall be acceptable for establishing work experience. The same shall be considered as an authentic document.

### 5.4.2. For Financial Criteria as per clause no. 5.2 above:

a) Bidder shall furnish Copy of Complete Audited Annual Financial Year Statements including Annual Report, Audited Balance Sheets, Profit and Loss Accounts and all other schedules etc. for previous three financial years along with the Bid to establish Bidder's conformance to Financial Criteria and prove existence since three years.

b) The Institute of Chartered Accountant of India at its 379th council meeting dated 17-18th December, 2018 made generation of Unique Document Identification Number (UDIN) mandatory for every signature of full time practicing chartered accountant in phased manner for following services:

i. All certificates with effect from 1st February, 2019.

ii. GST and Income Tax Audit with effect from 1st April, 2019.

iii. All Audit and Assurance Functions with effect from 1st July, 2019.

In view of the above, bidder shall ensure that any certificate/ reports issued/ attested by an practicing chartered accountant in India and submitted in the bid shall mandatorily include the UDIN number. Certificate / reports issued/ attested without UDIN number of practicing chartered accountant in India shall not be considered for evaluation.

However, this requirement of including UDIN shall not be applicable for certificate/reports issued/attested by a CA practicing in foreign country.

In case the financial year closing date is within 6 months of original bid due date and audited annual report of immediate preceding financial year is not available, Bidder has the option to submit the financial details of the three previous years immediately prior to the last financial year.

In case the financial year closing date is within 6 – 9 months of original bid due date and Audited annual report of immediate preceding financial year is not available, Bidder has the option to submit the financial details of the three previous years immediately prior to the last financial year provided Bidder submits a letter from CA stating the reasons of non-preparation/furnishing of the latest year's Audited Financial Statements.

In case the financial year closing date is beyond 9 months of original bid due date, it is compulsory to submit the financial details of the immediate three preceding financial years.

Example, in case, audited annual report of immediate preceding financial year (For Example year ending 31st March) is not available and where bid closing date is up to 31st December, the financial details of the three previous years immediately prior to the last financial year may be submitted. However, in case the bid closing date is after 31st December, it is compulsory to submit the financial details of the immediate three preceding financial years only.

c) **Submission of Consolidated Audited Financial Statement:**

i. In case a bidder (a Parent Company) is having wholly owned subsidiaries but only a single consolidated annual report is prepared and audited which includes the financial details of their wholly owned subsidiaries, consolidated audited annual report shall be considered for establishing the financial criteria subject to statutory auditor of the bidder certifying that separate annual report of bidder (without the financial data of subsidiaries) is not prepared and audited.

ii. Further, in case a bidder is a subsidiary company and separate annual report of the bidder is not prepared & audited, but only a consolidated annual report of the Parent Company is available, consolidated audited annual report shall be considered for establishing the financial criteria subject to statutory auditor of the parent company certifying that separate annual report of the Bidder is not prepared and audited.

d) Any shortfall information / document on Audited Annual Reports/ Financial Statements of the Company, audited and issued on or before the bid due date may be asked through CQ, but bidder shall not be allowed to submit the Financial Statements of the Company audited & issued post final bid due date & time. Accordingly, Financial Statements of the Company audited and issued post final bid due date & time shall not be considered for evaluation.

e) Bidder shall submit Certificate of Incorporation (or Partnership deed/ Proprietorship affidavit etc. as applicable) to fulfil the existence criteria as per clause **5.2.3** above.

**5.5. AUTHENTICATION AND VERIFICATION OF BQC DOCUMENTS:**

**5.5.1.** It is bidder's prime responsibility to submit genuine and authentic documents. No amount of checking or verification by the buyer/ EIL/ BPCL shall absolve bidder from his responsibility.

Under the EIL suspension / banning rules (available on EIL portal www.engineersindia.com) & guidelines and procedures for Holiday Listing as adopted by BPCL (available on BPCL website https://www.bharatpetroleum.in/pdf/holidaylistingpolicyfinal.pdf), the punishment for submission fake/false/forged documents/certificate is clearly mentioned. Moreover, other actions against the bidder like encashment of EMD or PBG depending upon the stage of discovery of the fraud / false documentation may be taken up by EIL/BPCL. Moreover, the bidder's organization is responsible for any and all actions of their employees and any claims seeking to pin point the blame on some employee of bidder and attempting to absolve the bidder's organization will not be entertained.

The bidder must also note that the EIL/BPCL reserves the right to proceed based on acceptable offer (who have submitted authenticated documents in line with the Clause No. **5.5.2** below) and reject outright the other bids which have some shortcomings including non-submission of authenticated documents. The bidder shall therefore submit the authenticated documents along with the offer itself and in case of rejection of his bid shall not have any right to seek another opportunity for submission of authenticated documents.

**5.5.2.** Bidder to comply the following:

i) Bidder shall furnish an undertaking in the format as per **Appendix-I to IFB** towards the authenticity of submitted BQC Documents, duly signed by the authorized signatory of Bidder holding Power of Attorney for signing of Bid.

Proprietorship/Partnership firms shall submit the undertaking as per **Appendix-I to IFB**, duly signed by the Proprietor/any two Partners.

ii) Requirement of above certification shall not be applicable to published audited annual financial statements in English, if original booklets are submitted.

iii) Bidders shall be required to upload the digitally signed authenticated copies of documents for meeting BQC on the e-tendering website only. Bidders shall not be required to submit the original of authenticated documents in physical form to EIL/ BPCL. In addition, bidder shall also confirm that all authenticated documents submitted for meeting the BQC are certified as per the authentication requirement defined in the Bidding Document.

**5.5.3.** The Bid and all correspondence incidental to and in connection with the Bid shall be in the English Language only. In case a Bidder submits any of the Bidder Qualification support documents in any language other than in English, then it shall be the responsibility of such Bidder to also provide the English translation copy of the same duly certified by either of the following:

a. Local Chamber of Commerce or Indian embassy in bidder's country or their embassy in India.
b. Any recognized/ authorized translator in India.

**5.5.4.** Submission of authentic documents is the prime responsibility of the Bidder. EIL/BPCL reserves the right of getting the document cross verified, at their discretion from the document issuing authority. Bidder shall provide all necessary assistance in this regard.

However, in addition to the above, EIL shall carry-out cross verification of the lowest evaluated bidders credentials submitted in the bid and considered by EIL for meeting the BQC- commercial experience

criteria and BQC - technical criteria from the document issuing authority. It shall be the responsibility of the bidder to assist EIL/BPCL in carrying out this exercise.

EIL/BPCL shall also reserve the right to communicate directly with the certificate issuing authority and /or carryout a visit to the office/works of the certificate issuing authority. Bidder shall provide complete assistance towards the same. Bidder to note that first payment against the contract, if placed, shall be released only on completion of the verification.

It shall, therefore, be the responsibility of the Bidder/ Contractor to get their BQC documents considered for qualification successfully verified as above.

Accordingly, bidder shall ensure that bidder shall submit those executed works meeting the qualification criteria for which they can arrange such verification.

Failure of cross verification shall entitle EIL/BPCL to reject the bid or terminate the Purchase Order / Contract, if already issued.

Bidder shall also render assistance in facilitating visit to the reference unit, if so considered necessary by owner. Cost of visit shall not be to the bidder's account.

**5.5.5.** In case the BQC documents have already been verified by EIL for any other enquiry/ tender, the same may also be considered verified on the strength of previous verification and accepted by EIL. However, in such a case, bidder shall indicate in their bid that PTR documents submitted in this bid has already been verified by EIL from Bidder's Client in tender no. _____ for the project _____.

**5.5.6.** The Bidder shall ensure submission of complete authentic information / documentation along with the Bid.

**5.5.7.** Wherever specific compliance to the relevant documentation from bidder in support of the criterion mentioned under Clause no. **5.1 & 5.2 above** is required post Bid submission, Owner/EIL reserves the right to directly interact with the Bidder's Owner/Consultants to verify the relevant documentation and the Bidder will render assistance in facilitating that.

**5.5.8.** Bidder shall also render assistance in facilitating visit to the reference unit, if so, considered necessary by owner. Cost of visit shall not be to the bidder's account. For further details please refer Clause No. 16.0 of ITB.

**5.6. GENERAL REQUIREMENTS:**

**5.6.1.** Failure to meet the above Qualifying Criteria at Clauses **5.1 & 5.2** above as applicable, will render the bid to be summarily rejected.

**5.6.2.** Bidder serving holiday listing order (valid as on final bid submission due date) issued by BPCL/MOP&NG/EIL or convicted of an offence under a) the Prevention of Corruption Act, 1988: or b) the Indian Penal Code or any other law for the time being in force, for causing any loss of life or property or causing a threat to public health as part of execution of a public procurement contract, shall not get qualified in this tender. A declaration to the above effect shall be submitted by bidder as on final bid submission due date. Offers not accompanied with such declaration shall make the bidders liable for rejection. Any wrong declaration in this context shall make the bidders liable for action under the holiday listing procedure.

**5.6.3.** A bidder who is on Holiday List /Negative List of EIL/BPCL on due date of submission of bid / during the process of evaluation of the bids, the offers of such bidders shall not be considered for bid opening/evaluation/award, as the case may be.

**5.6.4.** Bidders are required to submit all such past experience(s) (PTR) meeting the BQC along with relevant supporting documents in the first instance itself, along with the bid i.e. copies of work orders/ relevant pages of Contract/SOR/invoice/final Bill, completion certificate, from the Owner/ Consultant of work executed, copy of MOU with Sub-Contractor (as applicable), Audited annual Financial Statements

containing audited balance sheets and profit & loss accounts statement in the first instance itself, in support of their fulfilling the qualification criteria.Accordingly, only such past experience(s) shall be considered for qualification, details of which are provided in the bid by the bidder.

**5.6.5.** Bidder should ensure submission of complete information/documentation in the first instance itself, in support of their fulfilling the qualification/eligibility criteria. BPCL/EIL reserve the right to complete the evaluation based on the details furnished without seeking any additional information and / or in-house data, survey or otherwise. Subsequent to the submission of bid, bidders are not allowed to change the price or substance of the bid.

In case, a bidder does not meet the BQC based on experience documents (as specified in the Bidding Document) submitted in support of meeting the BQC**, their bid shall be rejected without issuing TQs/CQs.**

**However, if in case CQs/ TQs are issued,** bidders can be allowed to submit additional documents for any of the work out of the past experience(s) (PTR), list already submitted along with the bid, to support their bid meeting the BQC.

Bidders shall not be permitted to submit document related to new reference of work experience if not mentioned in the list (past experience) submitted along with the bid and any such submission shall not be considered for evaluation.

**5.6.6.** Bidders are required to sign all the pages of Integrity Pact and submit the scanned copy of Integrity Pact along with their bid. Format of INTEGRITY PACT is attached as Appendix-III to ITB. Non submission of Integrity Pact shall lead to the rejection of their bid.

**5.6.7.** Bidder shall not be under insolvency, liquidation, court receivership or similar proceedings. Bidder shall submit a self-certificate/declaration stating that they are not under insolvency, liquidation, court receivership or similar proceedings. Failure to do so or if the bidder is under insolvency, liquidation, court receivership or similar proceedings, their bids shall not be considered.

**5.6.8.** Bidder to ensure that relevant documents and information pertaining to PPP-MII, which are necessary for availing the relevant benefits during evaluation, must be updated / uploaded in the designated folder on Govt E-Tendering website.

**5.6.9.** The Bid and all correspondence incidental to and in connection with the Bid shall be in the English Language only. In case a Bidder submits any of the Bidder Qualification support documents in any language other than in English, then it shall be the responsibility of such Bidder to also provide the English translation copy of the same duly certified by either of the following:

a. Local Chamber of Commerce or Indian embassy in bidder's country or their embassy in India.
b. Any recognized/ authorized translator in India.

**5.6.10.** Any additional documents, if deemed necessary to establish the qualifying requirements may be submitted by the Bidder.

**5.6.11. Conflict of Interest**

A bidder shall not have conflict of interest with other bidders. Such conflict of interest can lead to anti-competitive practices to the detriment of Owner's interests. The bidder found to have a conflict of interest shall be disqualified.

A bidder may be considered to have a conflict of interest with one or more parties in this bidding process, if:

a. they have controlling partner (s) in common; or

b. they receive or have received any direct or indirect subsidy/ financial stake from any of them; or

c. they have the same legal representative/agent for purposes of this bid; or

d. they have relationship with each other, directly or through common third parties, that puts them in a position to have access to information about or influence on the bid of another Bidder; or

e. Bidder or any of its affiliates participated as a consultant in the preparation of the design or technical specifications of the contract that is the subject of the Bid;

f. In case of a holding company having multiple closely sister companies, then only one such companies should quote. Bidders must proactively declare such sister/ common business/ management units in same/ similar line of business.

**6. EARNEST MONEY DEPOSIT (EMD) / BID SECURITY:**

6.1 Bids must be accompanied with Earnest Money Deposit / Bid Security. Bids not accompanied with requisite Earnest Money deposit /Bid Security (or authenticated exemption certificate, wherever applicable) shall be considered as non-responsive and such Bids shall be summarily rejected.

EMD/Bid Security shall be in favour of Bharat Petroleum Corporation Limited in the form of Bank draft drawn in favour of Bharat Petroleum Corporation Limited or Electronic Fund Transfer to BPCL Bank Account (Details as per clause **6.2** below) or Bank Guarantee (BG) / e-Bank Guarantee (e-BG) executed as per eligible banks attached as **Appendix –V** to IFB in the proforma attached with Bidding Document/ Insurance Security Bond as per the provisions and format enclosed in General Conditions of Contract. **The BG/ Insurance Surety Bond shall remain valid for a period Two months beyond Bid validity subject to a minimum period of 6 months from final due date of opening of the tender.**

Bid Security shall be only **in INR.**

Proforma of Bank Guarantee/Insurance Surety Bond in lieu of Earnest Money Deposit shall be as per Proforma attached with General Conditions of Contract (GCC).

6.2 **Address of the Beneficiary** for the **Bank Guarantee/ Insurance Surety Bond in lieu of Earnest Money Deposit shall be as under:**

Bharat Petroleum Corporation Limited,
Administrative Building, Refinery Complex,
Petro Chemical Unit, Post BORL residential complex-470124
Bina, District-Sagar, Madhya Pradesh, India

In case of insurance surety bond, bidder shall also submit the Insurance Policy along with the Insurance Surety Bond.

6.3 **Bank Details of BPCL (For RTGS/NEFT)**

**Name of Bank:** State Bank of India
**Branch:** SARVODAYA CHAURAHA ,BINA, DIST. SAGAR (MP) - 470113
**Account No:** 32182313019
**IFSC Code:** SBIN0001427
**MICR Code:** 470002101

6.4 Scanned copy of EMD shall be uploaded in designated place in the above mentioned Govt E-Tendering website. Swift message/Cheque/Cash shall not be acceptable. In case, bidder fails to upload scanned copy of EMD on Govt E-Tendering website by the Final bid due date & time, such bid shall not be considered for evaluation.

6.5 EMD/ Bid Security, in addition to uploading on the Govt E-Tendering website along with the bid, shall also be submitted in Original physical form preferably before the bid due date and time but not later than **7 (Seven) calendar days** from bid due date and time. In case the EMD/ Bid Security in original physical form does not reach below mentioned address within the above cut-off date, his bid shall be rejected and not considered for further evaluation, irrespective of their status/ ranking in tender and notwithstanding the fact that a copy of EMD/Bid Security was earlier uploaded by the bidder on the e-Tendering website.

**Original EMD/Bid Security to be submitted at below address:**

**Mr. Jaydip Purkayastha, GM (SCM),**
**Engineers India Limited,**
**R&D Complex, Sector-16 (On N.H.-8),**
**Tower-1 (1ST Floor), Gurugram -122 001,**
**Haryana (India)**

6.6 In case EMD/ Bid Security is submitted through net-banking, submission of Original physical form of EMD/ Bid Security within the bid due date shall not be required. However, transaction details/ proof of submission of EMD/ Bid Security through net-banking shall be uploaded in designated place in the below-mentioned E-Tendering website http://eprocure.gov.in/eprocure/app.

6.7 Vendor shall insist their bank for issuance of SFMS Bank Guarantee for faster payments. Vendor shall provide BPCL's Bank Account No. & IFSC Code (Details given below) to their Bank as beneficiary at the time of application for Bank Guarantee in favour of BPCL. Issuing Bank shall issue the Bank Guarantee & send SFMS message to BPCL's Bank confirming the authenticity of Bank Guarantee who in turn shall send the confirmation to BPCL. Vendor should ensure the following for issue of e-bank guarantee:

a. The issuing bank is on SFMS platform.
b. SFMS Message type used is 760 COV and SFMS Delivery report /Message copy is sent along with original BG.
c. For BG amendment, message type 767COV is to be used.
d. SFMS contains following details:
   i. Beneficiary's bank name: ICICI Bank
   ii. IFSC Code: ICIC0000393
   iii. BPCL's Customer ID: BPCL583493800

e. BG Issuing bank should send the BG issuance advice through SFMS to BPCL's designated banker: ICICI Bank, Backbay Branch, Mumbai (IFSC: ICIC0000393).

f. BG Issuance advice should mention applicable Unique Identifier Code (UIC) in row/ field number 7037of SFMS Delivery Report.
   i. BPCL Location: Kharghar, Navi Mumbai
   ii. Head Office: Ballard Estate
   iii. UIC: BPCL583493800

g. The original BG should be submitted along with print out of SFMS Delivery report from the BG Issuing Bank Branch. SFMS BG will help in faster verification of BGs and prompt release of payment to vendors.SFMS BG will help in faster verification of BGs and prompt release of payment to vendors.

6.8 **There will be no exemption of submission of EMD/ Bid Security for MSE Bidders being a "Works Contract".**

## 7 SUBMISSION OF BIDS & VALIDITY:

7.1 Bids are required to be submitted only through above-mentioned E-Tendering website http://eprocure.gov.in/eprocure/app on or before the Bid submission date and time. Bidders are required to enroll on the E-Tendering website http://eprocure.gov.in/eprocure/app.

7.2 Bidders in their own interest are requested to upload/submit their bid well in time. In the event of failure in bidder's connectivity with the above-mentioned E-Tendering website http://eprocure.gov.in/eprocure/app during the last few hours, bidder is likely to miss the deadline for bid submission. Due date extension request due to above reason may not be entertained.

7.3 Physical Bids / Offers or Bids through any other mode shall not be accepted. The Offers submitted through above mentioned E-Tendering website http://eprocure.gov.in/eprocure/app shall only be considered for evaluation and ordering.

7.4 Bidders are requested to get acquainted with the E-Tendering website http://eprocure.gov.in/eprocure/app . in advance and obtain/seek clarifications, if any from EIL.

7.5 Bid shall remain valid for **04 (Four) months from the Bid Due Date or Extended Bid Due Date**, whichever is later.

## 8 PRE-BID MEETING AND IMPORTANCE OF ATTENDING PRE-BID MEETING:

8.1 Pre-bid Meeting shall be held on the scheduled date, time and place as stated in Sl. No. **4.1 d),4.1 e) & 4.1 f)** above.

8.2 Bidders or their competent authorized representatives are requested to attend the Pre-Bid Meeting so that their queries, if any, related to the Bidding document and Scope of Work etc. can be addressed during the pre-bid meeting to enable the bidder to submit Zero Deviation Bid.

8.3 Bidders shall treat the pre-bid meeting as of utmost importance in their own interest and depute competent & senior persons to understand the requirement and capable of taking spot decision to sort out all the technical, commercial and legal issues. Bidders are also advised to attend the pre-bid meeting along with their technical, commercial and legal representative, if so desired, to get all issues clarified to meet the project time schedule.

8.4 Bidders who are not attending the pre-bid meeting, it shall be considered that the bidder has a clear understanding of the scope, specifications, terms & conditions etc. of the bidding document and does not have any comments/ deviations to the requirements of the bidding document and their offer shall be strictly as per provisions of the bidding document without any deviation/clarification etc.

8.5 Bidders to note that BPCL/EIL reserves the right not to give any opportunity to the bidder after the final bid submission date and time for seeking any clarification or submission of balance documents not submitted earlier. Their bid shall be evaluated as per the documents submitted along with their bids.

8.6 To make the pre-bid meeting effective and result-oriented, the bidders are requested to send their queries/clarifications, if any, as per format included in the Bidding Document through **CPP Portal (https://eprocure.gov.in/eprocure/app)**within the cut-off date as mentioned against sl. no. 4.1 (c) above. Accordingly, queries which are not received through CPP Portal or after cut-off date may not be entertained. The clarifications to these shall be provided during the pre-bid meeting and consolidated response to these pre-bid queries will also be upload on the portal.

8.7 Any modification to the RFQ document, which may become necessary as a result of the pre-bid queries/ pre bid discussion, shall be intimated to all bidders through the issue of an Addendum/Amendment. Record notes/Replies of pre-bid meeting shall not be considered as part of RFQ/Bidding Document.

8.8 **Non- attendance of the pre-bid meeting will neither be a cause for disqualification of the bidder nor a cause for bidder's ignorance to submit the bid as per provisions of the bidding document and latest information uploaded in the Central Public Procurement Portal (CPPP)/Website of Government of India/ NIC Portal https://eprocure.gov.in/eprocure/app.**

9 **GENERAL GUIDELINES**

9.1 The complete Bidding Document can be downloaded from the CPP portal http://eprocure.gov.in/eprocure/app.

9.2 Bidders are required to submit their e-bids only through **CPP portal** http://eprocure.gov.in/eprocure/app in accordance with the instructions and terms & conditions of this Bidding Document.

9.3 Subsequent to the submission of bid, bidders are not allowed to change the price or substance of the bid i.e. scope of work, specifications, delivery schedule, completion period etc. including modification of the bid to meet the BQC.

9.4 Bids received after the Final Bid due date and time (refer late bids clause of ITB) shall be rejected and representative of such bidders shall not be allowed to attend the bid opening.

9.5 Consortium / Unincorporated Joint Venture Bids are **not acceptable.**

9.6 Bidder shall not be allowed to use the credentials of its parent company or any group company to meet the Experience Criteria-Commercial and Financial Criteria under clause no. 5 above.

9.7 In case any bidder is found to be involved in cartel formation, his bid will not be considered for evaluation/ placement of order. Such bidder will be debarred from bidding in future.

9.8 Canvassing in any form by the Bidder or by any other Bidder on their behalf may lead to disqualification of their Bid.

9.9 Purchase preference to central PSUs or any other government guidelines as applicable from time to time shall be considered.

9.10 **Physical / Fax / e-mail Bids (other than the documents specifically required to be submitted in hard form)** shall not be accepted.

9.11 Please acknowledge receipt of Bidding Document and immediately confirm your participation in the subject bidding as per proforma (ACKNOWLEDGEMENT CUM CONSENT LETTER) enclosed in the Bidding Document.

9.12 Unsolicited clarifications to the offer and / or change in the prices during the validity period would render the bid liable for rejection.

9.13 BPCL/EIL shall not be responsible for any expenses incurred by bidders in connection with the preparation & delivery of their bids, site visit and other expenses incurred during bidding process.

9.14 EIL/BPCL reserves the right to reject any or all Bids without assigning any reason, whatsoever.

9.15 Clarification, if any, can be obtained from GM (SCM), Engineers India Limited, R&D Complex, Sector-16 (On N.H.-8),Tower-1 (1st Floor), Gurugram-122 001,Haryana (India), Tel : +91 124 2891365/1307/1287 & E-mail: aritra.de@eil.co.in; bapi.baidya@eil.co.in ;jaydip@eil.co.in)

9.16 For detailed specifications, terms and conditions and other details, refer complete Bidding Document.

General Manager (SCM)
Engineers India Limited, Gurugram

**Appendix-I to IFB**

## FORMAT OF UNDERTAKING FOR AUTHENTICATION

**Bidding Document No.:**……
**Item/Work:**……

I, _____ S/o/D/o of _____, working as _____ {*authorized signatory of Bidder holding Power of Attorney for signing of Bid or proprietor / any two partners in case of Proprietorship / Partnership firms (indicate, as applicable) }* of the Company/Firm _____ having its registered office at _____ certify that all the details including documents pertaining to Bidder Qualification Criteria signed by undersigned vide our offer reference _____ against your Enquiry document _____, are true, authentic, genuine and exact copy of its original.

It is certified that none of the documents are false/forged or fabricated. All the documents has been submitted with full knowledge of (i) the provisions of the Indian laws in respect of offences including, but not limited to those pertaining to criminal breach of trust, cheating and fraud (ii) provisions of bidding conditions and iii) Suspension / Banning rules of Owner/ EIL, which entitle the Owner/EIL to initiate action in the event of such declaration turning out to be a misrepresentation or false representation.

It is further certified that, if any documents are required to be submitted by our company/Firm subsequent to submission of bid, shall also be submitted under my knowledge and shall be true, authentic, genuine copy of its original and shall not be false/forged or fabricated.

I hereby acknowledge that the Owner/EIL possesses the right to verify the BOC Documents from the relevant document issuing authority or end user. The results of this verification, as stated above, shall be binding upon our Company/Firm, without any opportunity for dissent or contestation.

I also accept that in case, at a later date, any of the document submitted in our bid referred above .is found to be false/forged or fabricated, I, shall be held responsible for the same and EIL/Owner has every right to take action against me and my company, as deemed fit as per law of land and provisions of the Bidding Documents and EIL/Owner's right to put our company on Suspension / Banning list for future business with EIL/Owner.

Specimen Signature of authorized signatory of bid

Signature
Name & Designation

(*authorized signatory of Bidder holding Power of Attorney for signing of Bid / Proprietor in case of Proprietorship Firm /any two Partners in case of Partnership firms (indicate, as applicable))*

**Appendix-IIA to IFB**

## DETAILSOFSPECIFICEXPERIENCEFULFILLINGQUALIFICATIONCRITERIA
## (AS CALLED FOR IN "BIDDER QUALIFICATION CRITERIA"OF NOTICE FOR INVITATION FOR BIDS)

**Name of Bidder: _____**
**Name of Works: MECHANICAL WORKS FOR ETHYLENE CRACKER UNIT(ECU)**
**Bidding Document No.: JP/B957-300-MR-T-3001/1030**

Furnished below are the details required for meeting the qualifying requirements as calledfor in Experience Criteria of IFB:

(For applicability mark √ and Non-applicability mark X in ☐)

| Sl. NO. | DESCRIPTION | DETAILS |
|---|---|---|
| 1.0 | **Bidder to indicate basis of Qualification considering One Contract/Two Contracts/ Three Contracts . Accordingly bidder to furnish details of their past Experience for each contract.** | One Contract ☐<br>TwoContracts ☐<br>Three Contracts ☐ |
| 2.0 | Name of Project and its location | |
| 3.0 | Name of work | |
| 5.0 | Name of Owner, Postal Address, Phone/ Fax No./ E-mail Address – Updated as on date | |
| 6.0 | Name of Consultant, Postal Address, Phone/ Fax No./ E-mail Address – Updated as on date | |
| 7.0 | Details of Work executed | |
| | Milestone Dates | • Date of award :_____<br>• Actual Completion Date :_____ |
| | Supporting Document for Experience Criteria | • Whether copy of Work Order/Contract Agreement /Schedule of Rates enclosed<br>YES ☐ NO ☐ |

| SI. NO. | DESCRIPTION | DETAILS |
|---|---|---|
| | | Ref. No.: _____ dated _____<br>**Awarded Value of Work** _____<br>• Whether Completion Certificate/Final certified bills enclosed.<br>YES ☐ NO ☐<br>Ref. No.: _____ dated _____<br>**Final Completed value of work** _____ |
| 8.0 | Whether Worked as Contractor directly with Client or Sub-contractor of Contractor | Executed the Workas<br>• Main Contractor ☐<br>• Sub-contractor ☐ |
| 9.0 | Supporting Document for Qualification Criteria | • Whether Work Order/ Contract Agreement / Schedule of Rates / Final certified bills / Completion Certificate is enclosed.<br>YES ☐ NO ☐<br>If Yes, (Please tick mark √the applicable)<br>1. Workorder :Yes/No<br>2. Contract Agreement :Yes/No<br>3. Schedule of Rates :Yes/No<br>4. Final certified bills :Yes/No<br>5. Completion Certificate :Yes/No<br>• Whether Annual Turnover and P&L account Statement for all the financial years as mentioned in IFB is enclosed.<br>☐ YES ☐ NO |

**SIGNATUREOF BIDDER** : _____

**NAMEOF BIDDER** : _____

**COMPANYSEAL** : _____

**Appendix-IIB to IFB**

| SL.NO. | DESCRIPTION OF WORK | POSTAL ADDRESS OF CLIENT &NAMEOF OFFICERIN CHARGE | CONTRACT VALUE | STARTING DATE | SCHEDULED COMPLETION DATE | ACTUAL COMPLETION DATE | ACTUAL COMPLETED VALUE | REASONS FORDELAY, IF ANY | WHETHER WORKS EXECUTEDASMAIN CONTRACTOR OR SUB CONTRACTOR |
|---|---|---|---|---|---|---|---|---|---|
| | | | | | | | | | |

**Note:** Copies of work order(s) and completion certificate(s) for above jobs should be submitted by the Bidder along-with this form.

**SIGNATUREOFBIDDER** : _____

**NAMEOFBIDDER** : _____

**COMPANYSEAL** : _____

**Appendix – III to IFB**

**PROFORMA OF DECLARATION TOWARDS "CONFLICT OF INTEREST"**
**(To be submitted by the participating bidders)**

I/We, ..... {Name(s) of Authorized Signatory (ies)}, on behalf of M/s. ..... do hereby declare that our company or any of its Directors/Partners/Employees/Allied Firms# do not have any conflict of interest as per the provisions covered in the Bidding Document and specifically confirm that our company or any of its Directors/Partners/Employees/Allied Firms# have not been engaged by BPCL as Consultant/Licensor or has providedservices for the need assessment/procurement planning$ of the Tender process .

I/We, ..... {Name(s) of Authorized Signatory (ies)}, on behalf of M/s. ..... do hereby undertake that our company or any of its Directors/Partners/Employees/ Allied Firms# shall refrain from entering into any business relationships or activities, which would result into a 'Conflict of Interest' with the agency/consultant/licensor, who has been engaged by BPCL to provide services for the need assessment/procurement planning$ of the project for which this tender (i.e. Tender No. .....) has been invited (floated).

Further, I/We, ..... {Name(s) of Authorized Signatory (ies)}, on behalf of M/s. ..... do hereby declare that our company or any of its Directors/Partners/Employees/Allied Firms# do not have any conflict of interest with one or more parties participating in the tendering process for the subject EPC works as per the provisions covered in the Bidding Document .

**#** *Allied Firm shall mean:*

"Allied firm" ('affiliates'/ 'affiliated firm', 'sister concern', 'associated firm', or 'related party') of a bidder/ contractor (Principal firm, including Joint Venture Company) is a firm/ concern (including Joint Venture Company) that comes within the sphere of effective control/ influence of the principal firm, wherein the Principal Firm –

i) being a proprietary firm, owns the Allied Firm,
ii) being a partnership firm, has common (all or majority of) partners, or any one of its partners has profit share of 20% or more, in the Allied Firm
iii) has common Management (say majority of director) with the Allied firm;
iv) its partners or directors have a majority interest in the management of the Allied Firm;
v) has a controlling voice by owning substantial (20% or more) shares in the Allied Firm;
vi) directly or indirectly controls or is controlled by or is under common control, by way of any agreement/ MoU or otherwise with the Allied Firm, v) has the Allied Firm as its successor/ subsidiary or vice-a-versa;
vii) has common offices/ manufacturing facilities with the Allied Firm.

**$** *need assessment/procurement planning shall mean preparation of - feasibility/ cost estimates/ Detailed Project Report (DPR), design/technical specifications, terms of reference (ToR)/ Activity Schedule/ schedule of requirements or the Tender Document etc.*

(Authorized Signatory)
Signature:
Name :
Designation:

## Bank Guarantee Clause

As per BPCL Standard policy on acceptance of Bank Guarantee (BG) , BG's as per following criteria will be accepted:

### Criteria for Acceptance of BG

| BG Value | Stipulation |
|---|---|
| Upto INR 1 Crores | Bank Guarantees from any Scheduled bank (including nationalised banks, other scheduled commercial banks, scheduled cooperative banks and scheduled regional rural banks) as appearing in the second schedule to the RBI Act 193 Shall be acceptable. |
| Greater than INR 1 Crores | Bank Guarantee which are issued by banks having long term issuer rating of "A2" from Moody's or equivalent from Fitch and S&P in case of the foreign bank and long-term issuer rating of at least "AA" from CRISIL or equivalent from CARE, ICRA and Indian rating in case on Indian Bank, shall be acceptable. In case rating for a bank is available from more than one rating agency, the lowest such rating shall be considered. Illustrative list of banks meeting the stipulated criteria as on 02.06.2025 are attached as annexure 1. |

**Annexure I**

**List of banks meeting the stipulated criteria as on 02.06.2025**

| Sr No. | Name of Bank | Category of Banks |
|---|---|---|
| 1 | AU Small Finance Bank Ltd | Indian Bank |
| 2 | Axis Bank Ltd | Indian Bank |
| 3 | Bank of Baroda | Indian Bank |
| 4 | Bank of India | Indian Bank |
| 5 | Bank of Maharashtra | Indian Bank |
| 6 | Canara Bank | Indian Bank |
| 7 | Federal Bank Ltd | Indian Bank |
| 8 | HDFC Bank Ltd | Indian Bank |
| 9 | ICICI Bank Ltd | Indian Bank |
| 10 | IDBI Bank Ltd | Indian Bank |
| 11 | IDFC First Bank Ltd | Indian Bank |
| 12 | Indian Bank | Indian Bank |
| 13 | Indian Overseas Bank | Indian Bank |
| 14 | IndusInd Bank Ltd | Indian Bank |
| 15 | Karur Vysya Bank Ltd | Indian Bank |
| 16 | Kotak Mahindra Bank Ltd | Indian Bank |
| 17 | Punjab National Bank | Indian Bank |
| 18 | State Bank of India | Indian Bank |
| 19 | UCO Bank | Indian Bank |
| 20 | Union Bank of India Ltd | Indian Bank |
| 21 | Abu Dhabi Commercial Bank PJSC | Foreign Bank |
| 22 | Bank of America NA | Foreign Bank |
| 23 | Bank of Nova Scotia | Foreign Bank |
| 24 | MUFG Bank Ltd | Foreign Bank |
| 25 | BNP Paribas SA | Foreign Bank |
| 26 | Shinhan Financial Group Co Ltd | Foreign Bank |
| 27 | Citibank NA | Foreign Bank |
| 28 | DBS Group Holdings Ltd | Foreign Bank |
| 29 | Hongkong & Shanghai Banking Co | Foreign Bank |
| 30 | JPMorgan Chase & Co | Foreign Bank |
| 31 | Mizuho Bank Ltd | Foreign Bank |
| 32 | Westpac Banking Corp | Foreign Bank |
| 33 | Industrial & Commercial Bank of China | Foreign Bank |
| 34 | Credit Agricole SA | Foreign Bank |
| 35 | Cooperative Rabobank UA | Foreign Bank |
| 36 | Doha Bank QPSC | Foreign Bank |
| 37 | Qatar National Bank QPSC | Foreign Bank |
| 38 | United Overseas Bank Ltd | Foreign Bank |
| 39 | KEB Hana Bank | Foreign Bank |
| 40 | Industrial Bank of Korea | Foreign Bank |
| 41 | First Abu Dhabi Bank PJSC | Foreign Bank |
| 42 | Emirates NBD Bank PJSC | Foreign Bank |
| 43 | NatWest Markets PLC | Foreign Bank |
| 44 | Bank of China Ltd | Foreign Bank |
| 45 | CTBC Bank Co Ltd | Foreign Bank |

**Note:**

1. The above list of banks is based on the credit rating as on date (Source: Bloomberg)
2. In case of any discrepancy/subsequent upgrade in credit rating, user department can contact Treasury for clarification.

# INSTRUCTIONS TO BIDDERS (ITB)

## TABLE OF CONTENTS

1.0 SCOPE OF BID ....4
2.0 ELIGIBLE BIDDERS ....5
3.0 FRAUDULENT PRACTICES ....6
4.0 BIDDING DOCUMENT ....6
5.0 SITE VISIT ....7
6.0 CLARIFICATION OF BIDDING DOCUMENT & PRE-BID MEETING ....7
7.0 AMENDMENT OF BIDDING DOCUMENT ....8
8.0 CONFIDENTIALITY OF BIDDING DOCUMENT ....9
9.0 ACKNOWLEDGEMENT & CONFIRMATION ....9
10.0 COST OF BIDDING ....9
11.0 LANGUAGE OF BID ....9
12.0 DOCUMENTS COMPRISING THE BID ....9
13.0 MULTIPLE/ALTERNATIVE BIDS ....12
14.0 BID PRICES AND DISCOUNTS ....13
15.0 CURRENCIES OF BID AND PAYMENT ....14
16.0 AUTHENTICATION OF DOCUMENT/SPECIAL DOCUMENTATION REQUIREMENT ....14
17.0 PERIOD OF VALIDITY OF BIDS ....15
18.0 BID SECURITY / EMD ....15
19.0 POWER OF ATTORNEY ....16
20.0 SEALING AND MARKING OF BIDS ....17
21.0 DEADLINE FOR SUBMISSION OF BIDS ....17
22.0 LATE BIDS /PHYSICAL BIDS ....18
23.0 WITHDRAWAL, SUBSTITUTION, AND MODIFICATION OF BIDS ....18
24.0 BID OPENING ....18
25.0 CONFIDENTIALITY ....19
26.0 DETERMINATION OF RESPONSIVENESS ....19
27.0 ZERO DEVIATION (NIL DEVIATION) ....19
28.0 DEVIATIONS, RESERVATIONS, AND OMISSIONS ....20
29.0 CLARIFICATION OF BIDS ....20
30.0 EVALUATION OF TECHNO-COMMERCIAL BIDS ....20
31.0 OPENING OF FINANCIAL (PRICE) BID ....21
32.0 DELETED ....21
33.0 CONVERSION TO SINGLE CURRENCY- NOT APPLICABLE ....21
34.0 EVALUATION AND COMPARISON OF PRICE BIDS ....21
35.0 BPCL'S RIGHT TO ACCEPT ANY BID, AND TO REJECT ANY OR ALL BIDS ....22
36.0 PREFERENCE TO MICRO OR SMALL ENTERPRISES ....22
37.0 POLICY FOR PROVIDING PREFERENCE TO DOMESTICALLY MANUFACTURED IRON & STEEL PRODUCTS IN GOVERNMENT PROCUREMENT (DMI&SP), FOR APPLICABILITY REFER BID DATA SHEET (BDS): ....22
38.0 PROVISION REGARDING POLICY OF PUBLIC PROCUREMENT (PREFERENCE TO MAKE IN INDIA) (PPP-MII), ....23
39.0 AWARD CRITERIA ....23
40.0 NOTIFICATION OF AWARD ....23
41.0 PERFORMANCE BANK GUARANTEE/ PERFORMANCE SECURITY DEPOSIT ....23
42.0 WAIVER OR TRANSFER OF THE AGREEMENT ....23
43.0 CARTEL FORMATION ....23
44.0 CORRUPT AND FRADULANT PRACTICE ....24
45.0 UNIQUE DOCUMENT IDENTIFICATION NUMBER ....24
46.0 POLICY FOR HOLIDAY LISTING OF VENDORS IN BPCL SHALL BE AS PER APPENDIX-V TO THIS ITB ....24

47.0 MSE VERIFICATION .....24
48.0 POWER OF ATTORNEY .....25

## Appendix to ITB

| Sl. No. | APPENDIX TO ITB |
|---|---|
| 1 | APPENDIX I : COMPLIANCE OF RESTRICTIONS FOR COUNTRIES WHICH SHARE LAND BORDER WITH INDIA. |
| 2 | APPENDIX II : PUBLIC PROCUREMENT ( PREFERENCE TO MAKE IN INDIA) (PPP-MII) & POLICY FOR PREFERENCE TO DOMESTICALLY MANUFACTURED ELECTRONIC & TELECOM |
| 3 | APPENDIX III : INTEGRITY PACT |
| 4 | APPENDIX IV : POLICY FOR PROVIDING PREFERENCE TO DOMESTICALLY MANUFACTURED IRON & STEEL PRODUCTS IN GOVERNMENT PROCUREMENT. |
| 5 | APPENDIX V : POLICY OF HOLIDAY LISTING OF VENDORS IN BPCL |
| 6 | APPENDIX VI : VERIFICATION OF MSE REGISTRATION CERTIFICATE BY CHARTERED ACCOUNTANT. |
| 7 | APPENDIX VII : ACKNOWLEDGEMENT CUM CONSENT LETTER. |
| 8 | APPENDIX VIII : E-PROCUREMENT GUIDELINES |
| 9 | APPENDIX-IX : PROVISIONS REGARDING ELIGIBLE BANKS FOR SUBMITTING EMD/ PBG AND LIST OF BANKS |

## A. GENERAL

### 1.0 SCOPE OF BID

1.1 In connection with the Notice Inviting Tender/Invitation for Bids/ Letter Inviting Bid (NIT/IFB/LIB), Bharat Petroleum Corporation Limited (BPCL) invites e-Bid(s), under single stage two bid system, for the entire scope covered under the Bidding Document [hereinafter for the purpose of these instructions collectively referred to as the "WORKS" as specified in Bid Data Sheet (BDS)].

1.2 Throughout the Bidding Document:

(a) The **PURCHASER/CLIENT/ OWNER** means Bharat Petroleum Corporation Limited (BPCL), having its Registered office at 4&6, Currimbhoy Road, Ballard Estate, Mumbai - 400 001 and shall include its successors and assignees.

(b) "EIL" shall mean Engineers India Ltd., having its registered office at 1, Bhikaiji Cama Place, R.K Puram, New Delhi-110066 (INDIA) and engaged by BPCL as PMC/EPCM for their Project.

(c) except where the context requires otherwise, words indicating the singular also include the plural and words indicating the plural also include the singular; and word written in capital or small letter or where the first letter capital have the same meaning.

(d) "Day" means calendar day.

(e) The term 'Bid Due Date' shall mean the 'Final Bid Due Date'.

(f) the term "bid"/ "tender"/"offer"/"proposal" and their derivatives ("RFQ/Bidding/Enquiry" documents, "bidder/tenderer", "Vendor/Supplier/Seller", "Bid/tender", "bidding/tendering", "Contract/Purchase Order" etc.) are synonymous,

(g) "Tender Document" or "Bidding Document" shall mean the documents issued to the bidder including any subsequent addenda to enable bidder submit his Bid.

(h) Throughout this Bidding Document, E-Tendering website/portal means Government of India Central Public Procurement (CPP) Portal (https://eprocure.gov.in/eprocure/app)

(i) **CONSULTANT :-**

BPCL has appointed ENGINEERS INDIA LIMITED (EIL) as the consultant for this project. Owner has also authorized the consultant to enter into correspondence with bidder(s) & obtain clarifications/ confirmations, if any with respect to this RFQ/ BIDDING DOCUMENT. By virtue of this authorization, EIL on behalf of BPCL may enter into correspondence / discussions & obtain clarifications / confirmations from bidder(s) if any.

(j) **"Notice Inviting Tender (NIT)"/"Letter Inviting Bid" (LIB)/ "Invitation for Bid" (IFB) shall mean EIL's request to Bidder for a Bid/ Tender together with the Bidding Document.**

(k) "Instructions to Bidders" shall mean the documents describing the manner in which Bidder shall prepare and submit his bid.

(l) **The words "un-incorporated Joint Venture (JV)" and "Consortium" have the same meaning.**

1.3 The successful bidder / "contractor" shall complete the Scope of Work within the Time Period/Completion Period stated in Bidding document.

## 2.0 ELIGIBLE BIDDERS

2.1 An Eligible bidder may be a firm or a company, who, have been issued the Bidding Document on Limited Competitive Basis or a bidder meeting the BQC criteria as per Invitation for Bids (IFB) on Open Competitive basis. **(Refer BDS)**

2.2 A bidder who is on **Holiday List / Negative List** of EIL/BPCL on due date of submission of bid / during the process of evaluation of the bids, the offers of such bidders shall not be considered for bid opening/evaluation/award. If the Bidding Document **is/was issued inadvertently to such Bidder/downloaded from website by such** Bidder, then Bid submitted by such Bidder shall not be considered for opening/ evaluation/ award.

Further, in case of a consortium, if any of the member(s) of consortium is on Holiday/ Negative / Suspension/ Banning list of EIL/BPCL on Final due date of submission of bid / during the process of evaluation of the bids, the offers of such consortium shall not be considered for bid opening/evaluation/Award. Bidder/ member(s) of consortium should be not under Liquidation, Court receivership or similar proceedings. Bidder/ member(s) of consortium to submit self-certificate in this regard.

2.3 Similarly, if a bidder is seeking qualification based on engaging a sub-contractor / sub-vendor who meets stipulated qualification criteria (in case allowed as per IFB/NIT) and such a sub-contractor is on **Holiday List / Negative List** of EIL / BPCL on Final due date of submission of bid / during the process of evaluation of the bids, the offer of such bidder shall not be considered for bid opening/evaluation /award. Refer **Appendix-V to ITB** for Policy of Holiday Listing of Vendors in BPCL.

2.4 If a Bidder (as per Clause No. 2.3 above) / proposed sub-contractor or sub-vendor / if any of the member of consortium (as per Clause no. 2.2 above ) , is placed on Holiday List / Negative List of EIL / BPCL after opening of price bid and such Bidder/consortium happens to be the lowest bidder, then the next lowest bidder shall be considered L1.

2.5 Bidder should not be under liquidation, court receivership or similar proceedings. Bidder should submit a self-certificate/declaration regarding the same as per Bidding Form **Form-G**.

2.6 The bidder shall not be under a declaration of ineligibility by OWNER for Fraudulent practices as defined at clause no. **44 of ITB**.

2.7 A bidder shall not be affiliated with a firm or entity:

i) that has provided consulting services related to the work to the Owner during the preparatory stages of the works or of the project of which the works form a part,

or

ii) That has been hired by the Owner as engineer/consultant for the contract.

Bidder to provide a self-declaration regarding the same as per Form-G of Bidding Forms.

2.8 **Department of Expenditure (DoE) vide O.M. No. 7/10/2021-PPD(1) dated 23.02.2023 has issued the revised guidelines for Restrictions on Procurement from Bidders from Country(ies) sharing Border with India. These guidelines are available on the website of DoE (https://doe.gov.in). In view of the above, Bidder to submit signed and stamped copy of the policy along with duly filled Form-IA/I-B/II (as applicable) (on Company's Letterhead) attached with Appendix-I of this ITB for compliance.**

If a bidder is from a country which shares a land border with India, then they will be eligible to bid if they are registered with the Competent Authority (**Appendix – I to to ITB**), otherwise their offer shall not be considered for evaluation/ award.

2.9 **Ministry of Petroleum & Natural Gas (MoPNG) vide File no. FP-20013/24/2017-FP-PNG-(E-17013) dated 21.08.2024, have forwarded revised Public Procurement (Preference to Make in India) (PPP-MII) Order, 2017 issued by DPIIT dated 19.07.2024 is enclosed as Appendix-II of ITB.**

**Under this policy, buyer reserves the right to allow Suppliers or Service providers in a tender and purchase preference as admissible under the prevailing policy, subject to complying with the requirements/ conditions defined herein and submitting documents required to support the same. Refer Appendix-II to ITB for details.**

2.10 Refer BDS for type of bidding and other criteria w.r.t. eligible Bidder, if any, as defined therein.

**3.0 FRAUDULENT PRACTICES**

Fraudulent Practices clause as per clause no. **44 of ITB** shall be applicable.

## B. CONTENTS OF BIDDING DOCUMENT

**4.0 BIDDING DOCUMENT**

4.1 The Bidding Document consisting of Commercial & Technical Section has been hosted on e-procurement website.

4.2 The Bidding Document shall in general consist of the following and should be read in conjunction with any amendment issued in accordance with Clause No. **7.0** of ITB.

i. Invitation for Bid (IFB)/ Letter Inviting Bid (LIB)
ii. Instructions to Bidders and its attachments.
iii. Bid Data Sheet
iv. Bidding Forms
v. General Conditions of Contract (GCC).
vi. Special Conditions of Contract (SCC) and its Annexures.
vii. Schedule of Rates (SOR)/ Schedule of Prices (SOP).
viii. Technical Specifications / Standards.
ix. Drawings, if any

4.3 Although all the details presented in this Bidding Document have been compiled with reasonable care, the bidder is expected to examine the Bidding Document, including all instructions, forms, terms, specifications and drawings in the Bidding Document and it includes all the documents as per Table of Contents. In case of any ambiguity or incompleteness, the bidder must bring it to the attention of BPCL/EIL immediately and prior to submission of Bid.

4.4 The bidder is expected to examine the Bidding document downloaded from the e-Procurement Portal, all instructions, formats, terms, specifications and drawings etc., enclosed in the Bidding documents. The invitation for bid (bidding) together with all its attachment thereto, shall be considered to be read, understood and accepted by the bidder in co-ordination to each other. Failure to furnish all information required by the Bidding documents or submission of a bid not substantially responsive to the Bidding documents in every respect will be at bidder's risk and may result in the rejection of the Bid.

4.5 Bidding document once issued in case of limited competitive bidding is non-transferable. However, in case of Open Competitive Bidding, since the Bidding Document is available for free downloading on the portal, any bidder may submit the Bid and the same shall be evaluated in line with the provisions of the Bidding Document.

## 5.0 SITE VISIT

5.1 Bidder, if required, may visit and examine the Project Site and its surroundings and obtain for itself on its own responsibility all information that may be necessary for preparing the bid. **Accordingly, bidder to submit Declaration confirming Knowledge about Work Site Visit and Surrounding Conditions as per Form – J of Bidding Forms.**

5.2 Bidder is advised to visit and examine the site or locations of warehouse (at his own cost), its surroundings and familiarise themselves of the existing facilities & environment, and collect all other information which he may require for preparing and submitting the bid and entering into the Contract. Claims and objections due to ignorance of existing conditions or inadequacy of information will not be considered after submission of the bid and during implementation. Bidder shall provide at least two days in advance the details of their representatives along with details of laptop, mobile or any other electronic device or any equipment if any, being carried so as to make arrangement for gate passes. Owner's decision on this regard shall be final and binding upon the bidder. The cost of visiting the site shall be at the bidder's own expense.

5.3 The bidder or any of its personnel or agents will be granted permission by the Owner to enter upon its premises and land for the purpose of such visits, but only upon the express condition that the bidder, its personnel, and agents will indemnify the Owner and its personnel and agents from and against all liabilities in respect thereof, and will be responsible for death or personal injury, loss of or damage to property, and any other loss, damage, costs, and expenses incurred during Site Visit and/ or as a result of the inspection.

5.4 For site visit, Bidder may contact persons as per details provided in Bid Data Sheet (BDS).

## 6.0 CLARIFICATION OF BIDDING DOCUMENT & PRE-BID MEETING

6.1 Bidder's authorized representative(s) shall attend the pre bid meeting on the prescribed day at the given venue specified in IFB/ LIB. During the pre-bid meeting, all the technical and commercial issues shall be discussed and concluded to ensure that the bid received subsequent to pre bid meeting shall be without any deviations to terms and conditions. Hence, bidders shall treat the pre bid meeting as utmost important and depute competent & senior person capable of taking on the spot decision to sort out all the technical and commercial issues.

However, in case any bidder does not attend the pre bid meeting, it shall be understood that the bidder has a clear understanding of the scope, terms & conditions of the bidding document and does not have any comments/ deviations to the requirements of the bidding document.

6.2 In order to ensure fruitful discussions during pre-bid meeting, the bidder is requested to submit any queries/clarification/information pertaining to Bidding document in writing. These queries shall be replied during pre-bid meeting. The bidders shall strictly submit their queries within cut-off date after which, EIL shall reserve the right not to entertain any queries.

For NIC CPP portal, bidder shall submit their queries only through NIC CPP portal strictly on or before cut-off date mentioned in IFB/LIB/CPP portal after which, EIL shall reserve the right not to entertain any queries. Queries sent through e-mails or any other mode by any bidder shall not be given any cognizance.

6.3 The bidders are required to participate in the pre-bid meeting after going through the entire Bidding Document along with BQC. Bidder shall come with all technical and commercial points on which they need clarifications and also to ensure that they possess all the supporting documentation for

meeting the BQC. In case of any doubt, they may discuss the same during the meeting to avoid any techno-commercial clarifications/ discussions post bid.

6.4 Replies to the pre-bid queries (including text of the queries raised by Bidder(s), without identifying the source) will be uploaded in NIC portal https://eprocure.gov.in/eprocure/app as expeditiously as possible. After pre-bid meeting, no further queries will be entertained from the bidders. The Reply to Pre-bid queries containing clarification shall not form part of the Bidding Document unless issued as an Addendum/ Amendment.

6.5 Any modification of the Bidding Document, which may become necessary as a result of the pre-bid discussion, shall be intimated to all bidders through the issue of an Addendum/Amendment.

6.6 After pre-bid meeting, no deviation shall be accepted. The applicable Form towards compliance to Bid Requirements & conforming no-deviation and techno-commercial compliance shall be signed and submitted by the bidders as part of their offer. Bidder in their own interest shall submit bid fully complying with Bidding Document requirements and EIL shall reserve the right to proceed with the available compliant bids for evaluation without raising any technical/ commercial queries.

6.7 Technical/ Commercial queries (TQ/CQ) shall not be issued once the bid have been opened. However, wherever CQ/ TQ are unavoidable, the same shall be raised and the cut-off date given for CQ/ TQ replies shall be adhered to. CQ/ TQs shall be issued through E-tendering portal and Bidder shall submit their replies through E-tendering portal only. Accordingly, CQ/ TQ replies through any other mode (e-mail, physical form) shall not be accepted. Offers shall be evaluated based on the information available upto cut-off date for CQ/ TQ replies. Bidder shall not submit any Price/ Price implication against TQ/ CQ raised unless specifically sought in writing.

6.8 Bidder is advised to visit and examine the Project Site and its surroundings and obtain for itself on its own responsibility all information that may be necessary for preparing the bid and entering into a contract for execution of the Works. All costs towards the same including the cost of visiting the Site shall be at the bidder's own expense.

6.9 Bidder and any of its personnel will be granted permission by EIL/ Owner to enter upon its premises and lands/ Project Site for the purpose of such visit, but only upon the express condition that the bidder and its personnel will relieve and indemnify EIL/ Owner and its personnel from and against all liability in respect thereof, and will be responsible for death or personal injury, loss of or damage to property, and any other loss, damage, costs, and expenses incurred during Site Visit and/ or as a result of the inspection. Bidder shall **refer BDS** for schedule and contact details related to site visit..

## 7.0 AMENDMENT OF BIDDING DOCUMENT

7.1 At any time prior to the deadline for submission of bids, the Owner may, for any reason whether at his own initiative or in response to the clarification requested by the prospective bidder(s), issue amendment in the form of Addendum during the bidding period or subsequent to receiving the bids. Any Addendum thus issued shall become part of Bidding Document and Bidder shall submit a copy of the Addendum duly signed and stamped in token of his acceptance. The addendum will be hosted on e-procurement website

7.2 All Amendments, Clarifications (if any) etc. will be uploaded in e-procurement portal. Generally, intimation of uploading of documents in website is sent to the bidders (all bidders in case of Limited bidding and to bidders who have submitted acknowledgement on tender portal in case of NIT/IFB) in their email id. It is the responsibility of the bidder to regularly check the E-tendering website and provide current and authenticated email id. Bidder shall submit a copy of the Addendum duly signed and stamped in token of his acceptance. Any revision, clarification, addendum, corrigendum, time extension, etc. will be hosted on these websites only. Bidders are requested to visit the websites regularly to keep themselves updated. Bidders have to take into consideration of all the addendum(s) / corrigendum (s) / clarifications issued/ web hosted, before submitting the bid.

7.3 In case Addendum is issued during the bidding period, Bidder shall consider its impact in his bid. In case Addendum is issued subsequent to receipt of bids, Bidder shall follow the instructions issued along with Addendum with regard to submission of impact on quoted price / revised price, if any.

7.4 The Owner/Consultant may, at its discretion, extend the date of submission of Bids in order to allow the bidders a reasonable time to furnish their most competitive bid.

**8.0 CONFIDENTIALITY OF BIDDING DOCUMENT**

8.1 The Bidding Document is and shall remain the exclusive property of Owner/Consultant without any right to Bidder to use them for any purpose except for the purpose of Bidding.

8.2 On no account will any agency to whom Bidding Documents is issued, part with possession thereof or copy or take copies or tracings of any drawing, plan etc. It should be understood that the information therein is confidential, and that the Bidding Documents are therefore being issued to bidders in the strictest confidence.

**9.0 ACKNOWLEDGEMENT & CONFIRMATION**

9.1 Bidder shall acknowledge and confirm his intention to bid for the tendered work/service/items as per proforma "Acknowledgement-Cum-Consent Letter" enclosed in Bidding Document as Appendix-VII to ITB. Further, within **10 days** of downloading of Bidding Document, bidders are requested to acknowledge and confirm their intention to bid for the tendered work on EIL website http://tenders.eil.co.in.

9.2 Bidder also must intimate their intention of not quoting if they are not submitting Bid.

9.3 In case of e- tendering the bidder shall post their intention to bid for the tendered work in the designated place of CPP Portal.

9.4 In case of limited competitive bidding, Bidders should respond to this enquiry either by submitting their bids or by explaining the reason for non-submission of the offer. In case there is no response either way continuously, the bidder shall be liable for suitable action including review of their enlistment with EIL for that particular item/trade category.

## C. PREPARATION OF BIDS

**10.0 COST OF BIDDING**

10.1 Bidder shall bear all direct and indirect costs associated with the preparation and submission of its Bid (including clarification meetings, and site visit, if any), and BPCL/EIL shall not be responsible or liable for those costs, regardless of the conduct or outcome of the bidding process.

**11.0 LANGUAGE OF BID**

11.1 The Bid prepared by the bidder, all correspondence/drawings and documents relating to the bid exchanged by the bidder with the Owner/Consultant shall be in English Language only. In case, any printed literature furnished by bidder written in another language so long as accompanied by an English translation, in which case, for the purpose of evaluation and interpretation of the bid, the English translation shall govern.

11.2 In the event of submission of any document/ certificate by the Bidder in a language other than English, proper English translation copy of the same shall also be furnished duly certified, stamped and signed by Local Chamber of Commerce or Any recognized/ authorized translator in India.

**12.0 DOCUMENTS COMPRISING THE BID**

No Physical Bids / Offers shall be permitted (other than the documents which are specifically mentioned to be submitted in physical form for which scanned copy already uploaded along with the

bid). The offers/bids submitted online through e-procurement portal as mentioned in clause 1.2 h) above along with the respective originals as specified in Bidding Document shall only be considered as bid for evaluation and ordering. Bidders are required to upload the Bid/offer along with all supporting documents including Priced bid on the **E-Tendering website only.** Electronic Bids (e-bid) shall be submitted on e-procurement Portal as per available functionalities.

Electronic Bids (e-bid) in three parts viz:
i) PART – I: Techno-commercial / Unpriced Bid
ii)PART II: Priced Bid

as detailed below shall be submitted in e-tendering portal in accordance with the instructions and terms & conditions enclosed with the Bidding Document.

12.1 **Deleted**

12.2 **PART I: TECHNO-COMMERCIAL/ UNPRICED BID (through e-tender portal)**

(a) Scanned Copy of Bid Security in accordance with relevant provision of NIT/IFB & ITB.

(b) Offer Covering letter (on bidder's letter head).

(c) Master Index of the Bidding Document and Amendment/ addendum (if any) duly signed and stamped by the bidder in token of having read all parts of the Bidding Document and having accepted and considered the same in preparing and submitting the Bid.

(d) Scanned copy of certified documents towards proof of meeting Bidder Qualification Criteria.

(e) Scanned Copy of Power of Attorney in favour of person (s) digitally signing the bid that such person (s) is/are authorised to sign the bid on behalf of the bidder and any consequence resulting due to such signing shall be binding on the bidder in line with clause **48.0 of ITB**.

(f) Integrity Pact (in the prescribed format as per **FORM-F** with the name of work & Bidding Document number duly filled signed & stamped) in accordance with Clause No.**12.5 of ITB**.

(g) Form of Bid as per **FORM-A of Bidding Forms,** Information about bidder in accordance with **FORM-B of Bidding Forms** provided in Bidding Forms.

(h) Details of Specific Experience fulfilling Qualification Criteria as per **Appendix-II A to IFB**.

(i) Past experience along with details and supporting documentation as called for in the Bidder Qualification Criteria (BQC) as per **Appendix-II B to IFB.**

(j) Compliance to Bid Requirement as per **FORM-E of Bidding Forms.**

(k) Self Declaration regarding not under Liquidation, Court receivership or similar proceedings, Current Litigation/ Arbitration and Black listing/ Holiday listing etc. as per **FORM-G of Bidding Forms.**

(l) Checklist for submission of bid as per **FORM-H of Bidding Forms.**

(m) Declaration as per **FORM-J of Bidding Forms.**

(n) Bank Mandate form as per **FORM-I of Bidding Forms** along with cancelled cheque duly signed and stamped with the Banker's certification.

(o) Financial details as per **FORM-M of Bidding Forms.**

(p) Complete Audited Annual Financial Year Report including Auditor's Report, Balance Sheet, Profit & Loss Account Statement and all other schedules for the immediate preceding three financial years.

(q) Copies of documents defining constitution or legal status, place of registration and principal place of business of the Company.

**Organization details**

- In case of a proprietorship firm, the name and address of proprietor and certified copy of Bank Account Details.
- In case bidder is a partnership firm, certified copy of the partnership deed.
- In case of company (whether private or public), certified copy of the `Certificate of Incorporation' together with certified copy of Memorandum/Articles of Association.

(r) Signed & stamped copy of Preamble to Price Schedule, Un-priced (replacing prices with the word quoted) Schedule of Rates (SOR) comprising **Form SP-0, Form-SP-1 (Prefilled Detailed SOR)**

(s) Any other document **required as per, Technical Specifications.**

(t) Any other document **required in the BDS/ITB/GCC**.

(u) Affidavit (Form-1)/ Undertaking of DMI&SP policy , if applicable as per BDS as per **FORM O of Bidding Forms.**

(v) Signed and stamped copy of Undertaking (on Company's Letterhead) attached **with (Form-IA/IB/II) Appendix-I** of this ITB in line with Government guidelines regarding procurement from bidders from a country or countries sharing Border with India.

(w) Self Certification by Bidder under PPP-MII Order, 2017 towards mandatory minimum Local Content (**FORM-2** attached **with Appendix-II of this ITB**), if applicable as per BDS.

(x) **Appendix-I** to NIT/IFB, as applicable.

(y) **Form – P:** VENDOR CODE CREATION FORM

(z) **Form Q** - HOLIDAY LISTING DECLARATION OF BPCL/EIL/MoPNG
***[Note: Bidders servicing listing or debarment or conviction in offences as per Form**-Q shall not be considered for further evaluation. Non-submission of declaration as per Form-Q shall lead to rejection of bid.]*

(aa) **GST registration details**

(bb) Proforma of declaration towards "Conflict of Interest- **Appendix-III** to IFB

(cc) EPF, ESI, PAN Registration documents

Note: The above shall be uploaded in "**PREQUAL /TECHNICAL"** folder in e-tendering portal.

12.3 **Priced Bid (through e-tender portal) (for each part)**

Price Bid shall be submitted by the bidder only on E-Tendering portal.

(a) Schedule of Prices/ Schedule of Rates with Unit rates/Percentage shall be filled in the price bid template provided in e-tender portal in accordance with instructions provided in Preamble to Schedule of Rates/Prices.

(b) Bidder shall also submit the applicable GST rate and SAC code.

(c) All items in SOR are mandatory. Bidder to quote for all SOR items in price bid without fail.

Notes:

(a) **Part-II shall be uploaded in "FINANCE" folder in e-tendering portal.**

(b) Bidder to note that if they submit prices in un-priced part of their bid, such prices shall not be considered. The prices as submitted in the priced part in e-tendering portal only shall be

considered for evaluation and award. If prices are not found in the priced part and even if mentioned elsewhere, the bid shall be rejected.

12.4 **Submission of Documents in Original**

Following documents shall be submitted in ORIGINAL **within the 7 calendar Days** from the final Bid due date and time of e-bid submission in the E-procurement portal & in a sealed envelope, with proper index and covering letter in bidder's letter head.

i) EMD (BG/DD/ISB)

In case of e-BG, no hard copy submission is admissible.

**The envelope shall be titled "ORIGINAL DOCUMENTS" with the Name of the Work, Bidding Document No., Name of the Project etc. along with the Bidder's name and address with contact no., email Id etc. and shall be submitted to the address as mentioned below:**

**Mr. Jaydip Purkayastha, GM (SCM),**
**Engineers India Limited,**
**R&D Complex, Sector-16 (On N.H.-8),**
**Tower-1 (1ST Floor), Gurugram -122 001,**
**Haryana (India),**

If the Bidder fails to submit EMD/ Bid Security (BG / ISB) physically in original within the above cut-off date to the above mentioned address, one notification / intimation shall be provided to bidder to submit the same within 5 calendar days from intimation.

If the Bidder fails to submit EMD/ Bid Security (BG / ISB) physically in original within the above cut-off date after intimation, his bid shall be rejected and not considered for further evaluation, irrespective of their status/ ranking in tender and notwithstanding the fact that a copy of Bid Security was earlier uploaded by the bidder on the etendering portal.

12.5 **INTEGRITY PACT** (If Applicable, for applicability refer BDS)

12.5.1 Bidder shall submit, the scanned copy of the Integrity Pact (IP) duly signed in all the pages and stamped in token of compliance in Part-I of the Bid (**enclosed with Bidding Document as Form-F of Bidding Forms**), wherever required as per Bid Data Sheet.

12.5.2 For detail of Independent External Monitors (IEMs), appointed by BPCL, in terms of Integrity Pact (IP), refer Integrity Pact.

12.5.3 No deviations / modifications in IP shall be acceptable. Bidder shall submit the same format of signed integrity pact (as provided in the bidding document duly signed by the buyer), duly filled-in, signed & stamped by the authorised signatory of bidder.

12.5.4 Integrity Pact shall be signed by the authorised signatory of the bid.

12.5.5 In case of e- tendering, duly signed & stamped hard copy of Integrity Pact is not required & scanned signed & stamped copy will suffice.

## 13.0 MULTIPLE/ALTERNATIVE BIDS

13.1 A bidder (i.e., the bidding entity) shall, on no account submit more than one bid either directly (as a single bidder or as a member of consortium) or indirectly (as a sub-contractor) failing which following actions shall be initiated:

i) All bids submitted by such bidder (say 'A') either as a single bidder or as a consortium, shall stand rejected and EMD/Bid security, if any, in case of all such bids submitted by bidder 'A' shall be forfeited.

ii) If another bidder (say 'B') has proposed bidder 'A' as a sub-contractor then bidder 'B''s bid shall also be rejected. However, in case the bidder 'B' has also proposed an alternative sub-contractor who is other than the bidder 'A', then bidder 'B''s bid shall be evaluated with the proposed alternative sub-contractor only. Hence, every bidder shall ensure in his own interest that his proposed sub-contractor is not submitting alternative/ multiple bids.

Note: However, in case BPCL/EIL has proposed a list of sub-contractors/ sub-vendors in the enquiry document itself which shall be common for all the Bidders, the provisions at Clause No. **13.1** ii) above shall not be applicable. It is further clarified that

➢ A sub-Contractor can be common to more than one Bidder, provided the sub-Contractor themselves are neither a Bidder nor a consortium member.

➢ Where an Enquiry has multiple Parts, the above condition shall be applicable individually for each Part, as if it is a separate Enquiry.

## 14.0 BID PRICES AND DISCOUNTS

14.1 The prices must be quoted strictly in the format provided in the Bidding Document. Conditional discount, if offered, shall not be considered for evaluation.

14.2 Unless stated otherwise in the Bidding Document, the Contract shall be for the total works as described in Bidding Document, based on the Schedule of Rates/ Prices submitted by the bidder and accepted by EIL/BPCL.

14.3 Bidder shall quote the Unit Rates in Schedule of Rates/Prices (SOP) after careful analysis of cost involved for the performance of the complete scope of work considering all parts of the Bidding Document. In case any activity is not specifically covered in description of item under `Schedule of Rates/Prices' but is required to complete the work as per Scope of Work, Scope of Supply, Specifications, Standards, Drawings, General Conditions of Contract, Special Condition of Contract or any other part of Bidding Document, the rates/ prices quoted shall be deemed to be inclusive of cost incurred for such activity.

14.4 Rates/ prices quoted by the bidder, shall remain firm, fixed and valid till the completion of the Works and will not be subject to variation on any account except as otherwise specifically provided in the Bidding Documents.

14.5 All duties, taxes, and other levies payable shall be as per Special Conditions of Contract. Further, ***Bidder has to obtain GSTIN registration at the location where Works Contract Services are to be performed or carried out. In case of other type of services, bidder is requested to obtain GSTIN in the state where job is required to be carried out/ executed. The bidder shall indicate in its bid the Goods & Service Tax registration No.***

Applicability of BOCW cess shall be as per GCC clause no 100 and bidder's quoted prices shall be inclusive of the same. It's bidder's responsibility to assess the applicable rate of BOCW and include the same in their quoted prices.

Building And Other Construction Workers (BOCW) cess shall be applicable on the Total Contract Price.

14.6 DELETED

14.7 It shall be the responsibility of the Bidder to duly enquire of their own and comply with all applicable laws, rules, regulations, orders and formalities applicable to Goods and Services Tax (GST), Custom Duty etc. on the manufacture, sale and/or supply of any material / services to Owner / EIL.

14.8 **Price basis w.r.t inclusion/exclusion of taxes**

The quoted price shall be deemed to be inclusive of all taxes and duties except "Goods and Services Tax" (GST) as per Provisions of taxes & duties specified in SCC.

14.9 **The Bidder shall keep the Owner / EIL indemnified from and against any and all claims, demands, prosecutions, penalties, damages, demurrages and/or other levies whatsoever** made or levied by any Court, Tribunal or the Customs or other Authorities with respect to any alleged breach, evasion or infraction of such duties, taxes, charges or levies or any breach or infraction of such laws, rules, regulations, orders or formalities concerning the same and from the consequence thereof.

## 15.0 CURRENCIES OF BID AND PAYMENT

15.1 Unless otherwise specified in BDS, bidder shall submit Bid in Indian Rupees only and payment shall be made in Indian Rupees only.

15.2 Payment shall be as per Payment terms mentioned in SCC.

## 16.0 AUTHENTICATION OF DOCUMENT/SPECIAL DOCUMENTATION REQUIREMENT

16.1 Submission of genuine and authentic documents is the prime responsibility of the bidder. No amount of checking or verification by EIL/Owner shall absolve bidder from his responsibility.

Under the EIL suspension/ banning rules (available on EIL portal www.engineersindia.com ), the punishment for submission of FORGED/FALSE documents is clearly mentioned. Moreover, the bidding document additionally indicates other actions against the bidder like encashment of EMD or PBG depending upon the stage of discovery of the fraud/false documentation. Moreover, the bidder's organisation is responsible for any and all actions of their employees and any claims seeking to pin point the blame on some employee of bidder and attempting to absolve the bidder's organisation will not be entertained.

**Bidder to note that the EIL/BPCL reserves the right to proceed based on acceptable offers (who have submitted authenticated documents in line with the mechanism mentioned in IFB) and reject outright the other bids which have some shortcoming including non-submission of authenticated documents. The bidder shall therefore submit the authenticated documents along with the offer itself and in case of rejection of his bid shall not have any right to seek another opportunity for submission of authenticated documents.**

The mechanism for bidders' certification regarding authenticity of BQC documents has been prescribed as under:
a) Bidder shall furnish an undertaking in the format as per **Annexure-I to NIT/IFB (Undertaking) in the Format** towards the authenticity of submitted BQC documents**)** towards the authenticity of submitted BQC Documents, duly signed by the authorized signatory of Bidder holding Power of Attorney for signing of Bid.
b) Proprietorship/ Partnership firms shall submit the undertaking as per **Annexure-I to NIT**, duly signed, respectively by the Proprietor/ any two Partners.

16.2 In addition to authentication of BQC document EIL shall verify the credentials of the evaluated bidder/ vendor/sub-contractor. The document(s) submitted by the bidder towards meeting the Bidder Qualification Criteria (BQC) as per NIT/IFB shall be subject to verification as per mechanism detailed below:

16.2.1 Documents submitted by the bidder for meeting the BQC shall be verified from the document issuing authority.

16.2.2 Verification of documents shall be carried out through e-mail/letter or visit by EIL Officials. Bidder shall provide complete assistance towards the same. It shall also be the responsibility of the bidder to assist EIL in carrying out this exercise.

Accordingly, bidder shall ensure that they submit only those executed & Completed works (PO/Contracts) meeting the qualification criteria for which they can arrange such verification from respective Clients.

16.2.3 Attempts shall be made to complete the verification process before award/ordering to L1 bidder. However, in case it gets delayed due to some reasons it shall not hold the award of the Job to the lowest bidder. However, payment shall not be released till verification is complete.

16.2.4 Failure of cross verification shall entitle EIL to reject the bid or terminate the Purchase Order/Contract, if issued.

16.2.5 In case, the BQC documents have already been verified by EIL for any other enquiry/tender , the same may also be considered verified on the strength of previous verification and acceptance by EIL. However, in such case, bidder shall indicate in their bid that BQC/PTR documents submitted in this bid has already been verified by EIL from bidder's client in Tender No._____for Project_____ .

16.2.6 In case bidder's supporting documents are not in English language and, bidder also submits duly certified translated documents, verification from document issuing authority shall be carried out only for the original documents issued by the client.

16.3 **Only such past experience(s) shall be considered for qualification, details of which are provided in the Bid by the bidder and / or out of the list of similar work experiences specified in the Bid (with or without submitting relevant qualification documents), and subsequently no additional past experience (PTR) which is not referred at all in the Bid in specific location, shall be permitted to be submitted by the bidder.**

## 17.0 PERIOD OF VALIDITY OF BIDS

17.1 Bids shall remain valid for the period specified in the **BDS** from the date of unpriced bid opening. A bid with shorter validity period shall be rejected by BPCL/EIL as non-responsive. Bidders shall not be entitled during the above period, without the consent of BPCL/EIL in writing, to revoke or cancel their Bid or to vary the Bid given or any term thereof. In case of bidders revoking or cancelling their Bid or varying any terms in regard thereof without the consent of BPCL/EIL in writing, BPCL/EIL shall forfeit Bid security, submitted along with the bid and shall reject their bids. Such Bidder may also be put on **Holiday List / Negative List**.

17.2 After opening of price bid, if the bidder increases the price, though within the validity period and even though the offer remains lowest, the bid shall be rejected. Such action of bidder shall result in forfeiture of earnest money and debarring for future enquiries. Holiday listing policy shall be followed if vendor's not ready to execute contract at quoted price.

17.3 Extension in Bid validity, if required in exceptional cases, shall be sought from bidders. However, efforts shall be made to complete the evaluation process and finalize the recommendation within one month from the original validity period of the tender.

Any validity extension, if necessary shall be sought without any change in terms & conditions and prices by the bidder. Bid security shall not be forfeited in case a bidder refuses validity extension.

## 18.0 BID SECURITY / EMD

18.1 EMD / Bid Security conditions are as specified in NIT/IFB.

18.2 Bid security of bidders shall be returned promptly as follows:

| | | | |
|---|---|---|---|
| a | On cancellation/annulment of Enquiry / Bidding document at any stage of the bidding process but before the award of work/ items (as applicable) | : | EMD of all the Bidders shall be returned at the earliest from the date of such decision. |
| b | Within 30 days of Publishing the result of Unpriced bid evaluation | : | EMD of Bidders who have submitted late bids/ where un priced bids not opened / whose price bids are not opened. |
| c | After award to the successful bidder | : | EMD of unsuccessful Bidders whose prices have been opened. |
| d | After order/ contract is effective and submission of CPBG/security deposit by successful bidder | : | EMD of the Respective successful Bidder(s). |

18.3 Conditions regarding forfeiture of bid security.

The bid security of a bidder shall be forfeited in any of the following situations:

a) If the bidder submits alternative bids; or
b) If the bidder suo moto modifies his bid; or
c) Withdraws his bid during the period of bid validity; or
d) In case, during evaluation of bid, it is found that any forged/fake document has been furnished.
e) In the case of a successful bidder, if the bidder fails or refuses:
   i) To accept the Purchase Order/signing of the Contract
   ii) To furnish Contract Performance Bank Guarantee.
   iii) To accept arithmetical corrections of its bid, as per the terms of the Bidding Document.

Note : In case, any of the above events happens, the bidder shall be given a notice of 7 days to take necessary corrective action [except for S/ No. a) & d) above] and in case corrective action is not taken, the bid security shall be encashed without any further notice.

18.4 **Bid security shall be in currency as per NIT/IFB**.

18.5 In case of a consortium bid (If permitted in the bidding document) the bid security may be submitted by any of the members of consortium, on behalf of the consortium.

18.6 Apart from the hard copy submission of BGs, bank guarantee issued towards EMD/CPBG/ABG etc. it shall be preferred that same is also routed through SFMS (Structured Financial Messaging System) platform for Bank Guarantee issuance and Verification. The information/message as per SFMS platform shall be sent by BG issuing bank branch to BPCL's Banker as per details below:

Name of Bank : ICICI Bank
Branch: Backbay Branch, Mumbai BPCL : BPCL583493800
IFSC Code : ICIC0000393
BPCL Customer ID: BPCL583493800

## 19.0 POWER OF ATTORNEY

Bids shall be signed by the authorized signatory of the bidder. Bidder shall submit a Power of Attorney in the name of such authorized signatory(ies). Along-with their offer in line with clause no. 48 of ITB.

19.1 **DIGITAL SIGNATORY**

In case of e-tendering, login and submission of bids by the bidder on the e-tendering portal is through requisite & valid digital signature certificate.

e-Bid Signatory who is using his digital signature for uploading / signing the e-bid, shall also carry the Power of Attorney.

All documents as submitted in the e-Procurement Portal using digital signature at any time during the Bidding process shall be deemed considered signed by the POA holder only, irrespective of POA holder's signature on all pages or not.

In case of a JV/Consortium bid (If permitted in the bidding document), the Bid shall be digitally signed (e-signed) using the digital signature of a authorized representative of the JV/ Consortium, and so as to be legally binding on all the members as evidenced by a power of attorney signed by their legally authorized representatives.

## 20.0 SEALING AND MARKING OF BIDS [APPLICABLE IN CASE OF OPEN COMPETITIVE BIDDING (NIT/IFB)]

20.1 The bidder shall submit the, original Documents as per the requirement of clause no**. 12.4** of ITB, in separately sealed envelopes, duly marking the envelopes as per following:

**Original Documents**

Name of Work: _____

Bidding Document No.:_____

Due date & Time of Submission: _____

From: [Name & Address of Bidder including contact details] _____

20.2 The envelope shall bear the name and address of the bidder and bear a warning "Do not open before the time and date of bid opening".

20.3 If envelopes are not sealed and marked as required, BPCL/EIL will assume no responsibility for the misplacement or premature opening of this envelope.

20.4 Bidder to ensure submission of Original EMD within 7 days from the Bid Due Date failing which his bid shall be liable for rejection.

## D. SUBMISSION AND OPENING OF BIDS

## 21.0 DEADLINE FOR SUBMISSION OF BIDS

21.1 Bidders shall submit their bids electronically in the e-tendering portal, within the date and time **specified in the Notice Inviting Tender/Invitation for Bids (NIT/IFB)** or any extension thereof. Bidders submitting bids electronically shall follow the E-Tendering Methodology attached as **Appendix-VIII** to this ITB.

No Physical bid shall be permitted other than submission of the documents categorically asked for in hard copies as part of e-bids submitted online through the e-tendering Portal. The bids submitted online through E-Tendering Website shall only be considered for evaluation and ordering. The e-bid must be complete in all respects, leaving no scope for ambiguity. Bidder shall be fully responsible for the bid submitted in e-tendering portal and no relief or consideration can be given for errors and omissions.

21.2 Original Bid Security must be received by BPCL at the address specified in NIT/IFB/ Bid Data Sheet within the date and time for submission as **specified in the NIT/IFB** or any extension thereof**.**

21.3 BPCL/EIL may, at its discretion, extend the deadline for the submission of bids by amending the Bidding Documents in accordance with Clause No. **7.0** of ITB, in which case all rights and obligations of BPCL/EIL and bidders previously subject to the deadline shall thereafter be subject to the deadline as extended.

**22.0 LATE BIDS /PHYSICAL BIDS**

22.1 E-tendering system shall close immediately after the deadline for submission of bid. Any bids being submitted in physical form (**other than Bid Security or documents specifically sought in physical form**) shall not be considered for opening / evaluation / award and in such case the bidder may collect their bid within 7 calendar days, thereafter EIL/Owner shall have no liability.

22.2 **In the event the Bid Security in original, in accordance with Clause No. 12.3 & 21.2 of ITB, are not submitted within the deadline as per NIT/IFB, the bids shall be declared late and shall be liable for rejection, notwithstanding the fact that the bid has been submitted in electronic form within the deadline. However, in case of exemption from submitting Bid Security under MSE/Start-up [Refer NIT/BDS for applicability], then bidder shall submit the documentary evidence of the same.**

22.3 Unsolicited bids or bids being submitted to place/website other than one specifically stipulated in the Bidding Document shall not be considered for opening/ evaluation / award.

**23.0 WITHDRAWAL, SUBSTITUTION, AND MODIFICATION OF BIDS**

23.1 The bidder may modify, re-submit or withdraw its e-bid after the bid submission, but, before the due date and time for submission of Bid following the electronic bid submission procedures**.**

23.2 No bid shall be withdrawn, substituted, or modified in the interval between the deadline for submission of bids and the expiration of the period of bid validity or any extension thereof. Such withdrawal shall be dealt as per provision of tender documents and prevailing policy(ies) of EIL/Owner.

23.3 DELETED

**24.0 BID OPENING**

24.1 The un-priced Bids shall be opened online through e-tender portal, at the specified date and time given in the RFQ document or on the extended due date, as applicable. Bidders can view the stages of evaluation on e-procurement Portal.

24.2 The order of opening of bids shall be as follows;

i. On scheduled date and time of Technical (Part-I: UNPRICED) bid opening, opening of **documents, submitted in electronic form shall be processed on the e-Procurement module of the e-tendering portal.**

ii. Financial (Part-II: Price) bid of only those bidders whose bids is determined to be technically and commercially acceptable by EIL/BPCL shall be opened. Bidders selected for opening of their priced bids shall be informed about the date and time of price bid opening and shall not be called for physical participation during bid opening.

NOTE:. Online opening as above, will be deemed as opened in public and there will be no separate public opening. Hence, bidders will not be called during opening of the bids.

24.3 If a supplier / an agency is placed on **Holiday List / Negative List** of EIL / Client / after issue of enquiry but before unpriced bid opening, their bid will not be considered for further evaluation. If a supplier / an agency is placed on **Holiday List / Negative List** of EIL / Client / ~~MoP&NG~~ after opening of unpriced bids but before opening of priced bids, further evaluation shall be stopped and the

corresponding priced bid will not be opened. If a supplier/ an agency is placed on **Holiday List / Negative List** of EIL / Client after opening of priced bids but before award of the contract and such a supplier/ agency happens to be the lowest or successful bidder then the next lowest bidder shall be considered L1.

Also, bidder shall submit the declaration in this regard.

## E. EVALUATION AND COMPARISON OF BIDS

### 25.0 CONFIDENTIALITY

25.1 A bidder may seek clarification regarding the Bidding Document provisions, bidding process and / or rejection of his bid. BPCL/EIL shall respond to such requests within a reasonable time. However, such information relating to the evaluation of bids and recommendation of award shall not be disclosed to any other persons not officially concerned with the bidding process.

25.2 Any attempt by a bidder to influence BPCL/EIL in the evaluation of the bids or award decisions shall render their Bid liable for rejection.

25.3 Notwithstanding Clause No. **25.2** of ITB, from the time of bid opening to the time of placement of Order, if a bidder wishes to contact BPCL/EIL on any matter related to the bidding process, it shall done so in writing only.

### 26.0 DETERMINATION OF RESPONSIVENESS

26.1 The Owner/EIL will examine the bids to determine whether they are complete based on the contents of the bid itself, as defined in Clause No.12.0 of ITB, whether any computational errors have been made, whether the documents have been properly signed, and whether the bids are generally in order.

26.2 Prior to the detailed evaluation, the Owner/EIL will determine whether each bid is of acceptable quality, is generally complete and is responsive to the RFQ Documents. For the purpose of this determination, a responsive bid is one that conforms to all the terms, conditions and specifications of the RFQ Documents without deviations, objections, conditionality or reservations.

26.3 Bidder shall not be allowed to submit any Price Implication or Revised Price after submission of Bid, unless there is change in the stipulations of the RFQ Document and such changes are incorporated through an Amendment. In case Exceptions and Deviations submitted by Bidder along with Bid are not considered as acceptable and no Amendment is issued, then in such a case the Bidders would be required to withdraw such Exceptions/Deviations in favor of stipulations of the RFQ document and Bidders would not be eligible for submission of Price Implication/Revised Price, failing which such Bid(s) shall be considered as non-responsive and rejected.

26.4 The Owner/EIL determination of a bid's responsiveness is to be based on the contents of the bid itself without recourse to extrinsic evidence. If a bid is not responsive, it will be rejected by the Owner/EIL, and may not subsequently be made responsive by the bidder by correction of the nonconformity.

26.5 Bidder should not be under liquidation, court receivership or similar proceedings. Bidder shall submit self certificate/declaration in this regard.

### 27.0 ZERO DEVIATION (NIL DEVIATION)

27.1 Bidders to note that enquiry is issued on Zero deviation basis. Bids are to be submitted on Zero deviation basis and in strict compliance with the terms & conditions, scope, specifications and other stipulations contained in the enquiry without any deviations.

27.2 Bidders shall adhere to all provisions of the Bidding Document without taking any deviations, failing which the Bid shall be considered as non-responsive and are liable to be rejected.

27.3 In view of this Bidder shall ensure submission of complete bid without any deviation as per requirement of Bidding Document in first instance itself.

## 28.0 DEVIATIONS, RESERVATIONS, AND OMISSIONS

28.1 During the evaluation of bids, the following definitions apply:

(a) "Deviation" is a departure from the requirements specified in the Bidding Document;

(b) "Reservation" is the setting of limiting conditions or withholding from complete acceptance of the requirements specified in the Bidding Document; and

(c) "Omission" is the failure to submit part or all of the information or documentation required in the Bidding Document.

## 29.0 CLARIFICATION OF BIDS

29.1 Bidders should ensure that the Bid submitted is substantially responsive Bid in the first instance itself. Evaluation may be completed based on the content of the Bid itself without seeking any subsequent additional information, which may result in rejection of Bid. However, BPCL may, at its discretion, may request bidder to submit the necessary information or documentation, within a reasonable period of time, to withdraw deviation, reservation, or rectify omission in the bid related to documentation requirements. Requesting information or documentation on such account shall not be related to any aspect of the price of the Bid. BPCL's request for clarification and the response shall be in writing.

29.2 No change, including any voluntary increase or decrease, in the prices or substance of the bid shall be sought, offered, or permitted. Bidder shall not be allowed to submit any price implication or revised price after submission of Bid unless the same is called for by BPCL in writing.

29.3 If a bidder does not provide clarifications of its bid by the date and time set in BPCL's request for clarification, its bid shall be evaluated with available information which may result in rejection of their bid.

## 30.0 EVALUATION OF TECHNO-COMMERCIAL BIDS

30.1 Prior to price opening of bids, BPCL/EIL will determine whether each bid is accompanied with requisite documents;

i) Fulfils the technical, financial and other requirements as specified in the Bidding Document;
ii) Bid's responsiveness and clarifications thereafter, if any;
iii) Any other relevant factor, if any that BPCL/EIL deemed necessary or prudent to be taken into consideration.
iv) Authentication of qualification documents (open competitive bidding)
v) EMD / Bid Security as per the requirement specified in NIT/ IFB(open competitive bidding)

30.2 EIL/Owner reserves the right to use in-house information for assessment of capability of bidder and their performance on jobs completed/ in progress for evaluation purpose, provided that reference of such job(s) has been mentioned in the bid.

30.3 Any unsolicited reduction in price offered by a bidder within the bid validity by way of discount or revised prices, subsequent to the bid due date, shall not be taken into account for comparison. However, such reduction in price shall be taken into account for ordering if such bidder happens to be recommended as per the originally quoted prices.

30.4 In the event of any unsolicited price increase sought by any bidder, subsequent to the bid due date, the bid of such a bidder shall be rejected, in case the bidder does not agree to withdraw the price

increase. In case, price increase is sought by the L1 bidder after priced bid opening and the bidder does not agree to withdraw the price increase, the order shall not be placed with price increase and the enquiry shall be re-floated.

Wherever, decision is taken to reject a bid, EMD, if submitted, by the Bidder, shall also be forfeited and appropriate action shall be taken against bidder as per company guidelines.

30.5 Technical or commercial queries shall not be raised. However, EIL reserves the right to raise queries under exceptional situations. CQ/ TQs, if any, shall be issued through E-tendering portal and Bidder shall submit their replies through E-tendering portal only. Original documents (if sought in CQ/TQ) shall be send to address as mentioned in clause no. 12.3 of ITB. Offers shall be evaluated based on the information available up to cut-off date for CQ/ TQ replies. Bidder shall not submit any Price against TQ/ CQ raised unless specifically sought in writing.

**31.0 OPENING OF FINANCIAL (PRICE) BID**

31.1 Priced Bid (Part-II) of only those bidders whose bids is determined to be technically and commercially acceptable by EIL/BPCL shall be opened. Bidders selected for opening of their priced bids shall be informed about the date & time of price bid opening by system generated emails by CPP e-tender portal.

31.2 In case of tenders having more than one part, the Price Bids of Qualified bidders whose bids are determined to be technically and commercially acceptable for the respective parts shall only be considered for Price Opening / Evaluation.

31.3 Bidders who qualify pursuant to unpriced bid evaluation, shall be notified through system generated e-mail regarding the time and date for online price bid opening in e-procurement portal.

31.4 The Price Bids of those Bidders who were not found to be Techno-commercially acceptable shall not be opened in e-tendering.

**32.0 DELETED**

**33.0 CONVERSION TO SINGLE CURRENCY- NOT APPLICABLE**

**34.0 EVALUATION AND COMPARISON OF PRICE BIDS**

34.1 EIL shall compare the price bids based on the award methodology and loading criteria, if any, provided in **NIT/IFB/BDS** to determine the lowest evaluated bid.

34.2 DELETED

34.3 When price implication is not specifically sought in writing from the bidder and the bidder on his own in response to CQ/TQ or any other reason submits the price implication, the same shall be treated as unsolicited price implication.

34.4 DELETED

34.5 While arriving at the final evaluated prices of all the Bidders, any suo-moto lumpsum/percentage or adhoc reduction by the Bidders after submission of the priced bid shall not be considered for evaluation. However, if such bidder happens to be lowest after evaluation such rebate shall be taken into account for award.

34.6 In case of unsolicited price increase by any bidder subsequent to the bid due date and before price bid opening, and does not agree to withdraw the price increase, the bid of such bidder shall be rejected. In such case, EMD/Bid Security of such bidder(s) shall be forfeited and further punitive action as per company policy shall be taken against the Bidder(s).

34.7 In case unsolicited price increase is sought by L1 bidder after price bid opening and the bidder does not agree to withdraw the price increase, the bid of such bidder shall be rejected. In such case, the enquiry shall be refloated and EMD of the Bidder shall be forfeited and further punitive action as per company policy shall be taken against the Bidder.

34.8 In an extreme situation, when there is a 'TIE' based on the evaluated price (after loadings, if any), recourse shall be taken on the basis of Bidder's maximum average annual turnover during the last 3 years as on BDD. For this purpose, average annual turnover of the bidders having tie, shall be tabulated for the past 3 years and maximum average annual turnover in any of the last 3 years shall be determined for each bidder. The Bidder whose average annual turnover is highest shall be the recommended Bidder.

34.9 Conditional discount, if offered, shall not be considered for evaluation.

34.10 If a bidder submits prices in un-priced part of bid, such prices shall not be considered. The prices as submitted in the price part only shall be considered for evaluation and ordering, if any. If prices are not found in the price part and even if mentioned elsewhere, the bid shall be rejected. Wherever e-procurement is followed, prices uploaded at the designated priced folder of the e-tendering website shall only be considered.

34.11 Preference to MSEs, if applicable as per BDS, as per clause no**. 36.0** below.

34.12 Public Procurement (Preference to Make in India) (PPP-MII), if applicable as per BDS, as per clause 38.0 below.

Note(s) :

a) Price evaluation mentioned above and elsewhere in the tender Documents, shall include ITC credit, commercial & technical loadings as per tender provision(s) on case to case basis. Refer BDS for the details of % age rate of GST Input Credit is available to Owner.
b) Prevailing Government guidelines and its amendment(s)/ addendum(s), if any, with respect to purchase preference as well as any other applicable Government guidelines shall be take into consideration during Price Bid Evaluation.
c) Lowest evaluated bid(s) which is/are technically and commercially acceptable for the respective part/ Tender shall be considered for placement of order.
d) wherever a tender contains two or more parts with stipulations that work of only one part would be awarded to a bidder or work of one or more parts would be awarded to a bidder based on his capacity. In such cases, prices of all parts shall be opened together and award of work on least cost basis to Client shall be considered.
e) Once the price bids have been opened, the scope of work shall not be altered. The selection of the lowest bidder as well as award is based on evaluation considering the scope as on the date of priced bid opening.

## 35.0 BPCL'S RIGHT TO ACCEPT ANY BID, AND TO REJECT ANY OR ALL BIDS

35.1 The BPCL reserves the right to accept or reject any bid, and to annul the bidding process and reject all bids at any time prior to award of the order without thereby incurring any liability to the affected bidder or bidders or any obligations to inform the affected bidder or bidders on the ground of such action by BPCL.

## 36.0 PREFERENCE TO MICRO OR SMALL ENTERPRISES

36.1 Preference, if applicable to MSEs, shall be as per BDS.

## 37.0 POLICY FOR PROVIDING PREFERENCE TO DOMESTICALLY MANUFACTURED IRON & STEEL PRODUCTS IN GOVERNMENT PROCUREMENT (DMI&SP)

FOR APPLICABILITY, REFER BID DATA SHEET (BDS).

37.1 Refer **Appendix – IV** TO ITB

37.2 A confirmation w.r.t compliance of this DMI&SP Policy shall be submitted by the bidder.

37.3 Bidder shall furnish self-certification as per format enclosed with the policy else bid of such bidder shall be rejected. As per the DMI&SP policy, affidavit is required to be issued by the manufacturer. Accordingly, bidder shall furnish self-certification as per the format enclosed with the policy else bid

of such bidder shall be rejected. However, in case bidders are not able to furnish this affidavit from Indian manufacturers at bidding stages, bidders may submit affidavit after placement of order. However, an undertaking to submit affidavit shall be submitted by the bidder along-with the bid.

**38.0 PROVISION REGARDING POLICY OF PUBLIC PROCUREMENT (PREFERENCE TO MAKE IN INDIA) (PPP-MII), FOR APPLICABILITY REFER BID DATA SHEET (BDS):**

Refer **Appendix – II** TO ITB for details.

## F. AWARD OF CONTRACT

**39.0 AWARD CRITERIA**

39.1 Pursuant to clause no. **35.1** of ITB,BPCL shall award the Contract to the bidder in line with Award Methodology mentioned in IFB/NIT/BDS. However, if in the opinion of EIL/BPCL, the total price or certain item rates quoted by the lowest evaluated bidder are considered high, EIL/BPCL may invite such bidder for price negotiation. Lowest quoted bidder shall attend such negotiation meetings and if requested by EIL/BPCL shall provide the analysis of rates/break-up of amount quoted by him for any or all items of Schedule of Rates/ Prices to demonstrate the reasonability. As a result of negotiation, bidder may offer rebate on his earlier quoted Price.

**40.0 NOTIFICATION OF AWARD**

40.1 Prior to the expiration of the period of bid validity, the BPCL shall notify the successful bidder, in writing, that its bid has been accepted. The notification letter (hereinafter and in the General Conditions of Contract called the "**Letter of Award / Letter of Acceptance (LOA)**" shall specify the sum that BPCL will pay the Contractor in consideration of the execution and completion of the Works.

40.2 Until a formal contract is prepared and executed, the notification of award along with this Bidding Document together with the annexed documents, modifications, deletions agreed upon by the BPCL shall constitute a binding contract between the successful bidder and BPCL.

40.3 **SIGNING OF CONTRACT:**

Promptly upon issue of LOA, the successful tenderer shall execute within one month from the date of acceptance of LOA. The payment shall not be processed till the time the agreement is executed. The cost of stamp-paper required for signing of Contract shall be borne by successful bidder.

**41.0 PERFORMANCE BANK GUARANTEE/ PERFORMANCE SECURITY DEPOSIT**

41.1 Within 15 days from the date of Letter of Acceptance, the Contractor shall furnish the Performance Bank Guarantee for the required value, period and in the proforma, in line with bidding document.

41.2 Failure of the successful bidder to submit the above-mentioned **Performance Bank Guarantee** shall constitute sufficient grounds for the annulment of the award.

41.3 Refer Special Conditions of Contracts (SCC) for details.

**42.0 WAIVER OR TRANSFER OF THE AGREEMENT**

42.1 The successful bidder shall not waive the Agreement or transfer it to third parties, whether in part or in whole, nor waive any interest that is included in the Agreement without the prior written permission of the Purchaser.

**43.0 CARTEL FORMATION**

43.1 In case any bidder is found to be involved in cartel formation, his bid will not be considered for evaluation /placement of order. Such bidder will also be debarred from bidding in future.

## 44.0 CORRUPT AND FRADULANT PRACTICE

44.1 The OWNER requires that Bidders/Vendors/Contractors observe the highest standard of ethics during the award/execution of Contract. "Fraudulent Practice" means a misrepresentation of facts in order to influence the award of a Contract to the detriment of the OWNER, and includes collusive practice among bidders (prior to or after bid submission) designed to establish bid prices at artificial non-competitive levels and to deprive the OWNER of the benefits of free and open competition.

44.2 The OWNER will reject a bid for award if it determines that the bidder recommended for award has engaged in fraudulent practices in competing for the Contract in question.

44.3 Bidder is required to furnish the complete and correct information/ documents required for evaluation of their bids, if the information/ documents forming basis of evaluation is found to be false/ forged, the same shall be considered adequate ground for rejection of bids and forfeiture of Earnest Money Deposit.

44.4 In case, the information/ document furnished by the Bidder/vendor/Contractor forming basis of evaluation of his bid is found to be false/ forged after the award of the contract, OWNER shall have full right to terminate the contract and get the remaining job executed at the risk & cost of such Bidder/Vendor/ Contractor without any prejudice to other rights available to OWNER under the contract such as forfeiture of PBG/Security Deposit, withholding of payment etc.

44.5 In case, this issue of submission of false document comes to the notice after execution of work, OWNER shall have full right to forfeit any amount due to the Bidder/Vendor/Contractor along with forfeiture of PBG/Security Deposit furnished by the Bidder/Vendor/Contractor.

44.6 Further, such Bidder/Vendor/ Contractor shall be put on Holiday/Negative List of OWNER debarring them from future business with OWNER and EIL for a time period, as per the prevailing policy of OWNER and EIL.

## 45.0 UNIQUE DOCUMENT IDENTIFICATION NUMBER

The Institute of Chartered Accountant of India at its 379th council meeting dated 17-18th December, 2018 made generation of Unique Document Identification Number (UDIN) mandatory for every signature of full time practicing chartered accountant in phased manner for following services:

**a)** All certificates with effect from 1st February, 2019.

**b)** GST and Income Tax Audit with effect from 1st April, 2019.

**c)** All Audit and Assurance Functions with effect from 1st July, 2019.

In view of the above, bidder shall ensure that any certificate/ reports issued/ attested by any practicing chartered accountant in India and submitted in the bid shall mandatorily include the UDIN number. Certificate / reports issued/ attested without UDIN number of practicing chartered accountant in India shall not be considered for evaluation. The requirement of including UDIN shall not be applicable for certificate/ reports issued/ attested by a chartered accountant practising in Foreign Country.

**46.0** Policy for Holiday listing of vendors in BPCL shall be as per **Appendix-V** to this ITB.

## 47.0 MSE VERIFICATION

MSE bidders shall provide the necessary valid documentary evidence issued under Udyam Registration or any other documents/certificates permitted by GoI.

MSEs shall provide the necessary valid documentary evidence, i.e. UDYAM Registration Certificate, Certification from a practicing Chartered Accountant (CA)-as per **Appendix-VI to ITB** (dated after the date of floating of tender and specific to the tender for which bid is being submitted). MSE Bidders

shall be eligible for exemption only if the URC Certificate / URC detail as submitted in the Bid. The Udyam registration certificate shall be verified from GoI Udyam registration portal (present web address is https://udyamreqistration.gov.in ).The status of the MSE Bidder as on the date of Unpriced Bid opening shall be considered.

**48.0 POWER OF ATTORNEY**

48.1 Bids shall be signed by the authorized signatory of the bidder holding power of attorney.

48.2 Bidder shall submit a Power of Attorney in the name of such authorized signatory(ies).

Requirements for submitting the POA shall be as follows:

i) **Company:** Bidder shall submit a specific Power of Attorney for the tender in the name of authorized person.

Alternatively, in case Bid signatory has General Power of Attorney or has the power as per their Board resolution, the same shall be submitted duly certified by Notary Public or CEO/CFO/Company Secretary (CS)/Member of Board of Directors.

In case, Bid is signed by CEO/CFO/CS/any member of board of Directors, no separate POA is required, provided the documentary evidence of their being CEO/CFO/CS/any member of board of Directors is reflected in the MOA/AOA/Financial Statements, else submitted separately in the Bid.

ii) **Partnership Firm:** In such case,

- Bid can be signed by all the partners of the Firm and in such case no separate POA is required. OR
- Bid can be signed by any of the Partner(s) holding Power of Attorney as specified in the Partnership deed, OR
- Bid can be signed by an authorized person and shall submit a specific POA for the tender duly signed by all the Partners.
- Bidder shall submit the copy of Partnership Deed.

iii) **Limited Liability Partnership (LLP) Entity:** Bid shall be signed by the person holding Power of Attorney as per the registered LLP Agreement for the Firm, OR, has the power as per their Board resolution, OR, a specific POA for the tender duly signed by all the LLP Partners.

Bidder shall submit (i) a copy of LLP Agreement, and (ii) a copy of Certificate of Incorporation.

**iv) Proprietorship: Proprietor shall sign the Bid.**

Bidder shall also submit a copy of (i) PAN card and (ii) Bank Mandate Form, duly certified by the Bidder's Banker.

v) **Unincorporated Joint Venture/Consortium** : Both members of the consortium shall authorize the Lead Member of the consortium with the authority to bind the consortium, through a Power of Attorney given jointly by all the members to the Lead Member.

Both Leader as well as Member of the Consortium/JV shall also submit a separate POA from their respective Company/ Firm in the name of the signatory signing the Consortium/JV Agreement. Depending on the formation/ registration/ constitution (Company/ Firm, etc.) of the Leader/Member of the Consortium/JV, POA shall be submitted in a manner, as applicable, as per the above clauses.

48.3 For Indian Bidder, POA shall be on non-judicial stamp paper of minimum value of INR 100/- and duly Notarized by a Notary Public in India.

For Foreign Bidders, POA shall be:

- on the Stamp Paper of appropriate value or engraving/embossing, in lieu of non-judicial stamp paper, as per applicable laws in Bidder's Country; or
- as per any other system prevailing in the bidder's country for the purpose of issuing POA.

Specific POA issued for the tender shall confirm that the authorized signatory have been authorized to do in the name and on behalf of the Company/Firm all or any of the acts, deeds or things necessary in connection with or incidental to the Bid submitted by the bidder for the subject Enquiry Document, including but not limited to the signing and submission of bid, participating in the meetings, responding to queries, submission of information / documents and generally to represent Company/Firm in all the dealings with BPCL/EIL or any person, in connection with the works, without any prejudice, limitations and exceptions till the completion of the bidding process.

# APPENDIX-I TO ITB

## Tender Clause on Procurement from Bidders from Country(ies) sharing land border with India

1.0 Department of Expenditure (DoE) vide **O.M. No. 7/10/2021-PPD(1) dated 23.02.2023** has issued the revised guidelines for Restrictions on Procurement from Bidders from Country(ies) sharing Border with India. These guidelines are available on the website of DoE (https://doe.gov.in).

2.0 **Requirement of registration from Competent Authority:**

i). Any Bidder from a country which shares a land border with India will be eligible to bid in any procurement whether of goods, services (including consultancy services and non-consultancy services) or works (including turnkey projects) only if the Bidder is registered with the Competent Authority, specified in **Annexure-I of DoE O.M. No. 7/10/2021-PPD(1) dated 23.02.2023.**.

ii). Any Bidder (including an Indian bidder) who has a Specified Transfer of Technology (ToT) arrangement with an entity from a country which shares a land border with India will be eligible to bid in any procurement whether of goods, services (including consultancy services and non-consultancy services) or works (including turnkey projects) only if the Bidder is registered with the Competent Authority, specified in **Annexure-I of DoE O.M. No. 7/10/2021-PPD(1) dated 23.02.2023.**

3.0 **This Order shall not apply to the following special cases:**

i). In projects which receive international funding with the approval of the Department of Economic Affairs (DEA), Ministry of Finance, the procurement guidelines applicable to the project shall normally be followed, notwithstanding anything contained in this order and without reference to the Competent Authority. Exceptions to this shall be decided in consultation with DEA.

ii). This order shall not apply to procurement by Indian missions and by offices of Government agencies/ undertakings located outside India.

iii). This order will not apply to Bidders (or Entities) from those countries (even if sharing a land border with India) to which the Government of India has extended lines of credit or in which the Government of India is engaged in development projects. Updated lists of countries to which lines of credit have been extended or in which development projects are undertaken are given on the website of the Ministry of External Affairs.

iv). Procurement of spare parts and other essential service support like Annual Maintenance Contract (AMC)/ Comprehensive Maintenance Contract (CMC), including consumables for closed systems, from Original Equipment Manufacturers (OEMs) or their authorized agents, shall be exempted from the requirement of registration.

4.0 **Definitions**:

i). **"Bidder"** (including the term 'Tenderer', 'Consultant' 'Vendor' or 'Service Provider' in certain contexts) means any person or firm or company, including any member of a Consortium or Joint Venture (that is an association of several Persons, or Firms or Companies), every artificial juridical person not falling in any of the descriptions of Bidders stated hereinbefore, including any Agency, Branch or Office controlled by such person, participating in a procurement process.



Page 80 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

ii). **"Tender"** will include other forms of procurement, except where the context requires otherwise.

iii). **"Transfer of Technology"** means dissemination and transfer of all forms of commercially usable knowledge such as transfer of know-how, skills, technical expertise, designs, processes and procedures, trade secrets, which enables the acquirer of such technology to perform activities using the transferred technology independently. (Matters of interpretation of this term shall be referred to the Registration Committee constituted by the Department for Promotion of Industry and Internal Trade, and the interpretation of the Committee shall be final.)

iv). **"Specified Transfer of Technology"** means a transfer of technology in the sectors and/ or technologies, specified in **paragraph 5.0**, occurring on or after 23.07.2020.

v). **"Bidder (or entity) from a country which shares a land border with India"** means

(a) An entity incorporated, established or registered in such a country; or

(b) A subsidiary of an entity incorporated, established or registered in such a country; or

(c) An entity substantially controlled through entities incorporated, established or registered in such a country; or

(d) An entity whose beneficial owner is situated in such a country; or

(e) An Indian (or other) agent of such an entity; or

(f) A natural person who is a citizen of such a country; or

(g) A Consortium or Joint Venture where any member of the Consortium or Joint Venture falls under any of the above.

vi). **Beneficial Owner** for the purposes of **paragraph 4.0 v) (d)** will be as under:

a) **In case of a Company or Limited Liability Partnership**, the beneficial Owner is the natural person(s), who, whether acting alone or together, or through one or more juridical person(s), has a controlling ownership interest or who exercises control through other means.

Explanation: -

1. "Controlling ownership interest" means ownership of, or entitlement to, more than twenty-five per cent of shares or capital or profits of the company;
2. "Control" shall include the right to appoint the majority of the Directors or to control the management or policy decisions, including by virtue of their shareholding or management rights or shareholders agreements or voting agreements;

b) **In case of a Partnership Firm**, the beneficial Owner is the natural person(s) who, whether acting alone or together, or through one or more juridical person, has ownership of entitlement to more than fifteen percent of capital or profits of the partnership;

c) **In case of an Unincorporated Association or body of Individuals**, the beneficial Owner is the natural person(s), who, whether acting alone or together, or through one or more juridical person, has ownership of or entitlement to more than fifteen percent of the property or capital or profits of such association or body of individuals;



Page 81 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

d) Where no natural person is identified under a) or b) or c) above, the beneficial Owner is the relevant natural person who holds the position of senior managing official;

e) **In case of a Trust**, the identification of beneficial Owner(s) shall include identification of the author of the trust, the trustee, the beneficiaries with fifteen percent or more interest in the trust and any other natural person exercising ultimate effective control over the trust through a chain of control or ownership.

vii). **"Agent'** is a person employed to do any act for another, or to represent another in dealings with third persons.

[Note:

i). A person who procures and supplies finished goods from an entity from a country which shares a land border with India will, regardless of the nature of his legal or commercial relationship with the producer of the goods, be deemed to be an Agent for the purpose of this Order.

ii). However, a Bidder who only procures raw material, components etc. from an entity from a country which shares a land border with India and then manufactures or converts them into other goods will not be treated as an Agent.]

5.0 **Sensitive Sectors/ Technologies (relevant only for the provisions on ToT arrangements):**

i). Certain sectors and technologies have been identified as sensitive from the national security point of view. **The sectors listed in Schedule I (copy attached) are considered Category-I sensitive sectors. The sectors listed in Schedule II (copy attached) are considered Category-II sensitive sectors**. The technologies listed in **Schedule III** (copy attached) are considered sensitive technologies.

ii). For **Category-I sensitive sectors**, Bidders with ToT arrangement in any technology with an entity from a country which shares a land border with India shall require registration.

iii). For **Category-II sensitive sectors**, Bidders with ToT arrangement in the sensitive technologies listed in **Schedule III**, with an entity from a country which shares a land border with India shall require registration.

iv). In **Category-II sensitive sectors**, the Secretary (or an officer not below the rank of Joint Secretary to Government of India, so authorized by the Secretary) of the Ministry/ Department of the Government of India is empowered, after due consideration, to waive the requirement of registration for a particular item/ application or a class of items/ applications from the requirement of registration, even if included in Schedule-III. The Ministry/ Department concerned shall intimate the Department for Promotion of Industry and Internal Trade (DPIIT) and National Security Council Secretariat (NSCS) of their decision to waive the requirement of registration.

Ministries/ Departments of the Government of India are not required to consult the DPIIT/ NSCS before deciding and are only required to intimate the decision to DPIIT/ NSCS. If any point is raised by DPIIT/ NSCS, it should be considered in future procurements; ongoing procurement for which the waiver was granted need not be interrupted or altered.

Based on security considerations, a Ministry/ Department in a **Category-II sensitive sector** or other Ministries/ Departments may recommend to DPIIT inclusion of any other technology in the list of sensitive technologies, either generally or for their Ministry/ Department.



24

Page 82 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

6.0 **Sub-contracting in works contracts**

In works contracts, including turnkey contracts, Contractors shall not be allowed to sub-contract works to any Contractor from a country which shares a land border with India unless such contractor is registered with the Competent Authority. The definition of **"Contractor from a country which shares a land border with India"** shall be as given in above paragraph 4.0 v).

[Note: Procurement of raw material, components, etc. does not constitute sub-contracting.]

7.0 **Certificate regarding compliance**

Bidder shall submit a certificate of Compliance in the enclosed Form-I A/ Form-I B/ Form - II (as applicable).

This certificate shall be on the Bidder's Letter head and shall be duly signed & stamped by the authorised signatory of the Bidder.

In case at any stage, it is found that the certification given by the Bidder is false, their Bid shall be rejected and shall be liable for other penal actions like placement on Suspension/ Banning or forfeiture of EMD (if applicable). However, if this is found after order placement, this would be ground for immediate termination and further legal actions in accordance with law/provisions of Bidding Document including Suspension/Banning and forfeiture of CPBG/ Security Deposit.



Page 83 of 4391 : B957-TENDER_DOC-B957-300-16-43-MR-T-3001 : Rev. A

## BIDDER'S UNDERTAKING

(On Company's Letter Head)

To,

M/s _____ (Name of the client)

Tender Name : _____

Tender No. : _____

"I have read the clause regarding restrictions on procurement from a Bidder of a country which shares a land border with India; I hereby certify that, Bidder M/s_____ (Name of the Bidder) is:

| | | |
|---|---|---|
| i). | Not from such a country | [ ] |
| ii). | If from such a country, has been registered with the Competent Authority | [ ] |

**Notes:**

a) Bidder to tick appropriate option (√) in either i) or ii) above)

b) In case of sl. no. ii) above, Bidder to attach evidence of valid registration by the Competent Authority.

I hereby certify that the Bidder fulfills all requirements in this regard and eligible to be considered.

Place :

Date :

Signature (#):

Name :

Designation :

Seal :

**(#) Undertaking shall be signed by the authorized signatory of the Bidder.**

**Form- I B**

## BIDDER'S UNDERTAKING IN CASE OF SUB-CONTRACTING IN WORK CONTRACTS

**(On Company's Letter Head)**

To,

M/s _____ (Name of the client)

Tender Name : _____

Tender No. : _____

"I have read the clause regarding restrictions on procurement from a Bidder of a country which shares a land border with India and on sub-Contracting to Contractors from such countries; I hereby certify that, Bidder M/s_____ (Name of the Bidder) is:

| | | |
|---|---|---|
| i). | Not from such a country and will not sub-Contract work to a Contractor from such countries unless such Contractor is registered with the Competent authority | [ ] |
| ii). | If from such a country, has been registered with the Competent Authority and will not sub-Contract work to a Contractor from such countries unless such Contractor is registered with the Competent authority | [ ] |
| **Notes:**<br>a) Bidder to tick appropriate option ($\surd$) in either i) or ii) above)<br>b) In case of sl. no. ii) above, Bidder to attach evidence of valid registration by the Competent Authority. | | |

I hereby certify that the Bidder fulfills all requirements in this regard and eligible to be considered.

Place :
Date :

Signature (#):
Name :
Designation :
Seal :

**(#) Undertaking shall be signed by the authorized signatory of the Bidder.**

FORM-II

## BIDDER'S UNDERTAKING IN CASE OF TRANSFER OF TECHNOLOGY (ToT) ARRANGEMENT

(On Company's Letter Head)

To,

M/s _____ (Name of the client)

Tender Name :

_____

Tender No. :

"I have read the clause regarding restrictions on procurement from a Bidder having Transfer of Technology (ToT) arrangement. Bidder M/s_____ (Name of the Bidder), hereby certify that,

| | | |
|---|---|---|
| i). | Bidder does not have any ToT arrangement requiring registration with the competent authority | [ ] |
| ii). | Bidder has valid registration to participate in this procurement | [ ] |

**Notes:**

a) Bidder to tick appropriate option (√) in either i) or ii) above)

b) In case of sl. no. ii) above, Bidder to attach evidence of valid registration by the Competent Authority.

I hereby certify that the Bidder fulfills all requirements in this regard and eligible to be considered.

Place :
Date :

Signature (#):
Name :
Designation :
Seal :

**(#) Undertaking shall be signed by the authorized signatory of the Bidder**

No.F.7/10/2021-PPD (1)
Government of India
Ministry of Finance
Department of Expenditure
Procurement Policy Division
264-C, North Block, New Delhi.
23.02.2023.

**Order (Public Procurement No. 4)**

**Subject: Restrictions under Rule 144(xi) of the General Financial Rules (GFRs), 2017.**

Attention is invited to Order (Public Procurement No. 1) issued vide F.6/18/2019-PPD dated 23.07.2020, Order (Public Procurement No. 2) issued vide F.6/18/2019-PPD dated 23.07.2020, Order (Public Procurement No. 3) issued vide F.6/18/2019-PPD dated 24.07.2020, Office Memorandum (OM) No. F.18/37/2020-PPD dated 08.02.2021, OM No. F.12/1/2021-PPD(Pt.) dated 02.03.2021 and OM No. F.7/10/2021-PPD dated 08.06.2021. In this regard, the following is hereby ordered under Rule 144(xi) (as amended vide OM No. F.7/10/2021-PPD dated 23.02.2023) on the grounds stated therein, in supersession to all of the above mentioned Orders/ clarifications:

**Requirement of registration:**

2. Any bidder from a country which shares a land border with India will be eligible to bid in any procurement whether of goods, services (including consultancy services and non-consultancy services) or works (including turnkey projects) only if the bidder is registered with the Competent Authority, specified in **Annexure I**.

3. Any bidder (including an Indian bidder) who has a Specified Transfer of Technology (ToT) arrangement with an entity from a country which shares a land border with India will be eligible to bid in any procurement whether of goods, services (including consultancy services and non-consultancy services) or works (including turnkey projects) only if the bidder is registered with the Competent Authority, specified in **Annexure I**.

4. The requirement of registration for cases covered by paragraph 2 above has been applicable since 23.07.2020. The requirement of registration for bidders covered by paragraph 3 above will be applicable for all procurements where tenders are issued/ published after 01.04.2023.

5. In tenders issued after 23.07.2020 or 01.04.2023, as the case may be, the provisions of requirement of registration of bidders and of other relevant provisions of this Order shall be incorporated in the tender conditions.

**Applicability:**

6. Apart from Ministries/ Departments, attached and subordinate bodies, notwithstanding anything contained in Rule 1 of the GFRs 2017, the Order shall also be applicable



Page 87 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

a) to all Autonomous Bodies;

b) to all public sector banks and public sector financial institutions;

c) to all Central Public Sector Enterprises;

d) to all procurement in Public Private Partnership projects receiving financial support from the Government or public sector enterprises/ undertakings; and

e) Union Territories, National Capital Territory of Delhi and all agencies/ undertakings thereof.

7. This order will not be applicable for cases falling under **Annexure II**.

**Definitions:**

8. "*Bidder*" for the purpose of the Order (including the term 'tenderer', 'consultant' 'vendor' or 'service provider' in certain contexts) means any person or firm or company, including any member of a consortium or joint venture (that is an association of several persons, or firms or companies), every artificial juridical person not falling in any of the descriptions of bidders stated hereinbefore, including any agency, branch or office controlled by such person, participating in a procurement process.

9. "*Tender*" for the purpose of the Order will include other forms of procurement, except where the context requires otherwise.

10. *"Transfer of Technology"* means dissemination and transfer of all forms of commercially usable knowledge such as transfer of know-how, skills, technical expertise, designs, processes and procedures, trade secrets, which enables the acquirer of such technology to perform activities using the transferred technology independently. (Matters of interpretation of this term shall be referred to the Registration Committee constituted by the Department for Promotion of Industry and Internal Trade, and the interpretation of the Committee shall be final.)

11. *"Specified Transfer of Technology"* means a transfer of technology in the sectors and/ or technologies, specified in paragraph 15, occurring on or after 23.07.2020.

12. *"Bidder (or entity) from a country which shares a land border with India"* for the purpose of the Order means

(a) An entity incorporated, established or registered in such a country; or

(b) A subsidiary of an entity incorporated, established or registered in such a country; or

(c) An entity substantially controlled through entities incorporated, established or registered in such a country; or

(d) An entity whose beneficial owner is situated in such a country; or

(e) An Indian (or other) agent of such an entity; or

(f) A natural person who is a citizen of such a country; or



Page 88 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

(g) A consortium or joint venture where any member of the consortium or joint venture falls under any of the above

13. *Beneficial owner* for the purposes of Para 12 (d) will be as under:

(i) In case of a company or Limited Liability Partnership, the beneficial owner is the natural person(s), who, whether acting alone or together, or through one or more juridical person(s), has a controlling ownership interest or who exercises control through other means.

*Explanation:-*

a. "Controlling ownership interest" means ownership of, or entitlement to, more than twenty-five per cent of shares or capital or profits of the company;

b. "Control" shall include the right to appoint the majority of the directors or to control the management or policy decisions, including by virtue of their shareholding or management rights or shareholders agreements or voting agreements;

(ii) In case of a partnership firm, the beneficial owner is the natural person(s) who, whether acting alone or together, or through one or more juridical person, has ownership of entitlement to more than fifteen percent of capital or profits of the partnership;

(iii) In case of an unincorporated association or body of individuals, the beneficial owner is the natural person(s), who, whether acting alone or together, or through one or more juridical person, has ownership of or entitlement to more than fifteen percent of the property or capital or profits of such association or body of individuals;

(iv) Where no natural person is identified under (i) or (ii) or (iii) above, the beneficial owner is the relevant natural person who holds the position of senior managing official;

(v) In case of a trust, the identification of beneficial owner(s) shall include identification of the author of the trust, the trustee, the beneficiaries with fifteen percent or more interest in the trust and any other natural person exercising ultimate effective control over the trust through a chain of control or ownership.

14. "*Agent*" for the purpose of the Order is a person employed to do any act for another, or to represent another in dealings with third persons.

[Note:

i. A person who procures and supplies finished goods from an entity from a country which shares a land border with India will, regardless of the nature of his legal or commercial relationship with the producer of the goods, be deemed to be an Agent for the purpose of this Order.

ii. However, a bidder who only procures raw material, components etc. from an entity from a country which shares a land border with India and then manufactures or converts them into other goods will not be treated as an Agent.]



Page 89 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**Sensitive Sectors/ Technologies** (relevant only for the provisions on ToT arrangements):

15. (i) Certain sectors and technologies have been identified as sensitive from the national security point of view. The sectors listed in Schedule I to this Order are considered Category-I sensitive sectors. The sectors listed in Schedule II to this Order are considered Category-II sensitive sectors. The technologies listed in Schedule III are considered sensitive technologies.

(ii) For Category-I sensitive sectors, bidders with ToT arrangement in any technology with an entity from a country which shares a land border with India shall require registration.

(iii) For Category-II sensitive sectors, bidders with ToT arrangement in the sensitive technologies listed in Schedule III, with an entity from a country which shares a land border with India shall require registration.

(iv) In Category-II sensitive sectors, the Secretary (or an officer not below the rank of Joint Secretary to Government of India, so authorized by the Secretary) of the Ministry/ Department of the Government of India is empowered, after due consideration, to waive the requirement of registration for a particular item/ application or a class of items/ applications from the requirement of registration, even if included in Schedule III. The Ministry/ Department concerned shall intimate the Department for Promotion of Industry and Internal Trade (DPIIT) and National Security Council Secretariat (NSCS) of their decision to waive the requirement of registration. Ministries/ Departments of the Government of India are not required to consult the DPIIT/ NSCS before deciding and are only required to intimate the decision to DPIIT/ NSCS. If any point is raised by DPIIT/ NSCS, it should be considered in future procurements; ongoing procurement for which the waiver was granted need not be interrupted or altered.

16. Based on security considerations, a Ministry/ Department in a Category II sensitive sector or other Ministries/ Departments may recommend to DPIIT inclusion of any other technology in the list of sensitive technologies, either generally or for their Ministry/ Department.

**Sub-contracting in works contracts**

17. In works contracts, including turnkey contracts, contractors shall not be allowed to sub-contract works to any contractor from a country which shares a land border with India unless such contractor is registered with the Competent Authority. The definition of "contractor from a country which shares a land border with India" shall be as in paragraph 12 above. This shall not apply to sub-contracts already awarded on or before 23.07.2020.

[Note: Procurement of raw material, components, etc. does not constitute sub-contracting.]



Page 90 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**Certificate regarding compliance**

18. An undertaking shall be taken from bidders in the tender documents **(Annexure III)** that the extant guidelines for participation in the tenders (which should include conditions for implementation of this Order) have been complied with. If such certificate given by a bidder whose bid is accepted is found to be false, this would be a ground for debarment and further legal action in accordance with law.

**Validity of registration**

19. In respect of tenders, registration should be valid at the time of submission of bids and at the time of acceptance of bids. In respect of supply otherwise than by tender, registration should be valid at the time of placement of order. If the bidder was validly registered at the time of acceptance / placement of order, registration shall not be a relevant consideration during contract execution.

**Government e-Marketplace (GeM)**

20. GeM shall remove non-compliant entities from GeM unless/ until they are registered in accordance with this Order.

**Model Clauses/ Certificates**

21. Model Clauses and Model Certificates which may be inserted in tenders/ obtained from Bidders are given at Annexure-III. While adhering to the substance of the Order, procuring entities are free to appropriately modify the wording of these clauses based on their past experience, local needs etc.

23/02/2023

(Kanwalpreet)
Director(PPD)
Tel.No. 2309 3811; email: kanwal.irss@gov.in

To

1. Secretaries of all Ministries/ Departments of Government of India for information and necessary action. They are also requested to inform these provisions to all procuring entities.
2. Secretary, Department of Public Enterprises with a request to immediately reiterate these orders in respect to public enterprises.
3. Secretary, Department of Financial Services with a request to immediately reiterate these orders in respect to public sector and public sector financial institutions.
4. Secretary DPIIT with a request to take action as provided under Annexure I.
5. Chief Secretaries/ Administrators of Union Territories/ National Capital Territory of Delhi.
6. CEO/ GeM with a request to ensure implementation of this order on GeM.



Page 91 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**Schedule I**

**List of Category-I Sensitive sectors:**

| Sr.No. | Sector |
|---|---|
| (i) | Atomic Energy |
| (ii) | Broadcasting/ Print and Digital Media |
| (iii) | Defence |
| (iv) | Space |
| (v) | Telecommunications |



Page 92 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**Schedule II**

**List of Category-II Sensitive sectors:**

| Sr.No. | Sector |
|---|---|
| (i) | Power and Energy (including exploration/ generation/ transmission/ distribution/ pipeline) |
| (ii) | Banking and Finance including Insurance |
| (iii) | Civil Aviation |
| (iv) | Construction of ports and dams & river valley projects |
| (v) | Electronics and Microelectronics |
| (vi) | Meteorology and Ocean Observation |
| (vii) | Mining and extraction (including deep sea projects) |
| (viii) | Railways |
| (ix) | Pharmaceuticals & Medical Devices |
| (x) | Agriculture |
| (xi) | Health |
| (xii) | Urban Transportation |



Page 93 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**Schedule-III**

**List of Sensitive Technologies:**

| Sr.No. | Sensitive Technologies |
|---|---|
| (i) | Additive Manufacturing (e.g. 3D Printing) |
| (ii) | Any equipment having electronic programmable components or autonomous systems (e.g. SCADA systems) |
| (iii) | Any technology used for uploading and streaming of data including broadcasting, satellite communication etc. |
| (iv) | Chemical Technologies |
| (v) | Biotechnologies including Genetic Engineering and Biological Technologies |
| (vi) | Information and Communication Technologies |
| (vii) | Software |



Page 94 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

ANNEXURE I

**Competent Authority and Procedure for Registration**

A. The Competent Authority for the purpose of registration under this order shall be/ continue to be the Registration Committee constituted by the Department for Promotion of Industry and Internal Trade (DPIIT)*. [This Committee was already constituted under Order (Public Procurement) No.1].

B. The Registration Committee shall have the following members*:

   i. An officer, not below the rank of Joint Secretary, designated for this purpose by DPIIT, who shall be the Chairman;

   ii. Officers (ordinarily not below the rank of Joint Secretary) representing the Ministry of Home Affairs, Ministry of External Affairs, and of those Departments whose sectors are covered by applications under consideration;

   iii. Any other officer whose presence is deemed necessary by the Chairman of the Committee.

   iv. With effect from 01.04.2023, an officer (ordinarily not below the rank of Joint Secretary) representing the National Security Council Secretariat.

C. DPIIT shall lay down the method of application, format etc. for such bidders as covered by the Order.

D. On receipt of an application seeking registration from a bidder covered by Para 2 and 3 of this order, the Competent Authority shall first seek political and security clearances from the Ministry of External Affairs and Ministry of Home Affairs, as per guidelines issued from time to time. Registration shall not be given unless political and security clearance have both been received.

E. The Ministry of External Affairs and Ministry of Home Affairs may issue guidelines for internal use regarding the procedure for scrutiny of such applications by them.

F. The decision of the Competent Authority, to register such bidder may be for all kinds of tenders or for a specified type(s) of goods or services, and may be for a specified or unspecified duration of time, as deemed fit. The decision of the Competent Authority shall be final.

G. Registration granted by the Competent Authority of the Government of India shall be valid not only for procurement by the Central Government and its bodies specified in para 6 of this order, but also for procurement by State Governments and their agencies/ public enterprises etc. No fresh registration at the State level shall be required.

H. The Competent Authority is empowered to cancel the registration already granted if it determines that there is sufficient cause. Such cancellation by itself, however, will



Page 95 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

not affect the execution of contracts already awarded. Pending cancellation, it may also suspend the registration of a bidder, and the bidder shall not be eligible to bid in any further tenders during the period of suspension.

l. For national security reasons, the Competent Authority shall not be required to give reasons for rejection/cancellation of registration of a bidder.

[*Note:

(i) In respect of application of the Order to procurement by/ under State Governments, all functions assigned to DPIIT shall be carried out by the State Government concerned through a specific department or authority designated by it. The composition of the Registration Committee shall be as decided by the State Government. However, the requirement of political and security clearance as per para D shall remain and no registration shall be granted without such clearance.

(ii) Registration granted by State Governments shall be valid only for procurement by the State Government and its agencies/ public enterprises etc. and shall not be valid for procurement in other states or by the Government of India and their agencies/ public enterprises etc.]



Page 96 of 4391 : B957-TENDER_DOC-B957-300-16-43-MR-T-3001 : Rev. A

**Special Cases**

A. In projects which receive international funding with the approval of the Department of Economic Affairs (DEA), Ministry of Finance, the procurement guidelines applicable to the project shall normally be followed, notwithstanding anything contained in this order and without reference to the Competent Authority. Exceptions to this shall be decided in consultation with DEA.

B. This order shall not apply to procurement by Indian missions and by offices of government agencies/ undertakings located outside India.

C. This order will not apply to bidders (or entities) from those countries (even if sharing a land border with India) to which the Government of India has extended lines of credit or in which the Government of India is engaged in development projects. Updated lists of countries to which lines of credit have been extended or in which development projects are undertaken are given on the website of the Ministry of External Affairs.

D. Procurement of spare parts and other essential service support like Annual Maintenance Contract (AMC)/ Comprehensive Maintenance Contract (CMC), including consumables for closed systems, from Original Equipment Manufacturers (OEMs) or their authorized agents, shall be exempted from the requirement of registration.



Page 97 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**Model Clause/ Certificate/ Undertaking to be inserted in tenders etc.**

[While adhering to the substance of the Order, procuring entities and GeM are free to appropriately modify the wording of the clause/ certificate based on their past experience, local needs etc.

The conditions relating to specified ToT (as shown in italics) should be incorporated only in the tenders which attract the restrictions due to specified ToT.]

**A. Model Clauses for Tenders (including tenders issued manually or any electronic portal including GeM):**

I. Any bidder from a country which shares a land border with India will be eligible to bid in any procurement whether of goods, services (including consultancy services and non-consultancy services) or works (including turnkey projects) only if the bidder is registered with the Competent Authority. *Further, any bidder (including bidder from India) having specified Transfer of Technology (ToT) arrangement with an entity from a country which shares a land border with India, shall also require to be registered with the same competent authority.*

II. "Bidder" (including the term 'tenderer', 'consultant' or 'service provider' in certain contexts) means any person or firm or company, including any member of a consortium or joint venture (that is an association of several persons, or firms or companies), every artificial juridical person not falling in any of the descriptions of bidders stated hereinbefore, including any agency branch or office controlled by such person, participating in a procurement process.

III. "Bidder (or entity) from a country which shares a land border with India" for the purpose of this Order means: -

(a) An entity incorporated, established or registered in such a country; or
(b) A subsidiary of an entity incorporated, established or registered in such a country; or
(c) An entity substantially controlled through entities incorporated, established or registered in such a country; or
(d) An entity whose beneficial owner is situated in such a country; or
(e) An Indian (or other) agent of such an entity; or
(f) A natural person who is a citizen of such a country; or
(g) A consortium or joint venture where any member of the consortium or joint venture falls under any of the above

IV. The beneficial owner for the purpose of (iii) above will be as under:

1. In case of a company or Limited Liability Partnership, the beneficial owner is the natural person(s), who, whether acting alone or together, or through one or more juridical person, has a controlling ownership interest or who exercises control through other means.

Explanation—



Page 98 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

a. "Controlling ownership interest" means ownership of or entitlement to more than twenty-five per cent. of shares or capital or profits of the company;

b. "Control" shall include the right to appoint majority of the directors or to control the management or policy decisions including by virtue of their shareholding or management rights or shareholders agreements or voting agreements;

2. In case of a partnership firm, the beneficial owner is the natural person(s) who, whether acting alone or together, or through one or more juridical person, has ownership of entitlement to more than fifteen percent of capital or profits of the partnership;

3. In case of an unincorporated association or body of individuals, the beneficial owner is the natural person(s), who, whether acting alone or together, or through one or more juridical person, has ownership of or entitlement to more than fifteen percent of the property or capital or profits of such association or body of individuals;

4. Where no natural person is identified under (1) or (2) or (3) above, the beneficial owner is the relevant natural person who holds the position of senior managing official;

5. In case of a trust, the identification of beneficial owner(s) shall include identification of the author of the trust, the trustee, the beneficiaries with fifteen percent or more interest in the trust and any other natural person exercising ultimate effective control over the trust through a chain of control or ownership.

V. An Agent is a person employed to do any act for another, or to represent another in dealings with third person.

VI. [To be inserted in tenders for Works contracts, including Turnkey contracts] The successful bidder shall not be allowed to sub-contract works to any contractor from a country which shares a land border with India unless such contractor is registered with the Competent Authority.

VII. The registration shall be valid at the time of submission of bid and at the time of acceptance of bid.

VIII. If the bidder was validly registered at the time of acceptance / placement of order, registration shall not be a relevant consideration during contract execution

**Model Certificate for Tenders:**

"I have read the clause regarding restrictions on procurement from a bidder of a country which shares a land border with India; I certify that this bidder is not from such a country or, if from such a country, has been registered with the Competent Authority. I hereby certify that this bidder fulfills all requirements in this regard and is eligible to be considered. [Where applicable, evidence of valid registration by the Competent Authority shall be attached.]"

**Model Certificate for Tenders for Works involving possibility of sub-contracting:**

"I have read the clause regarding restrictions on procurement from a bidder of a country which shares a land border with India and on sub-contracting to contractors from such countries; I certify that this bidder is not from such a country or, if from such a country, has been registered with the Competent Authority and will not sub-contract any



Page 99 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

work to a contractor from such countries unless such contractor is registered with the Competent Authority. I hereby certify that this bidder fulfills all requirements in this regard and is eligible to be considered. [Where applicable, evidence of valid registration by the Competent Authority shall be attached.]"

***Model additional certificate by Bidders in the cases of specified ToT:***

*"I have read the clause regarding restrictions on procurement from a bidder having Transfer of Technology (ToT) arrangement. I certify that this bidder does not have any ToT arrangement requiring registration with the competent authority."*

*OR*

*"I have read the clause regarding restrictions on procurement from a bidder having Transfer of Technology (ToT) arrangement. I certify that this bidder has valid registration to participate in this procurement."*

**B. Model Certificate for GeM (to be taken by the GeM from seller during registration on GeM. GeM should also obtain this certificate from all existing bidders as soon as possible):**

"I have read the clause regarding restrictions on procurement from a bidder of a country which shares a land border with India; I certify that this vendor/ bidder is not from such a country and does not have any specified Transfer of Technology (ToT) from such a country or, if from such a country or if having specified ToT from such a country has been registered with the Competent Authority. I hereby certify that this vendor/ bidder fulfills all requirements in this regard and is eligible to be considered for procurement on GeM. [Where applicable, evidence of valid registration by the Competent Authority shall be attached.]"

***



Page 100 of 4391 : B957-TENDER_DOC-B957-300-16-43-MR-T-3001 : Rev. A

# APPENDIX-II TO ITB

Annexure-2

**FORM – 2**

**SELF CERTIFICATION BY BIDDER UNDER PPP-MII ORDER, 2017**

**To**

**M/s** _____ <Insert name of Client>

**NAME OF WORK / ITEM:**

**TENDER /RFQ NO. :**

Dear Sir,

We, M/s _____ *<Name of Bidder>* hereby confirm that we meet the mandatory minimum requirement of Local Content (LC) for **Class-I local supplier / Class-II local supplier** *(strike out which is not applicable)* under Public Procurement (Preference to Make in India), Order 2017 (PPP-MII, 2017) and the work / Item shall have **LC of** _____**%.**

The details of the location(s) at which the local value addition is/shall be made, is/ areas under:

.....
.....
.....

We confirm compliance of Public Procurement (Preference to Make in India) (PPP-MII) Order 2017, vide Order No P-45021/2/2017-PP(BE-II)-Part-4)Vol.II, Notifications with respect to Electronics Products [File No. W-43/4/2019-IPHW-Meity dated 07.09.2020 and S.O. No 4591(E) dated 12.10.2023 issued by Meity], Cyber Security Products [File No.1(10)/2017-CLES dated 06.12.2019 issued by Meity] and Telecom Products [File No FP-18-10/2017-IP dated 21.10.2024 issued by Ministry of Telecommunication]. {Strike out which is not applicable}.

We also confirm that, the imported items sourced locally from resellers/distributors are excluded from calculation of local content. The cost of such locally sourced imported items (inclusive of taxes) along with break up on license/royalties paid/technical expertise etc. sourced from outside India shall be submitted at the time of execution as per Form-2A.

We further confirm that in case we fail to meet the minimum local content/domestic value addition, the same shall be treated as false information and Owner reserves the right to take appropriate action for debarment, Penalty after award etc. as per provision of the PPP-MII Order, 2017 and its subsequent Amendments and as more specifically mentioned in the Bidding/ RFQ document.

We also confirm that we are not debarred by any other procuring entity (GOI/PSU/PSE etc.)
or
Our debarment period is completed as on _____ <insert date>, and as such we are eligible to avail purchase preference under this Order.
***(## Strike out which is not applicable)***

_____
Signature of Bidder

Place:

Name :

Date:

Designation

Seal :



Page 102 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**FORM-2A**

**DETAILS OF IMPORTED COMPONENTS SOURCED FROM RESELLERS/DISTRIBUTORS EXCLUDED UNDER LOCAL CONTENT**

RFQ/TENDER No:

ITEM/WORKS DESCRIPTION:

| S. No | Cost component | Cost in INR (Refer Note-2) |
|---|---|---|
| a. | Locally-sourced imported items from resellers/distributors (inclusive of taxes) | i.<br>ii.<br>iii.<br>iv. |
| b. | License/Royalties paid/ Technical Expertise cost etc. for the items sourced from outside India<br>i. License<br>ii. Royalties Paid<br>iii. Technical Expertise Cost<br>iv. other | i.<br>ii.<br>iii.<br>iv. |
| DETAILS OF ITEMS SOLD BY BIDDER AS RESELLER | | |
| c. | Details of Items | OEM Certificate for country of origin |
| | i.<br>ii.<br>iii.<br>iv. | i.<br>ii.<br>iii.<br>iv. |

**Note –**

1. For contracts involving supply of multiple items, weighted average of all items to be taken while calculating the local content.
2. As regards cases where currency for above is other than Indian Rupee, exchange rate prevailing on the Bid Due Date shall be considered for the calculation of Local Content.
3. Bidder to enclose OEM Certificate for country of origin as specified in S. No (c) above.

| | |
|---|---|
| | Signature of Bidder |
| Place: | Name : |
| Date: | Designation |
| | Seal : |

**ANNEXURE-3**

**FORM – 3**

**(FOR CLASS-I LOCAL SUPPLIER/ CLASS-II LOCAL SUPPLIER HAVING VALUE OF PROCUREMENT MORE THAN INR 10 CRORE)**

**CERTIFICATE UNDER PPP-MII ORDER, 2017 TOWARDS MANDATORY MINIMUM LOCAL CONTENT**

**To**
**M/s** _____ <Insert name of Client/Owner>

**NAME OF WORK / ITEM:**

**TENDER /RFQ NO.:**

Dear Sir,

We, _____, the Statutory Auditor or Cost Auditor of the Company (in case of Companies) or are a practicing Cost Accountant or practicing Chartered Accountant (in respect of supplier other than companies) of M/s. _____ *<Name of Bidder>*, hereby certify that as per definition specified in above policy, M/s. _____ *<Name of Bidder>* is a Class-I Local Supplier / Class-II Local Supplier <as applicable>

We further confirm that M/s _____ *<Name of Bidder>* meet the mandatory minimum Local content requirement specified for Class-I Local supplier/ Class-II Local supplier <as applicable> under Policy for Public Procurement (Preference to Make in India), Order 2017 (PPP-MII) for their offer for the abovementioned Work/ Item and shall have local content of _____% .

The details of the location(s) at which the local value addition is/shall be made, is/ areas under:

.....
.....

We confirm compliance of Public Procurement (Preference to Make in India) (PPP-MII) Order 2017, vide Order No P-45021/2/2017-PP(BE-II)-Part-4)Vol.II, Notifications with respect to Electronics Products [File No. W-43/4/2019-IPHW-Meity dated 07.09.2020 and S.O. No 4591(E) dated 12.10.2023 issued by Meity], Cyber Security Products [File No.1(10)/2017-CLES dated 06.12.2019 issued by Meity] and Telecom Products [File No FP-18-10/2017-IP dated 21.10.2024 issued by Ministry of Telecommunication]. ***{Strike out which is not applicable}.***

We also confirm that, the imported items sourced locally from resellers/distributors are excluded from calculation of local content. The cost of such locally sourced imported items (inclusive of taxes) along with break up on license/royalties paid/technical expertise etc. sourced from outside India is enclosed as Form-3A.

We also confirm that M/s _____ <Name of Bidder> is not debarred by any other procuring entity (GOI/PSU/PSE etc.).
OR
M/s _____<Name of Bidder>'s debarment period is completed as on _____<insert date>, and as such M/s _____ <Name of Bidder> is eligible to availed purchase preference under this Order.
**## (Strike out which is not applicable)**

_____
Signature of certificate issuing authority

Place:

Name :

Date:

Name of Audit Firm:

Designation

Seal :



Page 104 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

Page 105 of 4391 : B957-TENDER_DOC-B957-300-16-43-MR-T-3001 : Rev. A

FORM-3A

**DETAILS OF IMPORTED COMPONENTS SOURCED FROM RESELLERS/DISTRIBUTORS EXCLUDED UNDER LOCAL CONTENT**

RFQ/TENDER No:

ITEM/WORKS DESCRIPTION:

| S. No | Cost component | Cost in INR (Refer Note-2) |
|---|---|---|
| a. | Locally-sourced imported items from resellers/distributors (inclusive of taxes) | i.<br>ii.<br>iii. |
| b. | License/Royalties paid/ Technical Expertise cost etc. for the items sourced from outside India<br>i. License<br>ii. Royalties Paid<br>iii. Technical Expertise Cost<br>iv. other | <br>i.<br>ii.<br>iii.<br>iv. |
| DETAILS OF ITEMS SOLD BY BIDDER AS RESELLER | | |
| c. | Details of Items | OEM Certificate for country of origin |
| | i.<br>ii.<br>iii. | i.<br>ii.<br>iii. |

**Note –**

1. For contracts involving supply of multiple items, weighted average of all items to be taken while calculating the local content.
2. As regards cases where currency for above is other than Indian Rupee, exchange rate prevailing on the Bid Due Date shall be considered for the calculation of Local Content.
3. Bidder to enclose OEM Certificate for country of origin as specified in S. No (c) above.
4. The above formats are indicative, the statutory auditor/Cost auditor/Chartered Accountant/ Cost Accountant can modify the format without changing the intent of certification.

_____

Signature of certificate issuing authority

Place:

Name:

Date:

Name of Audit Firm:

Designation

Seal:

**Form -2B**

**Format for Self-Certification regarding Local Content (LC) for Telecom Product, Services or Works to be submitted on non-judicial stamp paper of the value Rs. 100/-**

Date:

I_ _____S/o, D/o, W/o, Resident of _____ do hereby solemnly affirm and declare as under:

That I agree to abide by the terms and conditions of Department of Telecommunications, Government of India issued vide Notification No:_____ dated_____.

That the information furnished hereinafter is correct to the best of my knowledge and belief and I undertake to produce relevant records before the procuring entity or any other authority so nominated by the Department of Telecommunications, Government of India for the purpose of assessing the LC.

That the LC for all inputs which constitute the said Telecom Product/Services/Works has been verified by me and I am responsible for the correctness of the claims made therein.

That in the event of the LC of the Telecom Product/Services/Works mentioned herein is found to be incorrect and not meeting the prescribed LC norms, based on the assessment of an authority so nominated by the Department of Telecommunications, Government of India, I and my Statutory auditor or cost auditor (if applicable) will be liable for actions as specified in Clause (9) of the DPIIT PPP-MII Order dated 19.07.2024 for all incorrect/false facts and figures.

I agree to maintain detailed breakup / information (separately for each product) to substantiate my claim for LC in the Company's record for a period of 2 years and shall make this available for verification to any authority. I shall also maintain records of local content pertaining to items bought from other domestic manufacturers / traders.

[Please provide following information]

| | |
|---|---|
| i | Name and details of the local supplier - Registered Office, Manufacturing unit location, nature of legal entity |
| ii | Date of certificate issuance - Date on which this certificate is issued |
| iii | Telecom Product/Services/Works - Telecom Product/Services/Works for which the certificate is produced |
| iv | Procuring agency - Procuring agency to whom the certificate is furnished |
| v | Percentage of Local Content claimed - Percentage of LC claimed |
| vi | Manufacturer unit details - Name and contact details of the unit of the manufacturer |
| vii | Sale Price of the product - Sale Price of the product |
| viii | Ex-Factory Price of the product - Ex-Factory Price of the product |
| ix | Freight, insurance and handling - Freight, insurance and handling charges |
| x | Total Bill of Material - Total Bill of Material |



Page 106 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

Page 107 of 4391 : B957-TENDER_DOC-B957-300-16-43-MR-T-3001 : Rev. A

| | |
|---|---|
| xi | Local inputs cost - List and total cost value of inputs used for manufacture of the Telecom product/Services/Works |
| xii | Locally sourced inputs - List and total cost of inputs which are locally sourced. Please attach LC certificates from local suppliers, if the input is not produced in-house |
| xiii | Imported inputs cost - List and cost of inputs which are imported, directly or indirectly |

I hereby certify that, having read all the provisions of the above order and principles / basis of calculations, the local content calculation does not include the following:

a. Imported items sourced locally from resellers/distributors.

b. The license fees / royalties paid/ technical charges paid out of India

c. Procurement / supply of repackaged / refurbished/rebranded imported products

I hereby also certify to the best of my knowledge and belief that all the particulars furnished above are correct and complete. I agree to comply with the terms and conditions of the DPIIT PPP-MII order dated 19.07.2024 and DoT PPPMII Notification dated.....

I understand that any incorrect declaration regarding the local content or failure to substantiate the claim of LC will result in penalties as specified in Clause (9) of the DPIIT PPP-MII Order dated 19.07.2024.

I further certify and take personal responsibility that I have applied my mind to the calculations and principles of LC as specified in this order and I shall, having declared the LC shall not seek recourse to change it on any ground. Any changes made by me on any grounds in a bid in LC after bid submission shall make my bid non-responsive and I shall hold myself liable for civil/criminal action arising out of any such change. I understand and agree that any such post bid change in LC content shall also be a valid ground for blacklisting of the firm from future contracts/bids.

Signature:
Name:
Designation: CEO/MD
Address:
Email Address:
Mobile No.:
Place:
Date:

## Form-2C

**Format for Self-Declaration regarding local supplier' for Cyber Security Products**

This is to Certify that the organization_____ registered as_____with registration number_____ do hereby solemnly affirm and declare as under:

That we agree to abide by the terms and conditions of the Notification issued by Ministry of Electronics and Information Technology (MeitY), Government of India no: _____dated_____.

That the information furnished hereinafter is correct and we undertake to produce relevant records before the procuring entity or any other authority so nominated by the Ministry of Electronics and Information Technology (MeitY), Government of India for the purpose of establishing ownership of the Intellectual Property Rights(IPR), legal existence and revenue accrual, local content for the cyber security products nominated by the aforesaid organization.

That all IPR which constitute the said cyber security product has been verified by us and we are responsible for the correctness of the claims made therein and we take complete responsibility of the same.

We agree to maintain all information regarding our claim(s) for IPR ownership, legal existence and revenue accrual, local content in the organization's record throughout the existence of the product and shall make this available for verification to any authorities specified by Government of India.

In case of any change in the IPR ownership, legal existence and revenue accrual, local content we will be accountable to inform Ministry of Electronics and Information Technology, Government of India within one week or before applying for any public procurement or before referring this order for taking any advantage which so ever occurs first.

That in the event of the cyber security product mentioned herein is found to be incorrect and not meeting the prescribed norms, based on the assessment of an authority so nominated by the MeitY, Government of India and we will be liable as under clause 7 (f) of Public Procurement (Preference to Make in India) Order 2019 for cyber security product.

1. Name and details of the organization nominating product under this order (Registered Office, Manufacturing unit location, nature of legal entity)

2. Entity Registration Certificate number
   a. Type of registration

3. Date on which this certificate is issued

4. Percentage of Royalty/License fee to be paid to other entity with respect to estimated cost of the product

5. Name and contact details of the unit of the manufacturer

For and on behalf of_____ (Name of firm/entity)

Authorize signatory (To be duly authorized by the Board of Directors)



Page 108 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

Page 109 of 4391 : B957-TENDER_DOC-B957-300-16-43-MR-T-3001 : Rev. A

## FORM – 2D

### CERTIFICATE UNDER DOMESTICALLY MANUFACTURED/PRODUCED CYBER SECUIRTY PRODUCTS

### (HAVING VALUE OF PROCUREMENT MORE THAN INR 10 CRORE)

**To**
**M/s** _____ <Insert name of Client/Owner>

**NAME OF WORK / ITEM:**

**TENDER /RFQ NO.:**

Dear Sir,

We, _____, the Statutory Auditor or Cost Auditor of the Company (in case of Companies) or are a practicing Cost Accountant or practicing Chartered Accountant (in respect of supplier other than companies) of M/s. _____ *<Name of Bidder>*, hereby certify offered product(s) by M/s _____ *<Name of Bidder>* meets the definition of 'local supplier' of domestically manufactured/produced Cyber Security Products as per para 4 of Public Procurement (Preference to Make in India) Order 2019 for Cyber Security Products.

_____
Signature of certificate issuing authority

Place:

Name :

Date:

Name of Audit Firm:

Designation

Seal :

No. P-45021/2/2017-PP (BE-II)-Part(4)Vol.II
Government of India
Ministry of Commerce and Industry
Department for Promotion of Industry and Internal Trade
(Public Procurement Section)

Vanijya Bhawan, New Delhi
Dated: 19 July,2024

To

All Central Ministries/Departments/CPSUs/All concerned

**ORDER**

**Subject: Public Procurement (Preference to Make in India), Order 2017– Revision; regarding.**

**Department for Promotion of Industry and Internal Trade, in partial modification [Paras 2, 3, 5, 10 & 13] of Order No.P-45021/2/2017-B.E.-II dated 15.6.2017 as amended by Order No.P-45021/2/2017-B.E.-II dated 28.05.2018, Order No.P-45021/2/2017-B.E.-II dated 29.05.2019, Order No.P-45021/2/2017-B.E.-II dated 04.06.2020 and Order No.P-45021/2/2017-B.E.-II dated 16.09.2020 hereby issues the revised 'Public Procurement (Preference to Make in India), Order 2017" dated 19.07.2024 effective with immediate effect.**

**Whereas** it is the policy of the Government of India to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment, and

**Whereas** procurement by the Government is substantial in amount and can contribute towards this policy objective, and

**Whereas** local content can be increased through partnerships, cooperation with local companies, establishing production units in India or Joint Ventures (JV) with Indian suppliers, increasing the participation of local employees in services and training them,

**Now therefore the following Order is issued:**

1. This Order is issued pursuant to Rule 153 (iii) of the General Financial Rules 2017.
2. **Definitions**: For the purposes of this Order:
   *'Local content'* means the amount of value added in India which shall, unless otherwise prescribed by the Nodal Ministry, be the total value of the item procured (excluding net domestic indirect taxes) minus the value of imported content in the item (including all customs duties) as a proportion of the total value, in percent.

***Explanatory notes for calculation of local content given above***

a. Imported items sourced locally from resellers/distributors shall be excluded from calculation of local content.
b. The license fees/royalties paid/ technical charges paid out of India shall be excluded from local content calculation.



Page 110 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

c. Procurement/Supply of repackaged/refurbished/rebranded imported products as understood commonly shall be treated as reselling of imported products and shall be excluded from calculation of local content. The definition of repackaged/refurbished/rebranded imported products is as follows;

'Refurbishing' means repair or reconditioning of an imported product does not amount to manufacture because no new goods come into existence.

'Repackaging' means repacking of imported goods from bulk pack to smaller packs would not ordinarily amount to manufacture of a new item.

'Rebranding' means relabeling or renaming or change in symbol or logo/makes or corporate image of a company/organization/ firm for an imported product would amount to rebranding.

d. To ensure that imported items sourced locally from resellers/distributors are excluded from calculation of local content, procuring entities to obtain from bidders, the cost of such locally-sourced imported items (Inclusive of taxes) along with break-up on license/royalties paid/technical expertise cost etc. sourced from outside India. For items sold by bidder as reseller, OEM certificate for country of origin to be submitted.

e. For contracts involving supply of multiple items, weighted average of all items to be taken while calculating the local content.

'*Class-I local supplier*' means a supplier or service provider, whose goods, services or works offered for procurement, meets the minimum local content as prescribed for 'Class-I local supplier' under this Order.

*'Class-II local supplier'* means a supplier or service provider, whose goods, services or works offered for procurement, meets the minimum local content as prescribed for 'Class-II local supplier' but less than that prescribed for 'Class-I local supplier' under this Order.

*'Non - Local supplier'* means a supplier or service provider, whose goods, services or works offered for procurement, has local content less than that prescribed for 'Class-II local supplier' under this Order.

*'L1'* means the lowest tender or lowest bid or the lowest quotation received in a tender, bidding process or other procurement solicitation as adjudged in the evaluation process as per the tender or other procurement solicitation.

*'Margin of purchase preference'* means the maximum extent to which the price quoted by a "Class-I local supplier" may be above the L1 for the purpose of purchase preference.

*'Nodal Ministry'* means the Ministry or Department identified pursuant to this order in respect of a particular item of goods or services or works.

*'Procuring entity'* means a Ministry or department or attached or subordinate office of, or autonomous body controlled by, the Government of India and includes Government companies as defined in the Companies Act.

*'Works'* means all works as per Rule 130 of GFR- 2017, and will also include *'turnkey works'*.

**2A. *Special treatment for items covered under PLI Scheme***

The manufacturers manufacturing an item under PLI scheme shall be treated as deemed Class II local supplier for that item unless they have minimum local content equal to or higher than that notified for Class-I local supplier for that item, provided the manufacturer has received incentive from the concerned PLI Ministry for the item. The above shall be applicable for the specific time period only, as notified by concerned PLI Ministry.

**3. Eligibility of 'Class-I local supplier'/ 'Class-II local supplier'/ 'Non-local suppliers' for different types of procurement**

(a) In procurement of all goods, services or works in respect of which the Nodal Ministry / Department has communicated that there is sufficient local capacity and local competition, only 'Class-I local supplier', as defined under the Order, shall be eligible to bid irrespective of purchase value.

(b) Only 'Class-I local supplier' and 'Class-II local supplier', as defined under the Order, shall be eligible to bid in procurement undertaken by procuring entities, except when Global tender enquiry has been issued. In global tender enquiries, 'Non-local suppliers' shall also be eligible to bid along with 'Class-I local suppliers' and 'Class-II local suppliers'. In procurement of all goods, services or works, not covered by sub-para 3(a) above, and with estimated value of purchases less than Rs. 200 Crore, in accordance with Rule 161(iv) of GFR, 2017, Global tender enquiry shall not be issued except with the approval of competent authority as designated by Department of Expenditure.

(c) For the purpose of this Order, works includes Engineering, Procurement and Construction (EPC) contracts and services include System Integrator (SI) contracts.

**3.1 Mandatory sourcing of items, with sufficient local capacity and competition, from Class-I local suppliers in SI/EPC/Turnkey Contracts/Service Tenders**

a. The items, notified as having sufficient local capacity and competition, shall mandatory be sourced from Class-I local suppliers in SI/EPC/Turnkey Contracts/ Services tenders. This provision will be applicable only for those items which have been notified by the Nodal Ministry as Class I i.e. having sufficient local capacity and competition, with specific HSN codes."

b. Notwithstanding above, if in any project, it is considered that it is not practically feasible to source such items from Class I local suppliers, it may take relaxation from such stipulation with the approval of Secretary of the administrative Ministry/ Department concerned or with the approval of the Competent Authority specified by the Administrative Ministry/Department, on case-specific basis.

**3A. Purchase Preference**

(a) Subject to the provisions of this Order and to any specific instructions issued by the Nodal Ministry or in pursuance of this Order, purchase preference shall be given to 'Class-I local supplier' in procurement undertaken by procuring entities in the manner specified here under.

(b) In the procurement of goods or works, which are covered by para 3(b)

above and which are divisible in nature, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

i. Among all qualified bids, the lowest bid will be termed as L1. If L1 is 'Class-I local supplier', the contract for full quantity will be awarded to L1.

ii. If L1 bid is not a 'Class-I local supplier', 50% of the order quantity shall be awarded to L1. Thereafter, the lowest bidder among the 'Class-I local supplier' will be invited to match the L1 price for the remaining 50% quantity subject to the Class-I local supplier's quoted price falling within the margin of purchase preference, and contract for that quantity shall be awarded to such 'Class-I local supplier' subject to matching the L1 price. In case such lowest eligible 'Class-I local supplier' fails to match the L1 price or accepts less than the offered quantity, the next higher 'Class-I local supplier' within the margin of purchase preference shall be invited to match the L1 price for remaining quantity and so on, and contract shall be awarded accordingly. In case some quantity is still left uncovered on Class-I local suppliers, then such balance quantity may also be ordered on the L1 bidder.

(c) In the procurement of goods or works, which are covered by para 3(b) above and which are not divisible in nature, and in procurement of services where the bid is evaluated on price alone, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

i. Among all qualified bids, the lowest bid will be termed as L1. If L1 is Class -I local supplier', the contract will be awarded to L1.

ii. If L1 is not 'Class-I local supplier', the lowest bidder among the 'Class-I local supplier', will be invited to match the L1 price subject to Class-I local supplier's quoted price falling within the margin of purchase preference, and the contract shall be awarded to such 'Class-I local supplier' subject to matching the L1 price.

iii. In case such lowest eligible 'Class-I local supplier' fails to match the L1 price, the 'Class-I local supplier' with the next higher bid within the margin of purchase preference shall be invited to match the L1 price and so on and contract shall be awarded accordingly. In case none of the 'Class-I local supplier' within the margin of purchase preference matches the L1 price, the contract may be awarded to the L1 bidder.

(d) "Class-II local supplier" will not get purchase preference in any procurement, undertaken by procuring entities.

**3B. Applicability in tenders where contract is to be awarded to multiple bidders-** In tenders where contract is awarded to multiple bidders subject to matching of L1 rates or otherwise, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

a. In case there is sufficient local capacity and competition for the item to be procured, as notified by the nodal Ministry, only Class I local suppliers shall be eligible to bid. As such, the multiple suppliers, who would be awarded the contract, should be all and only 'Class I Local suppliers'.

b. In other cases, 'Class II local suppliers' and 'Non local suppliers' may also participate in the bidding process along with 'Class I Local suppliers' as per provisions of this Order.

c. If 'Class I Local suppliers' qualify for award of contract for at least

50% of the tendered quantity in any tender, the contract may be awarded to all the qualified bidders as per award criteria stipulated in the bid documents. However, in case 'Class I Local suppliers' do not qualify for award of contract for at least 50% of the tendered quantity, purchase preference should be given to the 'Class I local supplier' over 'Class II local suppliers'/ 'Non local suppliers' provided that their quoted rate falls within 20% margin of purchase preference of the highest quoted bidder considered for award of contract so as to ensure that the 'Class I Local suppliers' taken in totality are considered for award of contract for at least 50% of the tendered quantity.

d. First purchase preference has to be given to the lowest quoting 'Class-I local supplier', whose quoted rates fall within 20% margin of purchase preference, subject to its meeting the prescribed criteria for award of contract as also the constraint of maximum quantity that can be sourced from any single supplier. If the lowest quoting 'Class-I local supplier', does not qualify for purchase preference because of aforesaid constraints or does not accept the offered quantity, an opportunity may be given to next higher 'Class-I local supplier', falling within 20% margin of purchase preference, and so on.

e. To avoid any ambiguity during bid evaluation process, the procuring entities may stipulate its own tender specific criteria for award of contract amongst different bidders including the procedure for purchase preference to 'Class-I local supplier' within the broad policy guidelines stipulated in sub- paras above.

4. **Exemption of small purchases**: Notwithstanding anything contained in paragraph 3, procurement where the estimated value to be procured is less than Rs. 5 lakhs shall be exempt from this Order. However, it shall be ensured by procuring entities that procurement is not split for the purpose of avoiding the provisions of this Order.

**4A. Exemption in sourcing of spares and consumables of closed systems:**

Procurement of spare parts, consumables for closed systems and Maintenance/ Service contracts with Original Equipment Manufacturer/Original Equipment Supplier/Original Part Manufacturer shall be exempted from this Order.

5. **Minimum local content**: The 'local content' requirement to categorize a supplier as 'Class-I local supplier' is minimum 50%. For 'Class-II local supplier', the 'local content' requirement is minimum 20%. Nodal Ministry/ Department may prescribe only a higher percentage of minimum local content requirement to categorize a supplier as 'Class-I local supplier'/ 'Class- II local supplier'. For the items, for which Nodal Ministry/ Department has not prescribed higher minimum local content notification under the Order, it shall be 50% and 20% for 'Class-I local supplier'/ 'Class-II local supplier' respectively.

6. **Margin of Purchase Preference**: The margin of purchase preference shall be 20%.

7. **Requirement for specification in advance**: The minimum local content, the margin of purchase preference and the procedure for preference to Make in India shall be specified in the notice inviting tenders or other form of procurement solicitation and shall not be varied during a particular procurement transaction.

8. **Government E-marketplace**: In respect of procurement through the Government E-marketplace (GeM) shall, as far as possible, specifically mark the items which meet the minimum local content while registering the item for

display, and shall, wherever feasible, make provision for automated comparison with purchase preference and without purchase preference and for obtaining consent of the local supplier in those cases where purchase preference is to be exercised.

9. **Verification of local content**:

a. The 'Class-I local supplier'/ 'Class-II local supplier' at the time of tender, bidding or solicitation shall be required to indicate percentage of local content and provide self-certification that the item offered meets the local content requirement for 'Class-I local supplier'/ 'Class-II local supplier', as the case may be. They shall also give details of the location(s) at which the local value addition is made.

b. In cases of procurement for a value in excess of Rs. 10 crores, the 'Class-I local supplier'/ 'Class-II local supplier' shall be required to provide a certificate from the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) giving the percentage of local content.

c. The bidder shall give self-certification for local content in the quoted item (goods/works/services) at the time of tendering. However, at the time of execution of the project, for all contracts above INR 10 Crore, the contractor/ supplier shall be required to give local content certification duly certified by cost/ chartered accountant in practice. For cases where it is not possible to provide certification by Cost/Chartered Accountant at the time of execution of project, the supplier shall be permitted to provide the certificate for local content from Cost/ Chartered Accountant after completion of the contract, within time limit acceptable to the procuring entity. In case the contractor/ supplier does not meet the stipulated local content requirement and the category of the supplier changes from Class-I to Class-II/ Non-local or from Class-II to Non-local, a penalty upto 10% of the contract value may be imposed. However, contract once awarded shall not be terminated on this account.

d. Decisions on complaints relating to implementation of this Order shall be taken by the competent authority which is empowered to look into procurement-related complaints relating to the procuring entity.

e. Nodal Ministries may constitute committees with internal and external experts for independent verification of self-declarations and auditor's/ accountant's certificates on random basis and in the case of complaints.

f. Nodal Ministries and procuring entities may prescribe fees for such complaints.

g. False declarations will be in breach of the Code of Integrity under Rule 175(1)(i)(h) of the General Financial Rules for which a bidder or its successors can be debarred for up to two years as per Rule 151 (iii) of the General Financial Rules along with such other actions as may be permissible under law.

h. A supplier who has been debarred by any procuring entity for violation of this Order shall not be eligible for preference under this Order for procurement by any other procuring entity for the duration of the debarment. The debarment for such other procuring entities shall take effect prospectively from the date on which it comes to the notice of other procurement entities, in the manner prescribed under paragraph 9

i below.

i. The Department of Expenditure shall issue suitable instructions for the effective and smooth operation of this process, so that:
   i. The fact and duration of debarment for violation of this Order by any procuring entity are promptly brought to the notice of the Member-Convenor of the Standing Committee and the Department of Expenditure through the concerned Ministry /Department or in some other manner;
   ii. On a periodical basis such cases are consolidated and a centralized list or decentralized lists of such suppliers with the period of debarment is maintained and displayed on website(s);
   iii. In respect of procuring entities other than the one which has carried out the debarment, the debarment takes effect prospectively from the date of uploading on the website(s) in the such a manner that ongoing procurement are not disrupted.

10. **Specifications in Tenders and other procurement solicitations**:
   a. Every procuring entity shall ensure that the eligibility conditions in respect of previous experience fixed in any tender or solicitation do not require proof of supply in other countries or proof of exports.
   b. Procuring entities shall endeavour to see that eligibility conditions, including on matters like turnover, production capability and financial strength do not result in unreasonable exclusion of 'Class-I local supplier'/ 'Class-II local supplier' who would otherwise be eligible, beyond what is essential for ensuring quality or creditworthiness of the supplier.
   c. Procuring entities shall, within 2 months of the issue of this Order review all existing eligibility norms and conditions with reference to sub-paragraphs 'a' and 'b' above.
   d. **Reciprocity Clause**
      i. When a Nodal Ministry/Department identifies that Indian suppliers of an item are not allowed to participate and/ or compete in procurement by any foreign government, due to restrictive tender conditions which have direct or indirect effect of barring Indian companies such as registration in the procuring country, execution of projects of specific value in the procuring country etc., it shall provide such details to all its procuring entities including CMDs/CEOs of PSEs/PSUs, State Governments and other procurement agencies under their administrative control and GeM for appropriate reciprocal action.
      ii. Entities of countries which have been identified by the nodal Ministry/Department as not allowing Indian companies to participate in their Government procurement for any item related to that nodal Ministry shall not be allowed to participate in Government procurement in India for all items related to that nodal Ministry/ Department, except for the list of items published by the Ministry/ Department permitting their participation.
      iii. The stipulation in (ii) above shall be part of all tenders invited by the Central Government procuring entities stated in (i) above. All purchases on GeM shall also necessarily have the above provisions for items identified by nodal Ministry/ Department.
      iv. State Governments should be encouraged to incorporate similar provisions in their respective tenders.
      v. The term 'entity' of a country shall have the same meaning as under the FDI Policy of DPIIT as amended from time to time.
   e. Specifying foreign certifications/ unreasonable technical specifications/

brands/ models in the bid document is restrictive and discriminatory practice against local suppliers. If foreign certification is required to be stipulated because of non-availability of Indian Standards and/or for any other reason, the same shall be done only after written approval of Secretary of the Department concerned or any other Authority having been designated such power by the Secretary of the Department concerned.

f. "All administrative Ministries/Departments *whose procurement exceeds Rs. 1000 Crore per annum* shall notify/update their procurement projections every year, including those of the PSEs/PSUs, for the next 5 years on their respective website."

**10A. Action for non-compliance of the Provisions of the Order:** In case restrictive or discriminatory conditions against domestic suppliers are included in bid documents, an inquiry shall be conducted by the Administrative Department undertaking the procurement (including procurement by any entity under its administrative control) to fix responsibility for the same. Thereafter, appropriate action, administrative or otherwise, shall be taken against erring officials of procurement entities under relevant provisions. Intimation on all such actions shall be sent to the Standing Committee.

11. **Assessment of supply base by Nodal Ministries**: The Nodal Ministry shall keep in view the domestic manufacturing / supply base and assess the available capacity and the extent of local competition while identifying items and prescribing the higher minimum local content or the manner of its calculation, with a view to avoiding cost increase from the operation of this Order.

12. **Increase in minimum local content**: The Nodal Ministry may annually review the local content requirements with a view to increasing them, subject to availability of sufficient local competition with adequate quality.

13. **Manufacture under license/ technology collaboration agreements with phased indigenization**: While notifying the minimum local content, Nodal Ministries may make special provisions for exempting suppliers from meeting the stipulated local content if the product is being manufactured in India under a license from a foreign manufacturer who holds intellectual property rights and where there is a technology collaboration agreement / transfer of technology agreement for indigenous manufacture of a product developed abroad with clear phasing of increase in local content.

13A. In procurement of all goods, services or works in respect of which there is substantial quantity of public procurement and for which the nodal ministry has not notified that there is sufficient local capacity and local competition, the concerned nodal ministry shall notify an upper threshold value of procurement beyond which foreign companies shall enter into a joint venture with an Indian company to participate in the tender. Procuring entities, while procuring such items beyond the notified threshold value, shall prescribe in their respective tenders that foreign companies may enter into a joint venture with an Indian company to participate in the tender. The procuring Ministries/Departments shall also make special provisions for exempting such joint ventures from meeting the stipulated minimum local content requirement, which shall be increased in a phased manner.

14. **Powers to grant exemption and to reduce minimum local content**: The administrative Department undertaking the procurement (including

procurement by any entity under its administrative control), with the approval of their Minister-in-charge, may by written order, for reasons to be recorded in writing,

a. reduce the minimum local content below the prescribed level; or
b. reduce the margin of purchase preference below 20%; or
c. exempt any particular item or supplying entities from the operation of this Order or any part of the Order.

The Administrative Department, while seeking exemption under this para, shall certify that such an item(s) has not been notified by Nodal Ministry/ Department concerned under para 3 (a) of the Order.

A copy of every such order shall be provided to the Standing Committee and concerned Nodal Ministry / Department. The Nodal Ministry / Department concerned will continue to have the power to vary its notification on Minimum Local Content.

15. **Directions to Government companies**: In respect of Government companies and other procuring entities not governed by the General Financial Rules, the administrative Ministry or Department shall issue policy directions requiring compliance with this Order.
16. **Standing Committee**: A standing committee is hereby constituted with the following membership:
Secretary, Department for Promotion of Industry and Internal Trade - Chairman
Secretary, Commerce—Member
Secretary, Ministry of Electronics and Information Technology—Member Joint Secretary (Public Procurement), Department of Expenditure—Member Joint Secretary (DPIIT)—Member-Convenor

The Secretary of the Department concerned with a particular item shall be a member in respect of issues relating to such item. The Chairman of the Committee may co-opt technical experts as relevant to any issue or class of issues under its consideration.

17. **Functions of the Standing Committee:** The Standting Committee shall meet as often as necessary, but not less than once in six months. The Committee

a. shall oversee the implementation of this order and issues arising therefrom, and make recommendations to Nodal Ministries and procuring entities.
b. shall annually assess and periodically monitor compliance with this Order
c. shall identify Nodal Ministries and the allocation of items among them for issue of notifications on minimum local content
d. may require furnishing of details or returns regarding compliance with this Order and related matters
e. may, during the annual review or otherwise, assess issues, if any, where it is felt that the manner of implementation of the order results in any restrictive practices, cartelization or increase in public expenditure and suggest remedial measures
f. may examine cases covered by paragraph 13 above relating to manufacture under license/ technology transfer agreements with a view to satisfying itself that adequate mechanisms exist for enforcement of such agreements and for attaining the underlying objective of progressive indigenization



Page 118 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

g. may consider any other issue relating to this Order which may arise.

18. **Removal of difficulties**: Ministries /Departments and the Boards of Directors of Government companies may issue such clarifications and instructions as may be necessary for the removal of any difficulties arising in the implementation of this Order.

19. **Ministries having existing policies**: Where any Ministry or Department has its own policy for preference to local content approved by the Cabinet after 1st January 2015, such policies will prevail over the provisions of this Order. All other existing orders on preference to local content shall be reviewed by the Nodal Ministries and revised as needed to conform to this Order, within two months of the issue of this Order.

20. **Transitional provision**: This Order shall not apply to any tender or procurement for which notice inviting tender or other form of procurement solicitation has been issued before the issue of this Order.

19/7/24

(Himani Pande)
Additional Secretary to the Government of India
Tel: 011-23038888
E-mail: ashp.dpiit@gov.in



Page 119 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**File No: FP-20013/2/2017-FP-PNG-Part (4) (E-41432)**
**Government of India**
**Ministry of Petroleum and Natural Gas**
**(Flagship Programme Cell)**
****

Shastri Bhawan, New Delhi
Dated: 26th March, 2024

To

1. Chairman, IOCL
2. C&MD, ONGC/ BPCL/ HPCL/ OIL/ GAIL/ EIL/ Balmer Lawrie
3. Managing Director, CPCL/ NRL/ MRPL/ BCPL/ OVL
4. DG, DGH
5. DG, PPAC
6. Secretary, OIDB
7. ED, OISD
8. ED, CHT
9. Director, RGIPT/ IIPE
10. Secretary, PNGRB
11. CEO & MD, ISPRL

**Subject: Public Procurement (Preference to Make in India) Order, 2017-reg.**

Sir/ Madam,

I am directed to refer to this Ministry's letter of even number dated 26.04.2022 on the above mentioned subject.

2. In this regard, it is stated that the sector specific relaxation granted under para 2(b) of aforementioned letter, has been reviewed in the Ministry and it has been decided that scope of this relaxation shall be limited to the items (list enclosed) to be installed/ operated in flammable environment of oil and gas process industry.

3. This issues with the approval of Hon'ble Minister, P&NG.

Yours faithfully

Kala 26/3/24
(Kala)
Under Secretary to the Govt. of India
Tel.: 011-23381029

Encl.: as above

**Copy to:**

a. PS to Hon'ble Minister, P&NG
b. PS to Hon'ble MoS, P&NG
c. PPS/ PS to Secretary, P&NG
d. PPS/PS to AS&FA/ AS, MoPNG
e. PPS/ PS to JS (E & BR)/ JS(GP)/ JS (M& OR)/ JS (IC)/ JS (G)/ JS (IFD)/ DDG, MoPNG
f. Technical Director, NIC: with a request to upload the letter on MoPNG website

**Copy for information to,**

Secretary, DPIIT

**File No: FP-20013/2/2017-FP-PNG-Part (4) (E-41432)**
**Government of India**
**Ministry of Petroleum and Natural Gas**
**(Flagship Programme Cell)**
****

Shastri Bhawan, New Delhi
Dated 26th April, 2022

To,

1. Chairman, IOCL
2. C&MD, BPCL/ HPCL/ ONGC/ OIL/ GAIL/ EIL/ Balmer Lawrie
3. Managing Director, MRPL/NRL/CPCL// BCPL/ OVL
4. DG, DGH
5. DG, PPAC
6. Secretary, OIDB
7. ED, PCRA
8. ED, OISD
9. ED, CHT
10. Director, RGIPT
11. Secretary, PNGRB
12. CEO & MD, ISPRL

**Sub: Public Procurement (Preference to Make in India) (PPP-MII) Order, 2017-reg.**

Sir/Madam,

I am directed to refer to this Ministry's letter of even number dated 23.02.2022 regarding Policy to Provide Purchase Preference (linked with local content) (PP-LC) in all Public Sector Undertakings under the Ministry of Petroleum and Natural Gas (MoP&NG) and to say that Public Procurement (Preference to Make in India) Order, 2017 issued by DPIIT and as amended time to time shall be applicable to all the Public Sector Undertakings and their wholly owned subsidiaries under MoP&NG; Joint Ventures that have 51% or more equity by one or more Public Sector Undertakings under MoP&NG; attached and subordinate offices of MoPNG w.e.f. 01.04.2022.

2. Moreover, as per para 14 of the PPP-MII Order, the following modifications in the order shall be applicable on the procuring entities under this Ministry:

a. Limit for exemption of small purchase under para 4 of the PPP-MII Order, 2017 shall be Rs. 1 crore.

b. Local value addition through services such as transportation, insurance, installation, commissioning, training and after sales services support like AMC/ CMC etc. shall continue to be considered in local content calculation.

c. HP-HT operations in upstream oil and gas business activities shall be exempted from applicability of the Order.

3. This issues with the approval of Hon'ble Minister, Petroleum and Natural Gas.

Yours faithfully

26/04/2022

(Santanu Dhar)
Under Secretary to the Govt. of India
Tel.: 011-23388652

**Copy to:**

a. PS to Minister, PNG
b. PPS/ PS to Secretary/ AS&FA/ Sr. Economic Advisor, MoPNG
c. PPS/ PS to AS (E)/ JS(R)/ JS (M& GP)/ OSD (IC)/ JS (G)/ JS (IFD)/ DDG (ED), MoPNG
d. PPS/PS to Dir.(BR)/Dir.(E-II)/Dir.(E-I)/DS(GP)/DS(Mkt.)/DS(LPG)/DS(Admn.)/DS(RTI)/ DS (Gen) MoPNG

**Copy for information to:**

Secretary, DPIIT

**Items specifically to be used in flammable environment of oil and gas process industry in which value addition through services such as transportation, insurance installation, commissioning, training and after sales service support like AMC/CMC shall be continued to be conserved wile computing Local Content:**

| Sl. | Items Category of procurement |
|---|---|
| 1 | **Instrumentation items** like DCS/ ESD/ PLC, Emission Monitoring System, Machine Monitoring System, Condition Monitoring System, Fire Detection & Alarm System, Gas & Liquid Metering Systems, Mass Flow Meter, Process Analysers, Ultrasonic flowmeter, Anti surge & Governor Control system, Master control station for MOVs, Actuators, Transmitters, Radar gauges, multi-spot temperature sensors, Batch Controller unit, Additive blocks, Hydrocarbon detectors, Field instruments like Radar Gauges, Nucleonic gauges, Servo level gauging, Hydrastep, SMART Positioner in control valves, Multi point Reactor Thermocouple, Flame scanner, Viscosity cum Density meter, High Pressure/Temperature Special type valves, IS Test Equipment, Flare flow meter, Tank Farm Management System, Loading Automation System, Gas Detection System, Corrosion Monitoring System, Wireless Instrumentation, Surge Relief Valve Skid, Meter Provers, Pipeline Leak detection system (Negative Pressure wave type) etc |
| 2 | Equipment involved in drilling, completion, testing and production of oil and gas wells, Electronic carousel, Safety Relief valves, Compressors, turbines and blowers, heat ejectors, exchangers, condensers where SITC and / Expert Supervisory Services are involved, Equipment for which Life Cycle cost evaluation is done considering AMC/CAMC etc. |
| 3 | Electrical Equipment like Flameproof Plant Communication system, GIS (Gas Insulated Switchgear), Numerical Relays, Flameproof and/or explosion proof CCTV, Synchronous Machines, TETRA System etc |
| 4 | Laboratory and R&D Equipment like Gas Chromatographs, Spectrometers, Analytical equipment, Automatic liquid sampler, Dry colorimetric (tape) detectors; Mercury Free PVT Equipment; HT-HP Corrosion cell; Wheel Test Machine; Atmospheric and HT-HP- Consistometer; Ultra Sonic Cement Analyzer / HT-Ultra Sonic Cement Analyzer; Compressive strength tester; Stirred fluid loss apparatus; Total Sulfur analyzer; Colony counter; Laminar flow systems; Microscope with digital camera; Anaerobic Chamber; RockEval; TOC analyser; Simdist analyser; Cold Finger test apparatus; Microcoulometer; Atomic Absorption Spectrometer; High Performance Ion Chromatograph; Permeameter; Helium Porosimeter; Laser Scattering Particle Size Distribution Analyser; Microscope high magnification; Flame Photometer; U.V.- Visible Spectrophotometers; EP Lube tester; Differential sticking tester; Electrical stability Meter; Stemi-2000 microscope/ equivalent; Core Gama Logger; Energy Dispersive Spectrometer; Thin Section Machine; X-Ray Diffractometer; Wettability tester; Ambient Resistivity System; Flouroscope; Spin Drop Tensiometer; Fluid Eval; Mercury Inclusion Porosity meter; Tri-Axial test machine; Smoke point detector; Vitrinite Reflectance VRo Microscope; Curing Chamber/ HT curing chamber; Source Rock Pyrolyser with Sulphur/ without sulphur; NGA Gas Analyzer Flash Point Apparatus/ automatic; Compressive Strength Analyser; HT-HP Curing Chamber; Crush resistance test equipment; Manual Dry bath pore point Apparatus; Bench Type Dissolved Oxygen meter; Bench Type GRAIN Moisture meter; Rotational Viscometer; Capillary pressure instrument; Core Plugging Machine; Core Trimming machine; HP-HT filter press; BENCH TOP DENSITY METER; HP-HT ROLLER OVEN with AGING CELLS; Crude Oil Analyser; Static Gel Strength analyser; Oilwell cement Mechanical properties analyser; Poroperm; Acoustic velocity system; Auto Saturator; Porosimeter cum permeameter; Rock Testing System; Auto Core Saturator; Auto Imbibiometer for reverse permeability; Proppant Conductivity Tester etc |

| | |
|---|---|
| 5 | Pipeline Intrusion and Detection System (PIDS), SCADA & APPS system; Rim seal protection system, Chemical Treatment program which involves supply of Process chemicals, Dosing & monitoring the parameters etc |
| 6 | **Geophysical Services**<br>Seismic Data Acquisition System; VSP Data Acquisition System; Field Processing Unit; Geophysical equipment (non-Seismic including Gravity Magnetic, MT, EM etc.); Seismic Data Processing Software ; Seismic Data Interpretation Software ; Hydrocarbon Reservoir Software ; Seismic Data Archival Software ; Petro -Physical Software |
| 7 | **Geophysical Equipment**<br>Field Processing Unit, Global Navigation Satellite System, Specialised Geological Lab Equipment, Seismic Data Acquisition System, Seismic Data Processing/ Imaging Software, Tape Drive Unit, VSP Data Acquisition System, VSP Processing Software; High-End Servers for G&G Applications, HPCC Solution; Virtualization and Container Software |
| 8 | **Logging Services**<br>Logging unit, equipment and tools rated for hostile HPHT environment (Temperature > 300°F & Pressure > 10.000 psi). |

****

रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-07092020-221592
CG-DL-E-07092020-221592

असाधारण
EXTRAORDINARY

भाग I—खण्ड 1
PART I—Section 1

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 232] नई दिल्ली, सोमवार, सितम्बर 7, 2020/भाद्र 16, 1942
No. 232] NEW DELHI, MONDAY, SEPTEMBER 7, 2020/BHADRA 16, 1942

## इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय

## (आई.पी.एच.डब्ल्यू.)

## अधिसूचना

नई दिल्ली, 7 सितंबर, 2020

**विषय:** सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के अनुक्रम में इलेक्ट्रॉनिक उत्पादों को अधिसूचित करना

**संदर्भ : उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) के दिनांक 28.05.2018, 29.05.2019 और 04.06.2020 के आदेशों के जरिए यथासंशोधित आदेश संख्या पी-45021/2/2017-बीई-II दिनांक 15.06.2017**

**फा. सं. डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई.**—सरकार ने 'मेक इन इंडिया' को प्रोत्साहित करने और आय और रोजगार बढ़ाने के उद्देश्य से भारत में वस्तुओं और सेवाओं के विनिर्माण और उत्पादन को बढ़ावा देने के लिए उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) के दिनांक 28.05.2018, 29.05.2019 और 04.06.2020 के आदेशों के जरिए यथासंशोधित आदेश संख्या पी-45021/2/2017-बीई-II, दिनांक 15.06.2017 के तहत सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश, 2017 जारी किया है।

2. उपर्युक्त संदर्भ के जरिए अधिसूचित सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश, 2017 [पीपीपी-एमआईआई आदेश 2017] के अनुक्रम में और इसके तहत जारी की गई दिनांक 14.09.2017 की इलेक्ट्रॉनिक उत्पाद अधिसूचना संख्या 33(1)/2017-आईपीएचडब्ल्यू और दिनांक 01.08.2018 की अधिसूचना संख्या 33(5)/2017-आईपीएचडब्ल्यू के अधिक्रमण में इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय (एमईआईटीवाई) एतदद्वारा अधिसूचित करता है कि समय-समय पर संशोधित पूर्वोक्त आदेश के अनुसार स्थानीय रूप से विनिर्मित इलेक्ट्रॉनिक उत्पादों को सभी क्रय संस्थाओं द्वारा वरीयता प्रदान की जाएगी।



Page 124 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**3. इस अधिसूचना के उद्देश्य से:**

क. श्रेणी-I स्थानीय आपूर्तिकर्ता, श्रेणी-II स्थानीय आपूर्तिकर्ता और गैर-स्थानीय आपूर्तिकर्ता की परिभाषा समय-समय पर यथासंशोधित डीपीआईआईटी पीपीपी-एमआईआई आदेश, 2017 संख्या पी-45021/2/2017-पीपी (बीई-II), दिनांक 04.06.2020 के पैरा 2 के अनुसार होगी। समय-समय पर यथासंशोधित डीपीआईआईटी पीपीपी-एमआईआई आदेश, 2017 संख्या पी-45021/2/2017-पीपी (बीई-II), दिनांक 04.06.2020 के पैरा 5 के अनुसार इस अधिसूचना में अधिसूचित प्रत्येक इलेक्ट्रॉनिक उत्पाद के लिए स्थानीय सामग्री की गणना के लिए तंत्र निर्धारित किया गया है।

ख. समय-समय पर यथासंशोधित डीपीआईआईटी पीपीपी-एमआईआई आदेश, 2017 संख्या पी-45021/2/2017-पीपी (बीई-II), दिनांक 04.06.2020 के पैरा 3क क्रय के प्रतिशत के लिए संदर्भित किया जाएगा जिसके लिए अधिमानतः घरेलू स्तर पर विनिर्मित इलेक्ट्रॉनिक उत्पादों (मूल्य के संदर्भ में) को वरियता दी जानी है।

4. सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत निम्नलिखित इलेक्ट्रॉनिक उत्पाद अधिसूचित किए गए हैं:

**4.1 डेस्कटॉप पर्सनल कंप्यूटर (पीसी)**

**(क) परिभाषा:**

इस अधिसूचना के प्रयोजन से एक डेस्कटॉप पीसी में आवश्यक रूप से एक सीपीयू, मेमोरी, हार्ड डिस्क ड्राइव, की-बोर्ड, माउस और एक अलग या एकीकृत डिस्प्ले यूनिट शामिल होगी और इसे स्वतंत्र रूप से कार्य करने में सक्षर्थ होना चाहिए।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र:**

डेस्कटॉप पीसी की सामग्री का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| **बी.ओ.एम के प्रमुख इनपुट/डेस्कटॉप पीसी के विनिर्माण के लिए चरण** | **घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री** |
|---|---|
| **1** | **2** |
| मुख्य बोर्ड/मदरबोर्ड और सीपीयू/जीपीयू | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स** और सीपीयू/जीपीयू** का मूल्य शामिल है और बेयर पीसीबी का मूल्य इसमें शामिल नहीं है। हालाँकि, सीपीयू के कुल मूल्य का भार डेस्कटॉप पीसी के कुल बीओएम के 30% से अधिक नहीं होगा। |
| मेमोरी मॉड्यूल | बेयर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेयर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों से घरेलू पीसीबी असेंबली* एवं परीक्षण। |
| हार्ड डिस्क ड्राइव/सॉलिड स्टेट ड्राइव (एसएसडी) | बेयर पीसीबी के मूल्य को छोड़कर आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* एवं फाइनल उत्पाद असेम्बली और परीक्षण। |
| एलसीडी/एलईडी मॉनिटर | आयातित/घरेलू रूप से असेम्बल किए गए एलसीडी/एलईडी पैनल वाले कलपुर्जों से एलसीडी/एलईडी मॉनीटर की घरेलू स्तर पर असेम्बली और परीक्षण और घरेलू पीसीबी असेंबली*, घरेलू प्लास्टिक मोल्डिंग और बेयर पीसीबी के मूल्य को छोड़कर धातुई कलपूर्जों की स्टैम्पिंग। |

| | |
|---|---|
| डीवीडी ड्राइव | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| कैबिनेट + एमएसपीएस | घरेलू रूप से विनिर्मित कैबिनेट और घरेलू पीसीबी असेम्बली* और आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से एसएमपीएस की फाइनल असेम्बली और परीक्षण, इस शर्त के अध्यधीन कि "एसएमपीएस" की असेम्बली में उपयोग किए जाने वाले घरेलू विनिर्मित कलपुर्जे और संघटक न्यूनतम 20% होंगे ("एसएमपीएस" के विनिर्माण में उपयोग किए जाने वाले कलपुर्जों और संघटकों के कुल मूल्य के)। |
| की-बोर्ड और माउस | घरेलू पीसीबी असेम्बली* और आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से फाइनल असेम्बली और परीक्षण। |
| बेयर पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित। |
| (i) फाइनल असेंबली/परीक्षण और<br>(ii) डिजाइन/विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर (एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

**4.2 थिन क्लाइंट**

**(क) परिभाषा**:

इस अधिसूचना के प्रयोजन से किसी थिन क्लाइंट (टीसी) में अनिवार्य रूप से सीपीयू, मेमोरी, डोम, की-बोर्ड, माउस और एक अलग या एकीकृत डिस्प्ले यूनिट शामिल होते हैं और यह स्वतंत्र रूप से कार्य करने में सक्षम होना चाहिए।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र**:

थिन क्लाइंट की सामग्री का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| **बीओएम के प्रमुख इनपुट/थिन क्लाइंट के विनिर्माण के लिए चरण** | **घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री** |
|---|---|
| 1 | 2 |
| मुख्य बोर्ड/मदरबोर्ड और सीपीयू | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स** और सीपीयू** का मूल्य शामिल है और बेयर पीसीबी का मूल्य इसमें शामिल नहीं है। हालाँकि, सीपीयू के कुल मूल्य का भार थिन क्लाइंट के कुल बीओएम के 30% से अधिक नहीं होगा। |

| | |
|---|---|
| मेमोरी मॉड्यूल/डोम | बेयर पीसीबी के मूल्य को छोड़कर आयातित/घरेलू स्तर पर विनिर्मित बेयर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों से घरेलू पीसीबी असेंबली* और परीक्षण। |
| एसएमपीएस/पावर अडैप्टर | घरेलू रूप से पीसीबी असेंबलीं * और आयातित/ घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से एसएमपीएस / पावर अडैप्टर की फाइनल असेंबली और टेस्टिंग, इस शर्त के अधीन है कि "एसएमपीएस" की असेंबली में प्रयुक्त घरेलू विनिर्मित पुर्जे और कलपुर्जे न्यूनतम 20% होंगे ("एसएमपीएस") के विनिर्माण में उपयोग किए जाने वाले कलपुर्जों और संघटकों के कुल मूल्य के)। |
| एलसीडी/एलईडी मॉनिटर | आयातित/घरेलू रूप से असेंबली किए गए एलसीडी/एलईडी पैनल वाले कलपुर्जों से एलसीडी/एलईडी मॉनीटर की घरेलू स्तर पर असेम्बली और परीक्षण और घरेलू पीसीबी असेंबली*, घरेलू प्लास्टिक मोल्डिंग और बेयर पीसीबी के मूल्य को छोड़कर धातुई कलपूर्जों की स्टैम्पिंग। |
| कैबिनेट | घरेलू तौर पर विनिर्मित। |
| की-बोर्ड और माउस | घरेलू पीसीबी असेम्बली* और आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से फाइनल असेम्बली और परीक्षण। |
| बेयर पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित । |
| (i) फाइनल असेंबली / परीक्षण और<br>(ii) डिजाइन / विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर (एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

### 4.3 लैपटॉप पर्सनल कंप्यूटर (पीसी)

**(क) परिभाषा** :

इस अधिसूचना के प्रयोजन से किसी लैपटॉप पीसी (जिसे आमतौर पर लैपटॉप/नोटबुक/नेटबुक/अल्ट्राबुक आदि के रूप में बाजार में जाना जाता है) में आवश्यक रूप से सीपीयू, मेमोरी, हार्ड डिस्क ड्राइव, कीबोर्ड, टचपैड और/या ट्रैकपॉइंट एकीकृत प्रदर्शन इकाई, एकीकृत बैटरी शामिल होंगे और यह स्वतंत्र रूप से प्रचालित होने में सक्षम होना चाहिए।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र**:

लैपटॉप पीसी का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| **बीओएम प्रमुख इनपुट लैपटॉप के विनिर्माण के लिए चरण** | **घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/ स्थानीय सामग्री** |
|---|---|
| 1 | 2 |
| मुख्य बोर्ड/मदरबोर्ड और सीपीयू/जीपीयू | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स** और सीपीयू/जीपीयू** का मूल्य शामिल है और बेयर पीसीबी का मूल्य इसमें शामिल नहीं है। हालाँकि, सीपीयू के कुल मूल्य का भार लैपटॉप के कुल बीओएम के 35% से अधिक नहीं हो |
| पावर मॉड्यूल | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण । |
| मेमोरी मॉड्यूल | बेयर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेयर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों से घरेलू पीसीबी असेंबली* और परीक्षण । |
| हार्ड डिस्क ड्राइव/सॉलिड स्टेट ड्राइव (एसएसडी) | बेयर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और फाइनल उत्पाद असेम्बली और परीक्षण। |
| डिस्प्ले पैनल (एलसीडी, एलईडी, आदि) | बैक कवर और बेज़ेल में घरेलू असेंबली और बैक कवर और बेज़ेल के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर डिस्प्ले पैनल, एलईडी बैक लाइट, एंटेना से फाइनल परीक्षण। |
| डीवीडी ड्राइव | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण । |
| पावर अडैप्टर | घरेलू पीसीबी असेंबली के साथ आयातित/घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों से फाइनल घरेलू असेंबली* और परीक्षण, इस शर्त के अध्यधीन है कि "पावर अडैप्टर" की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों का मूल्य न्यूनतम 40% होगा ("पावर अडैप्टर" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का) । |
| बेयर पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित। |
| कीबोर्ड/टचपैड और/या ट्रैकपॉइंट | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण । |
| बैटरी | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण । |
| बॉटम कवर, बैक कवर, कीबोर्ड फेस बेजेल और डिस्प्ले फेस बेजल और हिंगेस सहित लैपटॉप के कैबिनेट/चेसिस | आयातित/घरेलू इनपुट का उपयोग करके इंजेक्शन मोल्डिंग / स्टांपिंग के माध्यम से घरेलू स्तर पर विनिर्मित । |
| ( i ) फाइनल असेंबली/परीक्षण और<br>(ii) डिजाइन/विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर (एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

### 4.4 कंप्यूटर मॉनिटर

**(क) परिभाषा** :

इस अधिसूचना के प्रयोजन से, एक कंप्यूटर मॉनीटर (जिसे आमतौर पर बाजार में मॉनीटर के रूप में जाना जाता है) में एक एलसीडी/एलईडी डिस्प्ले असेंबली, लॉजिक कार्ड, पॉवर सप्लाई अडैप्टर और कैबिनेट होता है जो इसे डेस्कटॉप पीसी या लैपटॉप पीसी या टैबलेट पीसी से कनेक्ट करने के लिए डिस्प्ले पोर्ट्स से युक्त होता है।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र** :

कंप्यूटर मॉनिटर का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| **बीओएम के प्रमुख इनपुट/कंप्यूटर मॉनिटर के विनिर्माण के लिए चरण** | **घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री** |
|---|---|
| 1 | 2 |
| लॉजिक कार्ड/माइक्रो कंट्रोलर | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स का मूल्य शामिल है और बेयर पीसीबी का मूल्य शामिल नहीं है। |
| एलसीडी/एलईडी पैनल | कैबिनेट/चेसिस के मूल्य को छोड़कर, मॉनिटर कैबिनेट/चेसिस में आयातित/घरेलू रूप से एकत्रित एलसीडी/एलईडी पैनल *** का घरेलू एकीकरण और परीक्षण । हालाँकि, एलसीडी/एलईडी पैनल के कुल मूल्य का भार कंप्यूटर मॉनीटर के कुल बीओएम के 35% से अधिक नहीं होगा। |
| केबल्स | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित और परीक्षण किया गया। |
| पावर अडैप्टर | घरेलू पीसीबी असेंबली के साथ आयातित/ घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों से फाइनल घरेलू असेंबली* और परीक्षण, इस शर्त के अध्यधीन है कि "पावर अडैप्टर" की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों का मूल्य न्यूनतम 40% होगा ("पावर अडैप्टर" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का)। |
| बेयर पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित। |
| कैबिनेट/चेसिस | मॉनिटर बेज़ेल, बैक कवर, स्टैंड, बेस और चेसिस जिसमें प्लास्टिक मोल्डिंग और धातु के हिस्सों की स्टैम्पिंग को आयातित/घरेलू इनपुट का उपयोग करके घरेलू स्तर पर किया जाता है। |

| | |
|---|---|
| ( i ) फाइनल असेंबली/परीक्षण और<br>(ii) डिजाइन/विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर (एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

**** इसकी समीक्षा तब की जाएगी जब भारत में कंप्यूटर मॉनिटर्स (प्रत्येक आकार और प्रकार के) का एलसीडी / एलईडी पैनल विनिर्माण संचालन में हो।*

**4.5 टैबलेट पर्सनल कंप्यूटर (पीसी)**

**क. परिभाषा** :

इस अधिसूचना के प्रयोजन से, एक टैबलेट पीसी में आवश्यक रूप से एक एकीकृत मदरबोर्ड जिसमें सीपीयू/प्रोसेसर, मेमोरी और पावर मॉड्यूल और बोर्ड होंगे शामिल होगा; डिस्प्ले पैनल (टच पैनल + एलसीडी/एलईडी मॉड्यूल) और एकीकृत बैटरी होंगे और यह स्वतंत्र रूप से संचालित करने में सक्षम होना चाहिए।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र** :

टैबलेट पीसी का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| **बीओएम के प्रमुख इनपुट/टैबलेट पीसी के विनिर्माण के लिए चरण** | **घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री** |
|---|---|
| 1 | 2 |
| ऑन बोर्ड सीपीयू/जीपीयू/प्रोसेसर के साथ इंटीग्रेटेड मदरबोर्ड | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स** और प्रोसेसर/ सीपीयू/जीपीयू** का मूल्य शामिल है और बेयर पीसीबी का मूल्य इसमें शामिल नहीं है। हालाँकि, सीपीयू के कुल मूल्य का भार टैबलेट पीसी के कुल बीओएम के 35% से अधिक नहीं होगा। |
| मेमोरी और पावर मॉड्यूल | बेयर पीसीबी के मूल्य को छोड़कर, आयातित/ घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण । |
| डिस्प्ले पैनल (टच पैनल + एलसीडी/एलईडी मॉड्यूल) | आयातित/घरेलू रूप से विनिर्मित टच पैनल, एलसीडी/एलईडी मॉड्यूल या संयोजन से घरेलू असेंबली और परीक्षण, इस शर्त के अध्यधीन है कि डिस्प्ले पैनल का बैकलाइट असेंबली और परीक्षण घरेलू स्तर पर किया जाएगा। |
| पावर अडैप्टर | घरेलू पीसीबी असेंबली के साथ, आयातित/घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों से फाइनल घरेलू असेंबली और परीक्षण, इस शर्त के अध्यधीन है कि "पावर अडैप्टर" की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित |

| | |
|---|---|
| | कलपूर्जों और संघटकों का मूल्य न्यूनतम 40% होगा ("पावर अडैप्टर" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का)। |
| बेयर पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित। |
| केसिंग | घरेलू स्तर पर विनिर्मित केसिंग। |
| बैटरी | आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| ऐक्सेसरी (कैमरा, स्पीकर, वाईफाई एंटीना, आदि) | आयातित/घरेलू स्तर पर कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| ( i ) फाइनल असेंबली/परीक्षण और<br>(ii) डिजाइन/विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर(एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

### 4.6 डॉट मैट्रिक्स प्रिंटर

**(क) परिभाषा** :

डॉट मैट्रिक्स प्रिंटर एक प्रकार का प्रभावी प्रिंटर है, जो 0.2 मिमी से 0.3 मिमी के व्यास के धातु पिन द्वारा कागज पर डॉट बनाता है, जो सोलनॉइड सिद्धांत के आधार पर इलेक्ट्रोमैग्नेट द्वारा संचालित होता है और डॉट मैट्रिक्स प्रिंटहेड केन क्षैतिज और ऊर्ध्वाधर रिजोलूशन द्वारा अपेक्षित कैरेक्टर का मैट्रिक्स उतपन्न होता है। डॉट मैट्रिक्स प्रिंटर पिन के यांत्रिक दबाव के आधार पर कार्बन प्रतियां और कार्बन रहित प्रतियां बना सकता है।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र** :

डॉट मैट्रिक्स प्रिंटर का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग- अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| **बीओएम के प्रमुख इनपुट/डॉट मैट्रिक्स प्रिंटर के विनिर्माण के लिए चरण** | **घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/ स्थानीय सामग्री** |
|---|---|
| **1** | **2** |
| मुख्य पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, इस शर्त के अधीन है कि "मुख्य पीसीबी" की असेंबली में प्रयुक्त घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों का मूल्य न्यूनतम 15% होगा (मुख्य पीसीबी के विनिर्माण में प्रयुक्त कलपूर्जों और संघटकों के कुल मूल्य का), बेयर पीसीबी के मूल्य को छोड़कर। |
| बेयर पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित। |

| | |
|---|---|
| एसएमपीएस | आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण, इस शर्त के अध्यधीन है कि "एसएमपीएस" की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित कल-पूर्जों और संघटकों का मूल्य न्यूनतम 20% होगा ("एसएमपीएस" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का)। |
| कैरिज मोटर्स और पेपर फीड मोटर्स | उप-असेंबली के रूप में आयात किया गया और मुख्य प्रिंटर तंत्र के साथ घरेलू रूप से परीक्षण किया गया। |
| फ्रंट कंट्रोल पैनल | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| होम पोजीशन / पेपर एंड सेंसर | आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| मुख्य प्रिंटर कैबिनेट और अन्य छोटे प्लास्टिक घटक | प्रिंटर कैबिनेट और अन्य भागों के घरेलू मोल्डिंग । |
| प्रिंटर मेकेनिज़्म असेंबली | घरेलू स्तर पर विनिर्मित रबर प्लेट्स, छोटे रबर भागों, शीट धातु के घटकों, प्लास्टिक गियर और टण्ड स्टील शाफ्ट के साथ अन्य प्लास्टिक भागों और ऊपर वर्णित सेंसर और मोटर्स का उपयोग करके घरेलू असेंबली। |
| प्रिंट हेड्स और इंटरकनेक्टिंग केबल्स | उप- असेंबली के रूप में आयात किया गया और मुख्य प्रिंटर तंत्र के साथ घरेलू रूप से परीक्षण किया गया। |
| (i) फाइनल असेंबली/परीक्षण और<br>(ii) डिजाइन/विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर कल पूर्जों/ संघटकों के प्रिंटेड सर्किट बोर्ड असेंबली (पीसीबीए) अनिवार्य रूप से भारत में किया जाना चाहिए।*

**4.7 स्मार्ट कार्ड**

**(क) परिभाषा** :

इस अधिसूचना के प्रयोजन से, स्मार्ट कार्ड आमतौर पर एक क्रेडिट कार्ड के आकार का प्लास्टिक कार्ड होता है, जिसमें एक एकीकृत सर्किट (आईसी) होता है। इस आईसी में एक माइक्रोप्रोसेसर और मेमोरी होती है। स्मार्ट कार्ड संपर्क, संपर्क रहित या दोहरे इंटरफ़ेस (संपर्क और संपर्क रहित दोनों) पर आधारित हो सकते हैं। स्मार्ट कार्ड के कुछ अनुप्रयोगों में पहचान पत्र, बैंकिंग कार्ड, स्वास्थ्य कार्ड, वाहन पंजीकरण कार्ड आदि हैं।

**I ( ख) कांटैक्ट स्मार्ट कार्ड के लिए स्थानीय सामग्री की गणना के लिए तंत्र**

कांटैक्ट स्मार्ट कार्ड का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| बीओएम के प्रमुख इनपुट/कॉन्टैक्ट स्मार्ट कार्ड के विनिर्माण के लिए चरण | घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री |
|---|---|
| 1 | 2 |
| प्लास्टिक कार्ड बॉडी | आयातित/घरेलू रूप से विनिर्मित, कलपुर्जों और संघटकों का उपयोग करके शीट कटिंग और पंचिंग, प्रिंटिंग, लेमिनेशन और परीक्षण सहित घरेलू विनिर्माण । |
| आईसी चिप मॉड्यूल | आयातित/घरेलू रूप से विनिर्मित कच्चे माल, कलपुर्जों और संघटकों का उपयोग करते हुए, आईसी चिप मॉड्यूल* की घरेलू असेंबली, पैकेजिंग और परीक्षण। |
| प्लास्टिक कार्ड पर आईसी चिप मॉड्यूल की मिलिंग और एंबेडिंग | प्लास्टिक कार्ड पर आईसी चिप मॉड्यूल की मिलिंग और एंबेडिंग घरेलू स्तर पर करना। |
| (i) फाइनल असेंबली और टेस्टिंग<br>(ii) डिजाइन / विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

**II ( ख) कॉन्टैक्टलेस स्मार्ट कार्ड के लिए स्थानीय सामग्री की गणना के लिए क्रियाविधि**

कॉन्टैक्टलेस स्मार्ट कार्ड का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| बीओएम में प्रमुख इनपुट/कॉन्टैक्टलेस स्मार्ट कार्ड के विनिर्माण के लिए चरण | इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री |
|---|---|
| 1 | 2 |
| प्लास्टिक कार्ड बॉडी | आयातित/घरेलू रूप से विनिर्मित कच्चे माल, कलपुर्जों और संघटकों का उपयोग करके शीट कटिंग और पंचिंग, प्रिंटिंग, लेमिनेशन और परीक्षण सहित घरेलू विनिर्माण । |
| कार्ड इनले (एंटीना) | घरेलू स्तर पर विनिर्मित आयातित कच्चे माल, कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| आईसी चिप मॉड्यूल | आयातित/घरेलू रूप से विनिर्मित कच्चे माल, कलपुर्जों और संघटकों का उपयोग करके आईसी चिप* मॉड्यूल की घरेलू असेंबली, पैकेजिंग और परीक्षण। |
| प्लास्टिक कार्ड पर आईसी चिप मॉड्यूल की मिलिंग और एंबेडिंग | प्लास्टिक कार्ड पर आईसी चिप मॉड्यूल की मिलिंग और एंबेडिंग घरेलू स्तर पर करना । |
| ( i ) फाइनल असेंबली और टेस्टिंग<br>(ii) डिजाइन / विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

**4.8 एलईडी उत्पाद**

**(क) परिभाषा :**

इस अधिसूचना के प्रयोजन से, एलईडी उत्पाद वे हैं जिनका कार्य एलईडी द्वारा उत्पादित प्रकाश का उपयोग करना और निम्नलिखित क्षेत्रों में इसका उपयोग बढ़ाना है:- ( i ) रोशनी, (ii) टू एलईडी टीवी सहित ऑप्टिकल डिस्प्ले, (iii) बैकलाइटिंग, (iv) ) सिग्नलिंग और इंडिकेशन और (v) परिवहन।

**(ख) स्थानीय सामग्री की गणना के लिए क्रियाविधि :**

एलईडी उत्पादों का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें: हालाँकि, (घ) हीट सिंक या थर्मल मैनेजमेंट सॉल्यूशंस, (ङ) सेकेंडरी ऑप्टिक्स और (च) सिस्टम फिक्सेटर और फिटिंग के कुल मूल्य का भार एलईडी उत्पाद के कुल बीओएम से 20% से अधिक नहीं होगा:

| **बीओएम के प्रमुख इनपुट/एलईडी उत्पादों के विनिर्माण के लिए चरण** | **इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन** |
|---|---|
| 1 | 2 |
| एलईडी एमिटर | आयातित/घरेलू रूप से विनिर्मित बेयर एलईडी डाई से पैकेजिंग, इस शर्त के अधीन है कि बेयर एलईडी डाई को आयातित/घरेलू विनिर्मित आदानों का उपयोग करके घरेलू रूप से विनिर्मित किया जाएगा। |
| ड्राइविंग इलेक्ट्रॉनिक्स | घरेलू असेंबली* और आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से परीक्षण, इस शर्त के अध्यधीन है कि "ड्राइविंग इलेक्ट्रॉनिक्स " की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित कल-पूर्जों और संघटकों (बेयर पीसीबी का मूल्य छोड़कर) का मूल्य न्यूनतम 30% होगा ("ड्राइविंग इलेक्ट्रॉनिक्स" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का)। |
| एमसीपीसीबी सहित बेयर पीसीबी | घरेलू रूप से आयातित/घरेलू स्तर पर विनिर्मित इनपुट का उपयोग करके विनिर्मित। |
| हीट सिंक या थर्मल प्रबंधन समाधान | घरेलू रूप से आयातित/घरेलू स्तर पर विनिर्मित इनपुट का उपयोग करके विनिर्मित। |
| माध्यमिक प्रकाशिकी | घरेलू रूप से आयातित/घरेलू स्तर पर विनिर्मित इनपुट का उपयोग करके विनिर्मित। |
| सिस्टम फिक्सर और फिटिंग | घरेलू तौर पर विनिर्मित। |
| फाइनल असेंबली/परीक्षण | समय-समय पर अधिसूचित भारतीय मानकों के अनुसार घरेलू रूप से असेंबली/परीक्षण किए गए। |

**4.9 <u>बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस</u>**

**(क) परिभाषा :**

इस अधिसूचना के प्रयोजन से, बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस में *अन्य बातों के साथ-साथ* एक फिंगर प्रिंट सेंसर/आइरिस सेंसर, नियंत्रक मॉड्यूल और बिजली की आपूर्ति शामिल होगी। इसमें डिस्प्ले यूनिट हो सकती है या नहीं भी। बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस के कुछ एप्लिकेशन फिजिकल एक्सेस कंट्रोल, टाइम और अटेंडेंस कंट्रोल आदि हैं।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र** :

बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| **बीओएम के प्रमुख इनपुट बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस के विनिर्माण के लिए चरण** | **इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन** |
|---|---|
| 1 | 2 |
| फिंगर प्रिंट सेंसर/आइरिस सेंसर | घरेलू स्तर पर विनिर्मित जैसा कि अधिसूचित है (पैराग्राफ 4.10 और 4.11 को देखें)। |
| मुख्य पीसीबी (नियंत्रक मॉड्यूल) | घरेलू असेंबली और आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से परीक्षण, बेयर पीसीबी के मूल्य को छोड़कर। |
| बेअर पीसीबी | आयातित/घरेलू स्तर पर विविनिर्मित इनपुट से घरेलू स्तर पर विविनिर्मित । |
| बिजली की आपूर्ति/बैटरी (यदि अलग हो) | आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| डिस्प्ले यूनिट | आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| वैकल्पिक विशेषताएं जैसे कि कैमरा, कीबोर्ड, आरएफआईडी, स्मार्ट कार्ड रीडर, जीपीआरएस मॉड्यूल, वाई-फाई, ब्लू टूथ आदि। | आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण। |
| प्लास्टिक हाउसिंग | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित। |
| युएसबी केबल्स | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित। |
| (i) फाइनल असेंबली और परीक्षण<br>(ii) डिजाइन/विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

**4.10 बायोमेट्रिक फिंगर प्रिंट सेंसर**

**(क) परिभाषा** :

इस अधिसूचना के उद्देश्य से, बॉयोमीट्रिक फिंगर प्रिंट सेंसर में एक नियंत्रक मॉड्यूल, सीएमओएस सेंसर और ऑप्टिक्स शामिल हैं। बायोमेट्रिक फिंगर प्रिंट सेंसर के अनुप्रयोग व्यक्तिगत पहचान और सत्यापन आदि हैं।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र:**

बायोमेट्रिक फिंगर प्रिंट सेंसर की घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| बीओएम के प्रमुख मुख्य इनपुट/बॉयोमीट्रिक फिंगर प्रिंट सेंसर के निर्माण के लिए चरण | इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन |
|---|---|
| 1 | 2 |
| मुख्य पीसीबी (नियंत्रक मॉड्यूल) | बेअर पीसीबी के मूल्य को छोड़कर आयातित / घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों का उपयोग करके घरेलू असेंबली और परीक्षण । |
| ऑप्टिक्स | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित । |
| सीएमओएस सेंसर | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से उपयोग करके सीएमओएस सेंसर की घरेलू असेंबली, पैकेजिंग और परीक्षण*। |
| बेअर पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण। |
| प्लास्टिक हाउसिंग | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण। |
| यूएसबी केबल्स | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण। |
| (i) फाइनल असेंबली और टेस्टिंग<br>(ii) डिजाइन/विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

### 4.11 बायोमेट्रिक आइरिस सेंसर

**(क) परिभाषा** :

इस अधिसूचना के उद्देश्य से, बॉयोमीट्रिक आइरिस सेंसर में एक नियंत्रक मॉड्यूल, सीएमओएस सेंसर और ऑप्टिक्स शामिल हैं। बायोमेट्रिक आइरिस सेंसर के आवेदन व्यक्तिगत पहचान और सत्यापन आदि हैं।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र:**

बायोमेट्रिक आइरिस सेंसर का का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| बीओएम के प्रमुख इनपुट/बॉयोमीट्रिक फिंगर प्रिंट सेंसर के विनिर्माण के लिए चरण | इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन |
|---|---|
| 1 | 2 |
| मुख्य पीसीबी (नियंत्रक मॉड्यूल) | बेअर पीसीबी के मूल्य को छोड़कर आयातित/ घरेलू स्तर पर विनिर्मित भागों और संघटकों का उपयोग करके घरेलू असेंबली और परीक्षण । |
| ऑप्टिक्स | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित । |

| | |
|---|---|
| सीएमओएस सेंसर | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से उपयोग करके सीएमओएस सेंसर की घरेलू असेंबली, पैकेजिंग और परीक्षण * |
| बेअर पीसीबी | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण। |
| प्लास्टिक हाउसिंग | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण । |
| यूएसबी केबल्स | आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण । |
| (i) फाइनल असेंबली और परीक्षण<br>(ii) डिजाइन/विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

* *भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी ।*

### 4.12 सर्वर

**(क) परिभाषा** :

इस अधिसूचना के प्रयोजन से, एक सर्वर में आवश्यक रूप से एक मदर बोर्ड, सीपीयू, मेमोरी (रैम), हार्ड डिस्क ड्राइव (एचडीडी)/सॉलिड स्टेट स्टोरेज ड्राइव (एसएसएसडी), पावर सप्लाई यूनिट (एसएमपीएस), चेसिस, कनेक्टिंग केबल्स और फर्मवेयर और ओएस शामिल होंगे।

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र** :

सर्वर की घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

| **बीओएम के प्रमुख इनपुट/सर्वर के विनिर्माण के लिए चरण** | **इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन** |
|---|---|
| **1** | **2** |
| सर्वर बोर्ड/मदर बोर्ड और सीपीयू(एस)/जीपीयू (एस) | सेमीकंडक्टर्स** और सीपीयू (एस)/जीपीयू (एस)को शामिल करके** और बेअर पीसीबी के मूल्य को छोड़कर आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण |
| मेमोरी मॉड्यूल | पीसीबी असेंबली और बेअर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेअर पीसीबी आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों/संघटको से घरेलू परीक्षण। |
| हार्ड डिस्क ड्राइव/सॉलिड स्टेट स्टोरेज ड्राइव (एसएसडी) | आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबली और परीक्षण। |
| कैबिनेट + एसएमपीएस | आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू रूप से घरेलू स्तर पर विनिर्मित कैबिनेट और एसएमपीएस का घरेलू असेंबली और परीक्षण, इस शर्त के |

| | |
|---|---|
| | अध्यधीन कि "एसएमपीएस" की असेंबली में उपयोग किए गए घरेलू स्तर पर विनिर्मित भागों और संघटकों का मूल्य न्यूनतम 25% होगा ("एसएमपीएस " के विनिर्माण में उपयोग किए जाने वाले भागों और संघटकों का कुल मूल्य) |
| बेअर पीसीबी | आयातित/घरेलू विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित |
| सहायक उपकरण (पावर केबल, कनेक्टर्स,आदि) | आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबली और परीक्षण। |
| ( i ) फाइनल असेंबली और टेस्टिंग<br>(ii) डिजाइन और विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

** यह आवश्यक है कि सीपीयू (एस) /जीपीयू (एस) /प्रोसेसर (एस) के प्रिंटेड सर्किट बोर्ड असेंबली (पीसीबीए), एसएमटी प्रक्रिया का उपयोग कर बेअर पीसीबी पर भागों/संघटकों को अनिवार्य रूप से भारत में किया जाना चाहिए।*

*** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

### 4.13 सेल्युलर मोबाइल फ़ोन

**(क) परिभाषा** :

इस अधिसूचना के प्रयोजन के लिए, एक सेलुलर मोबाइल फोन (फीचर फोन या स्मार्ट फोन) में मुख्य रूप से मुद्रित सर्किट बोर्ड (पीसीबी), बैटरी पैक, डिस्प्ले यूनिट, कुंजी पैड/टच पैनल, चार्जर/एडाप्टर, माइक्रोफोन और रिसीवर वाइब्रेटर मोटर/रिंगर और मैकेनिक्स शामिल होंगे। ,

**(ख) स्थानीय सामग्री की गणना के लिए तंत्र** :

सेल्युलर मोबाइल फ़ोनों के घरेलू बीओएम में निम्न तालिका के कॉलम1 में विनिर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्य अतिरिक्त आवश्यकता को पूरा करते हैं:

| **बीओएम के प्रमुख इनपुट/सेलुलर मोबाइल फोन के निर्माण के लिए चरण** | **इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन /स्थानीय सामग्री** |
|---|---|
| 1 | 2 |
| मुख्य पीसीबी* | प्रोसेसर/सेमीकंडक्टर** बीओएम( यानी मेन पीसीबी पर सेमीकंडक्टर चिप्स और मॉड्यूल ),को शामिल करके और बेअर पीसीबी के मूल्य को छोड़कर ,आयातित / घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबलीऔर परीक्षण। |
| बेयर पीसीबी | घरेलू रूप से आयात सामग्री का विनिर्माण/घरेलू स्तर पर विनिर्मित इनपुट। |
| बैटरी पैक | आयात सामग्री की घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| चार्जर/एडाप्टर | आयात सामग्री से घरेलू असेंबली और परीक्षण/ घरेलू स्तर पर विनिर्मित इनपुट। |
| वायर्ड हेडसेट | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| यांत्रिकी*** | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| डाई कट कलपुर्ज़े*** | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| माइक्रोफोन और रिसीवर | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| की-पैड | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |

| | |
|---|---|
| यूएसबी केबल | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| कैमरा मॉड्यूल | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| कनेक्टर्स | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| डिसप्ले यूनिट | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| टच पैनल/कवर ग्लास असेंबली | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| वाइब्रेटर मोटर/रिंगर | आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट। |
| (i) अंतिम असेंबली और परीक्षण<br>(ii) डिजाइन और विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर संसाधक/संघटक की प्रिंटेड सर्किट बोर्ड असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

*** भारत में सेमीकंडक्टर फैब प्रचालनरत होने पर इसकी समीक्षा की जाएगी।*

**** अनुबंध का संदर्भ लें।*

5. अधिसूचना तुरंत प्रभाव से लागू है। संशोधित अधिसूचना जारी होने तक यह अधिसूचना मान्य रहेगी।

6. सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत कोई भी इलेक्ट्रॉनिक उत्पाद अधिसूचना का भूतलक्षी प्रभाव नहीं होगा।

7. उपरोक्त इलेक्ट्रॉनिक उत्पादों की क्रय के लिए दिनांक 04.06.2020 के सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 में उल्लिखित प्रावधानों के अनुसार क्रय वरीयता प्रदान की जाएगी।

8. यदि भारत सरकार द्वारा परियोजना या योजना पूरी तरह से या आंशिक रूप से वित्त पोषित होती है, तो राज्यों और स्थानीय निकायों द्वारा बनाए गए इलेक्ट्रॉनिक उत्पादों की क्रय के लिए अधिसूचना सभी केंद्रीय योजनाओं (सीएस)/केंद्रीय क्षेत्र की योजनाओं (सीएसएस) पर भी लागू होगी।

**9. स्थानीय सामग्री/घरेलू मूल्यवर्धन की गणना करने हेतु प्रक्रिया**

9.1 घरेलू विनिर्माताओं (डीओएम-बीओएम) से प्राप्त सामग्री के बिल की गणना उपलब्ध आंकड़ों के आधार पर निम्नलिखित में से किसी एक के आधार पर की जा सकती है। इनमें से प्रत्येक गणना के सुसंगत परिणाम प्राप्त होने चाहिए।

क. सभी इनपुटों की लागतों का योग जो उस उत्पाद को बनाने के लिए आवश्यक है (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है) और जिनका आयात प्रत्यक्ष रूप से या घरेलू व्यापारी या माध्यस्थ के माध्यम से नहीं किया गया है।

ख. उत्पाद के फैक्ट्री बाह्य मूल्य से उत्पाद के उत्पादन में इनपुटों के रूप में उपयोग की गई सामग्री के आयातित बिल (प्रत्यक्ष या अप्रत्यक्ष रूप से) को घटाकर (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है) और उसमें से वारंटी लागत को घटाकर।

ग. बाजार मूल्य से उत्पादन पश्चात मालभाडा, बीमा और अन्य हथालन लागतों को घटाकर, उसमें से कर पश्चात लाभ, वारंटी लागत को घटाया जाता है, उसमें से उत्पादों के उत्पादन (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ लिया जा सकता है) में इनपुटों के रूप में उपयोग की गई सामग्री के आयातित बिल के योग को घटाया जाता है और बिक्री और विपणन खर्च को घटाया जाता है।

9.2 सामग्री के कुल बिल (कुल-बीओएम) की गणना उपलब्ध आंकड़ों पर आधारित निम्नलिखित में से किसी एक के आधार पर की जा सकती है। इनमें से प्रत्येक गणना के सुसंगत परिणाम प्राप्त होने चाहिए।

क. सभी इनपुटों की लागतों का योग जो उस उत्पाद को बनाने के लिए आवश्यक है (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है)।

ख. उत्पाद के फैक्टरी बाह्य मूल्य से कर पश्चात लाभ और वारंटी लागतों को घटाया जाता है।

ग. बाजार मूल्य से उत्पादन पश्चात मालभाडा, बीमा और अन्य हथालन लागतों को घटाकर उसमें से कर पश्चात लाभ, वारंटी लागत, बिक्री और विपणन खर्च घटाया जाता है।

9.3 निम्नलिखित फॉर्मूला के अनुसार प्रस्तुत जानकारी के आधार पर घरेलू मूल्य-वृद्धि के प्रतिशत की गणना की जा सकती है:

स्थानीय सामग्री/घरेलू मूल्य-वृद्धि का प्रतिशत $= \frac{\text{डीओएम} - \text{बीओएम}}{\text{कुल} - \text{बीओएम}} \times 100$

यह सिफ़ारिश की जाती है कि आकलन करने वाली प्रत्येक एजेंसी को उपरोक्त सूत्रों में से कम से कम दो का उपयोग करके स्थानीय सामग्री/घरेलू मूल्य-वृद्धि की गणना करनी चाहिए ताकि इस संबंध में आकलन को मान्य किया जा सके और यह सुनिश्चित किया जा सके कि दावाकृत घरेलू मूल्य सुसंगत है।

**10. स्थानीय सामग्री/घरेलू मूल्यवृद्धि का सत्यापन**

क. निविदा, बोली प्रक्रिया या सिफ़ारिश के समय स्थानीय आपूर्तिकर्ता स्व-प्रमाणन प्रदान करेगा कि प्रसतावित की गई वस्तुएं न्यूनतम स्थानीय सामग्री की आवश्यकताओं को पूरा करती हैं और उस स्थान (स्थानों) का विवरण देगा, जिस पर स्थानीय मूल्य वृद्धि की गई है।

ख.10 करोड़ रुपए से अधिक मूल्य की क्रय के मामलों में, स्थानीय आपूर्तिकर्ता स्थानीय सामग्री का प्रतिशत देते हुए कंपनी के सांविधिक लेखा परीक्षक (कंपनियों के मामले में) या लागत लेखापरीक्षक या किसी पेशेवर लागत लेखाकार या पेशेवर चार्टेड लेखाकार (कंपनियों के अलावा अन्य आपूर्तिकर्ताओं के संबंध में) से एक प्रमाणपत्र उपलब्ध कराएगा।

ग. यदि किसी इलेक्ट्रॉनिक उत्पाद के संबंध में स्थानीय सामग्री/घरेलू मूल्य वृद्धि के संबंध में बोलीकर्ता के दावे के खिलाफ क्रय एजेंसी या संबंधित मंत्रालय/विभाग द्वारा शिकायत प्राप्त की जाती है, तो उसे एसटीक्यूसी के पास भेजा जाएगा।

घ. एसटीक्यूसी को संदर्भित कोई भी शिकायत 4 सप्ताह के भीतर निपटा दी जाएगी। बोलीकर्ता को एसटीक्यूसी हेतु किसी इलेक्ट्रॉनिक उत्पाद में दावा की गई घरेलू मूल्य वृद्धि के समर्थन में आवश्यक दस्तावेज प्रस्तुत करने की आवश्यकता होगी। यदि बोलीकर्ता के द्वारा कोई जानकारी प्रस्तुत नहीं की जाती है, तो ऐसी प्रयोगशालाएं दावे की वास्तविकता को सिद्ध करने के लिए अगली आवश्यक कार्रवाई कर सकती हैं ।

ड़. 2 लाख रुपए या खरीदे जा रहे घरेलू रूप से विनिर्मित इलेक्ट्रॉनिक उत्पादों की कीमत का 1% शिकायत शुल्क (5 लाख रुपए की अधिकतम सीमा के अध्यधीन), जो भी अधिक हो, का डिमांड ड्राफ्ट द्वारा भुगतान किया जाएगा, जो एसटीक्यूसी में जमा जमा होगा। यदि शिकायत गलत पाई जाती है, तो शिकायत शुल्क जब्त कर लिया जाएगा। यदि, शिकायत को बरकरार रखा जाता है और काफी हद तक सही पाया जाता है तो शिकायतकर्ता को जमा शुल्क बिना किसी ब्याज के वापस कर दिया जाएगा।

च. सामान्य वित्तीय नियमों के विनियम 175(1) (i) (h) के तहत अखंडता संहिता के उल्लंघन में झूठी घोषणाएं की जाएगी तो इसके लिए एक बोलीकर्ता या उसके उत्तराधिकारियों पर सामान्य वित्तीय नियमों के विनियम 151(iii) के अनुसार दो साल तक के लिए रोक लगा दी जाएगी, इसके साथ-साथ कानून के तहत स्वीकार्य होने वाली अन्य कार्रवाई भी की जा सकती है।

11. इलेक्ट्रॉनिक उत्पाद अधिसूचना के कार्यान्वयन की निगरानी के लिए नोडल मंत्रालय एमईआईटीवाई होगा।

12. यदि प्रश्न उठता है कि क्या खरीदी जा रही कोई वस्तु एक इलेक्ट्रॉनिक उत्पाद है, जिसे सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत शामिल किया जाना है, तो इस मामले को स्पष्टीकरण के लिए इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय को संदर्भित किया जाएगा।

सौरभ गौड़, संयुक्त सचिव

**अनुबंध**

**यान्त्रिकी और डाई कट कलपुर्ज़े की सूची**

**क. यान्त्रिकी (मैकेनिक्स)**

1. बैटरी कवर (एचएस 39209999)
2. फ्रंट कवर (एचएस 39209999)
3. फ्रंट कवर (जिंक कास्टिंग के साथ) (एचएस 39209999)
4. मिडल कवर (एचएस 39209999)
5. जीएसएम एंटीना/किसी भी प्रौद्योगिकी का एंटीना (एचएस 39209999)
6. साइड की (एचएस 85389000)
7. मेन लेंस (एचएस 39209999)
8. कैमरा लेंस (एचएस 39209999)
9. पेंच (एचएस 73181500)
10. माइक्रो रबर केस (एचएस 40169990)
11. सेंसर रबड़ केस/सीलबंद गैसकेटों सहित सीलबंद गैसकेट/रबड़ केस यानि एसबीआर, ईपीडीएम, सीआर, सीएस, सिलिकॉन और सभी अन्य विशेष रबड़ या संयोजन/रबड़ के संयोजन (एचएस 40169990)

    11.1 पीयू केस /सीलबंद गैसकेट (एचएस 39269091) - सीलबंदी गैसकेट/केस की तरह पॉलीयुरेथेन फोम की अन्य सामग्री।

    11.2 सीलबंदी गास्केट/पीई, पीपी,ईपीएस, पीसीसे केस और सभी अन्य विशेष बहुलक या संयोजन/बहुलकों का संयोजन(एच एस 39269099)

12. सिम सॉकेट/अन्य मैकेनिकल (यान्त्रिकी) मदें (धातु) (एचएस 73269099)
13. सिम सॉकेट/अन्य मैकेनिकल (यान्त्रिकी) मदें (प्लास्टिक) (एचएस 39269099)
14. बैक कवर (एचएस 39209999)

**ख. डाई कट कलपुर्ज़े**

1.सुचालक कपड़ा (एचएस 39269099)

2. ऊष्मा उत्सर्जक स्टीकर बैटरी कवर (एचएस 39199090)

3. स्टीकर-बैटरी स्लॉट (एचएस 39199090)

4. मैन लेंस के लिए प्रोटेक्टिव फिल्म (एचएस 39199090)

5. एलसीडी एफपीसी के लिए माइलर (एचएस 39199090)

6. एलसीडी सुचालक फोम (एचएस 39269099)

7. फिल्म-फ्रंट फ्लैश (एचएस 39199090)

8. एलसीडी फोम (एचएस 39269099)

9. बीटी फोम (एचएस 39269099)

**MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY**

(IPHW DIVISION)

**NOTIFICATION**

New Delhi, the 7th September, 2020

**Subject : Public Procurement (Preference to Make in India) Order 2017-Notifying Electronic Products in furtherance of the Order**

**Reference : Department for Promotion of Industry and Internal Trade (DPIIT) Order No. P-45021/2/2017-B.E.-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019 and 04.06.2020**

**F. No. W-43/4/2019-IPHW-MeitY.—**The Government has issued Public Procurement (Preference to Make in India) Order 2017 vide the Department for Promotion of Industry and Internal Trade (DPIIT) Order No. P-45021/2/2017-B.E.-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019 and 04.06.2020, to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment.

2. In furtherance of the Public Procurement (Preference to Make in India) Order 2017 [PPP-MII Order 2017] notified vide reference cited above, and in supersession of the Electronic Product Notification Nos.33(1)/2017-IPHW dated 14.09.2017 and 33(5)/2017-IPHW dated 01.08.2018 issued thereunder, the Ministry of Electronics and Information Technology (MeitY) hereby notifies that preference shall be provided by all procuring entities to locally manufactured Electronic Products as per the aforesaid Order, as amended from time to time.

3. For the purpose of this notification:

a. The definition of Class-I local supplier, Class-II local supplier and Non-local supplier shall be as per paragraph 2 of the DPIIT PPP-MII Order 2017 No.P-45021/2/2017-PP(BE-II) dated 04.06.2020, as amended from time to time. The mechanism for calculation of local content has been prescribed for each notified Electronic Product in this notification, in accordance with paragraph 5 of the DPIIT PPP-MII Order 2017 No.P-45021/2/2017-PP(BE-II) dated 04.06.2020, as amended from time to time.

b. Paragraph 3A of the DPIIT PPP-MII Order 2017 No.P-45021/2/2017-PP(BE-II) dated 04.06.2020, as amended from time to time, shall be referred for percentage of procurement for which preference to domestically manufactured Electronic Products is to be provided (in value terms).

4. Following Electronic Products are notified under the Public Procurement (Preference to Make in India) Order 2017:

**4.1 <u>Desktop Personal Computers (PCs)</u>**

**(A) Definition**:

For the purpose of this Notification, a Desktop PC shall necessarily consist of a CPU, Memory, Hard disk drive, Keyboard, Mouse and a separate or integrated display unit and should be able to operate independently.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of Desktop PC would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/stages for manufacture of Desktop PC** | **Value addition/local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Main Board / Motherboard and CPU / GPU | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU/ GPU** and excluding |

| | |
|---|---|
| | the value of bare PCB. However, the weightage of total value of CPU shall not exceed 30% of the total BOM of the Desktop PC. |
| Memory Module | Domestic PCB Assembly* and testing from imported / domestically manufactured memory chips** and parts / components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB. |
| Hard Disk Drive / Solid State Drive (SSD) | Domestic PCB Assembly* and final product assembly and testing from imported / domestically manufactured parts and components, excluding the value of bare PCB. |
| LCD / LED Monitor | Domestic assembly and testing of LCD / LED Monitor from parts consisting of imported/domestically assembled LCD / LED Panel and Domestic PCB Assembly*, Domestic plastic moulding and Domestic stamping of metal parts, excluding the value of bare PCB. |
| DVD Drive | Domestic assembly and testing from imported / domestically manufactured parts and components. |
| Cabinet + SMPS | Domestically manufactured Cabinet and Domestic PCB Assembly* and the final assembly and testing of SMPS from imported/ domestically manufactured parts and components, subject to the condition that the domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 20% (of the total value of parts and components used in the manufacture of "SMPS"). |
| Keyboard/Mouse | Domestic PCB Assembly* and the final assembly and testing from imported / domestically manufactured parts and components. |
| Bare PCB | Domestically manufactured from imported / domestically manufactured inputs. |
| (i) Final Assembly / Testing and<br>(ii) Design / Development | (i) Domestically assembled/tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU/ processor(s) parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

**4.2 Thin Clients**

**(A) Definition**:

For the purpose of this Notification, a Thin Client (TC) shall necessarily consist of a CPU, Memory, DOM, Keyboard, Mouse and a separate or integrated display unit and should be able to operate independently.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of a Thin Client would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM / stages for manufacture of Thin Client** | **Value addition / local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Main Board / Motherboard and CPU | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU** and excluding the value of bare PCB. However, the weightage of total value of CPU shall not exceed 30% of the total BOM of the Thin Client. |
| Memory Module/ DOM | Domestic PCB Assembly* and testing from imported/ domestically manufactured memory chips** and parts/ components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB. |
| SMPS/ Power Adapter | Domestically PCB Assembly* and the final assembly and testing of SMPS/ Power Adapter from imported/ domestically manufactured parts and components, subject to the condition that the domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 20% (of the total value of parts and components used in the manufacture of "SMPS"). |
| LCD/ LED Monitor | Domestic assembly and testing of LCD/ LED Monitor from parts consisting of imported/ domestically assembled LCD/ LED Panel and Domestic PCB Assembly*, Domestic plastic moulding and Domestic stamping of metal parts, excluding the value of bare PCB. |
| Cabinet | Domestically manufactured. |
| Keyboard/Mouse | Domestic PCB Assembly* and the final assembly and testing from imported / domestically manufactured parts and components. |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| (i) Final Assembly/ Testing and<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ processor(s)/ parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

**4.3 <u>Laptop Personal Computers (PCs)</u>**

**(A) Definition**:

For the purpose of this Notification, a Laptop PC (commonly known in the market as Laptop/ Notebook/ Netbook/ Ultrabook, etc.) shall necessarily consist of a CPU, Memory, Hard disk drive, Keyboard, Touchpad and/ or Trackpoint, an integrated display unit, integrated battery and should be able to operate independently.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of a Laptop PC would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/ stages for manufacture of Laptop PC** | **Value addition/ local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Main Board/ Motherboard and CPU/ GPU | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU/ GPU** and excluding the value of bare PCB. However, the weightage of total value of CPU shall not exceed 35% of the total BOM of the Laptop PC. |
| Power Module | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components. |
| Memory Module | Domestic PCB Assembly* and testing from imported/ domestically manufactured memory chips** and parts/ components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB. |
| Hard Disk Drive/ Solid State Drive (SSD) | Domestic PCB Assembly* and final product assembly and testing from imported/ domestically manufactured parts and components, excluding the value of bare PCB. |
| Display Panel (LCD, LED, etc.) | Domestic assembly into the Back Cover and Bezel and final testing from imported/ domestically assembled Display Panel, LED Back light, Antennae, excluding the value of the Back Cover and Bezel. |
| DVD Drive | Domestic assembly and testing from imported / domestically manufactured parts and components. |
| Power Adapter | Domestic assembly with domestic PCB Assembly* and final testing from imported/ domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter"). |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| Keyboard/ Touchpad and/ or Trackpoint | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Battery | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Cabinet/ Chassis of Laptop including bottom cover, back cover, Keyboard face bezel and Display face bezel and Hinges | Domestically manufactured through injection moulding/ stamping using imported/ domestic inputs. |
| (i) Final Assembly/ Testing and<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU/ processor(s)/ parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

### 4.4 Computer Monitors

**(A) Definition**:

For the purpose of this Notification, a Computer Monitor (commonly known in the market as Monitor) shall necessarily consist of a LCD/ LED Display assembly, Logic card, Power Supply Adaptor and Cabinet with Display Ports for connecting it to a Desktop PC or Laptop PC or Tablet PC.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of a Computer Monitor would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/ stages for manufacture of Computer Monitor** | **Value addition/ local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Logic Cards/ Micro controller | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components including value of Semiconductors** and excluding the value of bare PCB. |
| LCD/ LED Panel | Domestic integration and testing of imported/ domestically assembled LCD/ LED Panel*** into the Monitor Cabinet/ Chassis, excluding the value of the Cabinet/ Chassis. However, the weightage of total value of LCD/ LED Panel shall not exceed 35% of the total BOM of the Computer Monitor. |
| Cables | Domestically manufactured and tested from imported/ domestically manufactured inputs. |
| Power Adapter | Domestic assembly with domestic PCB Assembly* and final testing from imported/ domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter"). |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| Cabinet/ Chassis | The Monitor Bezel, Back cover, Stand, Base and Chassis wherein the plastic mouldings and the stamping of metal parts is done domestically using imported/ domestic inputs. |
| (i) Final Assembly/ Testing and<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU processor(s)/ parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

**** This shall be reviewed when LCD/LED Panel manufacturing of Computer Monitors (of each size and type) in India is operational.*

**4.5 Tablet Personal Computers (PCs)**

A. **Definition**:

For the purpose of this Notification, a Tablet PC shall necessarily consist of an Integrated Motherboard with on board CPU/Processor, Memory and Power Module; Display Panel (Touch Panel + LCD/LED Module) and integrated battery and should be able to operate independently.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of Tablet PC would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/ stages for manufacture of Tablet PC** | **Value addition/ local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Integrated Motherboard with on board CPU/ GPU/ Processor | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including value of Semiconductors** and Processor/CPU/ GPU** and excluding the value of bare PCB. However, the weightage of total value of CPU shall not exceed 35% of the total BOM of the Tablet PC. |
| Memory and Power Module | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, excluding the value of bare PCB. |
| Display Panel (Touch Panel + LCD/ LED Module) | Domestic assembly and testing from imported/ domestically manufactured Touch Panel, LCD/ LED Module or combination, subject to the condition that backlight assembly and testing of Display Panel shall be done domestically. |
| Power Adapter | Domestic assembly and testing from imported/ domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter"). |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| Casing | Domestically manufactured Casing. |
| Battery | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Accessories (Camera, Speaker, WiFi Antenna, etc.) | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| (i) Final Assembly/ Testing and<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU/ GPU/ processor/ parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational*

### 4.6 Dot Matrix Printers

**(A) Definition**:

A Dot Matrix Printer is a type of impact printer that forms dot on paper by a metal pin of diameter 0.2 mm to 0.3 mm which is driven by electromagnet based on solenoid principle and required character matrix is produced by horizontal and vertical resolution of dot matrix printhead. Dot Matrix Printer can create carbon copies and carbonless copies based on mechanical pressure of pin.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of a Dot Matrix Printer would be the sum of the cost of main inputs specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/ stages for manufacture of Dot Matrix Printer** | **Value addition/ local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Main PCB | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, subject to the condition that value of domestically manufactured parts and components used in the assembly of "Main PCB" will be minimum 15% (of the total value of parts and components used in the manufacture of "Main PCB"), excluding the value of bare PCB. |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| SMPS | Domestic assembly and testing from imported/ domestically manufactured parts and components, subject to the condition that value of domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 20% (of the total value of parts and components used in the manufacture of "SMPS"). |
| Carriage Motors and Paper Feed Motors | Imported as sub-assembly and tested domestically along with main Printer Mechanism. |
| Front Control Panel | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Home Position/Paper End Sensors | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Main Printer Cabinet and other small plastic components | Domestic moulding of Printer Cabinet and other parts. |
| Printer Mechanism Assembly | Domestic assembly using domestically manufactured Rubber Platens, small rubber parts, sheet metal components, plastic gears and other plastic parts with turned steel shafts and above mentioned sensors and Motors. |
| Print Heads and Interconnecting Cables | Imported as sub-assembly and tested domestically along with main Printer Mechanism. |
| (i) Final Assembly/ Testing and<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

**4.7 Smart Cards**

**(A) Definition**:

For the purpose of this Notification, Smart Card is usually a Credit Card sized plastic Card with an Integrated Circuit (IC) contained inside. The IC contains a microprocessor and memory. Smart Cards can be contact, contactless or dual interface (both contact and contactless). Some of the applications of Smart Card are Identity Card, Banking Card, Health Card, Vehicle Registration Card etc.

**I(B) Mechanism for calculation of local content for Contact Smart Cards**

The domestic Bill of Material (BOM) of a Contact Smart Card would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/ stages for manufacture of Contact Smart Card** | **Value addition/ local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Plastic Card Body | Domestic manufacturing including sheet cutting & punching, printing, lamination and testing using imported/ domestically manufactured raw material, parts and components. |
| IC Chip Module | Domestic assembly, packaging and testing of IC Chip Module using imported/ domestically manufactured raw material, parts and components*. |
| Milling and Embedding of IC Chip Module on Plastic Card | Milling and Embedding of IC Chip Module on Plastic Card done domestically. |
| (i) Final Assembly and Testing<br>(ii) Design/ Development | (i) Domestically assembled/tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items, including fusion of domestically developed Operating System. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** This shall be reviewed when the Semiconductor FAB in India is operational.*

**II(B) Mechanism for calculation of local content for Contactless Smart Cards**

The domestic Bill of Material (BOM) of Contactless Smart Card would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/stages for manufacture of Contactless Smart Card** | **Value addition/local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Plastic Card Body | Domestic manufacturing including sheet cutting & punching, printing, lamination and testing using imported/ domestically manufactured raw material, parts and components. |
| Card inlay (Antenna) | Domestic assembly and testing from imported/ domestically manufactured raw material, parts and components. |
| IC Chip Module | Domestic assembly, packaging and testing of IC Chip Module using imported/ domestically manufactured raw material, parts and components*. |
| Milling and Embedding of IC Chip Module on Plastic Card | Milling and Embedding of IC Chip Module on Plastic Card done domestically. |

| | |
|---|---|
| (i) Final Assembly and Testing<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items, including fusion of domestically developed Operating System. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** This shall be reviewed when the Semiconductor FAB in India is operational.*

### 4.8 LED Products

**(A) Definition**:

For the purpose of this Notification, LED products are those whose function is to utilize light produced by LEDs and spanning applications in the areas of: (i) Illumination, (ii) Optical Displays including True LED TVs, (iii) Backlighting, (iv) Signalling & Indication and (v) Transportation.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of LED Products would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table. However, the weightage of total value of (d) Heat Sink or Thermal Management Solutions, (e) Secondary Optics and (f) System Fixture and Fitting shall not exceed 20% of the total BOM of the LED Product:

| **Main inputs in BOM/ stages for manufacture of LED Products** | **Value addition/ local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| LED Emitter | Packaging from imported/ domestically fabricated Bare LED Die, subject to the condition that the Bare LED Die shall be domestically fabricated using imported/ domestically manufactured inputs. |
| Driving Electronics | Domestic assembly from imported/ domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components (excluding the value of bare PCB) used in the assembly of "Driving Electronics" will be minimum 30% of the total value of parts and components used in the manufacture of "Driving Electronics". |
| Bare PCB including MCPCB | Domestically manufactured using imported/ domestically manufactured inputs. |
| Heat Sink or Thermal Management Solutions | Domestically manufactured using imported/ domestically manufactured inputs. |
| Secondary Optics | Domestically manufactured using imported/ domestically manufactured inputs. |
| System Fixture and Fitting | Domestically manufactured. |
| Final Assembly/ Testing | Domestically assembled/ tested meeting Indian Standards as notified from time to time. |

### 4.9 Biometric Access Control/Authentication Devices

**(A) Definition**:

For the purpose of this Notification, Biometric Access Control/ Authentication Device shall include *inter-alia* a Finger Print Sensor/ Iris Sensor, Controller Module and Power supply. It may or may not contain a display unit. Some of the applications of Biometric Access Control/ Authentication Device are Physical access control, Time and Attendance control etc.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of Biometric Access Control/ Authentication Device would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/ stages for manufacture of Biometric Access Control/ Authentication Device** | **Value addition/ local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Finger Print Sensor/ Iris Sensor | Domestically manufactured as notified (refer Paragraphs 4.10 and 4.11). |
| Main PCB (Controller Module) | Domestic assembly and testing from imported / domestically manufactured parts and components, excluding the value of bare PCB. |
| Bare PCB | Domestically manufactured from imported / domestically manufactured inputs. |
| Power Supply/ Battery(if separate) | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Display Unit | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Optional features such as Camera, Keyboard, RFID, Smart Card Reader, GPRS Module, Wi-Fi, Blue Tooth etc. | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Plastic Housing | Domestically manufactured from imported/ domestically manufactured inputs. |
| USB Cables | Domestically manufactured from imported/ domestically manufactured inputs. |
| (i) Final Assembly and Testing<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

**4.10 <u>Biometric Finger Print Sensors</u>**

**(A) Definition**:

For the purpose of this Notification, Biometric Finger Print Sensor consists of a Controller Module, CMOS Sensor and Optics. The applications of the Biometric Finger Print Sensor are personal identification and verification, etc.

**(B) Mechanism for calculation of local content:**

The domestic Bill of Material (BOM) of Biometric Finger Print Sensor would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/stages for manufacture of Biometric Finger Print Sensor** | **Value addition/local required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Main PCB (Controller Module) | Domestic assembly and testing using imported / domestically manufactured parts and components, excluding the value of bare PCB. |

| | |
|---|---|
| Optics | Domestically manufactured from imported / domestically manufactured inputs. |
| CMOS Sensor | Domestic assembly, packaging and testing of CMOS Sensor using imported/ domestically manufactured inputs*. |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| Plastic Housing | Domestically manufactured from imported / domestically manufactured inputs. |
| USB Cables | Domestically manufactured from imported / domestically manufactured inputs. |
| (i) Final Assembly and Testing<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

** This shall be reviewed when the Semiconductor FAB in India is operational.*

### 4.11 Biometric Iris Sensors

**(A) Definition**:

For the purpose of this Notification, Biometric Iris Sensor consists of a Controller Module, CMOS Sensor and Optics. The applications of the Biometric Iris Sensor are personal identification and verification, etc.

**(B) Mechanism for calculation of local content:**

The domestic Bill of Material (BOM) of Biometric Iris Sensor would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/stages for manufacture of Biometric Iris Sensor** | **Value addition/local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Main PCB (Controller Module) | Domestic assembly and testing using imported / domestically manufactured parts and components except value of bare PCB. |
| Optics | Domestically manufactured from imported/ domestically manufactured inputs. |
| CMOS Sensor | Domestic assembly, packaging and testing of CMOS Sensor using imported/ domestically manufactured inputs*. |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| Plastic Housing | Domestically manufactured from imported/ domestically manufactured inputs. |
| USB Cables | Domestically manufactured from imported/ domestically manufactured inputs. |
| (i) Final Assembly and Testing<br>(ii) Design/ Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM. |

**This shall be reviewed when the Semiconductor Fab in India is operational.*

**4.12 Servers**

**(A) Definition**:

For the purpose of this Notification, a Server shall necessarily consist of a Mother Board, CPU, Memory (RAM), Hard Disk Drive (HDD)/ Solid State Storage Drive (SSD), Power Supply Unit (SMPS), Chassis, Connecting Cables and Firmware & OS.

**(B) Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of a Server would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/ stages for manufacture of Server** | **Value addition /local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Server Board/ Mother Board and CPU(s)/ GPU(s) | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU(s)/ GPU(s)** and excluding the value of bare PCB. |
| Memory Module | Domestic PCB Assembly* and testing from imported/ domestically manufactured memory chips** and parts/ components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB. |
| Hard Disk Drive/ Solid State Storage Drive (SSD) | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Cabinet + SMPS | Domestically manufactured Cabinet and domestic assembly and testing of SMPS from imported / domestically manufactured parts and components, subject to the condition that value of domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 25% (of the total value of parts and components used in the manufacture of "SMPS"). |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| Accessories (Power Cables, Connectors, etc.) | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| (i) Final Assembly and Testing<br>(ii) Design and Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in the domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU(s)/ processor(s), parts/ components on the bare PCB using the SMT process should mandatorily be done in India*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

**4.13 Cellular Mobile Phones**

**(A) Definition**:

For the purpose of this Notification, a Cellular Mobile Phone (Feature Phone or Smart Phone) shall necessarily consist of a Main Printed Circuit Board (PCB), Battery Pack, Display Unit, Key Pad/ Touch Panel, Charger/ Adapter, Microphone & Receiver, Vibrator Motor/ Ringer and Mechanics.

**(B) Mechanism for calculation of local content**:

The domestic BOM of Cellular Mobile Phones would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| **Main inputs in BOM/stages for manufacture of Cellular Mobile Phone** | **Value addition/ local content required for the input to be classified as domestic BOM** |
|---|---|
| **1** | **2** |
| Main PCB* | Domestic assembly and testing from imported/ domestically manufactured parts and components including Processor and Semiconductor** BOM (i.e the Semiconductor Chips and Modules on Main PCB), and excluding value of bare PCB. |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| Battery Pack | Domestic assembly and testing of imported/ domestically manufactured inputs. |
| Charger/ Adapter | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Wired Headset | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Mechanics*** | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Die Cut Parts*** | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Microphone and Receiver | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Key Pad | Domestic assembly and testing from imported/ domestically manufactured inputs |
| USB Cable | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Camera Module | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Connectors | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Display Unit | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Touch Panel/ Cover Glass Assembly | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| Vibrator Motor/ Ringer | Domestic assembly and testing from imported/ domestically manufactured inputs. |
| (i) Final Assembly and Testing<br>(ii) Design and Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in the domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the processor/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational*

****Refer Annexure*

5. The Notification comes into effect immediately. This Notification shall remain valid till the revised Notification is issued.

6. No Electronic Product Notification under the Public Procurement (Preference to Make in India) Order 2017 shall have retrospective effect.

7. Purchase Preference shall be provided as per the provisions cited in the Public Procurement (Preference to Make in India) Order 2017 dated 04.06.2020 for the procurement of aforesaid electronics products.

8. The notification would also be applicable to all Central Schemes (CS)/ Central Sector Schemes (CSS) for the procurement of electronic products made by States and local bodies, if project or scheme is fully or partially funded by Government of India.

**9. Procedure for calculating local content/ domestic value addition**

9.1 Bill of Material sourced from domestic manufacturers (Dom-BOM) may be calculated based on one of the followings depending on data available. Each of these calculations should provide consistent result.

a. Sum of the costs of all inputs which go into the product (including duties and taxes levied on procurement of inputs except those for which credit/ set-off can be taken) and which have not been imported directly or through a domestic trader or an intermediary.

b. Ex-Factory Price of product minus profit after tax minus sum of imported Bill of Material used (directly or indirectly) as inputs in producing the product (including duties and taxes levied on procurement of inputs except those for which credit/ set-off can be taken) minus warranty costs.

c. Market price minus post-production freight, insurance and other handling costs minus profit after tax minus warranty costs minus sum of Imported Bill of Material used as inputs in producing the product (including duties and taxes levied on procurement of inputs except those for which credit / set-off can be taken) minus sales and marketing expenses.

9.2 Total Bill of Material (Total-BOM) may be calculated based on one of the following depending on data available. Each of these calculations should provide consistent result.

a. Sum of the costs of all inputs which go into the product (including duties and taxes levied on procurement of inputs except those for which credit / set-off can be taken).

b. Ex-Factory Price of product minus profit after tax, minus warranty costs.

c. Market price minus post-production freight, insurance and other handling costs minus profit after tax, minus warranty costs minus sales and marketing expenses.

9.3 The percentage of domestic value-addition may be calculated based on information furnished as per the following formula:

$$\text{Percentage of local content/ domestic value-addition} = \frac{\text{Dom-BOM}}{\text{Total-BOM}} \times 100$$

It is recommended that each agency assessing should calculate the domestic local content/ value-addition using at least two of the above formulae so as to validate the assessments in this regard and ensure that the domestic value addition that is claimed is consistent.

**10. Verification of local content/ Domestic Value Addition**

a. The local supplier at the time of tender, bidding or solicitation shall provide self-certification that the item offered meets the minimum local content and shall give details of the location(s) at which the local value addition is made.

b. In cases of procurement for a value in excess of Rs. 10 crore, the local supplier shall provide a certificate from the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) giving the percentage of local content.

c. In case a complaint is received by the procuring agency or the concerned Ministry/Department against the claim of a bidder regarding local content/ domestic value addition in an electronic product, the same shall be referred to STQC.

d. Any complaint referred to STQC shall be disposed of within 4 weeks. The bidder shall be required to furnish the necessary documentation in support of the domestic value addition claimed in an electronic product to STQC. If no information is furnished by the bidder, such laboratories may take further necessary action, to establish the bonafides of the claim.

e. A complaint fee of Rs.2 Lakh or 1% of the value of the domestically manufactured electronic products being procured (subject to a maximum of Rs. 5 Lakh), whichever is higher, to be paid by Demand Draft to be deposited with STQC. In case, the complaint is found to be incorrect, the complaint fee shall be forfeited. In case, the complaint is upheld and found to be substantially correct, deposited fee of the complainant would be refunded without any interest.

f. False declarations will be in breach of the Code of Integrity under Rule 175(1)(i)(h) of the General Financial Rules for which a bidder or its successors can be debarred for up to two years as per Rule 151 (iii) of the General Financial Rules along with such other actions as may be permissible under law.

11. MeitY shall be the Nodal Ministry to monitor the implementation of the Electronic Products Notification.

12. In case of a question whether an item being procured is an electronic product to be covered under the Public Procurement (Preference to Make in India) Order 2017, the matter would be referred to the Ministry of Electronics and Information Technology for clarification.

SAURABH GAUR, Jt. Secy.

**Annexure**

**Indicative List of Mechanics and Die Cut Parts**

**A. Mechanics**

1. Battery Cover (HS 39209999)
2. Front Cover (HS 39209999)
3. Front Cover (With Zinc Casting) (HS 39209999)
4. Middle Cover (HS 39209999)
5. GSM Antenna/ Antenna of any technology (HS 39209999)
6. Side Key (HS 85389000)
7. Main Lens (HS 39209999)
8. Camera Lens (HS 39209999)
9. Screw (HS 73181500)
10. Mic Rubber Case (HS 40169990)
11. Sensor Rubber Case/ Sealing Gasket including sealing gaskets/ cases from Rubbers like SBR, EPDM, CR, CS, Silicone and all other individual rubbers or combination/ combinations of rubbers (HS 40 169990)
    - 11.1 PU Case/ Sealing Gasket (HS 39269091) - Other articles of Polyurethane foam like sealing gaskets/ cases.
    - 11.2 Sealing Gaskets/ Cases from PE, PP, EPS, PC and all other individual polymers or combination/ combinations of polymers (HS 39269099)
12. SIM Socket/ Other Mechanical items (Metal) (HS 73269099)
13. SIM Socket/ Other Mechanical items (Plastic) (HS 39269099)
14. Back Cover (HS 39209999)

**B. Die Cut Parts**

1. Conductive Cloth (HS 39269099)
2. Heat Dissipation Sticker Battery Cover (HS 39199090)
3. Sticker-Battery Slot (HS 39199090)
4. Protective Film for Main Lens (HS 39199090)
5. Mylar for LCD FPC (HS 39199090)
6. LCD Conductive Foam (HS 39269099)
7. Film-Front Flash (HS 39199090)
8. LCD Foam (HS 39269099)
9. BT Foam (HS 39269099)

Uploaded by Dte. of Printing at Government of India Press, Ring Road, Mayapuri, New Delhi-110064
and Published by the Controller of Publications, Delhi-110054.

रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-21102023-249586
CG-DL-E-21102023-249586

असाधारण
EXTRAORDINARY

भाग II—खण्ड 3—उप-खण्ड (ii)
PART II—Section 3—Sub-section (ii)

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 4417] नई दिल्ली, बृहस्पितवार, अक्तूबर 19, 2023/आश्विन 27, 1945
No. 4417] NEW DELHI, THURSDAY, OCTOBER 19, 2023/ASVINA 27, 1945

## इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय

## (आईपीएचडब्ल्यू डिवीजन)

## अधिसूचना

नई दिल्ली, 12 अक्तूबर, 2023

**विषय: दिनांक 07.09.2020 के इलेक्ट्रॉनिक उत्पाद अधिसूचना फ़ा.सं.डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई के खंड संख्या 4.12 (सर्वर) में संशोधन संबंधी।**

**का.आ. 4591(अ).**—दिनांक 15.06.2017 के उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) सार्वजनिक खरीद (मेक इन इंडिया को वरीयता) आदेश 2017 जिसे दिनांक 28.05.2018, 29.05.2019, 04.06.2020 और 16.09.2020 के आदेशों द्वारा यथा संशोधित किया गया, को आगे बढ़ाते हुए दिनांक 07.09.2020 की इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय (एमईआईटीवाई) की राजपत्र अधिसूचना फा.सं. डब्लयु-43/4/2049-आईपीएचडब्ल्यु-एमईआईटीवाई के द्वारा इलेक्ट्रॉनिक उत्पादों को अधिसूचित किया गया था।

2. सर्वर के मामले में, खंड 4.12 (ख): स्थानीय सामग्री की गणना के लिए तंत्र को निम्नानुसार संशोधित किया गया है और यह तत्काल प्रभाव से लागू होगा:



Page 158 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**स्थानीय सामग्री की गणना के लिए संशोधित तंत्र:**

**सर्वर** की घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्य वर्धन आवश्यकता को पूरा करें। हालांकि, 'एड ऑन कंट्रोलर' के कुल मूल्य का वेटेज **सर्वर** के कुल बीओएम के **3%** से अधिक नहीं होगा।

| **बीओएम के प्रमुख इनपुट/ सर्वर के विनिर्माण के लिए चरण** | **मूल्य वर्धन/इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए अपेक्षित स्थानीय सामग्री** |
|---|---|
| 1 | 2 |
| सर्वर बोर्ड/मदर बोर्ड और सीपीयू(एस)/जीपीयू(एस) | सेमीकंडक्टर्स** और सीपीयू (एस) / जीपीयू (एस)** को शामिल करके" और बेअर पीसीबी के मूल्य को छोड़कर आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण |
| मेमोरी मॉड्यूल | पीसीबी असेंबली* और बेअर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेअर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों/संघटको से घरेलू परीक्षण। |
| हार्ड डिस्क ड्राइव/ सॉलिड स्टेट स्टोरेज ड्राइव (एसएसडी) | आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबली और परीक्षण। |
| कैबिनेट + एसएमपीएस | आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू रूप से घरेलू स्तर पर विनिर्मित कैबिनेट और एसएमपीएस का घरेलू असेंबली और परीक्षण, इस शर्त के अध्यधीन कि "एसएमपीएस" की असेंबली में उपयोग किए गए घरेलू स्तर पर विनिर्मित भागों और संघटकों का मूल्य न्यूनतम 25% होगा ("एसएमपीएस " के विनिर्माण में उपयोग किए जाने वाले भागों और संघटकों का कुल मूल्य) |
| बेयर पीसीबी | आयातित/घरेलू विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित |
| सहायक उपकरण (पावर केबल, कनेक्टर, आदि) | आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबली और परीक्षण। |
| **ऐड-ऑन कंट्रोलर**<br>I. आरएआईडी कंट्रोलर/एडाप्टर<br>II. नेटवर्क इंटरफ़ेस कंट्रोलर | पीसीबी असेंबली* और बेअर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेअर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित चिप्स** और कलपुर्जों/संघटको से घरेलू परीक्षण। |
| (i) फाइनल असेंबली और टेस्टिंग<br>(ii) डिजाइन और विकास | (i) घरेलू स्तर पर असेम्बल/परीक्षित और<br>(ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा। |

** यह आवश्यक है कि सीपीयू (एस)/जीपीयू (एस)/प्रोसेसर (एस) के प्रिंटेड सर्किट बोर्ड असेंबली (पीसीबीए), एसएमटी प्रक्रिया का उपयोग कर बेयर पीसीबी पर भागों/संघटकों को अनिवार्य **रूप से** भारत में किया जाना चाहिए।*

*** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

3. दिनांक 07.09.2020 की एमईआईटीवाई की राजपत्र अधिसूचना फ़ा.सं.डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई के अन्य सभी नियम और शर्तें अपरिवर्तित रहेंगी।

[फा. सं. डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई]

आशा नांगिया, समूह समन्वयक और वैज्ञानिक 'जी'

## MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY

**(IPHW Division)**

## NOTIFICATION

New Delhi, the 12th October, 2023

**Subject: Amendment to Electronic Products Notification F.No.W-43/4/2019-IPHW-MeitY dated 07.09.2020 w.r.t. Clause No. 4.12 (Servers) – reg.**

**S.O. 4591(E).—** Electronic Products were notified vide Ministry of Electronics and Information Technology (MeitY) Gazette Notification F.No.W-43/4/2019-IPHW-MeitY dated 07.09.2020, in furtherance of the Department for Promotion of Industry and Internal Trade (DPIIT) Public Procurement (Preference to Make in India) Order 2017 dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019, 04.06.2020 and 16.09.2020.

2. In case of Servers, Clause 4.12 (B): Mechanism for calculation of local content is amended as under and will be applicable with immediate effect:

**Revised Mechanism for calculation of local content**:

The domestic Bill of Material (BOM) of **Server** would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table. However, the weightage of total value of 'Add on Controller' shall not exceed **3%** of the total BOM of the **Server**.

| **Main inputs in BOM/ stages for manufacture of Server** | **Value addition /local content required for the input to be classified as domestic BOM** |
|---|---|
| 1 | 2 |
| Server Board/ Mother Board and CPU(s)/ GPU(s) | Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU(s)/ GPU(s)** and excluding the value of bare PCB. |
| Memory Module | Domestic PCB Assembly* and testing from imported/ domestically manufactured memory chips** and parts/ components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB. |
| Hard Disk Drive/ Solid State Storage Drive (SSD) | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| Cabinet + SMPS | Domestically manufactured Cabinet and domestic assembly and testing of SMPS from imported / domestically manufactured parts and components, subject to the condition that value of domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 25% (of the total value of parts and components used in the manufacture of "SMPS"). |
| Bare PCB | Domestically manufactured from imported/ domestically manufactured inputs. |
| Accessories (Power Cables, Connectors, etc.) | Domestic assembly and testing from imported/ domestically manufactured parts and components. |
| **Add-on Controllers**<br>i. RAID Controller/Adapter | Domestic PCB Assembly* and testing from imported/ domestically manufactured chips** and parts/ components on imported/ domestically |

| | |
|---|---|
| ii. Network Interface Controllers | manufactured bare PCB, excluding the value of bare PCB. |
| (i) Final Assembly and Testing<br>(ii) Design and Development | (i) Domestically assembled/ tested and<br>(ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in the domestic BOM. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU(s)/ processor(s), parts/ components on the bare PCB using the SMT process should **mandatorily** be done in India*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

3. All other terms and conditions of MeitY Gazette Notification F.No.W-43/4/2019-IPHW-MeitY dated 07.09.2020 remain unchanged.

[F. No. W-43/4/2019-IPHW-MeitY]

ASHA NANGIA, Group Coordinator & Scientist 'G'

Uploaded by Dte. of Printing at Government of India Press, Ring Road, Mayapuri, New Delhi-110064
and Published by the Controller of Publications, Delhi-110054.

No. 13(7)/2022-EG-II
Government of India
Ministry of Electronics and Information Technology
Electronics Niketan, 6, CGO Complex, New Delhi-110003.

Dated: 17.08.2022

**OFFICE MEMORANDUM**

**Subject: Exemption from Public Procurement (Preference to Make in India) Clause for procurement of various items – regarding**

This has reference to the request made by the Unique Identification Authority of India (UIDAI), vide letter no. T-11014/07/2017-Tech/87 dated 07.06.2022, for seeking exemption from Public Procurement (Preference to Make in India) Clause for procurement of various information security tools/items.

2. The items requested by UIDAI for exemption along with their justification for exemption are listed in the table at **Annexure-1** (08 Items).

3. In this regard, the Government has issued Public Procurement (Preference to Make in India) Order 2017 vide the Department for Promotion of Industry and Internal Trade (DPIIT) Order No.P-45021/2/2017-B.E-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019, 04.06.2020 and 16.09.2020 to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment.

4. In furtherance of the Public Procurement (Preference to Make in India) Order 2017 [PPP-MII Order 2017], Ministry of Electronics and Information Technology (MeitY) has notified the mechanism for calculation of local content for 13 Electronic Products vide Electronic Products Notification vide F.No.43/4/2019-IPHW-MeitY dated 07.09.2020; and Public Procurement (Preference to Make in India) Order 2019 for Cyber Security Products vide Notification No.1(10)/2017-CLES dated 06.12.2019.

5. In this regard, the undersigned is directed to convey the approval of Hon'ble Minister of Electronics and Information Technology for exemption from Public Procurement (Preference to Make in India) for procurement of the items requested by UIDAI (refer **Annexure-1**) as per Clause 14 of the Public Procurement (Preference to Make in India) Order 2017 notified vide DPIIT File No. P-45021/2/2017-B.E.-II dated 16.09.2020 with following conditions:

i. UIDAI will do a thorough check on Government e-Marketplace (GeM) for availability of the aforesaid items / services as per PPP-MII Order 2017 conditions before going for the exempted category of procurement.

Dir (IS) 20 Aug 22
DDG (IS) 23/8
Dhawan 24/8/22
846/CEO/UIDAI 17/8/22
149/DDG (ES & Eng.)/UIDAI 22/08/2022
DD/S
SO/IS

ii. Exemption shall be given for a maximum period of one year which may be reviewed any time after completion of six months.

iii. UIDAI shall adhere to the PPP-MII Order 2017 issued by DPIIT and the Electronic Products & Cyber Security Products Notifications issued by MeitY, as amended from time to time.

iv. Adherence to all codal formalities as per the provisions of General Financial Rules-2017, and Department of Expenditure and central Vigilance Commission's guidelines.

**(D. K. Sagar)**
**Joint Director**

Encl: As above.

To:

1. The Chief Executive Officer, UIDAI, Bangla Sahib Road, New Delhi.

2. The Secretary, DPIIT & Chairman, Standing Committee on PPP-MII Order 2017, New Delhi.

3. Group Coordinator (UIDAI), Ministry of Electronics and Information Technology, New Delhi.

**Annexure-1**

| List of various hardware and software items requested by UIDAI for Exemption of Make in India (MII) clause for procurement through GeM | | | |
|---|---|---|---|
| **SL. No.** | **ICT Item Categories** | **Item Details** | **Justification for MII Exemption** |
| 1 | Network Intrusion Prevention system (**NIPS**) | Network Intrusion Prevention system works by examining incoming/outgoing traffic for intrusions, vulnerabilities, exploits and provides remediation to protect network servers and applications. IPS provides holistic view of intrusions across the network through a single dashboard (existing IPS manager) where it stores vulnerability patches and signatures in single storage which can be pushed to all the IPS sensors across the network. The IPS managers can be utilized as to troubleshoot customer/ network issues related to IPS. In the present setup the Data Centre has IPS Solutions of McAfee. | 1. At present there is no OEM manufacturing this class of equipment in India.<br>2. Network Intrusion preventions works on signature based technology for basic solution coverage and hence it needs global and deep experience to have signature coverage for all latest attack patterns to provide efficient solution which is currently not available in India. |

**No. IV-24011/22/2020-Prov-I/270.**
**Government of India**
**Ministry of Home Affairs**
**Police Modernization Division**
**Prov-III Desk**

26, Man Singh Road,
Jaisalmer House, New Delhi
Dated the 26 April, 2024.

**Office Memorandum**

**Subject : Forwarding of MeitY's communications regarding CCTVs.**

**(i) Notification dated 06 March, 2024 on the amendments to Public Procurement Order (PPO)-2017 for CCTV/Video Surveillance Systems,**
**(ii) Amendment notification dated 09 April, 2024 to the "Electronics and information Technology Goods (Requirement of Compulsory Registration) Order, 2021**
**(iii) Advisory dated 11 March, 2024 on the Threat of Information through CCTV/Video Surveillance system."**

The undersigned is directed to say that Ministry of Electronics and Information Technology has notified amendment to Public Procurement (Preference to Make in India) Order 2017 for CCTV/Video Surveillance System for Security and furtherance of the order vide Gazette Notification dated 6th March, 2024 (copy enclosed). MeitY has also issued amendment notification dated 09 April, 2024 to the "Electronics and Information Technology Goods (Requirement of Compulsory Registration) Order, 2021" for the security of a CCTV system (copy enclosed).

2. All Government agencies are advised that henceforth they may procure their CCTVs and allied solutions and hardware on the basis of the Public Procurement Order-2017 and ensure the security of CCTV systems as mentioned in the above said notifications.

3. Further, MeitY has issued Advisory vide O.M. dated W-43/11/2021-IPHW dated 11 Mar, 2024 (copy enclosed) on the Threat of Information through CCTV/Video Surveillance System (VSS)/Digital Video Recorders/Network Video Recorders. All Government agencies are advised to adhere to the guidelines outlined within the ambit of the Public Procurement Orders to safeguard the overall security and integrity of CCTV Cameras and IoT Devices.

Encl:A/a

26/04/24

(Anuj Kumar)
2IC (Prov.)
Tel: 23386034
e-mail ID:anuj-kumar38@nic.in

To:

1. Chief Secretaries of all States.
2. Administrators of all UTs.
3. Commissioner of Police, Delhi.
4. Directors : CBI, IB, SVP NPA-Hyderabad, NEPA-Shillong, NCRB, NICFS.
5. DsG : AR, BSF, BPR&D, CISF, CRPF, ITBP, NDRF, NSG, SSB & NIA

Internal:

1. All Divisional Heads, MHA.
2. SO(IT) with the request to upload the OM on MHA's website.
3. Director (Procurement)/Director (PM-I & II).
4. US (Prov-I)/US(Prov-II).

रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-08032024-252738
CG-DL-E-08032024-252738

असाधारण
EXTRAORDINARY

भाग II—खण्ड 3—उप-खण्ड (ii)
PART II—Section 3—Sub-section (ii)

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 1062] नई दिल्ली, बृहस्पतिवार, मार्च 7, 2024/फाल्गुन 17, 1945
No. 1062] NEW DELHI, THURSDAY, MARCH 7, 2024/PHALGUNA 17, 1945

## इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय

## (आईपीएचडब्ल्यू प्रभाग)

## अधिसूचना

नई दिल्ली, 6 मार्च, 2024

**विषय: सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के अनुक्रम में सुरक्षा के लिए क्लोज्ड सर्किट टेलीविजन (सीसीटीवी)/वीडियो निगरानी प्रणाली को अधिसूचित करना**

**सन्दर्भ:**

**(i) उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) के दिनांक 28.05.2018, 29.05.2019 और 04.06.2020 के आदेशों के जरिए यथासंशोधित आदेश संख्या पी-45021/2/2017-बीई-II दिनांक 15.06.2017**

**(ii) इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय (एमईआईटीवाई) की दिनांक 07.09.2020 की इलेक्ट्रॉनिक उत्पाद अधिसूचना सं. डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई**

**का.आ. 1119(अ).**—सरकार ने 'मेक इन इंडिया' को प्रोत्साहित करने और आय और रोजगार बढ़ाने के उद्देश्य से भारत में वस्तुओं और सेवाओं के विनिर्माण और उत्पादन को बढ़ावा देने के लिए उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) के दिनांक **28.05.2018, 29.05.2019 और 04.06.2020 के आदेशों के जरिए यथासंशोधित आदेश संख्या पी-45021/2/2017-बीई-II दिनांक 15.06.2017 के तहत सार्वजनिक क्रय (मेक इन इंडिया वरीयता) आदेश, 2017 जारी किया है।**



Page 166 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**2.** उपर्युक्त संदर्भ के जरिये अधिसूचित सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 [पीपीपी-एमआईआई आदेश 2017] के अनुक्रम में इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय (एमईआईटीवाई) एतद्वारा अधिसूचित करता है कि समय-समय पर संशोधित पूर्वोक्त आदेश के अनुसार स्थानीय रूप से विनिर्मित इलेक्ट्रॉनिक उत्पादों को सभी क्रय संस्थाओं द्वारा वरीयता प्रदान की जाएगी।

**3.** इस अधिसूचना के उद्देश्य से :

3.1 श्रेणी- I स्थानीय आपूर्तिकर्ता, श्रेणी-II स्थानीय आपूर्तिकर्ता और गैर-स्थानीय आपूर्तिकर्ता की परिभाषा दिनांक 16.09.2020 के डीपीआईआईटी पीपीपी-एमआईआई आदेश 2017 संख्या समय-समय पर यथा संशोधित पी-45021/2/2017-पीपी(बीई-II) के पैराग्राफ 2 के अनुसार होगी।, । इस अधिसूचना में प्रत्येक अधिसूचित इलेक्ट्रॉनिक उत्पाद के लिए स्थानीय सामग्री की गणना के लिए तंत्र निर्धारित किया गया है।

3.2 समय-समय पर यथासंशोधित दिनांक 16.09.2020 के डीपीआईआईटी पीपीपी-एमआईआई आदेश 2017 सं. पी-45021/2/2017-पीपी(बीई-II) के पैराग्राफ 3 क को खरीद के प्रतिशत के लिए संदर्भित किया जाएगा, जिसके लिए घरेलू रूप से निर्मित इलेक्ट्रॉनिक उत्पादों को वरीयता प्रदान की जानी है (मूल्य के संदर्भ में)।

**4.** वीडियो निगरानी प्रणाली के निम्नलिखित इलेक्ट्रॉनिक उत्पादों को सार्वजनिक खरीद (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत अधिसूचित किया गया है:

**4.1 वीडियो निगरानी प्रणाली**

**परिभाषा:**

इस अधिसूचना के प्रयोजन के लिए, वीडियो निगरानी प्रणाली आमतौर पर एक प्रणाली है जिसमें *अन्य बातों के साथ-साथ* निम्नलिखित शामिल हैं: (i) क्लोज्ड सर्किट टेलीविजन (सीसीटीवी) कैमरा (एनालॉग/आईपी/एनालॉग स्पीड डोम/आईपी स्पीड डोम), (ii) डिजिटल वीडियो रिकॉर्डर (डीवीआर)/नेटवर्क वीडियो रिकॉर्डर (एनवीआर)। सुरक्षा और वीडियो निगरानी प्रणाली के कुछ अनुप्रयोग शहरों, स्कूलों, बैंकों, सरकारी कार्यालयों, सार्वजनिक स्थानों, यातायात निगरानी और गृह सुरक्षा आदि की निगरानी हैं।

**4.2 सीसीटीवी कैमरा (एनालॉग) की स्थानीय सामग्री की गणना के लिए तंत्र:**

सीसीटीवी कैमरा (एनालॉग) का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में यथा निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्य संवर्धन आवश्यकता को पूरा करते हों:

| क्रम सं. | बीओएम में मुख्य इनपुट / सीसीटीवी कैमरा (एनालॉग) के निर्माण के लिए चरण | इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए अपेक्षित मूल्य संवर्धन/स्थानीय सामग्री |
|---|---|---|
| | (1) | (2) |
| 1.0 | मुख्य पीसीबी* | सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण,. हालांकि, वैकल्पिक बोर्डों के साथ/इसके बिना मुख्य पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 10% से अधिक नहीं होगा |
| (i) | आई /ओ बोर्ड (वैकल्पिक) | |
| (ii) | इन्फ्रारेड (आईआर) बोर्ड (वैकल्पिक) | |
| (iii) | नियंत्रण बोर्ड (वैकल्पिक) | |
| 2.0 | बेयर पीसीबी | घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 5% से अधिक नहीं होगा |
| 3.0 | ऑप्टिक्स | घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 10% से अधिक नहीं होगा |
| 4.0 | इन-हाउस आर एंड डी # | घरेलू/इन हाउस आर एंड डी में स्वयं अपने संसाधन/विशेषज्ञता का उपयोग कर नये उत्पादों, प्रक्रियाओं, प्रौद्योगिकीयों या समाधानों के विकास के लिए वैज्ञानिक अनुसंधान, प्रयोग, प्रोटोटाइपिंग और परीक्षण अथवा भारत में वैज्ञानिक और औद्योगिक अनुसंधान विभाग (डीएसआईआर) के साथ पंजीकृत आर एंड डी इकाई के साथ कानूनी अनुबंध शामिल है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है। |

| | | | | |
|---|---|---|---|---|
| | | 2023-24 & 2024-25 | 2025-26 | 2026-27 के बाद |
| | | 7% | 10% | 12% |
| 5.0 | इन-हाउस डिजाइन/आईपीआर # | घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विषेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है। | | |
| | | 2023-24 & 2024-25 | 2025-26 | 2026-27 के बाद |
| | | 7% | 10% | 12% |
| 6.0 | हाउसिंग (प्लास्टिक/एल्यूमीनियम/एमएस) और कैमरा माउंट | घरेलू रूप से निर्मित इनपुट से घरेलू रूप से विनिर्माण । हाउसिंग और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 15% से अधिक नहीं होगा। | | |
| 7.0 | कनेक्टिंग केबल्स और कनेक्टर्स | घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल्स और कनेक्टर्स के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 5% से अधिक नहीं होगा। | | |
| 8.0 | अंतिम असेम्बली और परीक्षण | समय-समय पर अधिसूचित भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल / परीक्षित. अंतिम संयोजन और परीक्षण के कुल मूल्य का वेटेज सीसीटीवी कैमरे के कुल बीओएम के 10% से अधिक नहीं होगा | | |

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों के मुद्रित सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

*** भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।*

*# आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 4.0 (इन-हाउस आर एंड डी) और क्रम संख्या 5.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.*

| **वित्तीय वर्ष** | **2023-24 & 2024-25** | **2025-26** | **2026-27 के बाद** |
|---|---|---|---|
| आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.8.0) अंतिम असेंबली और परीक्षण और अन्य वैकल्पिक के रूप में | 25% | 35% | 45% |

### 4.3 सीसीटीवी कैमरा (आईपी) की स्थानीय सामग्री की गणना के लिए तंत्र:

सीसीटीवी कैमरा (आईपी) का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में यथा निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करते हों:

| **क्रम सं.** | **बीओएम में मुख्य इनपुट / सीसीटीवी कैमरा (आईपी) के निर्माण के लिए चरण** | **इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए आवश्यक मूल्य संवर्धन/स्थानीय सामग्री** |
|---|---|---|
| | **(1)** | **(2)** |
| 1.0 | मुख्य पीसीबी* कैप्चर और/या प्रोसेसर कार्ड के साथ | सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण. |

<table>
<tr><td>(i)</td><td>नेटवर्क इंटरफेस कार्ड (वैकल्पिक)</td><td rowspan="4">हालांकि, वैकल्पिक बोर्डों के साथ/इनके बिना मुख्य पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 10% से अधिक नहीं होगा</td></tr>
<tr><td>(ii)</td><td>इन्फ्रारेड (आईआर) बोर्ड (वैकल्पिक)</td></tr>
<tr><td>(iii)</td><td>आई/ओ बोर्ड (वैकल्पिक)</td></tr>
<tr><td>(iv)</td><td>पावर ओवर इथरनेट (पी ओ ई ) कार्ड (वैकल्पिक)</td></tr>
<tr><td>2.0</td><td>बेयर पीसीबी</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 5% से अधिक नहीं होगा</td></tr>
<tr><td>3.0</td><td>ऑप्टिक्स</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। प्रकाशिकी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 10% से अधिक नहीं होगा</td></tr>
<tr><td>4.0</td><td>इन-हाउस आर एंड डी #</td><td>घरेलू/इन हाउस आर एंड डी में स्वयं अपने संसाधन/विशेषज्ञता का उपयोग कर नये उत्पादों, प्रक्रियाओं, प्रौद्योगिकीयों या समाधानों के विकास के लिए वैज्ञानिक अनुसंधान, प्रयोग, प्रोटोटाइपिंग और परीक्षण अथवा भारत में वैज्ञानिक और औद्योगिक अनुसंधान विभाग (डीएसआईआर) के साथ पंजीकृत आर एंड डी इकाई के साथ कानूनी अनुबंध शामिल है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
<tr><th>2023-24 & 2024-25</th><th>2025-26</th><th>2026-27 के बाद</th></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table>
</td></tr>
<tr><td>5.0</td><td>इन-हाउस डिजाइन/आईपीआर #</td><td>घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विषेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
<tr><th>2023-24 & 2024-25</th><th>2025-26</th><th>2026-27 के बाद</th></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table>
</td></tr>
<tr><td>6.0</td><td>हाउसिंग (प्लास्टिक / एल्यूमीनियम / एमएस) और</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। हाउसिंग और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 15% से अधिक नहीं होगा।</td></tr>
<tr><td>7.0</td><td>कनेक्टिंग केबल्स और कनेक्टर्स</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल्स और कनेक्टर्स के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 5% से अधिक नहीं होगा।</td></tr>
<tr><td>8.0</td><td>अंतिम असेम्बली और परीक्षण</td><td>समय-समय पर यथा अधिसूचित भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल / परीक्षित .फाइनल असेंबलिंग और टेस्टिंग के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 10% से अधिक नहीं होगा.</td></tr>
</table>

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों की मुद्रित सर्किट बोर्ड असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।# आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 4.0 (इन-हाउस आर एंड डी) और क्रम संख्या 5.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.*

| वित्तीय वर्ष | 2023-24 & 2024-25 | 2025-26 | 2026-27 के बाद |
|---|---|---|---|
| आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.8.0) अंतिम असेंबली और परीक्षण और अन्य वैकल्पिक के रूप में | 25% | 35% | 45% |

### 4.4 सीसीटीवी कैमरा (एनालॉग स्पीड डोम) की स्थानीय सामग्री की गणना के लिए तंत्र:

सीसीटीवी कैमरा (एनालॉग स्पीड डोम) का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में यथा निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्य संवर्धन आवश्यकता को पूरा करते हों:

<table>
<tr><th>क्रम सं.</th><th>बीओएम में मुख्य इनपुट / सीसीटीवी कैमरा (एनालॉग स्पीड डोम) के निर्माण के लिए चरण</th><th>इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए आवश्यक मूल्य संवर्धन</th></tr>
<tr><td></td><td>(1)</td><td>(2)</td></tr>
<tr><td>1.0</td><td>मुख्य नियंत्रक बोर्ड*</td><td rowspan="3">सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण. हालांकि, वैकल्पिक बोर्डों के साथ/के बिना मुख्य नियंत्रक बोर्ड/मुख्य पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 10% से अधिक नहीं होगा</td></tr>
<tr><td>(i)</td><td>आई /ओ बोर्ड (वैकल्पिक)</td></tr>
<tr><td>(ii)</td><td>इन्फ्रारेड (आईआर) बोर्ड (वैकल्पिक)</td></tr>
<tr><td>2.0</td><td>बेयर पीसीबी</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा</td></tr>
<tr><td>3.0</td><td>इनहाउस आर एंड डी#</td><td>घरेलू/इन हाउस आर एंड डी में स्वयं अपने संसाधन/विशेषज्ञता का उपयोग कर नये उत्पादों, प्रक्रियाओं, प्रौद्योगिकीयों या समाधानों के विकास के लिए वैज्ञानिक अनुसंधान, प्रयोग, प्रोटोटाइपिंग और परीक्षण अथवा भारत में वैज्ञानिक और औद्योगिक अनुसंधान विभाग (डीएसआईआर) के साथ पंजीकृत आर एंड डी इकाई के साथ कानूनी अनुबंध शामिल है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
<tr><th>2023-24 & 2024-25</th><th>2025-26</th><th>2026-27 के बाद</th></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>4.0</td><td>इन-हाउस डिजाइन/आईपीआर#</td><td>घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विषेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
<tr><th>2023-24 & 2024-25</th><th>2025-26</th><th>2026-27 के बाद</th></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>5.0</td><td>हाउसिंग (प्लास्टिक/एल्यूमीनियम/एमएस) और</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। हाउसिंग और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के</td></tr>
</table>

| | | |
|---|---|---|
| | कैमरा माउंट | 5% से अधिक नहीं होगा। |
| 6.0 | कनेक्टिंग केबल्स और कनेक्टर्स | घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल्स और कनेक्टर्स के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा। |
| 7.0 | मोटर, हीटर और ब्लोअर, ज़ूम मॉड्यूल, बेल्ट, प्लास्टिक तंत्र भागों, ग्लास आदि | घरेलू रूप से आयातित/घरेलू रूप से निर्मित इनपुट भागों और यांत्रिक घटकों से निर्मित। हालांकि, इन सभी भागों/घटकों के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा |
| 8.0 | पावर एडाप्टर | घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से अंतिम असेम्बली और परीक्षण, बशर्ते कि "पावर एडाप्टर" की असेम्बली में इस्तेमाल घरेलू रूप से निर्मित कलपुर्जो और संघटकों का मूल्य न्यूनतम 40%होगा ("पावर एडाप्टर" के निर्माण में इस्तेमाल कलपुर्जो और संघटकों के कुल मूल्य का). हालांकि, "पावर एडॉप्टर" के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा |
| 9.0 | अंतिम असेम्बली और परीक्षण | समय-समय पर अधिसूचित भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल / परीक्षित. अंतिम संयोजन और परीक्षण के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 10% से अधिक नहीं होगा |

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों के मुद्रित सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

*** भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।*

*# आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 3.0 (इन-हाउस आर एंड डी) और क्रम संख्या 4.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.*

| **वित्तीय वर्ष** | **2023-24 & 2024-25** | **2025-26** | **2026-27 के बाद** |
|---|---|---|---|
| आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.8.0) अंतिम असेंबली और परीक्षण और वैकल्पिक के रूप में अन्य | 25% | 35% | 45% |

### 4.5 सीसीटीवी कैमरा (आईपी स्पीड डोम) की स्थानीय सामग्री की गणना के लिए तंत्र:

सीसीटीवी कैमरा (आईपी स्पीड डोम) का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करते हों:

| **क्रम सं.** | **बीओएम में मुख्य इनपुट / सीसीटीवी कैमरा (आईपी स्पीड डोम) के निर्माण के लिए चरण** | **इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए आवश्यक मूल्य संवर्धन/स्थानीय सामग्री** |
|---|---|---|
| | **(1)** | **(2)** |
| 1.0 | मुख्य नियंत्रक बोर्ड* | सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण. हालांकि, वैकल्पिक बोर्डों के साथ/के बिना मुख्य नियंत्रक बोर्ड के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 10% से अधिक नहीं होगा |
| (I) | आई /ओ बोर्ड (वैकल्पिक) | |
| (ii) | इन्फ्रारेड (आईआर) बोर्ड (वैकल्पिक) | |

<table>
<tr><td>(iii)</td><td>प्रोसेसर कार्ड (वैकल्पिक)</td><td rowspan="3"></td></tr>
<tr><td>(iv)</td><td>नेटवर्क इंटरफेस कार्ड (वैकल्पिक)</td></tr>
<tr><td>(v)</td><td>पावर ओवर इथरनेट (पी ओ ई ) कार्ड (वैकल्पिक)</td></tr>
<tr><td>2.0</td><td>बेयर पीसीबी</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा</td></tr>
<tr><td>3.0</td><td>इन-हाउस आर एंड डी #</td><td>घरेलू/इन हाउस आर एंड डी में स्वयं अपने संसाधन/विशेषज्ञता का उपयोग कर नये उत्पादों, प्रक्रियाओं, प्रौद्योगिकीयों या समाधानों के विकास के लिए वैज्ञानिक अनुसंधान, प्रयोग, प्रोटोटाइपिंग और परीक्षण अथवा भारत में वैज्ञानिक और औद्योगिक अनुसंधान विभाग (डीएसआईआर) के साथ पंजीकृत आर एंड डी इकाई के साथ कानूनी अनुबंध शामिल है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
<tr><th>2023-24 & 2024-25</th><th>2025-26</th><th>2026-27 के बाद</th></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table>
</td></tr>
<tr><td>4.0</td><td>इन-हाउस डिजाइन/आईपीआर #</td><td>घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विषेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
<tr><th>2023-24 & 2024-25</th><th>2025-26</th><th>2026-27 के बाद</th></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table>
</td></tr>
<tr><td>5.0</td><td>हाउसिंग (प्लास्टिक / एल्यूमीनियम / एमएस) और कैमरा माउंट</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। हाउसिंग और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा।</td></tr>
<tr><td>6.0</td><td>कनेक्टिंग केबल्स और कनेक्टर्स</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल्स और कनेक्टर्स के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा।</td></tr>
<tr><td>7.0</td><td>मोटर, हीटर और ब्लोअर, ज़ूम मॉड्यूल, बेल्ट, प्लास्टिक तंत्र भागों, ग्लास आदि</td><td>घरेलू रूप से आयातित/घरेलू रूप से निर्मित इनपुट भागों और यांत्रिक घटकों से निर्मित। तथापि, इन सभी भागों/संघटकों के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा।</td></tr>
<tr><td>8.0</td><td>पावर एडाप्टर</td><td>घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से अंतिम असेम्बली और परीक्षण, बशर्ते कि "पावर एडाप्टर" की असेम्बली में इस्तेमाल घरेलू रूप से निर्मित कलपुर्जो और संघटकों का मूल्य न्यूनतम 40%होगा ("पावर एडाप्टर" के निर्माण में इस्तेमाल कलपुर्जो और संघटकों के कुल मूल्य का). हालांकि, "पावर एडॉप्टर" के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा</td></tr>
<tr><td>9.0</td><td>अंतिम असेम्बली और परीक्षण</td><td>समय-समय पर यथाअधिसूचित भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल /परीक्षित . अंतिम संयोजन और परीक्षण के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 10% से अधिक नहीं होगा</td></tr>
</table>

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों के मुद्रित सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

*** भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।*

*# आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 3.0 (इन-हाउस आर एंड डी) और क्रम संख्या 4.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.*

| वित्तीय वर्ष | 2023-24 & 2024-25 | 2025-26 | 2026-27 के बाद |
|---|---|---|---|
| आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.9.0) अंतिम असेंबली और परीक्षण और अन्य वैकल्पिक के रूप में | 25% | 35% | 45% |

### 4.6 डीवीआर/एनवीआर की स्थानीय सामग्री की गणना के लिए तंत्र:

डीवीआर/एनवीआर का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में यथा निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करते हों:

<table>
<tr><th>क्रम सं.</th><th>बीओएम में मुख्य इनपुट / डीवीआर/एनवीआर के निर्माण के लिए चरण</th><th>इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए आवश्यक मूल्य संवर्धन/स्थानीय सामग्री</th></tr>
<tr><td></td><td>(1)</td><td>(2)</td></tr>
<tr><td>1.0</td><td>मुख्य पीसीबी*</td><td rowspan="3">सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण. तथापि, वैकल्पिक बोर्डों के साथ/के बिना मुख्य पीसीबी के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 10 % से अधिक नहीं होगा.</td></tr>
<tr><td>(i)</td><td>फ्रंट पैनल और एलईडी बोर्ड (वैकल्पिक)</td></tr>
<tr><td>(ii)</td><td>आई/ओ बोर्ड (वैकल्पिक)</td></tr>
<tr><td>2.0</td><td>बेयर पीसीबी</td><td>घरेलू रूप से विनिर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (डीवीआर / एनवीआर) के कुल बीओएम के 5% से अधिक नहीं होगा.</td></tr>
<tr><td>3.0</td><td>इन-हाउस आर एंड डी #</td><td>घरेलू/इन हाउस आर एंड डी में स्वयं अपने संसाधन/विशेषज्ञता का उपयोग कर नये उत्पादों, प्रक्रियाओं, प्रौद्योगिकीयों या समाधानों के विकास के लिए वैज्ञानिक अनुसंधान, प्रयोग, प्रोटोटाइपिंग और परीक्षण अथवा भारत में वैज्ञानिक और औद्योगिक अनुसंधान विभाग (डीएसआईआर) के साथ पंजीकृत आर एंड डी इकाई के साथ कानूनी अनुबंध शामिल है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 के बाद</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table>
</td></tr>
<tr><td>4.0</td><td>इन-हाउस डिजाइन/आईपीआर #</td><td>घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विषेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 के बाद</td></tr>
</table>
</td></tr>
</table>

| | | 7% | 10% | 12% |
|---|---|---|---|---|
| 5.0 | हाउसिंग (प्लास्टिक / एल्यूमीनियम / एमएस) और कैमरा माउंट | घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। आवास और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 5% से अधिक नहीं होगा। | | |
| 6.0 | कनेक्टिंग केबल, कनेक्टर्स और यूएसबी माउस | घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल, कनेक्टर्स और यूएसबी माउस के लिए इनपुट के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 5% से अधिक नहीं होगा। | | |
| 7.0 | रिमोट कंट्रोल | घरेलू असेंबली * और आयातित/घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण इस शर्त के अधीन है कि "रिमोट कंट्रोल" की असेंबली में उपयोग किए जाने वाले घरेलू रूप से निर्मित कलपुर्जो और संघटकों का मूल्य वर्ष 2 में न्यूनतम 20% होगा ("रिमोट कंट्रोल" के निर्माण में उपयोग किए जाने वाले कलपुर्जो और संघटकों के कुल मूल्य का), जो वित्तीय वर्ष 2025-26, 2026-27 और 2027-28 से आगे क्रमशः न्यूनतम 30%, 40% और 50% तक बढ़ जाएगा । | | |
| 8.0 | पावर एडाप्टर | घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से अंतिम असेम्बली और परीक्षण, बशर्ते कि "पावर एडाप्टर" की असेम्बली में इस्तेमाल घरेलू रूप से निर्मित कलपुर्जो और संघटकों का मूल्य न्यूनतम 40%होगा ("पावर एडाप्टर" के निर्माण में इस्तेमाल कलपुर्जो और संघटकों के कुल मूल्य का). हालांकि, "पावर एडाप्टर" के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 5% से अधिक नहीं होगा। | | |
| 9.0 | अंतिम असेम्बली और परीक्षण | समय-समय पर अधिसूचित वेटेज भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल / परीक्षित. अंतिम संयोजन और परीक्षण के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 10% से अधिक नहीं होगा। | | |

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों के मुद्रित सर्किट बोर्ड असेंबली (पीसीबीए) अनिवार्य रूप से भारत में किया जाना चाहिए।*

*** भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।*

*# आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 3.0 (इन-हाउस आर एंड डी) और क्रम संख्या 4.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.*

| वित्तीय वर्ष | 2023-24 & 2024-25 | 2025-26 | 2026-27 के बाद |
|---|---|---|---|
| आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.9.0) अंतिम असेंबली और परीक्षण और अन्य वैकल्पिक के रूप में | 25% | 35% | 45% |

**5.** निगरानी उपकरणों यानी सीसीटीवी कैमरों (एनालॉग/आईपी/एनालॉग स्पीड डोम/आईपी स्पीड डोम/आईपी स्पीड डोम) को समय-समय पर यथा संशोधित परिशिष्ट 'क' के अनुसार वीएसएस/सीसीटीवी सिस्टम की सुरक्षा सुनिश्चित करने के लिए एमईआईटीवाई द्वारा निर्धारित सुरक्षा के लिए आवश्यक आवश्यकताओं (ईआर) का अनु पालन करना चाहिए। सीसीटीवी/वीएसएस के लिए सुरक्षा परीक्षण प्रतिवेदन मानकीकरण परीक्षण और गुणवत्ता प्रमाणन (एसटीक्यूसी) प्रयोगशाला या एमईआईटीवाई द्वारा समय-समय पर अधिसूचित किसी अन्य एजेंसी द्वारा जारी किया जाएगा। एसटीक्यूसी लैब द्वारा जारी परीक्षण रिपोर्ट की वैधता रिपोर्ट के जारी होने की तारीख से तीन वर्ष होगी. सीसीटीवी कैमरों/वीएसएस प्रणाली की सुरक्षा के लिए इन अनिवार्य आवश्यकताओं (ईआर) को इस अधिसूचना के जारी होने की तारीख से 3 महीने के बाद लागू किया जाएगा। डीवीआर और एनवीआर के लिए सुरक्षा मानदंडों को बाद में अधिसूचित किया जाएगा।

**6.** अधिसूचना इस अधिसूचना के जारी होने की तारीख से 3 महीने के बाद प्रभावी होगी। यह अधिसूचना संशोधित अधिसूचना जारी होने तक वैध रहेगी। इस अधिसूचना के प्रयोजन के लिए 1 वर्ष 31.03.2025 तक होगा।

**7.** सार्वजनिक खरीद (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत किसी भी इलेक्ट्रॉनिक उत्पाद अधिसूचना का पूर्वव्यापी प्रभाव नहीं होगा।

**8.** पूर्वोक्त इलेक्ट्रॉनिक्स उत्पादों की खरीद के लिए समय-समय पर यथा संशोधित दिनांक 16.09.2020 के सार्वजनिक खरीद (मेक इन इंडिया को वरीयता) आदेश 2017 में उद्धृत प्रावधानों के अनुसार खरीद वरीयता प्रदान की जाएगी ।

**9.** यदि भारत सरकार द्वारा परियोजना या योजना पूरी तरह से या आंशिक रूप से वित्त पोषित होती है, तो राज्यों और स्थानीय निकायों द्वारा बनाए गए इलेक्ट्रॉनिक उत्पादों की क्रय के लिए अधिसूचना सभी केंद्रीय योजनाओं (सीएस)/केंद्रीय क्षेत्र की योजनाओं (सीएसएस) पर भी लागू होगी।

**10. स्थानीय सामग्री/घरेलू मूल्यवर्धन की गणना करने हेतु प्रक्रिया**

**10.1** घरेलू विनिर्माताओं (डीओएम-बीओएम) से प्राप्त सामग्री के बिल की गणना उपलब्ध आंकड़ों के आधार पर निम्नलिखित में से किसी एक के आधार पर की जा सकती है।

क. सभी इनपुटों की लागतों का योग जो उस उत्पाद को बनाने के लिए आवश्यक है (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है) और जिनका आयात प्रत्यक्ष रूप से या घरेलू व्यापारी या माध्यस्थ के माध्यम से नहीं किया गया है।

ख. उत्पाद के फैक्ट्री बाह्य मूल्य से उत्पाद के उत्पादन में इनपुटों के रूप में उपयोग की गई सामग्री के आयातित बिल (प्रत्यक्ष या अप्रत्यक्ष रूप से) को घटाकर (इनपुटों की क्रय पर लागए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है) और उसमें से वारंटी लागत को घटाकर।

ग. बाजार मूल्य से उत्पादन पश्चात मालभाडा, बीमा और अन्य हथालन लागतों को घटाकर, उसमें से कर पश्चात लाभ, वारंटी लागत को घटाया जाता है, उसमें से उत्पादों के उत्पादन (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ लिया जा सकता है) में इनपुटों के रूप में उपयोग की गई सामग्री के आयातित बिल के योग को घटाया जाता है और बिक्री और विपणन खर्च को घटाया जाता है।

**10.2** सामग्री के कुल बिल (कुल-बीओएम) की गणना उपलब्ध आंकडों पर आधारित निम्नलिखित में से किसी एक के आधार पर की जा सकती है।

क. सभी इनपुटों की लागतों का योग जो उस उत्पाद को बनाने के लिए आवश्यक है (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है)।

ख. उत्पाद के फैक्टरी बाह्य मूल्य से कर पश्चात लाभ और वारंटी लागतों को घटाया जाता है।

ग. बाजार मूल्य से उत्पादन पश्चात मालभाडा, बीमा और अन्य हथालन लागतों को घटाकर उसमें से कर पश्चात लाभ, वारंटी लागत, बिक्री और विपणन खर्च घटाया जाता है।

**10 .3** निम्नलिखित फॉर्मूला के अनुसार प्रस्तुत जानकारी के आधार पर घरेलू मूल्य-वृद्धि के प्रतिशत की गणना की जा सकती है:

$$\text{स्थानीय सामग्री/घरेलू मूल्य-वृद्धि का प्रतिशत} = \frac{\text{डीओएम-बीओएम}}{\text{कुल-बीओएम}} \times 100$$

**11. स्थानीय सामग्री/घरेलू मूल्यवृद्धि का सत्यापन**

**11.1.** निविदा, बोली प्रक्रिया या सिफ़ारिश के समय स्थानीय आपूर्तिकर्ता स्व-प्रमाणन प्रदान करेगा कि प्रसतावित की गई वस्तुएं न्यूनतम स्थानीय सामग्री की आवश्यकताओं को पूरा करती हैं और उस स्थान (स्थानों) का विवरण देगा, जिस पर स्थानीय मूल्य वृद्धि की गई है।

**11.2.** 10 करोड़ रुपए से अधिक मूल्य की क्रय के मामलों में, स्थानीय आपूर्तिकर्ता स्थानीय सामग्री का प्रतिशत देते हुए कंपनी के सांविधिक लेखा परीक्षक )कंपनियों के मामले में) या लागत लेखापरीक्षक या किसी पेशेवर लागत लेखाकार ये पेशेवर चार्टेड लेखाकार (कंपनियों के अलावा अन्य आपूर्तिकर्ताओं के संबंध में) से एक प्रमाणपत्र उपलब्ध कराएगा।

**11.3.** यदि किसी इलेक्ट्रॉनिक उत्पाद के संबंध में स्थानीय सामग्री/घरेलू मूल्य वृद्धि के संबंध में बोलीकर्ता के दावे के खिलाफ क्रय एजेंसी या संबंधित मंत्रालय/विभाग द्वारा शिकायत प्राप्त की जाती है, तो उसे एसटीक्यूसी के पास भेजा जाएगा।

**11.4.** एसटीक्यूसी को संदर्भित कोई भी शिकायत 4 सप्ताह के भीतर निपटा दी जाएगी। बोलीकर्ता को एसटीक्यूसी हेतु किसी इलेक्ट्रॉनिक उत्पाद में दावा की गई घरेलू मूल्य वृद्धि के समर्थन में आवश्यक दस्तावेज प्रस्तुत करने की आवश्यकता होगी। यदि बोलीकर्ता के द्वारा कोई जानकारी प्रस्तुत नहीं की जाती है, तो ऐसी प्रयोगशालाएं दावे के वास्तविकता को सिद्ध करने के लिए अगली आवश्यक कार्रवाई कर सकती हैं। **स्थानीय सामग्री की गणना में विसंगतियों के मामले में, स्थानीय सामग्री के प्रतिशत की गणना के लिए कंपनी के सांविधिक लेखा परीक्षक या लागत लेखा परीक्षक (कंपनियों के मामले में) या प्रैक्टिसिंग कॉस्ट एकाउंटेंट या प्रैक्टिसिंग चार्टर्ड एकाउंटेंट (कंपनियों के अलावा अन्य आपूर्तिकर्ताओं के संबंध में) से एक प्रमाण पत्र स्व-घोषणा प्रमाण पत्र पर अधिक्रमित होगा।**

**11.5.** 2 लाख रुपए या खरीदे जा रहे घरेलू रूप से विनिर्मात इलेक्ट्रॉनिक उत्पादों की कीमत का 1% शिकायत शुल्क (5 लाख रुपए की अधिकतदम सीमा के अध्यधीन), जो भी अधिक हो, का डिमांड ड्राफ्ट द्वारा भुगतान किया जाएगा, जो एसयीक्यूसी में जमा जमा होगा। यदि शिकायत गलत पाई जाती है, तो शिकायत शुल्क जब्त कर लिया जाएगा। यदि, शिकायत को बरकरार रखा जाता है और काफी हद तक सही पाया जाता है तो शिकायतकर्ता को जमा शुल्क बिना किसी ब्याज के वापस कर दिया जाएगा।

**11.6.** सामान्य वित्तीय नियम (जीएफआर) के नियम 175(1)(i)(एच) के तहत झूठी घोषणाएं सत्यनिष्ठा संहिता का उल्लंघन होंगी, जिसके लिए बोली लगाने वाले या उसके उत्तराधिकारियों को नियम 151 (iii) के अनुसार प्रतिबंधित किया जा सकता है। सामान्य वित्तीय नियमों के साथ-साथ बोली लगाने के ऐसे अन्य प्रावधान, एकल मंत्रालय/विभाग द्वारा रोक लगाना और व्यय विभाग के कार्यालय ज्ञापन संख्या एफ.1/20/2018-पीपीडी दिनांक 2 नवंबर, 2021 के अनुसार आदेशों को रद्द करना समय-समय पर संशोधित कानून के तहत अनुमन्य हो सकता है।

**12.** इलेक्ट्रॉनिक्स उत्पाद अधिसूचनाओं के कार्यान्वयन की निगरानी के लिए एमईआईटीवाई नोडल मंत्रालय होगा। एसटीक्यूसी द्वारा दिए गए निर्णय के विरुद्ध किसी विवाद/स्पष्टीकरण के मामले में, शिकायतों के सत्यापन/पुनरीक्षण, यादृच्छिक आधार पर स्व-घोषणाओं और लेखा परीक्षक/लेखाकार के प्रमाणपत्रों के स्वतंत्र सत्यापन, इलेक्ट्रॉनिकी उत्पादों के घरेलू विनिर्माताओं के विरुद्ध प्रतिबंधात्मक और भेदभावपूर्ण निबंधन और शर्तों के लिए निम्नलिखित घटकों वाली एक समिति गठित की जाती है: -

| | | |
|---|---|---|
| i) | समूह समन्वयक/वैज्ञानिक- 'जी' (आईपीएचडब्ल्यू) | - अध्यक्ष |
| ii ) | एसटीक्यूसी से वैज्ञानिक-'जी'/वैज्ञानिक-'एफ' | - सदस्य |
| iii) | वैज्ञानिक- 'ई'/सर्ट-इन/साइबर डिवीजन अथवा वरिष्ठ. | - सदस्य |
| vi) | अध्यक्ष द्वारा सहयोजित कोई अन्य सदस्य (सदस्यों) | -सदस्य |
| v) | आईपीएचडब्ल्यू प्रभाग से वैज्ञानिक-'ई'/प्रतिनिधि | -सदस्य सचिव |

**13.** यदि प्रश्न उठता है कि क्या खरीदी जा रही कोई वस्तु एक इलेक्ट्रॉनिक उत्पाद है, जिसे सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत शामिल किया जाना है, तो इस मामले को स्पष्टीकरण के लिए इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय को संदर्भित किया जाएगा।

[फ़ा. सं. डब्ल्यू-43/11/2021-आईपीएचडब्ल्यू]

आशा नांगिया, समूह समन्वयक और वैज्ञानिक 'जी'

**परिशिष्ट 'क'**

## सीसीटीवी की सुरक्षा के लिए अनिवार्य आवश्यकता

संवेदनशील जानकारी की सुरक्षा और सिस्टम को प्रभावी ढंग से संचालित करने के लिए सीसीटीवी (क्लोज-सर्किट टेलीविजन) प्रणाली को सुरक्षित करना महत्वपूर्ण है। परीक्षण के प्रमुख क्षेत्रों में एक्स्पोस्ड नेटवर्क सेवाएं, डिवाइस संचार प्रोटोकॉल, डिवाइस के यूएआरटी,जेटीएजी,एसडब्ल्युडी आदि तक भौतिक पहुंच, मेमोरी और फर्मवेयर निकालने की क्षमता, फर्मवेयर अपडेट प्रक्रिया सुरक्षा और डेटा का भंडारण और एन्क्रिप्शन शामिल हैं। सीसीटीवी सिस्टम की सुरक्षा के लिए यहां संक्षिप्त आवश्यकताएं दी गई हैं:

| | | | | |
|---|---|---|---|---|
| | | और विकास प्रक्रियाओं के हिस्से के रूप में एक या अधिक अद्यतन मैलवेयर पहचान उपकरण नियोजित किए जाएंगे।<br>अंतिम पैकेजिंग और प्रदायगी से पहले मैलवेयर पहचान तकनीकों का उपयोग किया जाएगा (उदाहरण के लिए, एक या अधिक अद्यतन मैलवेयर पहचान उपकरणों का उपयोग करके मैलवेयर के लिए तैयार उत्पादों और घटकों को स्कैन करना)। | पहचान टैनिंग/जालसाजी, सीएम टूल के ट्रैकिंग लक्ष्यों की आवश्यकता के रूप में की गई है।<br>गुणवत्ता आश्वासन प्रक्रिया को प्रस्तुत करने और उसे प्रदर्शित करने की आवश्यकता है। | |
| | | 4.4 आपूर्ति श्रृंखला जोखिम की पहचान, मूल्यांकन, प्राथमिकता और शमन आयोजित किया जाएगा। | | आपूर्ति श्रृंखला जोखिम / व्यापार निरंतरता योजना नीति दस्तावेज, प्लेबुक जो दर्शाती है कि आपूर्ति श्रृंखला व्यवधान को कैसे संभालना है, घटना के बाद सारांश दस्तावेजों को प्रस्तुत करने और उसी को प्रदर्शित करने की आवश्यकता है। |

**MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY**

**(IPHW DIVISION)**

**NOTIFICATION**

New Delhi, the: 6th March, 2024

**Subject: Public Procurement (Preference to Make in India) Order 2017-Notifying CCTV/ Video Surveillance System for Security in furtherance of the Order**

**Reference:**

**(i) Department for Promotion of Industry and Internal Trade (DPIIT) Order No. P-45021/2/2017-B.E.-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019, 04.06.2020 and 16.09.2020**

**(ii) Ministry of Electronics and Information Technology (MeitY) Electronic Products Notification No. W-43/4/2019-IPHW-MeitY dated 07.09.2020**

**S.O. 1119(E).**—The Government has issued Public Procurement (Preference to Make in India) Order 2017 vide the Department for Promotion of Industry and Internal Trade (DPIIT) Order No.P-45021/2/2017-B.E.-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019, 04.06.2020 and 16.09.2020, to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment.

2. In furtherance of the Public Procurement (Preference to Make in India) Order 2017 [PPP-MII Order 2017] notified vide reference cited above, the Ministry of Electronics and Information Technology (MeitY) hereby notifies

that preference shall be provided by all procuring entities to locally manufactured Video Surveillance System for Security as per the aforesaid Order, as amended from time to time.

3. For the purpose of this notification:

3.1 The definition of Class-I local supplier, Class-II local supplier and Non-local supplier shall be as per paragraph 2 of the DPIIT PPP-MII Order 2017 No. P-45021/2/2017-PP(BE-II) dated 16.09.2020, as amended from time to time. The mechanism for calculation of local content is prescribed for each notified Electronic Product in this notification.

3.2 Paragraph 3A of the DPIIT PPP-MII Order 2017 No. P-45021/2/2017-PP(BE-II) dated 16.09.2020, as amended from time to time, shall be referred for percentage of procurement for which preference to domestically manufactured Electronic Products is to be provided (in value terms).

4. Following electronic products of Video Surveillance System are notified under the Public Procurement (Preference to Make in India) Order 2017:

**4.1 Video Surveillance System**

**Definition:**

For the purpose of this Notification, Video Surveillance System is usually a system that *inter-alia* includes: (i) Closed Circuit Television (CCTV) Camera (Analog/ IP/ Analog Speed Dome/ IP Speed Dome), (ii) Digital Video Recorder (DVR) / Network Video Recorder (NVR). Some of the applications of Security and Video Surveillance System are surveillance of Cities, Schools, Banks, Government Offices, public places, traffic monitoring and home security, etc.

**4.2 Mechanism for calculation of local content of CCTV Camera (Analog):**

The domestic BOM of CCTV Camera (Analog) would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

<table>
<tr><th>Sr. No.</th><th>Main inputs in BOM / stages for manufacture of CCTV Camera (Analog)</th><th>Value addition / local content required for the input to be classified as domestic BOM</th></tr>
<tr><td></td><td>(1)</td><td>(2)</td></tr>
<tr><td>1.0</td><td>Main PCB*</td><td rowspan="4">Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main PCB with/without optional boards shall not exceed 10 % of the total BOM of the CCTV Camera (Analog)</td></tr>
<tr><td>(i)</td><td>I/O Board (optional)</td></tr>
<tr><td>(ii)</td><td>Infrared (IR) Board (optional)</td></tr>
<tr><td>(iii)</td><td>Control Board (optional)</td></tr>
<tr><td>2.0</td><td>Bare PCB</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total BOM of the CCTV Camera (Analog)</td></tr>
<tr><td>3.0</td><td>Optics</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Optics shall not exceed 10 % of the total BOM of the CCTV Camera (Analog)</td></tr>
<tr><td>4.0</td><td>In-house R&D #</td><td>Domestically/In-house R&D includes scientific research, experimentation, prototyping and testing for development of new products, process, technologies, or solutions using its own resources/expertise or legal contract with R&D unit registered with Department of Scientific and Industrial Research (DSIR) in India. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>5.0</td><td>In-house Design/IPR #</td><td>Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property</td></tr>
</table>

| | | |
|---|---|---|
| | | Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.: |

| 2023-24 & 2024-25 | 2025-26 | 2026-27 onwards |
|---|---|---|
| 7% | 10% | 12% |

| | | |
|---|---|---|
| 6.0 | Housing (Plastic /Aluminium/MS) and Camera Mount | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed to 15 % of the total BOM of the CCTV Camera (Analog). |
| 7.0 | Connecting Cables & Connectors | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables and Connectors shall not exceed 5% of the total BOM of the CCTV Camera (Analog). |
| 8.0 | Final Assembly and Testing | Domestically assembled / tested meeting Indian Standards as notified from time to time. The weightage of the total value of final assembling and testing shall not exceed 10% of the total BOM of the CCTV Camera. |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

*# The applicant will be eligible to avail the benefit of Sr. No. 4.0 (In-house R&D) & Sr. No. 5.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.*

| Financial Year | 2023-24 & 2024-25 | 2025-26 | 2026-27 onwards |
|---|---|---|---|
| Minimum Value Addition/Local Content of (Sr. No. 1) Main PCB and (Sr. No.8) Final Assembly and Testing as -Essential and others as optional | 25% | 35% | 45% |

**4.3 Mechanism for calculation of local content of CCTV Camera (IP):**

The domestic BOM of CCTV Camera (IP) would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| Sr. No. | Main inputs in BOM / stages for manufacture of CCTV Camera (IP) | Value addition / local content required for the input to be classified as domestic BOM |
|---|---|---|
| | 1 | 2 |
| 1.0 | Main PCB* with Capture and/or Processor Card | Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main PCB with/without optional boards shall not exceed 10 % of the total BOM of the CCTV Camera (IP) |
| (i) | Network Interface Card (optional) | |
| (ii) | Infrared (IR) Board (optional) | |
| (iii) | I/O Board (optional) | |
| (iv) | Power over Ethernet (PoE) Card (optional) | |
| 2.0 | Bare PCB | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total BOM of the CCTV Camera (IP) |
| 3.0 | Optics | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Optics shall not exceed 10 % of the total BOM of the CCTV Camera (IP) |
| 4.0 | In-house R&D # | Domestically/In-house R&D includes scientific research, experimentation, |

| | | |
|---|---|---|
| | | prototyping and testing for development of new products, process, technologies, or solutions using its own resources/expertise or legal contract with R&D unit registered with *Department of Scientific and Industrial Research (DSIR)* in India. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.: |

| 2023-24 & 2024-25 | 2025-26 | 2026-27 onwards |
|---|---|---|
| 7% | 10% | 12% |

| | | |
|---|---|---|
| 5.0 | In-house Design/IPR # | Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.: |

| 2023-24 & 2024-25 | 2025-26 | 2026-27 onwards |
|---|---|---|
| 7% | 10% | 12% |

| | | |
|---|---|---|
| 6.0 | Housing (Plastic / Aluminium / MS) and | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed 15 % of the total BOM of the CCTV Camera (IP). |
| 7.0 | Connecting Cables and Connectors | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables and Connectors shall not exceed 5% of the total BOM of the CCTV Camera (IP). |
| 8.0 | Final Assembly and Testing | Domestically assembled / tested meeting Indian Standards as notified from time to time. The weightage of the total value of Final Assembling and Testing shall not exceed 10% of the total BOM of the CCTV Camera (IP) |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

*# The applicant will be eligible to avail the benefit of Sr. No. 4.0 (In-house R&D) & Sr. No. 5.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.*

| Financial Year | 2023-24 & 2024-25 | 2025-26 | 2026-27 onwards |
|---|---|---|---|
| Minimum Value Addition/Local Content of (Sr. No. 1.0) Main PCB and (Sr. No. 8.0) Final Assembly and Testing as -Essential and others as optional | 25% | 35% | 45% |

**4.4 Mechanism for calculation of local content of CCTV Camera (Analog Speed Dome):**

The domestic BOM of CCTV Camera (Analog Speed Dome) would be the sum of the costs of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

| Sr. No. | Main inputs in BOM / stages for manufacture of CCTV Camera (Analog Speed Dome) | Value addition required for the input to be classified as domestic BOM |
|---|---|---|
| | 1 | 2 |
| 1 | Main Controller Board* | Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main Controller Board/Main PCB with/without optional boards shall not exceed 10 % of the total BoM of the CCTV Camera (ASD) |
| (i) | I/O Board (optional) | |
| (ii) | Infrared (IR) Board (optional) | |
| 2.0 | Bare PCB | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total |

<table>
<tr><td></td><td></td><td>BoM of the CCTV Camera (ASD)</td></tr>
<tr><td>3.0</td><td>Inhouse R&D#</td><td>Domestically/In-house R&D includes scientific research, experimentation, prototyping and testing for development of new products, process, technologies, or solutions using its own resources/expertise or legal contract with R&D unit registered with Department of Scientific and Industrial Research (DSIR) in India. The weightage of this will be calculated based on the percentage of the domestic BoM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>4.0</td><td>In-house Design/IPR#</td><td>Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BoM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>5.0</td><td>Housing (Plastic/ Aluminium/ MS) and Camera Mount</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed 5 % of the total BoM of the CCTV Camera (ASD).</td></tr>
<tr><td>6.0</td><td>Connecting Cables and Connectors</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables and Connectors shall not exceed 5% of the total BoM of the CCTV Camera (ASD).</td></tr>
<tr><td>7.0</td><td>Motor, Heater & Blower, Zoom Module, Belt, Plastic Mechanism Parts, Glass etc.</td><td>Domestically manufactured from imported / domestically manufactured input parts and mechanical components. However, the weightage of the total value of all these parts/components shall not exceed 5% of the total BoM of the CCTV Camera (ASD)</td></tr>
<tr><td>8.0</td><td>Power Adapter</td><td>Domestic PCB assembly* and the final assembly and testing from imported / domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of “Power Adapter” will be minimum 40% (of the total value of parts and components used in the manufacture of “Power Adapter”). However, the weightage of the total value of “Power Adapter” shall not exceed 5% of the total BoM of the CCTV Camera (ASD)</td></tr>
<tr><td>9.0</td><td>Final Assembly and Testing</td><td>Domestically assembled / tested meeting Indian Standards as notified from time to time. The weightage of the total value of final assembling and testing shall not exceed 10 % of the total BoM of the CCTV Camera (ASD)</td></tr>
</table>

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

*# The applicant will be eligible to avail the benefit of Sr. No. 3.0 (In-house R&D) & Sr. No. 4.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.*

| **Financial Year** | **2023-24 & 2024-25** | **2025-26** | **2026-27 onwards** |
|---|---|---|---|
| Minimum Value Addition/Local Content of (Sr. No. 1.0) Main PCB and (Sr. No. 9.0) Final Assembly and Testing as -Essential and others as optional | 25% | 35% | 45% |

**4.5 Mechanism for calculation of local content of CCTV Camera (IP Speed Dome):**

The domestic BOM of CCTV Camera (IP Speed Dome) would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

<table>
<tr><th>Sr. No.</th><th>Main inputs in BOM / stages for manufacture of CCTV Camera (IP Speed Dome)</th><th>Value addition / local content required for the input to be classified as domestic BOM</th></tr>
<tr><td></td><td>1</td><td>2</td></tr>
<tr><td>1.0</td><td>Main Controller Board*</td><td rowspan="6">Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main Controller Borad with/without optional boards Shall not exceed 10 % of the total BoM of the CCTV Camera (IPSD)</td></tr>
<tr><td>(i)</td><td>I/O Board (optional)</td></tr>
<tr><td>(ii)</td><td>Infrared (IR) Board (optional)</td></tr>
<tr><td>(iii)</td><td>Processor Card (optional)</td></tr>
<tr><td>(iv)</td><td>Network Interface Card (Optional)</td></tr>
<tr><td>(v)</td><td>Power over Ethernet (PoE) Card (optional)</td></tr>
<tr><td>2.0</td><td>Bare PCB</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total BoM of the CCTV Camera (IPSD)</td></tr>
<tr><td>3.0</td><td>In-house R&D #</td><td>Domestically/In-house R&D includes scientific research, experimentation, prototyping and testing for development of new products, process, technologies, or solutions using its own resources /expertise or legal contract with R&D unit registered with Department of Scientific and Industrial Research (DSIR) in India. The weightage of this will be calculated based on the percentage of the domestic BoM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>4.0</td><td>In-house Design/IPR #</td><td>Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BoM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>5.0</td><td>Housing (Plastic / Aluminium / MS) and Camera Mount</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed 5 % of the total BoM of the CCTV Camera (IPSD).</td></tr>
<tr><td>6.0</td><td>Connecting Cables and Connectors</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables and Connectors shall not exceed 5% of the total BoM of the CCTV Camera (IPSD).</td></tr>
<tr><td>7.0</td><td>Motor, Heater & Blower, Zoom Module, Belt, Plastic Mechanism Parts, Glass etc.</td><td>Domestically manufactured from imported / domestically manufactured input parts and mechanical components. However, the weightage of the total value of all these parts/components shall not exceed 5% of the total BoM of the CCTV Camera (IPSD).</td></tr>
<tr><td>8.0</td><td>Power Adapter</td><td>Domestic PCB assembly* and the final assembly and testing from imported / domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the</td></tr>
</table>

| | | |
|---|---|---|
| | | assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter"). However, the weightage of the total value of "Power Adapter" shall not exceed 5% of the total BoM of the CCTV Camera (IPSD) |
| 9.0 | Final Assembly and Testing | Domestically assembled / tested meeting Indian Standards as notified from time to time. The weightage of the total value of final assembling and testing shall not exceed 10 % of the total BoM of the CCTV Camera (IPSD) |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

*# The applicant will be eligible to avail the benefit of Sr. No. 3.0 (In-house R&D) & Sr. No. 4.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.*

| Financial Year | 2023-24 & 2024-25 | 2025-26 | 2026-27 onwards |
|---|---|---|---|
| Minimum Value Addition/Local Content of (Sr. No. 1.0) Main PCB and (Sr. No. 9.0) Final Assembly and Testing as -Essential and others as optional | 25% | 35% | 45% |

**4.6 Mechanism for calculation of local content of DVR/ NVR:**

The domestic BOM of DVR/ NVR would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

<table>
<tr><th>Sr No.</th><th>Main inputs in BOM / stages for manufacture of DVR / NVR</th><th>Value addition / local content required for the input to be classified as domestic BOM</th></tr>
<tr><td></td><td>1</td><td>2</td></tr>
<tr><td>1.0</td><td>Main PCB*</td><td rowspan="3">Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main PCB with/without optional boards shall not exceed 10 % of the total BoM of the DVR/NVR.</td></tr>
<tr><td>(i)</td><td>Front Panel & LED Board (optional)</td></tr>
<tr><td>(ii)</td><td>I/O Board (optional)</td></tr>
<tr><td>2.0</td><td>Bare PCB</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total BoM of the CCTV Camera (DVR/NVR)</td></tr>
<tr><td>3.0</td><td>In-house R&D #</td><td>Domestically/In-house R&D includes scientific research, experimentation, prototyping and testing for development of new products, process, technologies, or solutions using its own resources/expertise or legal contract with R&D unit registered with Department of Scientific and Industrial Research (DSIR) in India. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>4.0</td><td>In-house Design/IPR #</td><td>Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:</td></tr>
</table>

| | | 2023-24 & 2024-25 | 2025-26 | 2026-27 onwards |
|---|---|---|---|---|
| | | 7% | 10% | 12% |
| 5.0 | Housing (Plastic / Aluminium / MS) and Camera Mount | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed 5 % of the total BoM of the DVR/NVR. | | |
| 6.0 | Connecting Cables, Connectors and USB Mouse | Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables, Connectors and USB Mouse shall not exceed 5% of the total BoM of the DVR/NVR. | | |
| 7.0 | Remote Control | Domestic assembly* and testing from imported / domestically manufactured parts and components subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Remote Control" will be minimum 20% (of the total value of the parts and components used in the manufacture of "Remote Control") in Year 2, which will increase to minimum 30%, 40% and 50% in Financial Years 2025-26, 2026-27 and 2027-28 onwards respectively. | | |
| 8.0 | Power Adapter | Domestic PCB assembly* and the final assembly and testing from imported / domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter"). However, the weightage of the total value of "Power Adapter" shall not exceed 5% of the total BoM of the DVR/NVR. | | |
| 9.0 | Final Assembly and Testing | Domestically assembled/tested meeting Indian Standards as notified from time to time. The weightage of the total value of final assembling and testing shall not exceed 10 % of the total BOM of the DVR/NVR. | | |

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

*# The applicant will be eligible to avail the benefit of Sr. No. 4.0 (In-house R&D) & Sr. No. 5.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.*

| Financial Year | 2023-24 & 2024-25 | 2025-26 | 2026-27 onwards |
|---|---|---|---|
| Minimum Value Addition/Local Content of (Sr. No. 1.0) Main PCB and (Sr. No. 9.0) Final Assembly and Testing as -Essential and others as optional | 25% | 35% | 45% |

**5.** The surveillance devices i.e., CCTV Cameras (Analog/ IP/ Analog Speed Dome/ IP Speed Dome) should comply with the Essential Requirements (ERs) for security prescribed by MeitY to ensure the security of the VSS / CCTV systems, as per the Appendix 'A', as amended from time to time. The security testing report for CCTV/VSS to be issued by Standardisation Testing and Quality Certification (STQC) Laboratory or any other agency notified by MeitY from time to time. The validity of the test report issued by STQC Lab will be three years from the date of issue of the report. These Essential Requirements (ERs) for security of CCTV Cameras/VSS system will be enforced after 3 months from the date of issuance of this Notification. The security norms for the DVR and NVR will be notified subsequently.

**6.** The notification will come into effect after 3 months from the date of issuance of this Notification. This Notification shall remain valid till the revised Notification is issued. The Year 1 for the purpose of this notification would be upto 31.03.2025.

**7.** No Electronic Product Notification under the Public Procurement (Preference to Make in India) Order 2017 shall have retrospective effect.

**8.** Purchase Preference shall be provided as per the provisions cited in the Public Procurement (Preference to Make in India) Order 2017 dated 16.09.2020 and, as amended from time to time, for the procurement of aforesaid electronics products.

**9.** The notification would also be applicable to all Central Schemes (CS)/ Central Sector Schemes (CSS) for the procurement of electronic products made by States and local bodies, if project or scheme is fully or partially funded by Government of India.

**10. Procedure for calculating local content/ domestic value addition**

10.1 Bill of Material sourced from domestic manufacturers (Dom-BOM) may be calculated based on one of the followings depending on data available:

a) Sum of the costs of all inputs which go into the product (including duties and taxes levied on procurement of inputs except those for which credit/ set-off can be taken) and which have not been imported directly or through a domestic trader or an intermediary.

b) Ex-Factory Price of product minus profit after tax minus sum of imported Bill of Material used (directly or indirectly) as inputs in producing the product (including duties and taxes levied on procurement of inputs except those for which credit/ set-off can be taken) minus warranty costs.

c) Market price minus post-production freight, insurance and other handling costs minus profit after tax minus warranty costs minus sum of Imported Bill of Material used as inputs in producing the product (including duties and taxes levied on procurement of inputs except those for which credit / set-off can be taken) minus sales and marketing expenses.

10.2 Total Bill of Material (Total BOM) may be calculated based on one of the following depending on data available:

a) Sum of the costs of all inputs which go into the product (including duties and taxes levied on procurement of inputs except those for which credit / set-off can be taken).

b) Ex-Factory Price of product minus profit after tax, minus warranty costs.

c) Market price minus post-production freight, insurance and other handling costs minus profit after tax, minus warranty costs minus sales and marketing expenses.

10.3 The percentage of domestic value-addition may be calculated based on information furnished as per the following formula:

Percentage of local content/ domestic value-addition = [(Dom-BOM) / (Total BOM)]*100

**11. Verification of local content/ Domestic Value Addition**

**11.1.** The local supplier at the time of tender, bidding or solicitation shall provide self-certification that the item offered meets the minimum local content and shall give details of the location(s) at which the local value addition is made.

**11.2.** In cases of procurement for a value in excess of Rs.10 crore, the local supplier shall provide a certificate from the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) giving the percentage of local content.

**11.3.** In case a complaint is received by the procuring agency or the concerned Ministry/Department against the claim of a bidder regarding local content/ domestic value addition in an Electronic Product(s), the same shall be referred to STQC.

**11.4.** Any complaint referred to STQC shall be disposed of within 4 weeks. The bidder shall be required to furnish the necessary documentation in support of the domestic value addition claimed in an Electronic Product(s) to STQC. If no information is furnished by the bidder, such laboratories may take further necessary action, to establish the bonafides of the claim. In case of the discrepancies in computation of local content, a certificate from the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) for calculating the percentage of local content will supersede over the self-declaration certificate.

**11.5.** A complaint fee of Rs.2 Lakh or 1% of the value of the domestically manufactured Electronic Products being procured (subject to a maximum of Rs. 5 Lakh), whichever is higher, to be paid by Demand Draft to be deposited with STQC. In case, the complaint is found to be incorrect, the complaint fee shall be forfeited. In case, the complaint is upheld and found to be substantially correct, deposited fee of the complainant would be refunded without any interest.

**11.6.** False declarations will be in breach of the Code of Integrity under Rule 175(1)(i)(h) of the General Financial Rules (GFR) for which a bidder or its successors can be debarred as per Rule 151 (iii) of the General Financial Rules along with such other provisions of bidding, debarment by a single Ministry/Department and revocation of orders as per the Department of Expenditure O.M-No. F.1/20/2018-PPD dated 2nd Nov, 2021 may be permissible under law amended from time to time.

**12.** MeitY shall be the Nodal Ministry to monitor the implementation of the Electronic Products notifications. In case of any dispute/clarifications against the decision given by STQC, a committee is constituted with the following

compositions for verification/vetting the complaints, independent verification of self-declarations and auditor's/accountant's certificates on random basis, restrictive and discriminating terms and conditions against the domestic manufactures of Electronics Products(s): -

| | | | |
|---|---|---|---|
| i) | Group Coordinator/Scientist- 'G' (IPHW) | - | Chairperson |
| ii) | Scientist-'G'/Scientist-'F' from STQC | - | Member |
| iii) | Scientist- 'E' or above from Cert-In/Cyber Division | - | Member |
| vi) | Any other member(s) as co-opted by the Chairperson | - | Member |
| v) | Representative from IPHW Division | - | Member Secretary |

**13.** In case of a question whether an item being procured is an Electronic Product(s) to be covered under the Public Procurement (Preference to Make in India) Order 2017, the matter would be referred to the Ministry of Electronics and Information Technology for clarification.

[F. No. W-43/11/2021-IPHW]

ASHA NANGIA, Group Coordinator & Scientist 'G'

**Appendix 'A'**

**Essential Requirement(s) for Security of CCTV**

Securing a CCTV (Closed-Circuit Television) system is crucial to protect sensitive information and ensure the system operates effectively. Key areas of testing include exposed network services, device communication protocols, physical access to the device's UART, JTAG, SWD, etc., the ability to extract memory and firmware, firmware update process security and storage and encryption of data. Here are brief requirements for the security of a CCTV system:

1) Physical Security - Use tamper-resistant camera enclosures and locking mechanisms to deter physical tampering.
2) Access Control by Authentication, Role-Based Access Control (RBAC) and regularly review and update access permissions to reflect personnel changes.
3) Network Security by employing encryption of data transmission
4) Software Security by Regular Updates, Disable Unused Features and Strong Password Policies
5) Penetration Testing: Employ penetration testing to assess the system's resistance to cyberattacks and address vulnerabilities.

**Essential Security Requirements**

| Sr. No. | Category | Testing Parameter | What to be tested | Documents Required |
|---|---|---|---|---|
| 1) | Hardware Level Security Parameter (supported by software) | 1.1 Verify that application layer debugging interfaces such USB, UART, and other serial variants are disabled or protected by a complex password. | 1. Identification of the availability of debugging interfaces such as USB, UART, and other serial variants<br>through the Datasheet of the SoC being used in the device under test<br>2. Verification and validation of the ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same as declared in the vendor documentation<br>3. Testing, in presence of | 1. Datasheet of the SoC being used in the device.<br>2. Documentation related to ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same.<br>3. Process flow of the Manufacturing/Provisioning of the device |

| | | | | |
|---|---|---|---|---|
| | | | OEM team, to verify the enabling/disabling of all the ports and debugging interfaces such as USB, UART, and other serial variants using their relevant hardware based debuggers and access control mechanisms in case the interface is enabled.<br><br>4. Process audit of the manufacturing facility to validate the vendor's claim regarding the debugging interfaces which are closed/disabled during provisioning.<br><br>[For instance, through Block connection diagram depicting pin connections between the host microcontroller and its interactions with various sub components/peripherals.] | |
| | | 1.2 Verify that cryptographic keys and certificates are unique to each individual device. | Identifying all the keys and certificates being used in the device eco-system and verification through:<br>• Testing, in presence of OEM team<br>• Code review<br>• Process audit of the key-life cycle process | 1. List of all keys and certificates being used in the device ecosystem<br><br>2. Key management life cycle (purpose, generation, storage, destruction/zeroization, validity, key changeover/rotation) |
| | | 1.3 Verify that on-chip debugging interfaces such as JTAG or SWD are disabled or that available protection mechanism is enabled and configured appropriately. | 1. Identification of the availability of debugging interfaces such as USB, UART, and other serial variants<br><br>through the Datasheet of the SoC being used in the device under test<br><br>2. Verification and validation of the ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same as declared in the vendor documentation<br><br>3. Testing, in presence of OEM team, to verify the enabling/disabling of all the | 1. Datasheet of the SoC being used in the device.<br><br>2. Documentation related to ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same.<br><br>3. Process flow of the Manufacturing/Provisioning of the device |

| | | | | |
|---|---|---|---|---|
| | | | ports and debugging interfaces such as USB, UART, and other serial variants using their relevant hardware based debuggers and access control mechanisms in case the interface is enabled.<br><br>4. Process audit of the manufacturing facility to validate the vendor's claim regarding the debugging interfaces which are closed/disabled during provisioning.<br><br>[For instance, through Block connection diagram depicting pin connections between the host microcontroller and its interactions with various sub components/peripherals.] | |
| | | 1.4 Verify that trusted execution is implemented and enabled, if available on the device SoC or CPU. | Identifying whether TEE/SE/TPM is available or not in the device through the SoC datasheet and technical documentation submitted by the vendor.<br><br>Further assessment is done on the basis of scenarios as applicable to device as defined below:<br><br>**CASE 1: TEE/SE/TPM is not available:**<br><br>No further assessment<br><br>**CASE 2: TEE/SE/TPM is available and enabled:**<br><br>Verification through code-review that crypto functions are called through TEE/SE/TPM APIs.<br><br>**CASE 3: TEE/SE/TPM is available but not enabled by the vendor:**<br><br>Termed as non-conformance to the requirement. OEM is required to enable and implement the TEE/SE/TPM. | 1. Datasheet of the SoC being used in the device.<br><br>2. User manual/ Technical specifications of the device<br><br>3. Code snippets of the TEE API call, wherever applicable |
| | | 1.5 Verify that sensitive data, private keys and certificates are stored securely in a Secure Element, TPM, | Identifying all the keys and certificates being used in the device eco-system, sensitive data and their storage mechanism(s); and verification through: | 1. List of all keys and certificates being used in the device ecosystem<br><br>2. List of all the sensitive data with their intended usage and secure storage |

| | | | | |
|---|---|---|---|---|
| | | TEE (Trusted Execution Environment), or protected using strong cryptography. | • Testing, in presence of OEM team<br>• Code review<br>• Process audit of the key-life cycle process | mechanism(s) as implemented along with secure configurations to be enabled in the device.<br>3. Key management life cycle (purpose, generation, storage, destruction/zeroization, validity, key changeover/rotation) private keys and certificates. |
| | | 1.6Verify the presence of tamper resistance and/or tamper detection features. | Testing, in presence of OEM team, to verify the measures implemented in the device to prevent software and hardware tampering. | 1. Measures available in the device to prevent software tampering.<br>2. Measures available in the device to prevent hardware tampering. |
| | | 1.7 Verify that any available Intellectual Property protection technologies provided by the chip manufacturer are enabled. | Testing, in presence of OEM team, to verify the enabling of the Intellectual Property protection technologies provided by the chip manufacturer, if available. | 1. Datasheet of the SoC<br>2. Documentation regarding the Intellectual Property protection technologies provided by the chip manufacturer which have been enabled.<br>3. In case, no Intellectual Property protection technologies are being provided by the chip manufacturer, then a declaration stating the same. |
| | | 1.8 Verify the device validates the boot image signature before loading. | Testing, in presence of OEM team, to verify the following:<br>1. Device boots up successfully with the documented secure boot process when a valid boot image is provided.<br>2. Device does not boot up when a tampered boot image (like with missing signature, invalid signature) is provided. | 1. Datasheet of the SoC<br>2.Technical specifications of the device regarding secure boot (should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented.) |
| | | 1.9 Verify usage of cryptographically secure pseudo-random number generator on embedded device (e.g., using chip-provided random number | Verification of the documentation provided by the vendor regarding the random number generators being used in the device.<br>Verification through code-review that random number generators or related | Documentation regarding the random generators (either hardware based or software based or both) being used in the device with their intended usage.<br>In case, hardware based random number generators are being used, vendors |

| | | | | |
|---|---|---|---|---|
| | | generators). | libraries as applicable are being used in the device. | shall submit the following:<br>1. Datasheet of the SoC<br>2. Technical specifications of the device regarding random generators<br>In case, software based random number generators are being used, vendors shall provide the libraries being used for the same. |
| 2) | Software/Firmware | 2.1 Verify that memory protection controls such as ASLR and DEP are enabled by the embedded/IoT operating system, if applicable. | Testing, in presence of OEM team, to verify the declared memory protection controls available and enabled in the device using command line-based tools/commands or any other open-source tool like DEP, EMET tool. | Declaration of the memory protection controls available and enabled in the device. |
| | | 2.2 Verify that the firmware apps protect data-in-transit using transport layer security. | 1. Verifying that strong encryption algorithms and secure TLS version is supported by the device to establish secure communication.<br>2. Verifying that device properly validates the server's TLS certificate to ensure that it is trusted and has not been tampered with.<br>3. Testing for vulnerabilities which can affect the security of TLS connection such as padding oracle attacks, or weak cipher suites.<br>4. Using tools such as Nmap to identify open ports through which device can be accessed leading to unintended data retrieval.<br>5. Verifying that theTLS session(s) are resistant to attemptsof interception and decryption of network traffic using man-in-the-middle attacks using tools like Burpsuite. | Specifications and documentation related to the configurations available in the applications and firmware related to transport layer security. |
| | | 2.3 Verify that the firmware apps validate the digital signature of server connections. | 1. Identifying the scenarios when the device establishes the server connections with the external world and verifying the following:<br>• Security features, related to secure server connections and digital | Document mentioning the use-cases when the device establishes server connections with the external world, with detailed information about the security measures in place while validating the digital signatures of the |

| | | | | |
|---|---|---|---|---|
| | | | signature validation as implemented like strong cipher suites, secure TLS version, SSL pinning etc. supported by code walkthrough.<br>• Proper certificate validation, certificate chain validation and certificate revocation checks are implemented in the device.<br>2. Testing for vulnerabilities which can affect the security of TLS connection such as padding oracle attacks, or weak cipher suites.<br>3. Using tools such as Nmap to identify open ports through which device can be accessed leading to unintended data retrieval.<br>4. Verifying that TLS session(s) are resistant to attemptsof interception and decryption of network traffic using man-in-the-middle attacks using tools like Burpsuite. | server connections. |
| | | 2.4 Verify that any use of banned C functions are replaced with the appropriate safe equivalent functions. | Secure code review [both automated and manual], in presence of OEM team, using a licensed static analysis tool through any of the following approaches:<br>1. Visit to the evaluation agency by the vendor with the firmware code and installing the licensed static analysis tool available with the evaluation agency in their systems. [Recommended]<br>2. Visit to the evaluation agency by the vendor with the firmware code and any licensed static analysis tool available with them and demonstrating the code review activity in the presence of representatives of evaluation agency. | 1. Firmware binaries for code review.<br>2. Internal code review reports |

| | | | | |
|---|---|---|---|---|
| | | | 3. Giving a remote access of the systems at vendor site to the evaluation agency for installing their licensed static analysis tool available with them.<br><br>4. Giving a remote access of the systems at vendor site to the evaluation agency containing the firmware code along with the licensed static analysis tool available with the vendors. | |
| | | 2.5 Verify that each firmware maintains a software bill of materials cataloging third party components, versioning, and published vulnerabilities. | Verification of the submitted list of third-party components by running automated tools like FACT on the firmware.<br><br>Identifying vulnerabilities in the third-party component(s) through publically available vulnerability databases<br><br>Verification and validation of the process defined by the vendor for providing regular security updates and patches for the firmware to address any known vulnerabilities in third-party components. | 1. Documentation for information on software bill of materials, including third-party components and versions.<br><br>2. Organization process and policies for the following:<br><br>• Addressing and patching any identified vulnerabilities in third-party components.<br><br>• Informing the customers about the security issues or vulnerabilities and providing security updates and patches for the same.<br><br>3. Configuration management system and related policies for maintaining firmware and third-party binaries, libraries and frameworks along with the patches/fixes issued to the devices. |
| | | 2.6 Verify all code including third-party binaries, libraries, frameworks are reviewed for hardcoded credentials (backdoors). | Independent secure code review [both automated and manual] using a licensed static analysis tool through any of the following approaches:<br><br>1. Visit to the evaluation agency by the vendor with the firmware code and installing the licensed static analysis tool available with the evaluation agency in their systems. | 1. Firmware binaries for code review.<br><br>2. Internal code review reports |

| | | | | |
|---|---|---|---|---|
| | | | [Recommended]<br>2. Visit to the evaluation agency by the vendor with the firmware code and any licensed static analysis tool available with them and demonstrating the code review activity in the presence of representatives of evaluation agency.<br>3. Giving a remote access of the systems at vendor site to the evaluation agency for installing their licensed static analysis tool available with them.<br>4. Giving a remote access of the systems at vendor site to the evaluation agency containing the firmware code along with the licensed static analysis tool available with the vendors. | |
| | | 2.7 Verify that the firmware apps pin the digital signature to a trusted server(s). | 1. Identifying the scenarios when the device establishes the server connections with the external world and verifying the following:<br>• Security features, related to secure server connections and digital signature validation as implemented like strong cipher suites, secure TLS version, SSL pinning etc. supported by code walkthrough.<br>• Proper certificate validation, certificate chain validation and certificate revocation checks are implemented in the device. | Document mentioning the use-cases when the device establishes server connections with the external world, with detailed information about the security measures in place while validating the digital signatures of the server connections. |
| | | 2.8 Verify security controls are in place to hinder firmware reverse engineering (e.g.removal of verbose debugging symbols). | Testing, in presence of OEM team, to verify the security controls as provided by the vendor to hinder firmware reverse engineering. | Documentation regarding the security controls in place to hinder firmware reverse engineering. |
| | | 2.9 Verify that | Testing, in presence of | Measures implemented in |

| | | | | |
|---|---|---|---|---|
| | | the firmware update process is not vulnerable to time-of-check vs time-of-use attacks. | OEM team, to verify the measures implemented in the device to make it resistant to time-of-check vs.time-of-use attacks. | the device to make it resistant to time-of-check vs. time-of-use attacks. |
| | | 2.10 Verify the device uses code signing and validates firmware upgrade files before installing. | Testing, in presence of OEM team, to verify the following:<br>i) Device gets successfully updated with the documented secure upgrade process when a valid update package is provided.<br>ii) Device does not boot up when a tampered update package (like with missing signature, invalid signature) is provided. | Process of achieving secure firmware upgrade which should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented. |
| | | 2.11 Verify that the device cannot be downgraded to old versions (anti-rollback) of valid firmware. | Testing, in presence of OEM team, to verify that the device cannot be downgraded to old versions (anti-rollback) of valid firmware. | Process of achieving secure firmware upgrade which should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented. |
| | | 2.12 Verify that firmware can perform automatic firmware updates upon a predefined schedule. | Verification shall be done as per the applicable scenario:<br>**Case 1: Automatic OTA updates are available:**<br>A standard operating procedure for issuing automatic updates/upgrades to the in-field devices is required to be submitted by the vendor which can then be evaluated by the evaluation agency as per C20, C21 and C22 security requirement.<br>**Case 2: Automatic OTA updates are not available and vendor provides manual updates:**<br>A standard operating procedure for issuing manual updates/upgrades to the in-field devices is required to be submitted by the vendor which can then be evaluated by the | 1. Modes of updates available i.e. automatic, manual or both.<br>2. Organizational process and policies regarding the issuing of updates to the devices. |

| | | | | |
|---|---|---|---|---|
| | | | evaluation agency as per C20, C21 and C22 security requirement. | |
| 3) | Secure Process Conformance | 3.1 Verify that wireless communications are mutually authenticated. | Testing, in presence of OEM team, to verify the process of mutual authentication as laid down in the documentation by the vendor. | The documentation regarding the process of mutual authentication as implemented in the device when wireless communications are initiated.<br>In case, the device does not support wireless communications, the vendor shall provide a declaration for the same. |
| | | 3.2 Verify that wireless communications are sent over an encrypted channel. | Identifying all the security mechanisms being used in the communication process verification through:<br>• Testing, in presence of OEM team<br>• Code review<br>• Process audit of the key-life cycle process | Documentation regarding the security measures implemented in the device to prevent tampering of the data being sent through wireless mode of communication.<br>In case, the device does not support wireless communications, the vendor shall provide a declaration for the same. |
| | | 3.3 Verify that whether trusted sources are being used for sourcing the components of the device i.e. trusted supply chain through a managed Bill of materials for critical hardware components (related to security functions like SoC) is in use. | | Bill of materials for critical hardware components (related to security functions like SoC). |
| | | 3.4 Supply chain risk identification, assessment, prioritization, and mitigation shall be conducted. Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption, | | Supply chain risk identification, assessment, prioritization, and mitigation documents.<br>Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption, post-incident summary documents. |

| | | | | |
|---|---|---|---|---|
| | | post-incident summary documents need to be submitted and demonstrate the same. | | |
| | | 3.5 Verify the no proprietary network protocols are being used in the device. If yes, then complete implementation details and the source code for the same shall be provided. | | Document for Network protocols used in the device. |
| 4) | Security Conformance at product development stage | 4.1 Design and architecture details till the PCBA and SoC level to be provided to aid in counterfeit mitigation and malware detection. | | Design and architecture documents till the PCBA and SoC level. |
| | | 4.2 Threat mitigation strategies for tainted and counterfeit products shall be implemented as part of product development. | Process and method artifacts need to be submitted and demonstrate the same. | |
| | | 4.3 One or more up-to-date malware detection tools shall be deployed as part of the code acceptance and development processes.<br><br>Malware detection techniques shall be used before final packaging and delivery (e.g., scanning finished products and components for malware using one or more up-to-date | List of components that have been identified as requiring tracking targets of tainting/counterfeiting, CM tool.<br><br>Quality assurance process need to be submitted and demonstrate the same. | |

| | | | | |
|---|---|---|---|---|
| | | malware detection tools). | | |
| | | 4.4 Supply chain risk identification, assessment, prioritization, and mitigation shall be conducted. | | Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption, post-incident summary documents need to be submitted and demonstrate the same. |

Uploaded by Dte. of Printing at Government of India Press, Ring Road, Mayapuri, New Delhi-110064
and Published by the Controller of Publications, Delhi-110054.

रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-09042024-253632
CG-DL-E-09042024-253632

असाधारण
EXTRAORDINARY

भाग II—खण्ड 3—उप-खण्ड (ii)
PART II—Section 3—Sub-section (ii)

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 1569] नई दिल्ली, मंगलवार, अप्रैल 9, 2024/चैत्र 20, 1946
No. 1569] NEW DELHI, TUESDAY, APRIL 9, 2024/CHAITRA 20, 1946

## इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय

## (आईपीएचडब्ल्यू प्रभाग )

## आदेश

नई दिल्ली, 9 अप्रैल, 2024

**विषय: "इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी माल में संशोधन" (अनिवार्य पंजीकरण की आवश्यकता) आदेश, 2021"**

**का.आ. 1652(अ).**—भारतीय मानक ब्यूरो अधिनियम, 2016, (2016 का 11) की धारा 25 की उपधारा (3) के साथ पठित धारा 16 की उप-धारा (1) और (2) द्वारा प्रदत्त शक्तियों का प्रयोग करते हुए, केंद्र सरकार का यह मत है कि सार्वजनिक हित में ऐसा करना आवश्यक या समीचीन है, इसके द्वारा "इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी माल (अनिवार्य पंजीकरण के लिए आवश्यकताएं) आदेश, 2021" में निम्नलिखित संशोधन किए जाते हैं:

2. सी.सी.टी.बी. कैमरे हेतु, कॉलम (5) की निम्नलिखित प्रविष्टि को "इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी माल (अनिवार्य पंजीकरण के लिए आवश्यकताएं) आदेश, 2021 की अनुसूची में क्रम संख्या 41 पर जोड़ा जाएगा।

| क्रमांक (1) | माल या सामान (2) | भारतीय मानक (3) | भारतीय मानक का शीर्षक (4) | अपेक्षित आवश्यकता (आवश्यकताएँ) (5) |
|---|---|---|---|---|
| 41 | सीसीटीवी कैमरा | आईएस 13252 : भाग 1 : 2010 | सूचना तकनीकी उपकरण - सुरक्षा सामान्य आवश्यकताएं-- | अनुलग्नक के अनुसार सीसीटीवी हेतु अनिवार्य आवश्यकता (आवश्यकताएँ) |



Page 198 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

3. "इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी माल (अनिवार्य पंजीकरण के लिए आवश्यकताएं) आदेश, 2021" के प्रावधान इस अधिसूचना के आधार पर उक्त आदेश की अनुसूची में जोड़े गए कॉलम (2) में निर्दिष्ट माल या सामान पर आधिकारिक राजपत्र में इस अधिसूचना के प्रकाशन की तारीख से छह महीने की समाप्ति पर, कॉलम (5) में निर्दिष्ट किए गए संबंधित अपेक्षित आवश्यकताओं के अनुरूप लागू होंगे। बीआईएस अनुरूपता मूल्यांकन विनियम, 2018 की योजना II के अनुसार बीआईएस मान्यता प्राप्त प्रयोगशालाओं से परीक्षण रिपोर्ट जमा करना मानक चिन्ह का उपयोग करने के लिए लाइसेंस प्राप्त करने हेतु एक पूर्व-आवश्यकता होगी।

[फा.सं. डब्ल्यू-43/11/2021-आईपीएचडब्ल्यू]
आशा नांगिया, समूह समन्वयक और वैज्ञानिक 'जी'

**अनुलग्नक**

## सीसीटीवी की सुरक्षा के लिए अनिवार्य आवश्यकता

संवेदनशील जानकारी की सुरक्षा और सिस्टम को प्रभावी ढंग से संचालित करने के लिए सीसीटीवी (क्लोज-सर्किट टेलीविजन) प्रणाली को सुरक्षित करना महत्वपूर्ण है। परीक्षण के प्रमुख क्षेत्रों में एक्स्पोस्ड नेटवर्क सेवाएं, डिवाइस संचार प्रोटोकॉल, डिवाइस के यूएआरटी,जेटीएजी,एसडब्ल्युडी आदि तक भौतिक पहुंच, मेमोरी और फर्मवेयर निकालने की क्षमता, फर्मवेयर अपडेट प्रक्रिया सुरक्षा और डेटा का भंडारण और एन्क्रिप्शन शामिल हैं। सीसीटीवी सिस्टम की सुरक्षा के लिए यहां संक्षिप्त आवश्यकताएं दी गई हैं:

1. भौतिक सुरक्षा - भौतिक छेड़छाड़ को रोकने के लिए छेड़छाड़-प्रतिरोधी कैमरा एन्क्लोज़र और लॉकिंग तंत्र का उपयोग करें।
2. प्रमाणीकरण द्वारा अभिगम नियंत्रण, भूमिका-आधारित अभिगम नियंत्रण (आरबीएसी) और कर्मियों के परिवर्तनों को प्रतिबिंबित करने के लिए अभिगम अनुमतियों की नियमित रूप से समीक्षा और अद्यतनीकरण ।
3. डेटा ट्रांसमिशन के एन्क्रिप्शन को नियोजित करके नेटवर्क सुरक्षा
4. नियमित अपडेट द्वारा सॉफ़्टवेयर सुरक्षा, अप्रयुक्त सुविधाओं को अक्षम करना और सुदृढ़ पासवर्ड नीतियाँ
5. पेनीट्रेशन परीक्षण: साइबर हमलों के लिए सिस्टम के प्रतिरोध का आकलन करने और कमजोरियों को दूर करने के लिए पेनीट्रेशन परीक्षण को नियोजित करें।

**अनिवार्य सुरक्षा आवश्यकताएँ**

| क्रमांक | वर्ग | परीक्षण पैरामीटर | क्या परीक्षण किया जाए | अपेक्षित दस्तावेज़ |
|---|---|---|---|---|
| | हार्डवेयर स्तर सुरक्षा पैरामीटर (सॉफ़्टवेयर द्वारा समर्थित) | 1.1 एक जटिल पासवर्ड द्वारा यह सत्यापित करें कि एप्लिकेशन लेयर डिबगिंग इंटरफ़ेस जैसे यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट अक्षम या संरक्षित हैं। | 1. परीक्षण के तहत डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट के माध्यम से यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट जैसे डिबगिंग इंटरफेस की उपलब्धता की पहचान करना<br>2. विक्रेता दस्तावेज़ीकरण में घोषित की गई सुरक्षा के लिए उत्पादन उपकरणों और संबंधित पहुंच नियंत्रण तंत्र में सक्षम पोर्ट/इंटरफ़ेस का सत्यापन और वेधता हार्डवेयर आधारित डिबगर्स और एक्सेस कंट्रोल तंत्र का उपयोग करके सभी पोर्ट और यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट जैसे डिबगिंग इंटरफेस को सक्षम/अक्षम करने को सत्यापित करने के लिए ओईएम | विक्रेता द्वारा निम्नलिखित को उपलब्ध करना होगा:<br>1. डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट।<br>2. उत्पादन उपकरणों में सक्षम पोर्ट/इंटरफ़ेस से संबंधित दस्तावेज़ीकरण और उसकी सुरक्षा के लिए संबंधित एक्सेस नियंत्रण तंत्र।<br>3. डिवाइस के विनिर्माण/प्रावधान की प्रक्रिया प्रवाह |

Page 200 of 4391 : B957-TENDER_DOC-B957-300-16-43-MR-T-3001 : Rev.A



| | | | | |
|---|---|---|---|---|
| | | | टीम की उपस्थिति में परीक्षण।<br>4. डिबगिंग इंटरफेस के बारे में विक्रेता के दावे को मान्य करने के लिए विनिर्माण सुविधा की प्रक्रिया लेखा परीक्षा जो प्रावधान के दौरान बंद/अक्षम हैं।<br>[उदाहरण के लिए, ब्लॉक कनेक्शन आरेख के माध्यम से होस्ट माइक्रोकंट्रोलर के बीच पिन कनेक्शन और विभिन्न उप घटकों/परिधीय के साथ इसकी बातचीत को दर्शाया गया है।] | |
| | | 1.2 सत्यापित करें कि क्रिप्टोग्राफ़िक कुंजी और प्रमाणपत्र प्रत्येक व्यक्तिगत डिवाइस के लिए अद्वितीय हैं। | डिवाइस इको-सिस्टम में उपयोग की जा रही सभी कुंजियों और प्रमाणपत्रों की पहचान करना और इनके माध्यम से सत्यापन करना:<br>ओईएम टीम की उपस्थिति में परीक्षण<br>कोड समीक्षा<br>कुंजी-जीवन चक्र प्रक्रिया संबंधी प्रक्रिया लेखा परीक्षा | विक्रेता द्वारा निम्नलिखित को प्रस्तुत करना होगा:<br>1. डिवाइस इकोसिस्टम में उपयोग की जा रही सभी कुंजियों और प्रमाणपत्रों की सूची<br>2. मुख्य प्रबंधन जीवन चक्र (उद्देश्य, उत्पादन, भंडारण, विनाश/शून्यीकरण, वैधता, कुंजी परिवर्तन/रोटेशन) |
| | | 1.3 सत्यापित करें कि जेटीएजी या एसडब्ल्यूडी जैसे ऑन-चिप डिबगिंग इंटरफ़ेस अक्षम हैं या उपलब्ध सुरक्षा तंत्र सक्षम और उचित रूप से कॉन्फ़िगर किया गया है। | 1. परीक्षण के तहत डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट के माध्यम से यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट जैसे डिबगिंग इंटरफेस की उपलब्धता की पहचान करना<br>2. विक्रेता दस्तावेज़ में घोषित की गई सुरक्षा के लिए उत्पादन उपकरणों और संबंधित पहुंच नियंत्रण तंत्र में सक्षम पोर्ट/इंटरफ़ेस का सत्यापन और वेधता<br>3. इंटरफ़ेस सक्षम होने की स्थिति में उनके प्रासंगिक हार्डवेयर आधारित डिबगर्स और एक्सेस कंट्रोल तंत्र का उपयोग करके सभी पोर्ट और यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट जैसे डिबगिंग इंटरफेस को सक्षम/अक्षम करने को सत्यापित करने के लिए ओईएम टीम की उपस्थिति में परीक्षण।<br>4. डिबगिंग इंटरफेस के बारे में विक्रेता के दावे को मान्य करने के लिए विनिर्माण सुविधा की प्रक्रिया लेखा परीक्षा जो प्रावधान | विक्रेता द्वारा निम्नलिखित को उपलब्ध करना होगा:<br>1. डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट।<br>2. उत्पादन उपकरणों में सक्षम पोर्ट/इंटरफ़ेस से संबंधित दस्तावेज़ीकरण और उसकी सुरक्षा के लिए संबंधित एक्सेस नियंत्रण तंत्र।<br>3. डिवाइस के विनिर्माण/प्रावधान की प्रक्रिया प्रवाह |

| | | | | |
|---|---|---|---|---|
| | | | के दौरान बंद/अक्षम हैं।<br>[उदाहरण के लिए, ब्लॉक कनेक्शन आरेख के माध्यम से होस्ट माइक्रोकंट्रोलर के बीच पिन कनेक्शन और विभिन्न उप घटकों/परिधीय के साथ इसकी बातचीत को दर्शाया गया है।] | |
| | | 1.4 सत्यापित करें कि विश्वसनीय निष्पादन लागू और सक्षम है, यदि डिवाइस एसओसी या सीपीयू पर उपलब्ध है। | विक्रेता द्वारा प्रस्तुत एसओसी डेटाशीट और तकनीकी दस्तावेज के माध्यम से डिवाइस में टीईई/एसई/टीपीएम उपलब्ध है या नहीं, इसकी पहचान करना।<br>आगे का मूल्यांकन डिवाइस पर लागू परिदृश्यों के आधार पर किया जाता है जैसा कि नीचे परिभाषित किया गया है:<br>**स्थिति 1: टीईई/एसई/टीपीएम उपलब्ध नहीं है:**<br>कोई और अग्रिम मूल्यांकन नहीं<br>**स्थिति 2: टीईई/एसई/टीपीएम उपलब्ध और सक्षम है:**<br>कोड-समीक्षा के माध्यम से सत्यापन कि क्रिप्टो फ़ंक्शन को टीईई/एसई/टीपीएम एपीआई के माध्यम से बुलाया जाता है।<br>**स्थिति 3: टीईई/एसई/टीपीएम उपलब्ध है लेकिन विक्रेता द्वारा सक्षम नहीं किया गया है:**<br>आवश्यकता के अनुरूप न होने के रूप में करार दिया गया। टीईई/एसई/टीपीएम को सक्षम और कार्यान्वित करने के लिए ओईएम की आवश्यकता होती है। | विक्रेता द्वारा निम्नलिखित को उपलब्ध कराना होगा:<br>1. डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट।<br>2. डिवाइस का उपयोगकर्ता मैनुअल/तकनीकी विनिर्देश<br>3. टीईई एपीआई कॉल के कोड स्निपेट, जहां भी लागू हो |
| | | 1.5 सत्यापित करें कि संवेदनशील डेटा, निजी कुंजियाँ और प्रमाणपत्र एक सुरक्षित तत्व, टीपीएम, टीईई (विश्वसनीय निष्पादन पर्यावरण) में सुरक्षित रूप से संग्रहीत हैं, या सुदृढ़ क्रिप्टोग्राफी का उपयोग करके संरक्षित हैं। | डिवाइस इको-सिस्टम, संवेदनशील डेटा और उनके भंडारण तंत्र में उपयोग की जा रही सभी कुंजियों और प्रमाणपत्रों की पहचान करना; और इसके माध्यम से सत्यापन करना :<br>• ओईएम टीम की उपस्थिति में परीक्षण<br>• कोड समीक्षा<br>• कुंजी-जीवन चक्र प्रक्रिया संबंधी प्रक्रिया लेखा परीक्षा | विक्रेता द्वारा निम्नलिखित को प्रस्तुत करना होगा:<br>1. डिवाइस इकोसिस्टम में उपयोग की जा रही सभी कुंजियों और प्रमाणपत्रों की सूची<br>2. डिवाइस में सक्षम किए जाने वाले सुरक्षित कॉन्फ़िगरेशन के साथ कार्यान्वित सभी संवेदनशील डेटा की उनके इच्छित उपयोग और सुरक्षित भंडारण तंत्र (ओं) के साथ सूची।<br>3. मुख्य प्रबंधन जीवन चक्र (उद्देश्य, उत्पादन, भंडारण, विनाश/शून्यीकरण, वैधता, कुंजी परिवर्तन/रोटेशन) निजी कुंजी |

| | | | | |
|---|---|---|---|---|
| | | | | और प्रमाणपत्र। |
| | | 1.6 टैम्पर रेसिस्टेंस और/या टैम्पर का पता लगाने वाली सुविधाओं की उपस्थिति सत्यापित करें। | सॉफ़्टवेयर और हार्डवेयर से टैंपरिंग को रोकने के लिए डिवाइस में लागू किए गए उपायों को सत्यापित करने के लिए ओईएम टीम की उपस्थिति में परीक्षण। | विक्रेता द्वारा निम्नलिखित को प्रस्तुत करना होगा:<br>1. सॉफ्टवेयर से टैंपरिंग रोकने के लिए डिवाइस संबंधी उपलब्ध उपाय।<br>2. हार्डवेयर से टैंपरिंग रोकने के लिए डिवाइस संबंधी उपलब्ध उपाय। |
| | | 1.7 चिप निर्माता द्वारा प्रदान की गई कोई भी उपलब्ध बौद्धिक संपदा सुरक्षा तकनीक सक्षम है। | यदि उपलब्ध हो तो चिप निर्माता द्वारा प्रदान की गई बौद्धिक संपदा सुरक्षा तकनीकों को सक्षम करने के लिए ओईएम टीम की उपस्थिति में परीक्षण। | विक्रेता द्वारा निम्नलिखित को प्रस्तुत करना होगा:<br>1. एसओसी की डेटाशीट<br>2. चिप निर्माता द्वारा प्रदान की गई बौद्धिक संपदा संरक्षण प्रौद्योगिकियों के संबंध में दस्तावेज़ीकरण, जिन्हें सक्षम किया गया है।<br>3. यदि चिप निर्माता द्वारा कोई बौद्धिक संपदा संरक्षण तकनीक प्रदान नहीं की जा रही है, तो एक घोषणा जिसमें समरूप बात हो। |
| | | 1.8 सत्यापित करें कि डिवाइस लोड करने से पहले बूट छवि हस्ताक्षर को सत्यापित करता है। | निम्नलिखित को सत्यापित करने के लिए ओईएम टीम की उपस्थिति में परीक्षण करना :<br>1. वैध बूट छवि प्रदान किए जाने पर डिवाइस दस्तावेज़ीकृत सुरक्षित बूट प्रक्रिया के साथ सफलतापूर्वक बूट हो जाता है।<br>2. छेड़छाड़ की गई बूट छवि (जैसे मिसिंग हस्ताक्षर, अमान्य हस्ताक्षर) प्रदान किए जाने पर डिवाइस बूट नहीं होता है। | विक्रेता द्वारा निम्नलिखित को प्रस्तुत करना होगा:<br>1. एसओसी की डेटाशीट<br>2. सुरक्षित बूट के संबंध में डिवाइस के तकनीकी विनिर्देश (इसमें शामिल कुंजियाँ और उनका प्रबंधन जीवन चक्र ', हस्ताक्षर सत्यापन प्रक्रिया और लागू होने पर कोई अन्य सुरक्षित तंत्र शामिल होना चाहिए।) |
| | | 1.9 एम्बेडेड डिवाइस पर क्रिप्टोग्राफ़िक रूप से सुरक्षित छद्म-यादृच्छिक संख्या जनरेटर के उपयोग को सत्यापित करें (उदाहरण के लिए, चिप-प्रदत्त यादृच्छिक संख्या जनरेटर का उपयोग करके)। | डिवाइस में उपयोग किए जा रहे यादृच्छिक संख्या जनरेटर के संबंध में विक्रेता द्वारा प्रदान किए गए दस्तावेज़ का सत्यापन करना।<br>कोड-समीक्षा के माध्यम से सत्यापन कि डिवाइस में यादृच्छिक संख्या जनरेटर या संबंधित लाइब्रेरी का उपयोग किया जा रहा है। | विक्रेता को अपने इच्छित उपयोग के साथ डिवाइस में उपयोग किए जा रहे यादृच्छिक जेनरेटर (या तो हार्डवेयर आधारित या सॉफ़्टवेयर आधारित या दोनों) के संबंध में दस्तावेज़ प्रस्तुत करना होगा।<br>यदि हार्डवेयर आधारित यादृच्छिक संख्या जनरेटर का उपयोग किया जा रहा है, तो विक्रेताओं को निम्नलिखित प्रस्तुत करना होगा:<br>1. एसओसी की डेटाशीट<br>2. यादृच्छिक जनरेटर के संबंध में डिवाइस की तकनीकी विशिष्टताएँ यदि सॉफ्टवेयर आधारित |

| | | | | |
|---|---|---|---|---|
| | | | | यादृच्छिक संख्या जनरेटर का उपयोग किया जा रहा है, तो विक्रेताओं को इसके लिए उपयोग की जाने वाली लाइब्रेरी प्रदान करनी होगी। |
| 2. | सॉफ्टवेयर/फर्मवेयर | 2.1 सत्यापित करें कि एएसएलआर और डीईपी जैसे मेमोरी सुरक्षा नियंत्रण एम्बेडेड/आईओटी ऑपरेटिंग सिस्टम द्वारा सक्षम हैं, यदि लागू हो। | कमांड लाइन-आधारित टूल/कमांड या डीईपी, ईएमईटी टूल जैसे किसी अन्य ओपन-सोर्स टूल का उपयोग करके डिवाइस में उपलब्ध और सक्षम घोषित मेमोरी सुरक्षा नियंत्रणों को सत्यापित करने के लिए ओईएम टीम की उपस्थिति में परीक्षण करना। | विक्रेता को डिवाइस में उपलब्ध और सक्षम मेमोरी सुरक्षा नियंत्रणों की घोषणा प्रस्तुत करनी होगी। |
| | | 2.2 सत्यापित करें कि फ़र्मवेयर ऐप्स ट्रांसपोर्ट लेयर सुरक्षा का उपयोग करके ट्रांज़िट में डेटा की सुरक्षा करते हैं। | 1. यह सत्यापित करना कि सुरक्षित संचार स्थापित करने के लिए सुदृढ़ एन्क्रिप्शन एल्गोरिदम और सुरक्षित टीएलएस संस्करण डिवाइस द्वारा समर्थित है।<br>2. यह सत्यापित करना कि डिवाइस सर्वर के टीएलएस प्रमाणपत्र को ठीक से मान्य करता है ताकि यह सुनिश्चित हो सके कि यह विश्वसनीय है और इसके साथ छेड़छाड़ नहीं की गई है।<br>3. सुभेद्यताओं का परीक्षण जो टीएलएस कनेक्शन की सुरक्षा को प्रभावित कर सकता है जैसे पैडिंग ऑरिकल हमले, या सुभेद्य सिफर सुइट्स।<br>4. खुले पॉर्ट्स की पहचान करने के लिए एनएमएपी जैसे टूल का उपयोग करना जिसके माध्यम से डिवाइस तक पहुंचा जा सकता है जिससे अनपेक्षित डेटा पुनर्प्राप्ति हो सकती है।<br>5. यह सत्यापित करना कि टीएलएस सत्र बर्पसुइट जैसे टूल का उपयोग करके मैन-इन-द-मिडिल हमलों का उपयोग करके नेटवर्क ट्रैफ़िक के अवरोधन और डिक्रिप्शन के प्रयासों के लिए प्रतिरोधी हैं। | विक्रेता ट्रांसपोर्ट लेयर सुरक्षा से संबंधित एप्लिकेशन और फर्मवेयर में उपलब्ध कॉन्फ़िगरेशन से संबंधित विनिर्देश और दस्तावेज प्रस्तुत करेगा। |
| | | 2.3 सत्यापित करें कि फ़र्मवेयर ऐप्स सर्वर कनेक्शन के डिजिटल हस्ताक्षर को मान्य करते हैं। | 1. उन परिदृश्यों की पहचान करना जब डिवाइस बाह्य दुनिया के साथ सर्वर कनेक्शन स्थापित करता है और निम्नलिखित की पुष्टि करता है: | विक्रेता को उपयोग के मामलों का उल्लेख करते हुए एक दस्तावेज़ प्रस्तुत करना होगा जब डिवाइस बाहरी दुनिया के साथ सर्वर कनेक्शन स्थापित करता है, जिसमें सर्वर कनेक्शन के डिजिटल |

| | | | | |
|---|---|---|---|---|
| | | | • सुरक्षित सर्वर कनेक्शन और डिजिटल हस्ताक्षर सत्यापन से संबंधित सुरक्षा सुविधाएँ, जैसे सुदृढ़ साईफर सुइट्स, सुरक्षित टीएलएस संस्करण, एसएसएल पिनिंग आदि कोड वॉकथ्रू द्वारा समर्थित हैं।<br>• डिवाइस में उचित प्रमाणपत्र सत्यापन, प्रमाणपत्र श्रृंखला सत्यापन और प्रमाणपत्र निरस्तीकरण जांच लागू की जाती हैं।<br>2. सुभेद्धताओं का परीक्षण जो टीएलएस कनेक्शन की सुरक्षा को प्रभावित कर सकता है जैसे पैडिंग ऑरेकल हमले, या सुभेद्ध सिफर सुइट्स।<br>3. खुले पोर्ट की पहचान करने के लिए एनएमएपी जैसे टूल का उपयोग करना जिसके माध्यम से डिवाइस तक पहुंचा जा सकता है जिससे अनपेक्षित डेटा पुनर्प्राप्ति हो सकती है।<br>4. यह सत्यापित करना कि टीएलएस सत्र बर्पसुइट जैसे उपकरणों का उपयोग करके मैन-इन-द-मिडिल हमलों का उपयोग करके नेटवर्क ट्रैफ़िक के अवरोधन और डिक्रिप्शन के प्रयासों के लिए प्रतिरोधी हैं। | हस्ताक्षरों को मान्य करते समय सुरक्षा उपायों के बारे में विस्तृत जानकारी होगी। |
| | | 2.4 सत्यापित करें कि प्रतिबंधित सी फ़ंक्शंस के किसी भी उपयोग को उचित सुरक्षित समकक्ष फ़ंक्शंस के साथ बदल दिया गया है। | निम्नलिखित में से किसी भी दृष्टिकोण के माध्यम से लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण का उपयोग करके ओईएम टीम की उपस्थिति में सुरक्षित कोड समीक्षा [स्वचालित और मैन्युअल दोनों]:<br>1. फ़र्मवेयर कोड के साथ विक्रेता द्वारा मूल्यांकन एजेंसी का दौरा करना और मूल्यांकन एजेंसी के पास उपलब्ध लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण को | विक्रेता द्वारा उपलब्ध करना होगा:<br>1. कोड समीक्षा के लिए फ़र्मवेयर बायनेरिज़।<br>2. आंतरिक कोड समीक्षा रिपोर्ट |

| | | | | |
|---|---|---|---|---|
| | | | अपने सिस्टम में स्थापित करना। [अनुशंसित]<br>2. विक्रेता द्वारा फर्मवेयर कोड और उनके पास उपलब्ध किसी भी लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण के साथ मूल्यांकन एजेंसी का दौरा करना और मूल्यांकन एजेंसी के प्रतिनिधियों की उपस्थिति में कोड समीक्षा गतिविधि का प्रदर्शन करना।<br>3. मूल्यांकन एजेंसी को उनके पास उपलब्ध लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण स्थापित करने के लिए विक्रेता साइट पर सिस्टम की रिमोट एक्सेस प्रदान करना।<br>4. विक्रेताओं के पास उपलब्ध लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण के साथ फर्मवेयर कोड वाले मूल्यांकन एजेंसी को विक्रेता साइट पर सिस्टम की दूरस्थ अभिगम प्रदान करना। | |
| | | 2.5 सत्यापित करें कि प्रत्येक फर्मवेयर तृतीय पक्ष के घटकों, संस्करण और प्रकाशित सुभेद्धताओं को सूचीबद्ध करने वाली सामग्री का एक सॉफ्टवेयर बिल रखता है। | फ़र्मवेयर पर एफ़एसीटी जैसे स्वचालित उपकरण चलाकर तृतीय-पक्ष घटकों की प्रस्तुत सूची का सत्यापन करना।<br>सार्वजनिक रूप से उपलब्ध सुभेद्यता डेटाबेस के माध्यम से तीसरे पक्ष के घटकों में सुभेद्धताओं की पहचान करना<br>तृतीय पक्ष के घटकों में किसी भी ज्ञात सुभेद्धता को दूर करने के लिए फर्मवेयर के लिए नियमित सुरक्षा अपडेट और पैच प्रदान करने के लिए विक्रेता द्वारा परिभाषित प्रक्रिया का सत्यापन और वैधता। | विक्रेता द्वारा निम्नलिखित को प्रस्तुत करना होगा:<br>1. तृतीय पक्ष के घटकों और संस्करणों सहित सामग्री के सॉफ़्टवेयर बिल की जानकारी के लिए दस्तावेज़ीकरण करना।<br>2. निम्नलिखित के लिए संगठन प्रक्रिया और नीतियां:<br>• तृतीय पक्ष के घटकों में पहचानी गई किसी भी सुभेद्धता को संबोधित करना और ठीक करना।<br>• ग्राहकों को सुरक्षा मुद्दों या सुभेद्धताओं के बारे में सूचित करना और उसके लिए सुरक्षा अद्यतन और पैच प्रदान करना।<br>3. उपकरणों के लिए जारी किए गए पैच/फिक्स के साथ फर्मवेयर और तृतीय-पक्ष बाइनरी, लाइब्रेरी और फ्रेमवर्क को बनाए रखने के लिए कॉन्फ़िगरेशन प्रबंधन प्रणाली और संबंधित नीतियां। |
| | | 2.6 हार्डकोडेड क्रेडेंशियल्स (बैकडोर) के लिए तृतीय-पक्ष बायनेरिज़, लाइब्रेरीज़, | निम्नलिखित में से किसी भी दृष्टिकोण के माध्यम से लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण का उपयोग करके स्वतंत्र सुरक्षित | विक्रेता द्वारा उपलब्ध करना होगा:<br>1. कोड समीक्षा के लिए फ़र्मवेयर बायनेरिज़। |

Page 206 of 4391 : B957-TENDER_DOC-B957-300-16-43-MR-T-3001 : Rev.A



| | | | | |
|---|---|---|---|---|
| | | फ्रेमवर्क सहित सभी कोड की समीक्षा की जाती है। | कोड समीक्षा [स्वचालित और मैन्युअल दोनों]:<br>1. फ़र्मवेयर कोड के साथ विक्रेता द्वारा मूल्यांकन एजेंसी का दौरा करना और मूल्यांकन एजेंसी के पास उपलब्ध लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण को अपने सिस्टम में स्थापित करना। [अनुशंसित]<br>2. विक्रेता द्वारा फर्मवेयर कोड और उनके पास उपलब्ध किसी भी लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण के साथ मूल्यांकन एजेंसी का दौरा करना और मूल्यांकन एजेंसी के प्रतिनिधियों की उपस्थिति में कोड समीक्षा गतिविधि का प्रदर्शन करना।<br>3. मूल्यांकन एजेंसी को उनके पास उपलब्ध लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण स्थापित करने के लिए विक्रेता साइट पर सिस्टम की दूरस्थ पहुंच प्रदान करना।<br>4. विक्रेताओं के पास उपलब्ध लाइसेंस प्राप्त स्थैतिक विश्लेषण उपकरण के साथ फर्मवेयर कोड वाले मूल्यांकन एजेंसी को विक्रेता साइट पर सिस्टम की दूरस्थ पहुंच प्रदान करना। | 2. आंतरिक कोड समीक्षा रिपोर्ट |
| | | 2.7 सत्यापित करें कि फ़र्मवेयर ऐप्स डिजिटल हस्ताक्षर को किसी विश्वसनीय सर्वर पर पिन करते हैं। | 1. उन परिदृश्यों की पहचान करना जब डिवाइस बाहरी दुनिया के साथ सर्वर कनेक्शन स्थापित करता है और निम्नलिखित की पुष्टि करता है:<br>• सुरक्षित सर्वर कनेक्शन और डिजिटल हस्ताक्षर सत्यापन से संबंधित सुरक्षा सुविधाएँ, जैसे सुदृढ़ सिफर सुइट्स, सुरक्षित टीएलएस संस्करण, एसएसएल पिनिंग आदि कोड वॉकथ्रू द्वारा समर्थित हैं।<br>• डिवाइस में उचित प्रमाणपत्र सत्यापन, प्रमाणपत्र श्रृंखला सत्यापन और प्रमाणपत्र निरस्तीकरण जांच लागू की जाती हैं | विक्रेता को उपयोग के मामलों का उल्लेख करते हुए एक दस्तावेज़ प्रस्तुत करना होगा जब डिवाइस बाहरी दुनिया के साथ सर्वर कनेक्शन स्थापित करता है, जिसमें सर्वर कनेक्शन के डिजिटल हस्ताक्षरों को मान्य करते समय सुरक्षा उपायों के बारे में विस्तृत जानकारी होगी। |

| | | | | |
|---|---|---|---|---|
| | | 2.8 (वर्बोज़ डिबगिंग प्रतीकों को हटाने ) में बाधा डालने के लिए सुरक्षा नियंत्रण मौजूद हैं। | फ़र्मवेयर रिवर्स इंजीनियरिंग में बाधा डालने के लिए विक्रेता द्वारा प्रदान किए गए सुरक्षा नियंत्रणों को सत्यापित करने के लिए, ओईएम टीम की उपस्थिति में परीक्षण करना। | फ़र्मवेयर रिवर्स इंजीनियरिंग में बाधा डालने के लिए विक्रेता को सुरक्षा नियंत्रण के संबंध में दस्तावेज़ प्रस्तुत करना होगा। |
| | | 2.9 सत्यापित करें कि फ़र्मवेयर अपडेट प्रक्रिया समय जांच बनाम उपयोग के समय के हमलों के प्रति संवेदनशील नहीं है। | डिवाइस में लागू किए गए उपायों को सत्यापित करने के लिए ओईएम टीम की उपस्थिति में परीक्षण किया गया, ताकि इसे समय- समय पर उपयोग किए जाने वाले हमलों के प्रति प्रतिरोधी बनाया जा सके। | विक्रेता को डिवाइस में लागू किए गए उपायों को प्रस्तुत करना होगा ताकि इसे समय-जांच बनाम उपयोग के समय के हमलों के प्रति प्रतिरोधी बनाया जा सके। |
| | | 2.10 सत्यापित करें कि डिवाइस इंस्टॉल करने से पहले कोड साइनिंग का उपयोग करता है और फ़र्मवेयर अपग्रेड फ़ाइलों को मान्य करता है। | निम्नलिखित को सत्यापित करने के लिए ओईएम टीम की उपस्थिति में परीक्षण करना :<br>क. वैध अपडेट पैकेज उपलब्ध कराए जाने पर डिवाइस दस्तावेज़ीकृत सुरक्षित अपग्रेड प्रक्रिया के साथ सफलतापूर्वक अपडेट हो जाता है।<br>ख. छेड़छाड़ किए गए अपडेट पैकेज (जैसे मिसिंग हस्ताक्षर, अमान्य हस्ताक्षर) प्रदान किए जाने पर डिवाइस बूट नहीं होता है। | विक्रेता को सुरक्षित फ़र्मवेयर अपग्रेड प्राप्त करने की प्रक्रिया प्रस्तुत करनी होगी जिसमें शामिल कुंजियाँ और उनका प्रबंधन जीवन चक्र ", हस्ताक्षर सत्यापन प्रक्रिया और लागू होने पर कोई अन्य सुरक्षित तंत्र शामिल होना चाहिए। |
| | | 2.11 सत्यापित करें कि डिवाइस को वैध फर्मवेयर के पुराने संस्करण (एंटी-रोलबैक) में डाउनग्रेड नहीं किया जा सकता है। | यह सत्यापित करने के लिए कि डिवाइस को वैध फर्मवेयर के पुराने संस्करणों (एंटी-रोलबैक) में डाउनग्रेड नहीं किया जा सकता है, ओईएम टीम की उपस्थिति में परीक्षण किया जा रहा है। | विक्रेता को सुरक्षित फ़र्मवेयर अपग्रेड प्राप्त करने की प्रक्रिया प्रस्तुत करनी होगी जिसमें शामिल कुंजियाँ और उनका प्रबंधन जीवन चक्र ", हस्ताक्षर सत्यापन प्रक्रिया और लागू होने पर कोई अन्य सुरक्षित तंत्र शामिल होना चाहिए। |
| | | 2.12 सत्यापित करें कि फ़र्मवेयर पूर्वनिर्धारित शेड्यूल पर स्वचालित फ़र्मवेयर अपडेट कर सकता है। | सत्यापन लागू परिदृश्य के अनुसार किया जाएगा:<br>**स्थिति 1: स्वचालित ओटीए अपडेट उपलब्ध हैं:**<br>इन-फील्ड उपकरणों को स्वचालित अपडेट/अपग्रेड जारी करने के लिए एक मानक संचालन प्रक्रिया विक्रेता द्वारा प्रस्तुत की जानी आवश्यक है जिसका मूल्यांकन, मूल्यांकन एजेंसी द्वारा सी20, सी21 और सी22 सुरक्षा आवश्यकता के अनुसार किया जा सकता है। | विक्रेता निम्नलिखित प्रदान करेगा:<br>विक्रेता द्वारा निम्नलिखित को प्रस्तुत कराना होगा:<br>1. उपलब्ध अपडेट के तरीके यानी स्वचालित, मैन्युअल या दोनों।<br>2. उपकरणों को अपडेट जारी करने के संबंध में संगठनात्मक प्रक्रिया और नीतियां। |

| | | | | |
|---|---|---|---|---|
| | | | **स्थिति 2: स्वचालित ओटीए अपडेट उपलब्ध नहीं हैं और विक्रेता मैन्युअल अपडेट प्रदान करता है:**<br>इन-फील्ड डिवाइसों में मैन्युअल अपडेट/अपग्रेड जारी करने के लिए विक्रेता द्वारा एक मानक संचालन प्रक्रिया प्रस्तुत की जानी आवश्यक है जिसका मूल्यांकन, मूल्यांकन एजेंसी द्वारा सी20, सी21 और सी22 सुरक्षा आवश्यकता के अनुसार किया जा सकता है। | |
| 3. | सुरक्षित प्रक्रिया अनुरूपता | 3.1 सत्यापित करें कि वायरलेस संचार परस्पर प्रमाणित हैं। | विक्रेता द्वारा दस्तावेज़ में निर्धारित आपसी प्रमाणीकरण की प्रक्रिया को सत्यापित करने के लिए, ओईएम टीम की उपस्थिति में परीक्षण करना। | विक्रेताओं को वायरलेस संचार शुरू होने पर डिवाइस में लागू पारस्परिक प्रमाणीकरण की प्रक्रिया के संबंध में दस्तावेज़ प्रदान करना होगा।<br>यदि डिवाइस वायरलेस संचार का समर्थन नहीं करता है, तो विक्रेता को इसके लिए एक घोषणा पत्र प्रदान करना होगा। |
| | | 3.2 सत्यापित करें कि वायरलेस संचार एक एन्क्रिप्टेड चैनल पर भेजा जाता है। | संचार प्रक्रिया सत्यापन में उपयोग किए जा रहे सभी सुरक्षा तंत्रों की पहचान करना:<br>• ओईएम टीम की उपस्थिति में परीक्षण करना<br>• कोड समीक्षा<br>• कुंजी-जीवन चक्र प्रक्रिया संबंधी प्रक्रिया लेखा परीक्षा लेखा परीक्षा | संचार के वायरलेस मोड के माध्यम से भेजे जाने वाले डेटा से छेड़छाड़ को रोकने के लिए विक्रेताओं को डिवाइस में लागू सुरक्षा उपायों के संबंध में दस्तावेज उपलब्ध कराने होंगे।<br>यदि डिवाइस वायरलेस संचार का समर्थन नहीं करता है, तो विक्रेता को इसके लिए एक घोषणा पत्र प्रदान करना होगा। |
| | | 3.3 सत्यापित करें कि क्या डिवाइस के घटकों की सोर्सिंग के लिए विश्वसनीय स्रोतों का उपयोग किया जा रहा है यानी महत्वपूर्ण हार्डवेयर घटकों (एसओसी जैसे सुरक्षा कार्यों से संबंधित) के लिए सामग्रियों के प्रबंधित बिल के माध्यम से विश्वसनीय आपूर्ति श्रृंखला का उपयोग किया जा रहा है। | | विक्रेता को महत्वपूर्ण हार्डवेयर घटकों (एसओसी जैसे सुरक्षा कार्यों से संबंधित) के लिए सामग्री का बिल प्रस्तुत करना होगा। |
| | | 3.4 आपूर्ति श्रृंखला जोखिम की पहचान, | | विक्रेता निम्नलिखित प्रस्तुत करेगा:<br>आपूर्ति श्रृंखला जोखिम की |

Page 208 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

| | | | | |
|---|---|---|---|---|
| | | मूल्यांकन, प्राथमिकता और शमन आयोजित किया जाएगा। आपूर्ति शृंखला जोखिम/व्यवसाय निरंतरता योजना नीति दस्तावेज़, आपूर्ति शृंखला व्यवधान को संभालने के तरीके को दर्शाने वाली प्लेबुक, घटना के बाद के सारांश दस्तावेज़ प्रस्तुत करने और उन्हें प्रदर्शित करने की आवश्यकता है। | | पहचान, मूल्यांकन, प्राथमिकता और शमन दस्तावेज़।<br><br>आपूर्ति श्रृंखला जोखिम / व्यापार निरंतरता योजना नीति दस्तावेज, प्लेबुक जो दर्शाती है कि आपूर्ति श्रृंखला व्यवधान को कैसे संभालना है, घटना के बाद सारांश दस्तावेजों को प्रस्तुत करना। |
| | | 3.5 सत्यापित करें कि डिवाइस में कोई प्रप्राइइटेरी नेटवर्क प्रोटोकॉल का उपयोग नहीं किया जा रहा है। यदि हाँ, तो संपूर्ण कार्यान्वयन विवरण और उसके लिए स्रोत कोड प्रदान किया जाएगा। | | डिवाइस में प्रयुक्त नेटवर्क प्रोटोकॉल के लिए दस्तावेज़। |
| 4. | उत्पाद विकास चरण में सुरक्षा अनुरूपता | 4.1 नकली शमन और मैलवेयर का पता लगाने में सहायता के लिए पीसीबीए और एसओसी स्तर तक डिजाइन और आर्किटेक्चर विवरण प्रदान किया जाएगा। | | पीसीबीए और एसओसी स्तर तक डिज़ाइन और आर्किटेक्चर दस्तावेज़। |
| | | 4.2 उत्पाद विकास के हिस्से के रूप में खराब और नकली उत्पादों के लिए खतरा कम करने की रणनीतियों को लागू किया जाएगा। | प्रक्रिया और विधि के विरूपण साक्ष्य प्रस्तुत करने और उन्हें प्रदर्शित करने की आवश्यकता है। | |
| | | 4.3 कोड स्वीकृति और विकास प्रक्रियाओं के हिस्से के रूप में एक या अधिक अद्यतन मैलवेयर पहचान उपकरण नियोजित किए जाएंगे।<br>अंतिम पैकेजिंग और प्रदायगी से पहले मैलवेयर पहचान | उन घटकों की सूची जिनकी पहचान टैनिंग/जालसाजी, सीएम टूल के ट्रैकिंग लक्ष्यों की आवश्यकता के रूप में की गई है।<br>गुणवत्ता आश्वासन प्रक्रिया को प्रस्तुत करने और उसे प्रदर्शित करने की आवश्यकता है। | |

| | | | | |
|---|---|---|---|---|
| | | तकनीकों का उपयोग किया जाएगा (उदाहरण के लिए, एक या अधिक अद्यतन मैलवेयर पहचान उपकरणों का उपयोग करके मैलवेयर के लिए तैयार उत्पादों और घटकों को स्कैन करना)। | | |
| | | 4.4 आपूर्ति श्रृंखला जोखिम की पहचान, मूल्यांकन, प्राथमिकता और शमन आयोजित किया जाएगा। | | आपूर्ति श्रृंखला जोखिम / व्यापार निरंतरता योजना नीति दस्तावेज, प्लेबुक जो दर्शाती है कि आपूर्ति श्रृंखला व्यवधान को कैसे संभालना है, घटना के बाद सारांश दस्तावेजों को प्रस्तुत करने और उसी को प्रदर्शित करने की आवश्यकता है। |

**MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY**

**(IPHW Division)**

**ORDER**

New Delhi, the 9th April, 2024

**Subject: Amendment to the "Electronics and Information Technology Goods (Requirement of Compulsory Registration) Order, 2021"**

**S.O. 1652(E).**—In exercise of the powers conferred by sub-section (1) and (2) of section 16 read with sub section (3) of section 25 of the Bureau of Indian Standards Act, 2016, (11 of 2016), the Central Government is of the opinion that it is necessary or expedient so to do in the public interest, hereby makes the following amendments to the "Electronics and Information Technology Goods (Requirements for Compulsory Registration) Order, 2021":

2. For CCTV Camera, the following entry of Column (5) be added at S. No. 41 in the Schedule of the "Electronics and Information Technology Goods (Requirements for Compulsory Registration) Order, 2021.

| Sr. No. (1) | Goods or Articles (2) | Indian Standard (3) | Title of Indian Standard (4) | Essential Requirement(s) (5) |
|---|---|---|---|---|
| 41 | CCTV Camera | IS 13252: Part 1: 2010 | Information Technology Equipment - Safety General Requirements-- | Essential Requirement(s) for CCTV as per Annexure |

3. The provisions of "Electronics and Information Technology Goods (Requirements for Compulsory Registration) Order, 2021" shall apply on the Goods or articles as specified in the column (2) added to the schedule of the said Order by virtue of this notification, for conforming to the corresponding Essential Requirement(s) as specified in the column (5), on the expiry of six months from the date of publication of this notification in the Official Gazette. As per Scheme II of BIS Conformity Assessment Regulations, 2018, submission of test reports from BIS recognized labs, shall form a pre -requisite for obtaining license to use Standard Mark.

[F.No. W-43/11/2021-IPHW]

ASHA NANGIA, Group Coordinator & Scientist 'G'

**Annexure**

**Essential Requirement(s) for Security of CCTV**

Securing a CCTV (Closed-Circuit Television) system is crucial to protect sensitive information and ensure the system operates effectively. Key areas of testing include exposed network services, device communication protocols, physical access to the device's UART, JTAG, SWD, etc., the ability to extract memory and firmware, firmware update process security and storage and encryption of data. Here are brief requirements for the security of a CCTV system:

1. Physical Security - Use tamper-resistant camera enclosures and locking mechanisms to deter physical tampering.
2. Access Control by Authentication, Role-Based Access Control (RBAC) and regularly review and update access permissions to reflect personnel changes.
3. Network Security by employing encryption of data transmission
4. Software Security by Regular Updates, Disable Unused Features and Strong Password Policies
5. Penetration Testing: Employ penetration testing to assess the system's resistance to cyberattacks and address vulnerabilities.

**Essential Security Requirements**

| Sr. No. | Category | Testing Parameter | What to be tested | Documents Required |
|---|---|---|---|---|
| 1. | Hardware Level Security Parameter (supported by software) | 1.1 Verify that application layer debugging interfaces such USB, UART, and other serial variants are disabled or protected by a complex password. | 1. Identification of the availability of debugging interfaces such as USB, UART, and other serial variants through the Datasheet of the SoC being used in the device under test<br>2. Verification and validation of the ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same as declared in the vendor documentation<br>3. Testing, in presence of OEM team, to verify the enabling/disabling of all the ports and debugging interfaces such as USB, UART, and other serial variants using their relevant hardware-based debuggers and access control mechanisms in case the interface is enabled.<br>4. Process verification of the manufacturing facility to validate the vendor's claim regarding the debugging interfaces which are closed/disabled during provisioning.<br>[For instance, through Block connection diagram depicting pin connections between the host | The vendor shall provide the following:<br>a. Datasheet of the SoC being used in the device.<br>b. Documentation related to ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same.<br>c. Process flow of the Manufacturing/Provisioning of the device |

| | | | | |
|---|---|---|---|---|
| | | | microcontroller and its interactions with various sub components/peripherals.] | |
| | | 1.2 Verify that cryptographic keys and certificates are unique to each individual device. | Identifying all the keys and certificates being used in the device eco-system and verification through:<br>• Testing, in presence of OEM team<br>• Code review<br>• Process audit of the key-life cycle process | Vendor shall submit the following:<br>1. List of all keys and certificates being used in the device ecosystem<br>2. Key management life cycle (purpose, generation, storage, destruction/zeroization, validity, key changeover/rotation) |
| | | 1.3 Verify that on-chip debugging interfaces such as JTAG or SWD are disabled or that available protection mechanism is enabled and configured appropriately. | 1. Identification of the availability of debugging interfaces such as USB, UART, and other serial variants through the Datasheet of the SoC being used in the device under test<br>2. Verification and validation of the ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same as declared in the vendor documentation<br>3. Testing, in presence of OEM team, to verify the enabling/disabling of all the ports and debugging interfaces such as USB, UART, and other serial variants using their relevant hardware based debuggers and access control mechanisms in case the interface is enabled.<br>4. Process audit of the manufacturing facility to validate the vendor's claim regarding the debugging interfaces which are closed/disabled during provisioning.<br>[For instance, through Block connection diagram depicting pin connections between the host microcontroller and its interactions with various sub components/peripherals.] | The vendor shall provide the following:<br>a. Datasheet of the SoC being used in the device.<br>b. Documentation related to ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same.<br>c. Process flow of the Manufacturing/Provisioning of the device |

| | | | | |
|---|---|---|---|---|
| | | 1.4 Verify that trusted execution is implemented and enabled, if available on the device SoC or CPU. | Identifying whether TEE/SE/TPM is available or not in the device through the SoC datasheet and technical documentation submitted by the vendor.<br>Further assessment is done on the basis of scenarios as applicable to device as defined below:<br>**CASE 1: TEE/SE/TPM is not available:**<br>No further assessment<br>**CASE 2: TEE/SE/TPM is available and enabled:**<br>Verification through code-review that crypto functions are called through TEE/SE/TPM APIs.<br>**CASE 3: TEE/SE/TPM is available but not enabled by the vendor:**<br>Termed as non-conformance to the requirement. OEM is required to enable and implement the TEE/SE/TPM. | The vendor shall provide the following:<br>1. Datasheet of the SoC being used in the device.<br>2. User manual/ Technical specifications of the device<br>3. Code snippets of the TEE API call, wherever applicable |
| | | 1.5 Verify that sensitive data, private keys and certificates are stored securely in a Secure Element, TPM, TEE (Trusted Execution Environment), or protected using strong cryptography. | Identifying all the keys and certificates being used in the device eco-system, sensitive data and their storage mechanism(s); and verification through:<br>• Testing, in presence of OEM team<br>• Code review<br>• Process audit of the key-life cycle process | Vendor shall submit the following:<br>1. List of all keys and certificates being used in the device ecosystem<br>2. List of all the sensitive data with their intended usage and secure storage mechanism(s) as implemented along with secure configurations to be enabled in the device.<br>3. Key management life cycle (purpose, generation, storage, destruction/zeroization, validity, key changeover/rotation) private keys and certificates. |
| | | 1.6Verify the presence of tamper resistance and/or tamper detection features. | Testing, in presence of OEM team, to verify the measures implemented in the device to prevent software and hardware tampering. | Vendor shall submit the following:<br>1. Measures available in the device to prevent software tampering.<br>2. Measures available in the device to prevent hardware tampering. |
| | | 1.7 Verify that any available Intellectual | Testing, in presence of OEM team, to verify the enabling of the | Vendor shall submit the following:<br>1. Datasheet of the SoC |

| | | | | |
|---|---|---|---|---|
| | | Property protection technologies provided by the chip manufacturer are enabled. | Intellectual Property protection technologies provided by the chip manufacturer, if available. | 2. Documentation regarding the Intellectual Property protection technologies provided by the chip manufacturer which have been enabled.<br>3. In case, no Intellectual Property protection technologies are being provided by the chip manufacturer, then a declaration stating the same. |
| | | 1.8 Verify the device validates the boot image signature before loading. | Testing, in presence of OEM team, to verify the following:<br>1. Device boots up successfully with the documented secure boot process when a valid boot image is provided.<br>2. Device does not boot up when a tampered boot image (like with missing signature, invalid signature) is provided. | Vendor shall submit the following:<br>1. Datasheet of the SoC<br>2. Technical specifications of the device regarding secure boot (should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented.) |
| | | 1.9 Verify usage of cryptographically secure pseudo-random number generator on embedded device (e.g., using chip-provided random number generators). | Verification of the documentation provided by the vendor regarding the random number generators being used in the device.<br>Verification through code-review that random number generators or related libraries as applicable are being used in the device. | Vendor shall submit the documentation regarding the random generators (either hardware based or software based or both) being used in the device with their intended usage.<br>In case, hardware based random number generators are being used, vendors shall submit the following:<br>1. Datasheet of the SoC<br>2. Technical specifications of the device regarding random generators<br>In case, software based random number generators are being used, vendors shall provide the libraries being used for the same. |
| 2. | Software/Firmware | 2.1 Verify that memory protection controls such as ASLR and DEP are enabled by the embedded/IoT operating system, if applicable. | Testing, in presence of OEM team, to verify the declared memory protection controls available and enabled in the device using command line-based tools/commands or any other open-source tool like DEP, EMET tool. | Vendor shall submit the declaration of the memory protection controls available and enabled in the device. |
| | | 2.2 Verify that the firmware apps protect data-in-transit using transport layer | 1. Verifying that strong encryption algorithms and secure TLS version is supported by the device to establish secure | The vendor shall submit the specifications and documentation related to the configurations available in the applications and |

| | | | | |
|---|---|---|---|---|
| | | security. | communication.<br>2. Verifying that device properly validates the server's TLS certificate to ensure that it is trusted and has not been tampered with.<br>3. Testing for vulnerabilities which can affect the security of TLS connection such as padding oracle attacks, or weak cipher suites.<br>4. Using tools such as Nmap to identify open ports through which device can be accessed leading to unintended data retrieval.<br>5. Verifying that theTLS session(s) are resistant to attemptsof interception and decryption of network traffic using man-in-the-middle attacks using tools like Burpsuite. | firmware related to transport layer security. |
| | | 2.3 Verify that the firmware apps validate the digital signature of server connections. | 1. Identifying the scenarios when the device establishes the server connections with the external world and verifying the following:<br>• Security features, related to secure server connections and digital signature validation as implemented like strong cipher suites, secure TLS version, SSL pinning etc. supported by code walkthrough.<br>• Proper certificate validation, certificate chain validation and certificate revocation checks are implemented in the device.<br>2. Testing for vulnerabilities which can affect the security of TLS connection such as padding oracle attacks, or weak cipher suites. | Vendor shall submit a document mentioning the use-cases when the device establishes server connections with the external world, with detailed information about the security measures in place while validating the digital signatures of the server connections. |

| | | | | |
|---|---|---|---|---|
| | | | 3. Using tools such as Nmap to identify open ports through which device can be accessed<br><br>leading to unintended data retrieval.<br>4. Verifying that TLS session(s) are resistant to attemptsof interception and decryption of network traffic using man-in-the-middle attacks using tools like Burpsuite. | |
| | | 2.4 Verify that any use of banned C functions are replaced with the appropriate safe equivalent functions. | Secure code review [both automated and manual], in presence of OEM team, using a licensed static analysis tool through any of the following approaches:<br>1. Visit to the evaluation agency by the vendor with the firmware code and installing the licensed static analysis tool available with the evaluation agency in their systems. [Recommended]<br>2. Visit to the evaluation agency by the vendor with the firmware code and any licensed static analysis tool available with them and demonstrating the code review activity in the presence of representatives of evaluation agency.<br>3. Giving a remote access of the systems at vendor site to the evaluation agency for installing their licensed static analysis tool available with them.<br>4. Giving a remote access of the systems at vendor site to the evaluation agency containing the firmware code along with the licensed static analysis tool available with the vendors. | Vendor shall provide :<br>1. Firmware binaries for code review.<br><br>2. Internal code review reports |
| | | 2.5 Verify that each firmware maintains a software bill of materials cataloging third party | Verification of the submitted list of third-party components by running automated tools like FACT on the firmware.<br>Identifying vulnerabilities | Vendor shall submit the following:<br>1. Documentation for information on software bill of materials, including third-party components and versions. |

| | | | | |
|---|---|---|---|---|
| | | components, versioning, and published vulnerabilities. | in the third-party component(s) through publically available vulnerability databases<br>Verification and validation of the process defined by the vendor for providing regular security updates and patches for the firmware to address any known vulnerabilities in third-party components. | 2. Organization process and policies for the following:<br>• Addressing and patching any identified vulnerabilities in third-party components.<br>• Informing the customers about the security issues or vulnerabilities and providing security updates and patches for the same.<br>3. Configuration management system and related policies for maintaining firmware and third-party binaries, libraries and frameworks along with the patches/fixes issued to the devices. |
| | | 2.6 Verify all code including third-party binaries, libraries, frameworks are reviewed for hardcoded credentials (backdoors). | Independent secure code review [both automated and manual] using a licensed static analysis tool through any of the following approaches:<br>1. Visit to the evaluation agency by the vendor with the firmware code and installing the licensed static analysis tool available with the evaluation agency in their systems. [Recommended]<br>2. Visit to the evaluation agency by the vendor with the firmware code and any licensed static analysis tool available with them and demonstrating the code review activity in the presence of representatives of evaluation agency.<br>3. Giving a remote access of the systems at vendor site to the evaluation agency for installing their licensed static analysis tool available with them.<br>4. Giving a remote access of the systems at vendor site to the evaluation agency containing the firmware code along with the licensed static analysis tool available with the vendors. | Vendor shall provide:<br>1. Firmware binaries for code review.<br>2. Internal code review reports |

| | | | | |
|---|---|---|---|---|
| | | 2.7 Verify that the firmware apps pin the digital signature to a trusted server(s). | 1. Identifying the scenarios when the device establishes the server connections with the external world and verifying the following:<br>• Security features, related to secure server connections and digital signature validation as implemented like strong cipher suites, secure TLS version, SSL pinning etc. supported by code walkthrough.<br>• Proper certificate validation, certificate chain validation and certificate revocation checks are implemented in the device. | Vendor shall submit a document mentioning the use-cases when the device establishes server connections with the external world, with detailed information about the security measures in place while validating the digital signatures of the server connections. |
| | | 2.7 Verify security controls are in place to hinder firmware reverse engineering (e.g.removal of verbose debugging symbols). | Testing, in presence of OEM team, to verify the security controls as provided by the vendor to hinder firmware reverse engineering. | Vendor shall submit the documentation regarding the security controls in place to hinder firmware reverse engineering. |
| | | 2.8 Verify that the firmware update process is not vulnerable to time-of-check vs time-of-use attacks. | Testing, in presence of OEM team, to verify the measures implemented in the device to make it resistant to time-of-check vs.time-of-use attacks. | Vendor shall submit the measures implemented in the device to make it resistant to time-of-check vs. time-of-use attacks. |
| | | 2.9 Verify the device uses code signing and validates firmware upgrade files before installing. | Testing, in presence of OEM team, to verify the following:<br>1. Device gets successfully updated with the documented secure upgrade process when a valid update package is provided.<br>2. Device does not boot up when a tampered update package (like with missing signature, invalid signature) is provided. | Vendor shall submit the process of achieving secure firmware upgrade which should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented. |

| | | | | |
|---|---|---|---|---|
| | | 2.10 Verify that the device cannot be downgraded to old versions (anti-rollback) of valid firmware. | Testing, in presence of OEM team, to verify that the device cannot be downgraded to old versions (anti-rollback) of valid firmware. | Vendor shall submit the process of achieving secure firmware upgrade which should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented. |
| | | 2.11 Verify that firmware can perform automatic firmware updates upon a predefined schedule. | Verification shall be done as per the applicable scenario:<br>**Case 1: Automatic OTA updates are available:**<br>A standard operating procedure for issuing automatic updates/upgrades to the in-field devices is required to be submitted by the vendor which can then be evaluated by the evaluation agency as per C20, C21 and C22 security requirement of OWASP open standard.<br>**Case 2: Automatic OTA updates are not available and vendor provides manual updates:**<br>A standard operating procedure for issuing manual updates/upgrades to the in-field devices is required to be submitted by the vendor which can then be evaluated by the evaluation agency as per C20, C21 and C22 security requirement of OWASP open standard. | Vendor shall provide the following:<br>1. Modes of updates available i.e. automatic, manual or both.<br>2. Organizational process and policies regarding the issuing of updates to the devices. |
| 3. | Secure Process Conformance | 3.1 Verify that wireless communications are mutually authenticated. | Testing, in presence of OEM team, to verify the process of mutual authentication as laid down in the documentation by the vendor. | Vendors shall provide the documentation regarding the process of mutual authentication as implemented in the device when wireless communications are initiated.<br>In case, the device does not support wireless communications, the vendor shall provide a declaration for the same. |
| | | 3.2 Verify that wireless communications are sent over an encrypted | Identifying all the security mechanisms being used in the communication process verification through: | Vendors shall provide the documentation regarding the security measures implemented in the device to prevent tampering of the data |

| | | | | |
|---|---|---|---|---|
| | | channel. | • Testing, in presence of OEM team<br>• Code review<br>• Process audit of the key-life cycle process | being sent through wireless mode of communication.<br><br>In case, the device does not support wireless communications, the vendor shall provide a declaration for the same. |
| | | 3.3 Verify that whether trusted sources are being used for sourcing the components of the device i.e. trusted supply chain through a managed Bill of materials for critical hardware components (related to security functions like SoC) is in use. | | Vendor shall submit Bill of materials for critical hardware components (related to security functions like SoC). |
| | | 3.4 Supply chain risk identification, assessment, prioritization, and mitigation shall be conducted. Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption, post-incident summary documents need to be submitted and demonstrate the same. | | Vendor shall submit the following:<br>Supply chain risk identification, assessment, prioritization, and mitigation documents.<br>Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption, post-incident summary documents. |
| | | 3.5 Verify the no proprietary network protocols are being used in the device. If yes, then complete implementation details and the source code for the same shall be provided. | | Document for Network protocols used in the device. |
| 4. | Security Conformance at | 4.1 Design and architecture details till the PCBA and SoC | | Design and architecture documents till the PCBA and SoC level. |

| | | | | |
|---|---|---|---|---|
| | product development stage | level to be provided to aid in counterfeit mitigation and malware detection. | | |
| | | 4.2 Threat mitigation strategies for tainted and counterfeit products shall be implemented as part of product development. | Process and method artifacts need to be submitted and demonstrate the same. | |
| | | 4.3 One or more up-to-date malware detection tools shall be deployed as part of the code acceptance and development processes.<br>Malware detection techniques shall be used before final packaging and delivery (e.g., scanning finished products and components for malware using one or more up-to-date malware detection tools). | List of components that have been identified as requiring tracking targets of tainting/counterfeiting, CM tool.<br>Quality assurance process need to be submitted and demonstrate the same. | |
| | | 4.4 Supply chain risk identification, assessment, prioritization, and mitigation shall be conducted. | | Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption, post-incident summary documents need to be submitted and demonstrate the same. |

Uploaded by Dte. of Printing at Government of India Press, Ring Road, Mayapuri, New Delhi-110064
and Published by the Controller of Publications, Delhi-110054.

MANOJ KUMAR VERMA

**W-43/11/2021-IPHW**
**Government of India**
**Ministry of Electronics and Information Technology**
**(IPHW Division)**

Electronics Niketan,
6, CGO Complex,
Lodhi Road, New Delhi-110003.

Dated: 11 Mar, 2024

## OFFICE MEMORANDUM

**Subject: -Advisory on the Threat of Information Leakage through CCTV/ Video Surveillance system (VSS)/ Digital Video Recorders /Network Video Recorders-reg**

The reference is made to the concerns raised by various Ministries/Departments regarding the security implications associated with the deployment of Closed-Circuit Television (CCTV) Cameras and the conduct of cyber auditing and testing of hardware pertaining to CCTV cameras and other Internet of Things (IoT) devices. The Ministry of Electronics and Information Technology (MeitY) has formulated comprehensive security guidelines for CCTV cameras as included in **Annexure 'A'**.

2. In light of these concerns, Government Ministries/Departments are strongly advised to adhere to the guidelines outlined within the ambit of the Public Procurement Orders to safeguard the overall security and integrity of CCTV Cameras and IoT Devices.

3. This issues with the approval of the Competent Authority.

**(Asha Nangia)**
**Group Coordinator & Scientist-'G'**
**Ph. 011-24301965**

**To,**

**i) Secretaries of All Ministries/Department of Government of India**

**ii) Chief Secretaries/Administrators of Union Territories/National Capital Territory of Delhi**

**Annexture- 'A'**

A video surveillance system, also known as Closed-Circuit Television (CCTV) system, is a collection of cameras and other related equipment used to monitor and record activities in a specific area commonly used for security and surveillance purposes.

2. Key components of a video surveillance system typically include cameras, (Analog, Digital, IP Cameras), Video Management System (VMS) Software, Storage (Network Video Recorders (NVRs) or Digital Video Recorders (DVRs)), Power Supply etc.

3. While these surveillance technologies undoubtedly offer a range of benefits and are valuable tools for monitoring and security, they also raise certain concerns and risks. Some of the growing risks associated with CCTV systems include data security, privacy breach, hacking and cyber-attack etc. Various incidents have also been reported due to security flaw in the surveillance cameras.

4. The cybersecurity is an ongoing process, so staying vigilant and keeping system up to date with the latest security practices can significantly enhance the security of CCTV system and protect it from potential threats and unauthorized access. In this regard, the following measures are advised to minimize the risk associated with CCTV surveillance system:

i) The Rules and regulations as applicable, notified by the Government or procurement of goods and services must be followed e.g.
   a) Public procurement Order (Make in India), 2017
   b) Electronics and Information Technology Goods (Requirement of Compulsory Registration) Order, 2021

ii) BIS has formulated Blank Detail Specification (BDS) for IS 16910 for performance requirements of CCTVs. The procuring government agency can stipulate their own technical requirements for the parameters listed in the BDS and the testing can be done as per the test methods prescribed in the standard.

iii) The procurement of Video Surveillance System from the brand having history of security breaches and data leakages should be avoided.

iv) **Hardware Security**: For the Hardware Security testing of CCTV cameras, the government agencies should use the testing infrastructure available with Standardization Testing and Quality Certification (STQC) Laboratory or any other agency notified by MeitY from time to time for testing the CCTVs as per the Essential Requirement(s) notified under the PPO for CCTV.

v) **Network Security**: The general cyber security practices for installation and monitoring should be also be adopted. Maintain the network isolation (Air-Gap) from the public network to minimize the risk of unauthorized access and potential cyberattacks. Wherever, air gap is not possible, Network segmentation, secure tunnel/Virtual Private Network (VPN) /Dedicated Lease Line etc. should be used for restricting access to CCTV systems and isolate them from critical infrastructure and sensitive data. Use MAC address binding to prevent the unauthorized access by unidentified devices.

vi) **Secure Physical Access:** Restrict physical access to the CCTV control room and equipment. Only authorized personnel should have access to the system. Use locks, access control systems, and surveillance measures to protect the equipment.

vii) **Strong Passwords:** Change default passwords immediately upon installation and use strong, unique passwords for all cameras, recorders, and access points. Avoid using easily guessable information or common words.

viii) **Regular Firmware Updates:** Manufacturers often release updates that address security vulnerabilities. Regularly check for updates and apply them promptly keeps the firmware and software of your CCTV devices up to date.

ix) **Encryption of Data:** Ensure all communication between cameras, recorders, and viewing devices is encrypted. This prevents unauthorized individuals from intercepting and accessing sensitive information.

x) **Disable Unused Features:** Turn off or disable any features and services that are not necessary for the proper functioning of the CCTV system. Each enabled feature potentially introduces another security vulnerability.

xi) **Secure Remote Access:** If remote access is required for maintenance or monitoring, implement a secure VPN (Virtual Private Network) for remote connections. Avoid exposing the system directly to the internet whenever possible. IPBEUs (IP-Based Encryption Unit) to safeguard data transmission between cameras and recording devices, Lease Line for dedicated and secure

network connectivity and Implementation of data diodes to ensure unidirectional flow of information, enhancing security.

xii) **Regular Auditing and Monitoring:** Monitor the CCTV system logs for unusual activities and potential security breaches. Regularly audit the system to ensure that everything is functioning correctly and there are no unauthorized access attempts.

xiii) **Physical Camera Security:** Position cameras in a way that prevents tampering and vandalism. Use vandal-resistant camera housings and install them in high and secure locations where they are less likely to be tampered with.

xiv) **User Access Control:** Implement a strict access control policy to limit the number of individuals who can access the CCTV system and its data. Assign different levels of access based on roles and responsibilities.

xv) **Data Storage and Retention:** Ensure proper data storage and retention policies are in place. Securely store recordings and define how long data should be retained before it gets automatically deleted. Data Storage should be in terms of storage duration (number of Days) based on operational requirements rather than storage capacity. The data storage of all CCTVs installed at Government Establishment/Public Places should be mandated to be within the India even if it is stored in cloud platforms.

xvi) **Staff Training:** Provide comprehensive training to employees and system administrators on security best practices. Make sure they understand the potential risks and how to mitigate them effectively.

xvii) **Regular Security Assessments:** Conduct periodic security assessments and penetration tests to identify vulnerabilities and weaknesses in the CCTV system. Address any issues discovered promptly.

xviii) **Tender/RFP** should encompass both Hardware and Software parts of the Bill of Materials (BoM) combined presenting comprehensive specifications for these components to facilitate the interoperability of the HW/SW as a whole in the VSs system. Model Technical Specifications/Guidelines for CCTVs/VSS issued by MHA from time to time, should be adopted while formulating the technical specifications for procurement of CCTV/VSS.

xix) **CCTV Device testing and certification:** CCTV Cameras (Analog/ IP/ Analog Speed Dome/ IP Speed Dome) should comply with the Essential Requirements (ERs) notified as part of the PPO for CCTV in Gazatte of India (EXTRAORDINARY, PART II—Section 3—Sub-section (ii) dated 7th March,

2024, at Sr. No. No. 1062) to ensure the security of the VSS / CCTV systems, as amended from time to time. The security testing certificate for CCTV/VSS to be issued by Standardisation Testing and Quality Certification (STQC) Laboratory or any other agency notified by MeitY from time to time. The validity of the test report issued by STQC Lab will be three years from the date of issue of the report.

5. In this regard, the Government Ministries, Departments are advised to instruct the Chief Information Security Officers (CISOs) of their respective organizations and subordinate organizations for enforcing the above measures to address the security threats of the CCTV network vulnerability and to ensure the overall security and integrity of CCTV/Video Surveillance Systems.

======**********======

रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-22102024-258138
CG-DL-E-22102024-258138

असाधारण
EXTRAORDINARY

भाग I—खण्ड 1
PART I—Section 1

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 300] नई दिल्ली, मंगलवार, अक्तूबर 22, 2024/आश्विन 30, 1946
No. 300] NEW DELHI, TUESDAY, OCTOBER 22, 2024/ASVINA 30, 1946

## संचार मंत्रालय

## (दूरसंचार विभाग)

## अधिसूचना

नई दिल्ली, 21 अक्तूबर, 2024

**विषय: सरकारी अधिप्राप्ति (मेक इन इंडिया को प्राथमिकता) आदेश 2017- दूरसंचार उत्पादों, सेवाओं अथवा कार्यों संबंधी अधिसूचना - के संबंध में।**

**फा. सं. 18-10/2017-आईपी.—संदर्भ:** i) औद्योगिक नीति एवं संवर्धन विभाग (डीआईपीपी) आदेश संख्या पी-45021/2/2017-बी.ई.-II दिनांक 15.06.2017

ii) औद्योगिक नीति और संवर्धन विभाग (डीआईपीपी) आदेश सं. पी-45021/2/2017-पीपी (बीई-II) संशोधन दिनांक 28.05.2018

iii) उद्योग संवर्धन और आंतरिक व्यापार विभाग (डीपीआईआईटी) आदेश सं. पी-45021/2/2017 (बी.ई.-II) संशोधन दिनांक 29.05.2019

iv) उद्योग संवर्धन और आंतरिक व्यापार विभाग (डीपीआईआईटी) आदेश सं. पी-45021/2/2017 (बी.ई.-II) संशोधन दिनांक 04.06.2020



Page 227 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

**v) उद्योग संवर्धन और आंतरिक व्यापार विभाग (डीपीआईआईटी) आदेश सं. पी-45021/2/2017 (बी.ई.-II) संशोधन दिनांक 16.09.2020**

**vi) उद्योग संवर्धन और आंतरिक व्यापार विभाग (डीपीआईआईटी) आदेश सं. पी-45021/2/2017-पीपी (बी.ई.-II)-खंड(4) खंड.II संशोधन दिनांक 19.07.2024**

सरकार ने पूर्ववर्ती औद्योगिक नीति और संवर्धन विभाग (डीआईपीपी) के दिनांक 15.06.2017 के आदेश संख्या पी-45021/2/2/2017-बीई-II के माध्यम से सरकारी अधिप्राप्ति (मेक इन इंडिया को प्राथमिकता), आदेश 2017 (इसके बाद "पीपीपी-एमआईआई आदेश" के नाम से जाना गया) जारी किया था जिसे 'मेक इन इंडिया' को प्रोत्साहन देने और आय तथा रोज़गार बढ़ाने के उद्देश्य से भारत में वस्तुओं और सेवाओं के विनिर्माण और उत्पादन को बढ़ावा देने के लिए दिनांक 28.05.2018, 29.05.2019, 04.06.2020, 16.09.2020 और 19.07.2024 के आदेशों द्वारा संशोधित किया गया था।

2. तदनुसार दूरसंचार विभाग ने एतद्वारा दिनांक 29.08.2018 और 31.08.2021 की अपनी पिछली अधिसूचना संख्या 18-10/2017-आईपी का अधिक्रमण करते हुए यह अधिसूचना जारी की है।

3. यह अधिसूचना कंपनी अधिनियम में यथा परिभाषित सरकारी कंपनियों सहित भारत सरकार के अधीन सभी संबद्ध अथवा अधीनस्थ कार्यालयों या स्वायत्त निकायों और/अथवा सभी केंद्रीय स्कीमों/केंद्रीय क्षेत्र की स्कीमों के अंतर्गत अधिप्राप्ति करने वाले राज्यों और स्थानीय निकायों द्वारा की गई अधिप्रापण के संबंध में लागू होगी जहां यह स्कीम पूर्ण रूप से या आंशिक रूप से भारत सरकार द्वारा वित्त पोषित की जाती है। यह अधिसूचना उन परियोजनाओं पर भी लागू होगी जिनमें डिजिटल भारत निधि द्वारा वस्तुओं, सेवाओं या कार्यों का वित्तपोषण किया जा रहा हो अथवा उन्हें बोलियों के माध्यम से आवंटित किया जा रहा हो।

4. डीपीआईआईटी के पीपीपी-एमआईआई आदेश दिनांक 19.07.2024 के खंड 2, 3 और 11 के अनुसार अधिसूचित किया जाता है कि **तालिका-क** में सूचीबद्ध दूरसंचार उत्पादों, सेवाओं और कार्यों में पर्याप्त स्थानीय क्षमता और स्थानीय प्रतिस्पर्धा है। श्रेणी-I के स्थानीय आपूर्तिकर्ता को तालिका-क में प्रत्येक मद के लिए निर्दिष्ट न्यूनतम घरेलू सामग्री कंटेंट (एमएलसी) की आवश्यकताओं को पूरा करना चाहिए। तालिका-क में प्रत्येक मद के संबंध में कुल घरेलू सामग्री (एलसी) में से डिजाइन के लिए एलसी प्रतिशत की अधिकतम सीमा भी विनिर्दिष्ट की गई है। इनपुट को घरेलू सामग्री (एलसी) के रूप में योग्यता प्राप्त करने के लिए शर्तें तालिका-ख में विनिर्दिष्ट की गई हैं।

5. डीपीआईआईटी के पीपीपी-एमआईआई आदेश दिनांक 19.07.2024 के खंड 2 क के अनुसार दूरसंचार और नेटवर्किंग उत्पादों के लिए पीएलआई स्कीम के अंतर्गत उत्पादों का निर्माण करने वाले और प्रोत्साहन प्राप्त करने वाले विनिर्माताओं की सूची समय-समय पर https://dot.gov.in/public-procurement-preference-make-india और https://pli-telecom.udyamimitra.in/ पर प्रकाशित और अपलोड की जाएगी। ऐसे विनिर्माताओं को विनिर्दिष्ट अवधि तक सूची में विनिर्दिष्ट उत्पादों के लिए श्रेणी-।। के स्थानीय आपूर्तिकर्ता माना जाएगा।

6. डीपीआईआईटी के पीपीपी-एमआईआई आदेश दिनांक 19.07.2024 के खंड 9 (क) के संदर्भ में निविदा, बोली या अनुरोध करते समय आपूर्तिकर्ता फार्म-1 में स्व-प्रमाणन संबंधी सूचना प्रदान करेगा जिसमें यह विनिर्दिष्ट किया जाएगा कि प्रस्तावित मद (मदें) न्यूनतम घरेलू सामग्री (सामग्रियां) की आवश्यकताओं को पूरा करती है और उस स्थान (स्थानों) का विवरण देगा जहां घरेलू मूल्य संवर्धन किया गया है।

7. डीपीआईआईटी के पीपीपी-पीएमआई आदेश दिनांक 19.07.2024 के खंड 9 (ङ) के संदर्भ में शिकायतों की जांच करने और यादृच्छिक आधार पर स्थानीय सामग्री के संबंध में स्व-घोषणाओं और लेखा परीक्षकों/लेखाकारों के प्रमाणपत्रों का स्वतंत्र रूप से सत्यापन करने के लिए एतद्वारा निम्नलिखित समिति का गठन किया गया है:

| | |
|---|---|
| क) उप महानिदेशक (टीसी), टीईसी, नई दिल्ली | - अध्यक्ष |
| ख) निदेशक (तकनीकी), सी-डॉट | - सदस्य |
| ग) अध्यक्ष द्वारा चुना गया कोई अन्य सदस्य | - सदस्य |

घ) डीजी, टीईपीसी - सदस्य

ङ) निदेशक (वित्त), दूरसंचार विभाग - सदस्य

च) निदेशक (आईपी) - सदस्य

छ) निदेशक, टीईसी - संयोजक

8. पीपीपी-एमआईआई के दिनांक 19.07.2024 के आदेश के खंड 9 (च) के संदर्भ में दो लाख रुपये का शिकायत शुल्क अथवा घरेलू रूप से आपूर्ति किए गए दूरसंचार उत्पादों, सेवाओं अथवा कार्यों के मूल्य का 1% (जो भी अधिक हो, अधिकतम 5 लाख रुपये तक) का भुगतान अनिवार्य रूप से डिमांड ड्राफ्ट अथवा ऑनलाइन द्वारा किया जाना चाहिए और शिकायतकर्ता की शिकायत के साथ दूरसंचार इंजीनियरिंग केंद्र (टीईसी) में जमा किया जाना चाहिए। यदि शिकायत गलत पाई जाती है तो शिकायत शुल्क जब्त कर लिया जाएगा। हालांकि यदि शिकायत आंशिक या पूर्ण रूप से सही पाई जाती है, तो शिकायतकर्ता का जमा शुल्क बिना किसी ब्याज के वापस कर दिया जाएगा।

9. समिति के निष्कर्षों को दिनांक 19.07.2024 के पीपीपी-एमआईआई के आदेश के खंड 9 के अनुसार उचित कार्रवाई के लिए प्रापण इकाई को भेजा जाएगा।

10. **तालिका-क** में सूचीबद्ध उत्पादों, सेवाओं अथवा कार्यों के लिए जिनके पास संबद्ध टीईसी जीआर / आईआर है, प्रापण इकाई को न्यूनतम आवश्यकता के रूप में संबंधित टीईसी जीआर / आईआर विनिर्दिष्ट करना होगा।

11. स्टार्ट-अप (उद्योग संवर्धन और आंतरिक व्यापार विभाग द्वारा पंजीकृत) के लिए पूर्व टर्नओवर और पूर्व अनुभव की शर्त में छूट दी जा सकती है बशर्ते कि स्टार्ट-अप आवश्यक गुणवत्ता और तकनीकी विशिष्टताओं को पूरा करता हो।

12. स्वदेशी प्रौद्योगिकियों का समर्थन और संवर्धन करने के लिए प्रूफ ऑफ कॉन्सेप्ट (पीओसी) को योग्यता अनुभव, जहां कहीं भी लागू हो, के विकल्प के रूप में निविदाओं और आरएफपी में शामिल किया जा सकता है।

13. उल्लेखनीय है कि देश में फिलहाल स्वदेशी प्रौद्योगिकी वाले 5जी उत्पादों का परीक्षण किया जा रहा है। तालिका-क की समय-समय पर समीक्षा की जाएगी और विनिर्माण क्षमता के आधार पर 5जी उत्पादों/वर्चुअल राउटर को शामिल करने पर विचार किया जाएगा। घरेलू विनिर्माताओं और उनके संघों (एसोसिएशन) को प्रोत्साहित किया जाता है ताकि वे दूरसंचार विभाग को समय-समय पर सक्रिय रूप से विनिर्माण क्षमता का साक्ष्य usip.hq-dot@gov.in पर ईमेल द्वारा उपलब्ध कराएं ताकि ऐसे उत्पादों को शामिल किया जा सके।

14. आयातित उत्पादों की पेशकश करने वाले बोलीदाता गैर-स्थानीय आपूर्तिकर्ताओं की श्रेणी में आएंगे। वे परिवहन, बीमा, स्थापना, कमीशनिंग, प्रशिक्षण और एएमसी/सीएमसी आदि जैसी बिक्री के बाद सेवा सहायता जैसी सेवाओं का स्थानीय मूल्यवर्धन के रूप में दावा करके स्वयं को श्रेणी-1 स्थानीय आपूर्तिकर्ता/श्रेणी-2 स्थानीय आपूर्तिकर्ता होने का दावा नहीं कर सकते।

15. यह अधिसूचना अधिसूचित होने की तारीख से लागू होगी। स्पष्ट किया जाता है कि इस अधिसूचना में निहित विशिष्ट शर्तों को छोड़कर समय-समय पर संशोधित सरकारी अधिप्राप्ति (मेक इन इंडिया को प्राथमिकता) आदेश 2017 की अन्य सभी शर्तें प्रभावी हैं और इनका सख्ती से पालन किया जाना है।

**तालिका-क**

| **क्र. सं.** | **प्रोडक्ट केटेगरी** | **एचएसएन कोड** | **उत्पाद का विवरण** | **मिनिमम लोकल कंटेंट (एमएलसी) (% में)** | **कुल एलसी में से डिजाइन के लिए एलसी की अधिकतम सीमा (% में)** |
|---|---|---|---|---|---|
| 1 | एन्क्रिप्शन/ यूटीएम (यूनिफाइड थ्रेट मैनेजमेंट) प्लेटफ़ॉर्म (टीडीएम और आईपी) | 85176290 | टीडीएम (टाइम डिवीजन मल्टीप्लेक्स) | 65 | 55 |
| | | | आईपी (इंटरनेट प्रोटोकॉल) | 65 | 55 |

| | | | | | |
|---|---|---|---|---|---|
| 2 | आईपी/ एमपीएलएस कोर राउटर्स/ एज/एग्रीगेशन/ राउटर | 85176290 | आईपी एज, एग्रीगेशन और कोर राउटर (समग्र क्षमता <=1 टीबीपीएस) | 60 | 40 |
| | | | सेल साइट राउटर (सीएसआर); (कुल क्षमता ≤1.2 टीबीपीएस) जिसमें वर्चुअल राउटर शामिल हैं | 60 | 40 |
| | | | एसडी-डब्ल्यूएएन राउटर्स (एसडीएन केटेगरी ) (इंटरफ़ेस =<10 जीबीपीएस) | 60 | 40 |
| 3 | मैनेज्ड लीज़्ड लाइन नेटवर्क इक्विपमेंट, आईपी बेस्ड एक्सेस सिस्टम-डीएसएल | 85176290, 85176990 | सेंट्रल ऑफिस इक्विपमेंट और डीएसएल/एचडीएसएल/एस-एचडीएसएल के सीपीई | 60 | 40 |
| 4 | ईथरनेट स्विचेज (एल2 और एल 3) | 85176290 | एल2/एल3 ईथरनेट स्विच 1-100 जीबीई स्टैकेबल / स्टैंडअलोन / मॉड्यूलर स्विच, कोर / डिस्ट्रीब्यूशन / एक्सेस लेयर्स (पीओई / पीओई + सहित) के लिए) | 60 | 40 |
| | | | | | |
| | | | इंडस्ट्रियल ग्रेड एलएएन 1, 10 जीबीई पीओई/पीओई+/ नॉन -पीओई स्विच (ईथरनेट पर पावर) | 60 | 40 |
| 5 | आईपी आधारित सॉफ्ट स्विच, आईएमएस, यूनिफाइड कम्युनिकेशन सिस्टम | 85176290, 85176990 | आईपी पीबीएक्स / यूनिफाइड कम्युनिकेशन सिस्टम (यूसीएस) | 60 | 40 |
| | | | यूसीएस ( नॉन-आईएमएस बेस्ड): | 60 | 40 |
| 6 | वायरलेस पीएबीएक्स / आईपी पीबीएक्स | 85176290 | वायरलाइन पीएबीएक्स/सर्विस पीबीएक्स | 65 | 45 |
| 7 | मीडिया गेटवे | 85176290, 85176990 | मीडिया गेटवे | 65 | 45 |
| 8 | कस्टमर प्रीमाइसेस इक्विपमेंट (सीपीई) (वाई-फाई एक्सेस पॉइंटस, कम क्षमता वाले राउटर्स, मीडिया कन्वर्टर सहित), | 85176290, 85176990 | सीपीई ( वाई - फाई अभिगम बिंदु और राउटर्स सहित), | 50 | 30 |
| | | | मीडिया कनवर्टर | 50 | 30 |
| | | | टीडीएम ओवर आईपी कनवर्टर | 50 | 30 |

| | | | | | |
|---|---|---|---|---|---|
| | सीपीई - एनएफवी / एसडीएन / लीज्ड-लाइन मोडेम | | सीपीई - एनएफवी/एसडीएन (वर्चुअलाइज्ड सीपीई विथ क्लाउड मैनेजमेंट) | 50 | 30 |
| | | | लीज़्ड-लाइन मोडेम एन* 2एमबीपीएस/सर्विस | 50 | 30 |
| 9 | एसडीएच/ एनजी-एसडीएच | 85176290 | एसडीएच/एनजी-एसडीएच (एसटीएम 1/4/16/64) | 65 | 45 |
| 10 | ईथरनेट/एमपीएलएस- टीपी/ पैकेट ऑप्टिकल ट्रांसपोर्ट इक्विपमेंट /पीटीएन सिस्टम | 85176290 | एमपीएलएस- टीपी/ पैकेट ऑप्टिकल ट्रांसपोर्ट इक्विपमेंट/पीटीएन (विद और विदाउट ओटीएन इंटरफेसेस) सिस्टम्स | 65 | 45 |
| 11 | सीडब्ल्यूडीएम सिस्टम | 85176290 | सीडब्ल्यूडीएम (एनx100जी, एनx10जी) | 60 | 40 |
| 12 | डीडब्ल्यूडीएम सिस्टम | 85176290, 85176270 | डीडब्ल्यूडीएम (10जी तक) मक्स/डी मक्स ट्रांसपोंडर/मक्सपोंडर के साथ; आरओएडीएम (रेकॉन्फ़िगराबल ऑप्टिकल ऐड ड्राप मल्टीप्लेक्सर), पैसिव डीडब्ल्यूडीएम एमयूएक्स/डीएमयूएक्स | 60 | 40 |
| 13 | जीपीओएन/एक्सजीपीओएन इक्विपमेंट (ओएनटी और ओएलटी सहित) | 85176290, 85172990 | जीपीओएन/एक्सजीपीओएन इक्विपमेंट (ओएनटी और ओएलटी सहित) | 60 | 40 |
| 14 | एक्सजीएस-पीओएन इक्विपमेंट (ओएनटी और ओएलटी सहित) | 85176290, 85172990 | एक्सजीएस-पीओएन (10जी डीएस - 10जी यूएस) (ओएनटी और ओएलटी सहित) | 60 | 40 |
| 15 | एसडीएच/पीडीएच क्रॉस कनेक्टस | 85176290 | एसडीएच/पीडीएच क्रॉसकनेक्टेड (एसटीएम: 1/4/16/64; ई1/ई3/डीएस3; ईथरनेट इंटरफेसेस) | 60 | 40 |
| 16 | स्मॉल साइज रेडियो सब सिस्टम | 85176290 | माइक्रो 2जी बीटीएस | 60 | 40 |
| 17 | | 85176290, 85176990 | मैक्रो ईनोड बी, टीईसी ईएनबी जीआर (टीडीडी/एफडीडी) के अनुसार | 60 | 40 |
| | | | माइक्रो इनोडबी, टीईसी ईएनबी जीआर (टीडीडी/एफडीडी) के अनुसार | 60 | 40 |

| | | | | | |
|---|---|---|---|---|---|
| | एलटीई/एलटीई-आर बेस्ड मोबाइल सिस्टम, इसके विभिन्न व्युत्पन्न के साथ | | पिको इनोडबी, टीईसी ईएनबी जीआर (टीडीडी/एफडीडी) के अनुसार | 60 | 40 |
| | | | होम बेस स्टेशन/ फेमटो | 60 | 40 |
| | | | ईपीसी | 60 | 40 |
| | | | 4जी एनआईबी स्मॉल सेल | 60 | 40 |
| 18 | वाई-फाई बेस्ड ब्रॉडबैंड वायरलेस एक्सेस सिस्टम - इनडोर | 85176290, 85176990 | इनडोर एपी (802.11 एक्स एमआईएमओ, 2.4 और 5 गीगाहट्र्ज बैंड) | 55 | 35 |
| | | | इनडोर एपी (802.11 एसी एमआईएमओ, 2.4 और 5 गीगाहट्र्ज बैंड) | 55 | 35 |
| 19 | वाई-फाई बेस्ड ब्रॉडबैंड वायरलेस एक्सेस सिस्टम - आउटडोर | 85176290, 85176990 | आउटडोर एपी (802.11एसी - एमआईएमओ 2.4 और 5 गीगाहट्र्ज बैंड) - आईपी67 रेटेड | 55 | 35 |
| | | | आउटडोर एपी (802.11एक्स एमआईएमओ, 2.4 और 5 गीगाहट्र्ज बैंड) | 55 | 35 |
| 20 | वाई-फाई एक्सेस कंट्रोलर (विद इंटरऑपरेबिलिटी और मल्टी-वेंडर एपी सपोर्ट) | 85176290 | टाइप 1: <= 2000 एपी सपोर्ट | 55 | 35 |
| | | | टाइप 2: 5000 एपी सपोर्ट तक | 55 | 35 |
| 21 | ऑथेंटिकेशन, ऑथॉरिज़ेशन एंड एकाउंटिंग (एएए) सर्वर | 85176290 | एएए ब्लॉक (रेडियस) | 50 | 35 |
| | | | एएए ब्लॉक (रेडियस/डायमीटर) | 50 | 35 |
| 22 | रेडियो सिस्टम (आईपी/हाइब्रिड) | 85176290 | रेडियो सिस्टम (आईपी/हाइब्रिड) (5 गीगाहट्र्ज बैंड - लाइसेंस छूट बैंड) | 55 | 35 |
| 23 | सॉफ्टवेयर डिफाइंड रेडियो कॉग्निटिव रेडियो सिस्टम | 85176290 | रगेडाइज्ड हैंडहेल्ड, रगेडाइज्ड या नॉन-रगेडाइज्ड व्हीकल माउंट, पी2पी या पी2एमपी या मोबाइल एडहॉक टोपोलॉजी, अनलाइसेंसड बैंड ऑपरेशन | 55 | 35 |
| 24 | रिपीटर्स (आरएफ/आरएफ-ओवर-ऑप्टिकल), आईबीएस | 85176290, 85177100 | रिपीटर्स (आरएफ/आरएफ-ओवर-ऑप्टिकल), आईबीएस और डिस्ट्रिब्युटेड एंटीना | 60 | 40 |

| | | | | | |
|---|---|---|---|---|---|
| | और डिस्ट्रिब्यूटेड एंटीना सिस्टम (इनडोर/आउटडोर) | | सिस्टम (इनडोर/आउटडोर) जिसमें सक्रिय और निष्क्रिय सहायक उपकरण शामिल हैं | | |
| 25 | वीसैट टर्मिनल सबसिस्टम - ओडीयू/ | 85176290, 85256091 | एंटीना | 50 | 25 |
| 26 | वीसैट हब सबसिस्टम | 85256091 | एनएमएस एच/डब्ल्यू और एस/डब्ल्यू | 50 | 25 |
| | | | एंटीना (>=7 मीटर) और सहायक उपकरण आदि | 50 | 25 |
| 27 | सैटेलाइट फोन (एस बैंड) | 85176990 | वॉयस और डेटा दोनों (9.6 केबीपीएस तक) | 50 | 25 |
| 28 | डिजास्टर कम्युनिकेशन सिस्टम्स आदि, जिसमें बैकपैक सैटेलाइट उत्पाद (एस बैंड) शामिल हैं | 85176990 | पोर्टेबल टर्मिनल वॉयस और डेटा (2 एमबीपीएस यूएल) | 50 | 25 |
| 29 | सैटेलाइट बेस्ड सिस्टम, टर्मिनल जिसमें लोकेशन, रिसोर्सेज ट्रैकिंग (एल, एस और के यू , के ए बैंड) शामिल हैं | 85176990 | टू वे एमएसएस डेटा टर्मिनल (सैटेलाइट रिसीवर विद लोकेशन डेटा) एस - बैंड (विभिन्न एप्लीकेशनों के लिए सैटेलाइट आईओटी डिवाइस यानी पोजीशन ट्रैकिंग, संदेश भेजना आदि) | 50 | 25 |
| | | | वन वे रिसीवर एमएसएस डेटा टर्मिनल (सैटेलाइट ट्रांसमीटर और रिसीवर - वन वे) एस - बैंड (सिंप्लेक्स / हाफ-डुप्लेक्स, मोबाइल सैटेलाइट सर्विस (एमएसएस) टर्मिनल, सैटेलाइट आईओटी डिवाइस) | 50 | 25 |
| 30 | टेलीकॉम नेटवर्क मैनेजमेंट सिस्टम (एनएमएस) इसके विभिन्न व्युत्पन्न के साथ | 85176290 | | 65 | 50 |
| 31 | ऑप्टिकल फाइबर | 9001000 | सिंगल मोड | 50 | 0 |
| 32 | ऑप्टिकल फाइबर केबल | 85447090 | ऑप्टिकल फाइबर केबल (यूजी और ओएच) | 55 | 0 |
| 33 | टेलीकॉम पावर सिस्टम (सौर ऊर्जा सहित) | 85176990 | यूपीएस, पावर प्लांट, इन्वर्टर (सौर ऊर्जा सहित) 0.5-1500 केवीए/ पावर प्लांट: 1-2000 केवीए (मॉड्यूलर) | 55 | 30 |

| | | | | | |
|---|---|---|---|---|---|
| 34 | टेलीकॉम बैटरी (लीड एसिड) | 85176990 | 5000 एएच तक लीड एसिड (वीआरएलए सहित) | 55 | 30 |
| 35 | आईपी ऑडियो/वीडियो फोन/एडेप्टर | 85176990 | आईपी ऑडियो / वीडियो फोन / एडाप्टर | 50 | 15 |
| 36 | आईपी/इंटरनेट सेट-टॉप बॉक्स | 85176990 | आईपी / इंटरनेट सेट-टॉप बॉक्स | 55 | 35 |

एमएलसी%- मेक इन इंडिया दूरसंचार उत्पाद, सेवा या कार्य के रूप में अर्हता प्राप्त करने के लिए कुल सामग्री बिल (उत्पादन लागत) के प्रतिशत के रूप में न्यूनतम स्थानीय सामग्री।

**तालिका-ख**

**दूरसंचार उत्पादों के विनिर्माण के लिए मुख्य इनपुट/स्टेज और घरेलू सामग्री (कंटेंट) के रूप में पात्र बनने के लिए इनपुट संबंधी शर्त**

| **दूरसंचार उत्पादों के विनिर्माण के लिए मुख्य इनपुट/स्टेज *** | **इनपुट को स्थानीय सामग्री के रूप में योग्य बनाने के लिए पूरी की जाने वाली शर्तें** |
|---|---|
| 1) डिजाइन<br>हार्डवेयर डिजाइन<br>सॉफ्टवेयर डिजाइन और विकास | डिजाइन के लिए अधिकतम घरेलू कंटेंट (सामग्री) (एलसी) का प्रतिशत **तालिका-क (अंतिम कॉलम)** के अनुसार अतिरिक्त शर्तों के अधीन है जिसका दावा स्थानीय विनिर्माता द्वारा भारत में आईपीआर सृजित करने के लिए वहन की गई की गई /परिशोधित इन-हाउस/देश में आर एंड डी लागतों के आधार पर दूरसंचार उत्पादों के लिए किया जा सकता है<br>हार्डवेयर डिजाइन के लिए बौद्धिक संपदा अधिकार (आईपीआर) भारत के पास है; एवं सॉफ्टवेयर डिजाइन एवं विकास का कॉपीराइट भारत के पास है। |
| 2) कंपोनेंट<br>इंटीग्रेटेड चिपस (आईसी) - प्रोसेसर, मेमोरी आदि।<br>एक्टिव कंपोनेंट - ट्रांजिस्टर, डायोड आदि।<br>पेसिव कंपोनेंट – रेजिस्टर, केपेसिटर, इंडक्टर आदि। | भारत में विनिर्मित होना चाहिए |
| 3) पीसीबी फेब्रिकेशन | भारत में विनिर्मित होना चाहिए |
| 4) केबल/चेसिस आदि<br>चेसिस<br>केबल<br>रैक<br>हीट सिंक<br>एंक्लोजर | भारत में विनिर्मित होना चाहिए |
| 5) आरएफ कंपोनेंट/सबसिस्टम<br>डुप्लेक्सर/फिल्टर<br>एंटीना | भारत में विनिर्मित होना चाहिए |
| 6) असेंबली/इन्टीग्रेशन/टेस्टिंग# | **तालिका-क** में सूचीबद्ध दूरसंचार उत्पादों के संबंध में असेंबली/इन्टीग्रेशन/टेस्टिंग के लिए घरेलू स्थानीय सामग्री (कंटेंट) (एलसी) की अधिकतम सीमा कुल उत्पाद सामग्री के बिल की 10% होगी। |
| * उत्पाद में उपर्युक्त उल्लिखित कुछ/सभी इनपुट/स्टेज शामिल हो सकते हैं। घरेलू सामग्री (कंटेंट) की गणना करते समय केवल उन इनपुट/स्टेज पर विचार किया जाएगा जो दूरसंचार उत्पाद के विनिर्माण में प्रासंगिक हैं। | |

#यदि किसी सिस्टम या सबसिस्टम को केवल असेंबल/इन्टीग्रेट/टेस्ट किया गया है, तो वास्तविक घरेलू सामग्री (कंटेंट) को सिस्टम/सबसिस्टम की 10% लागत के रुप में माना जाएगा।

**फॉर्म 1**

**दूरसंचार उत्पाद, सेवाओं या कार्यों के लिए घरेलू सामग्री (कंटेंट) (एलसी) के संबंध में स्व-प्रमाणन का प्रारूप 100/- रुपये के गैर-न्यायिक स्टाम्प पेपर पर प्रस्तुत किया जाना है।**

**दिनांक:**

मैं _____**पुत्र/श्री, पुत्री/श्री, पत्नी/श्री**, निवासी _____ एतद्वारा सत्यनिष्ठा से पुष्टि करता/करती हूं और निम्नलिखित घोषणा करता/करती हूं:

कि मैं दूरसंचार विभाग, भारत सरकार के दिनांक_____ की अधिसूचना संख्या:_____ द्वारा जारी किए गए निबंधन और शर्तों का पालन करने के लिए सहमत हूं।

यहां दी गई जानकारी मेरे सर्वोत्तम ज्ञान और विश्वास के अनुसार सही है और मैं एल.सी. का मूल्यांकन करने के प्रयोजन से प्रायण यूनिट या दूरसंचार विभाग, भारत सरकार द्वारा नामित किसी अन्य प्राधिकारी के समक्ष प्रासंगिक रिकॉर्ड प्रस्तुत करने का वचन देता हूँ।

मेरे द्वारा उक्त दूरसंचार उत्पादों/सेवाओं/कार्यों सहित सभी इनपुट की एलसी का सत्यापन किया गया है और मैं इसमें किए गए दावों की सत्यता के लिए जिम्मेदार हूं।

कि यदि यहां उल्लिखित दूरसंचार उत्पाद/सेवाओं/कार्यों की एलसी गलत पाई जाती है और निर्धारित एलसी मानदंडों को पूरा नहीं करती है तो दूरसंचार विभाग, भारत सरकार द्वारा नामित किसी प्राधिकारी के आकलन के आधार पर **मैं और मेरे सांविधिक लेखा परीक्षक या लागत लेखा परीक्षक (यदि लागू हो) ऐसे सभी असत्य/गलत तथ्यों और आंकड़ों के लिए दिनांक 19.07.2024 के डीपीआईआईटी पीपीपी-एमआईआई के आदेश के खंड (9) में विनिर्दिष्ट कार्रवाई के लिए उत्तरदायी होंगे।**

मैं 2 वर्ष की अवधि के लिए कंपनी के रिकॉर्ड में एलसी के लिए अपने दावे की पुष्टि करने के लिए विस्तृत विवरण/सूचना (प्रत्येक उत्पाद के लिए अलग से) रखने के लिए सहमत हूं और इसे किसी भी प्राधिकारी को सत्यापन के लिए उपलब्ध कराऊंगा। मैं अन्य घरेलू विनिर्माताओं/व्यापारियों से खरीदी गई मदों से संबंधित स्थानीय सामग्री (कंटेट) का रिकॉर्ड भी रखूंगा।

[कृपया निम्नलिखित सूचना उपलब्ध करावें]

i स्थानीय आपूर्तिकर्ता का नाम और विवरण (पंजीकृत कार्यालय, विनिर्माण यूनिट का स्थान, कानूनी संस्था की प्रकृति)

ii. वह तिथि जिस दिन यह प्रमाणपत्र जारी किया गया है

iii. दूरसंचार उत्पाद/सेवाएं/कार्य जिसके लिए प्रमाणपत्र प्रस्तुत किया गया है

iv. वह प्रायण एजेंसी जिसे प्रमाण पत्र प्रस्तुत किया गया है

v. दावा किए गए एलसी का प्रतिशत

vi. विनिर्माता यूनिट का नाम और संपर्क विवरण

vii. उत्पाद का विक्रय मूल्य

viii. उत्पाद की फैक्ट्री से बाहर कीमत

ix. माल ढुलाई, बीमा और हैंडलिंग

x. सामग्री का कुल बिल

xi. दूरसंचार उत्पाद/सेवाओं/कार्यों के विनिर्माण के लिए प्रयुक्त इनपुट की सूची और कुल लागत मूल्य

xii. स्थानीय रूप से प्राप्त इनपुट की सूची और कुल लागत। यदि इनपुट का उत्पादन इन-हाउस नहीं किया गया है तो कृपया स्थानीय आपूर्तिकर्ताओं से एलसी प्रमाणपत्र संलग्न करें।

xiii. प्रत्यक्ष या अप्रत्यक्ष रूप से आयातित इनपुट की सूची और लागत

मैं एतद्वारा प्रमाणित करता हूं कि उपर्युक्त आदेश के सभी प्रावधानों और सिद्धांतों/गणना के आधार को पढ़ने के बाद स्थानीय सामग्री (कंटेट) की गणना में निम्नलिखित शामिल नहीं है:

(क) आयातित वस्तुएं स्थानीय स्तर पर पुनर्विक्रेताओं (रिसेलर)/वितरक से प्राप्त की जाती हैं।

(ख) भारत से बाहर भुगतान की गई लाइसेंस फीस / रॉयल्टी / तकनीकी प्रभार

(ग) पुनःपैक किए गए/नवीनीकृत/पुनःब्रांडेड आयातित उत्पादों की खरीद/आपूर्ति

मैं अपने सर्वोत्तम ज्ञान और विश्वास के अनुसार यह भी प्रमाणित करता हूँ कि ऊपर दिए गए सभी विवरण सही और पूर्ण हैं। मैं दिनांक 19.07.2024 के डीपीआईआईटी पीपीपी-एमआईआई के आदेश और दिनांक …….. के डीओटी की पीपीपी-एमआईआई अधिसूचना के निबंधन और शर्तों का पालन करने के लिए सहमत हूँ।

**मैं सहमत हूँ कि घरेलू सामग्री (कंटेट) के संबंध में कोई भी गलत घोषणा देने या एलसी के दावे को प्रमाणित करने में विफल होने पर दिनांक 19.07.2024 के डीपीआईआईटी पीपीपी-एमआईआई के आदेश के खंड (9) में विनिर्दिष्ट दंड लगाया जाएगा।**

मैं यह भी प्रमाणित करता हूं तथा व्यक्तिगत जिम्मेदारी लेता हूं कि मैंने इस आदेश में निर्दिष्ट एलसी की गणनाओं और सिद्धांतों पर ध्यान दिया है तथा एलसी की घोषणा करने के बाद मैं किसी भी आधार पर इसमें परिवर्तन करने का प्रयास नहीं करूंगा। बोली प्रस्तुत करने के बाद एलसी की बोली में किसी भी आधार पर मेरे द्वारा किए गए कोई भी परिवर्तन से मेरी बोली अप्रसांगिक हो जाएगी और मैं ऐसे किसी भी परिवर्तन से उत्पन्न होने वाली सिविल/आपराधिक कार्रवाई के लिए स्वयं को उत्तरदायी मानूंगा। मुझे ज्ञात है मैं सहमत हूं कि बोली के बाद एलसी सामग्री में किया गया कोई भी परिवर्तन भविष्य के संविदाओं/बोलियों से फर्म को ब्लेकलिस्ट करने का वैध आधार भी होगा।

**हस्ताक्षर:**
**नाम:**
**पदनाम: सीईओ/एमडी**
**पता:**
**ईमेल एड्रेस:**
**मोबाइल नंबर:**
**स्थान:**
**दिनांक:**

**<u>अधिसूचना में प्रयुक्त संक्षिप्ताक्षर की सूची</u>**

| क्र. सं. | संक्षिप्ताक्षर | पूर्ण रूप |
|---|---|---|
| 1. | एएए | प्रमाणीकरण प्राधिकरण एवं लेखांकन |
| 2. | एएमसी | वार्षिक रखरखाव अनुबंध |
| 3. | एपी | एक्सेस प्वाइंट |
| 4. | बीबीयू | बेस बैंड यूनिट |
| 5. | बीआईएस | भारतीय मानक ब्यूरो |
| 6. | बी-आरएएस | ब्रॉडबैंड रिमोट एक्सेस सर्वर |
| 7. | बीटीएस | बेस ट्रांसीवर स्टेशन |

| | | |
|---|---|---|
| 8. | सीडॉट | टेलीमेटिक्स विकास केंद्र |
| 9. | सीएमसी | व्यापक रखरखाव अनुबंध |
| 10. | सीपीई | उपभोक्ता परिसर उपकरण |
| 11. | सीएस | केंद्रीय स्कीम |
| 12. | सीएसआर | सेल साइट राउटर |
| 13. | सीएसएस | केंद्रीय क्षेत्र के स्कीम |
| 14. | सीडब्ल्यूडीएम | कोआर्स वेवलेंथ डिवीजन मल्टीप्लेक्सिंग |
| 15. | डीआईपीपी | औद्योगिक नीति और संवर्धन विभाग |
| 16. | डीओटी | दूरसंचार विभाग |
| 17. | डीपीआईआईटी | उद्योग संवर्धन और आंतरिक व्यापार विभाग |
| 18. | डीएसएल | डिजिटल सब्सक्राइबर लाइन |
| 19. | डीएसएलएएम | डिजिटल सब्सक्राइबर लाइन एक्सेस मल्टीप्लेक्सर |
| 20. | डीडब्ल्यूडीएम | डेन्स वेवलेंथ डिवीजन मल्टीप्लेक्सिंग |
| 21. | ई-नोड बी (ईएनबी) | ईवाल्व नोड बी |
| 22. | ईपीसी | इंजीनियरिंग प्रोक्योरमेंट कंस्ट्रक्शन |
| 23. | एफडीडी | फ़्रीक्वेंसी डिवीज़न डुप्लेक्सिंग |
| 24. | जीएनबी | नेक्स्ट जेनरेशन नोड बी |
| 25. | जीएफआर | सामान्य वित्तीय नियम |
| 26. | जीपीओएन | गीगाबिट पैसिव ऑप्टिकल नेटवर्क |
| 27. | जीआर | सामान्य आवश्यकताएँ |
| 28. | जीएसएम | ग्लोबल सिस्टम फॉर मोबाइल |
| 29. | एचडीएसएल | हाई बिट-रेट डिजिटल सब्सक्राइबर लाइन |
| 30. | आईबीएस | एकीकृत बिल्डिंग सिस्टम |
| 31. | आईसी | इंटीग्रेटेड चिप |
| 32. | आईएमएस | आईपी मल्टीमीडिया सबसिस्टम |
| 33. | आईओटी | इंटरनेट ऑफ़ थिंग्स |
| 34. | आईपी | इंटरनेट प्रोटोकॉल |
| 35. | आईपीआर | बौद्धिक संपदा अधिकार |
| 36. | आईआर | इंटरफ़ेस आवश्यकताएँ |
| 37. | लैन | लोकल एरिया नेटवर्क |
| 38. | एल-2 | लैअर-2 |
| 39. | एल-3 | लैअर-3 |
| 40. | एलसी | लोकल कंटेन्ट |
| 41. | एलआई-आयन | लिथियम-आयन |
| 42. | एलटीई | दीर्घकालिक विकास |
| 43. | एलटीई-आर | दीर्घकालिक विकास-रेलवे |

| | | |
|---|---|---|
| 44. | एमआईएमओ | मल्टीपल इनपुट मल्टीपल आउटपुट |
| 45. | एमएलसी | मिनिमम लोकल कंटेन्ट |
| 46. | एमपीएलएस | मल्टी-प्रोटोकॉल लेबल स्विचिंग |
| 47. | एमपीएलएस-टीपी | मल्टीप्रोटोकॉल लेबल स्विचिंग-ट्रांसपोर्ट प्रोफ़ाइल |
| 48. | एमएसएस | मोबाइल सैटेलाइट सर्विस |
| 49. | एमयूएक्स | मल्टीप्लेक्सर |
| 50. | एनएफवी | नेटवर्क फ़ंक्शन वर्चुअलाइज़ेशन |
| 51. | एनजी-पीओएन2 | नेक्स्ट जेनरेशन गीगाबिट पैसिव ऑप्टिकल नेटवर्क 2 |
| 52. | एनआईबी | नेटवर्क इन बॉक्स |
| 53. | एनएमएस | नेटवर्क प्रबंधन प्रणाली |
| 54. | ओएडीएम | ऑप्टिकल ऐड-ड्रॉप मल्टीप्लेक्सर |
| 55. | ओडीयू | आउटडोर यूनिट |
| 56. | ओएलटी | ऑप्टिकल लाइन टर्मिनल |
| 57. | ओएनटी | ऑप्टिकल नेटवर्क टर्मिनल |
| 58. | ओटीएन | ऑप्टिकल ट्रांसपोर्ट नेटवर्क |
| 59. | पी2पी | पॉइंट टू पॉइंट |
| 60. | पी2एमपी | पॉइंट टू मल्टी पॉइंट |
| 61. | पीएबीएक्स | प्राइवेट ऑटो ब्रांच एक्सचेंज |
| 62. | पीबीएक्स | प्राइवेट ब्रांच एक्सचेंज |
| 63. | पीसीबी | प्रिंटेड सर्किट बोर्ड |
| 64. | पीडीएच | प्लेसियोक्रोनस डिजिटल हाइरार्की |
| 65. | पीएमआई | मेक इन इंडिया को प्राथमिकता |
| 66. | पीटीएन | पैकेट ट्रांसपोर्ट नेटवर्क |
| 67. | पीओसी | प्रूफ ऑफ कॉन्सेप्ट |
| 68. | पीओई | पावर ओवर ईथरनेट |
| 69. | पीपीपी-एमआईआई | सार्वजनिक खरीद (मेक इन इंडिया को प्राथमिकता) |
| 70. | पीटीएन | पैकेट ट्रांसपोर्ट नेटवर्क |
| 71. | आरओएडीएम | रीकॉन्फिगरेबल ऑप्टिकल ऐड-ड्रॉप मल्टीप्लेक्सर |
| 72. | आरएंडडी | अनुसंधान और विकास |
| 73. | आरएफ | रेडियो फ्रीक्वेंसी |
| 74. | एस-एचडीएसएल | सिंगल पेयर हाई स्पीड डिजिटल सब्सक्राइबर लाइन |
| 75. | एसडीएच | सिंक्रोनस डिजिटल हाइरार्की |
| 76. | एसडीएन | सॉफ्टवेयर डिफाइन्ड नेटवर्क |
| 77. | एसडी-वैन | सॉफ्टवेयर डिफाइन्ड - वाइड एरिया नेटवर्क |
| 78. | एसटीएम | सिंक्रोनस ट्रांसपोर्ट मॉड्यूल |
| 79. | टीडीडी | टाइम डिवीजन डुप्लेक्सिंग |

| | | |
|---|---|---|
| 80. | टीडीएम | टाइम डिवीजन मल्टीप्लेक्सिंग |
| 81. | टीईसी | दूरसंचार अभियांत्रिकी केंद्र |
| 82. | टीईपीसी | दूरसंचार निर्यात संवर्धन परिषद |
| 83. | यूसीएस | एकीकृत संचार प्रणाली |
| 84. | यूएल | एकीकृत लाइसेंस |
| 85. | यूएसओएफ | सार्वभौमिक सेवा दायित्व निधि |
| 86. | यूटीएम | एकीकृत खतरा प्रबंधन |
| 87. | वीआरएलए | वाल्व रेगुलेटेड लीड एसिड |
| 88. | वीसैट | वेरी स्मॉल एपर्चर टर्मिनल |
| 89. | वाई-फाई | वायरलेस फ़िडेलिटी |
| 90. | एक्सजी-पीओएन | 10 गीगाबिट पैसिव ऑप्टिकल नेटवर्क |
| 91. | एक्सजीएस-पीओएन | 10 गीगाबिट सममित पैसिव ऑप्टिकल नेटवर्क |

अशोक कुमार जैन, उप महानिदेशक

**MINISTRY OF COMMUNICATIONS**

**(Department of Telecommunications)**

**NOTIFICATION**

New Delhi, the 21st October, 2024

**Subject: Public Procurement (Preference to Make in India) Order 2017- Notification of Telecom Products, Services or Works - regarding.**

**F. No. 18-10/2017-IP.—Reference: i) Department of Industrial Policy & Promotion (DIPP) Order No. P-45021/2/2017-B.E.-II dated 15.06.2017**

**ii) Department of Industrial Policy & Promotion (DIPP) Order No. P-45021/2/2017-PP (BE-II) dated 28.05.2018 – Revision**

**iii) Department for Promotion of Industry & Internal Trade (DPIIT) Order No. P-45021/2/2017 (B.E.-II) dated 29.05.2019 – Revision**

**iv) Department for Promotion of Industry & Internal Trade (DPIIT) Order No. P-45021/2/2017 (B.E.-II) dated 04.06.2020 – Revision**

**v) Department for Promotion of Industry & Internal Trade (DPIIT) Order No. P-45021/2/2017 (B.E.-II) dated 16.09.2020 – Revision**

**vi) Department for Promotion of Industry & Internal Trade (DPIIT) Order No. P-45021/2/2017-PP (B.E.-II)-Part(4) Vol.II dated 19.07.2024 – Revision**

The Government had issued the Public Procurement (Preference to Make in India), Order 2017 (hereinafter called as "PPP-MII Order") vide the erstwhile Department of Industrial Policy and Promotion (DIPP) Order No. P-45021/2/2017-B.E.-II dated 15.06.2017 which was further revised vide Orders dated 28.05.2018, 29.05.2019, 04.06.2020, 16.09.2020 and 19.07.2024 to encourage 'Make in India' and to promote manufacturing and production of goods and services in India with a view to enhancing income and employment.

2. Accordingly, the Department of Telecommunications, in supersession of its previous notifications No. 18-10/2017-IP dated 29.08.2018 and 31.08.2021, hereby issues this notification.

3. This Notification shall be applicable in respect of the procurement made by all attached or subordinate offices or autonomous bodies under the Government of India including Government Companies as defined in the Companies Act, and/or the States and Local Bodies making procurement under all Central Schemes/ Central Sector Schemes where the Scheme is fully or partially funded by the Government of India. This Notification shall also be applicable in respect of projects wherein funding of goods, services or works is by the Digital Bharat Nidhi to the extent of having being awarded through bids.

4. In terms of Clause 2, 3 and 11 of the DPIIT's PPP-MII Order dated 19.07.2024, it is hereby notified that telecom products, services and works listed in **Table-A** have sufficient local capacity and local competition. A Class-I

local supplier must meet the Minimum Local Content (MLC) requirement specified against each item in Table-A. Table-A also specifies the maximum ceiling of LC percentage for design out of total LC against each item. The conditions for the inputs to be qualified as Local Content (LC) are specified in Table-B.

5. In accordance with clause 2A of the DPIIT's PPP-MII Order dated 19.07.2024, the list of manufacturers manufacturing products under the PLI scheme for Telecom and Networking products and having received incentive will be published and uploaded from time to time on https://dot.gov.in/public-procurement-preference-make-india and https://pli-telecom.udyamimitra.in/. Such manufacturers will be treated as deemed Class-II local suppliers for the products specified in the list and upto the specified period.

6. In terms of clause 9 (a) of DPIIT's PPP-MII Order dated 19.07.2024, a supplier at the time of tender, bidding or solicitation shall provide self-certification in Form-1 specifying that the item(s) offered meet the minimum local content requirement and shall give details of the location(s) at which the local value addition is made.

7. In terms of clause 9 (e) of the DPIIT's PPP-PMI Order dated 19.07.2024, the following Committee is hereby constituted to examine complaints and conduct independent verification of self-declarations and auditor's/accountant's certificates regarding Local content on random basis:

a) DDG (TC), TEC, New Delhi -Chairperson
b) Director (Technical), C-DOT - Member
c) Any other member(s) as co-opted by the chairperson - Member
d) DG, TEPC - Member
e) Director (Finance), DoT - Member
f) Director (IP) - Member
g) Director, TEC - Convener

8. In terms of clause 9 (f) of DPIIT's PPP-MII Order dated 19.07.2024, a complaint fee of Rs. 2 Lakh or 1% of the value of the locally supplied telecom products, services or works being procured (whichever is higher, up to a maximum of Rs. 5 Lakh) must be paid by Demand Draft or online, and to be deposited with Telecommunications Engineering Centre (TEC), along with the complaint by the complainant. If the complaint is found to be incorrect, the complaint fee shall be forfeited. However, if the complaint is upheld in part or full, deposited fee of the complainant will be refunded without any interest.

9. The Committee's findings shall be forwarded to the procuring entity for appropriate action in accordance with Clause 9 of the DPIIT's PPP-MII Order dated 19.07.2024.

10. For the products, services or works listed in **Table-A** that have an associated TEC GR/IR, the procuring entity must specify the relevant TEC GR/IR as the minimum requirement.

11. The condition of prior turnover and prior experience may be relaxed for Start-ups (registered by Department for Promotion of Industry and Internal Trade), provided that the Start-up meet the necessary quality & technical specifications.

12. To support and promote indigenous technologies, Proof of Concept (PoC) may be included in tenders and RFPs as a substitute for qualifying experience, wherever applicable.

13. It is noted that 5G products with indigenous technology are presently being tested in the country. Table-A shall be reviewed from time to time and addition of 5G products/virtual routers shall be considered based on manufacturing capacity. Domestic manufacturers and their associations are encouraged to pro-actively provide evidence of manufacturing capacity from time to time to DoT to enable inclusion of such products by email to usip.hq-dot@gov.in.

14. The bidders offering imported products will fall under the category of non-local suppliers. They can not claim themselves as Class-I local suppliers/Class-II local suppliers by claiming the services such as transportation, insurance, installation, commissioning, training and after sales service support like AMC/CMC etc. as local value addition.

15. This Notification comes into effect from the date of notification. It is clarified that, except specific conditions contained in this notification, all the other conditions of the Public Procurement (Preference to Make in India) Order 2017 as amended from time to time shall prevail and are to be followed strictly.

**TABLE-A**

| S. No. | Product Category | HSN code | Product Details | Minimum Local Content (MLC) (in %) | Ceiling of LC for Design out of total LC (in %) |
|---|---|---|---|---|---|
| 1 | Encryption/ UTM (Unified threat management) platforms (TDM and IP) | 85176290 | TDM (Time Division Multiplex) | 65 | 55 |
| | | | IP (Internet Protocol) | 65 | 55 |

| | | | | | |
|---|---|---|---|---|---|
| 2 | IP/ MPLS Core routers/ Edge/Aggregation/ Router | 85176290 | IP Edge, Aggregation & Core Routers (overall capacity <=1 Tbps) | 60 | 40 |
| | | | Cell Site Router (CSR); (Overall capacity ≤1.2 Tbps) including virtual routers | 60 | 40 |
| | | | SD-WAN Routers (SDN Category) (Interface Capacity =<10 Gbps) | 60 | 40 |
| 3 | Managed Leased Line Network Equipment, IP Based access systems-DSL | 85176290, 85176990 | Central Office Equipment and CPEs of DSL/HDSL/S-HDSL | 60 | 40 |
| 4 | Ethernet Switches (L2 and L3) | 85176290 | L2/L3 Ethernet Switches 1-100 GbE interface Switches (stackable / standalone / modular switches), for Core / Distribution / Access Layers (including PoE/PoE+) | 60 | 40 |
| | | | Industrial Grade LAN 1, 10 GbE PoE/PoE+/Non-PoE Switches (Power over Ethernet) | 60 | 40 |
| 5 | IP based Soft Switches, IMS, Unified Communication Systems | 85176290, 85176990 | IP PBX / Unified Communication Systems(UCS) | 60 | 40 |
| | | | UCS (non-IMS based): | 60 | 40 |
| 6 | Wireline PABXs / IP PBX | 85176290 | Wireline PABXs / IP PBX | 65 | 45 |
| 7 | Media Gateways | 85176290, 85176990 | Media Gateways | 65 | 45 |
| 8 | Customer Premises Equipment (CPEs) (including Wi-Fi Access points, low capacity Routers, Media Converters), CPE - NFV/ SDN/ Leased-line Modems | 85176290, 85176990 | CPE (including Wi-Fi Access points and Routers), | 50 | 30 |
| | | | Media convertor | 50 | 30 |
| | | | TDM over IP Converter | 50 | 30 |
| | | | CPE - NFV/ SDN (Virtualized CPE with cloud management) | 50 | 30 |
| | | | Leased-line Modems n* 2Mbps / IP | 50 | 30 |
| 9 | SDH/ NG-SDH | 85176290 | SDH/ NG-SDH (STM 1/4/16/64) | 65 | 45 |
| 10 | Ethernet/MPLS- TP/ Packet Optical Transport equipment/ PTN systems | 85176290 | MPLS- TP / Packet Optical Transport equipment/ PTN (with or without OTN interfaces) systems | 65 | 45 |
| 11 | CWDM systems | 85176290 | CWDM (Nx100G, Nx10G) | 60 | 40 |
| 12 | DWDM systems | 85176290, 85176270 | DWDM (upto 10G) with Mux/De MUX with Transponder / Muxponder; ROADM (Reconfigurable Optical Add Drop Multiplexer), Passive DWDM MUX/DeMUX | 60 | 40 |
| 13 | GPON/XGPON equipment (including ONT and OLT) | 85176290, 85172990 | GPON/ XGPON equipment (including ONT and OLT) | 60 | 40 |
| 14 | XGS-PON equipment (including ONT and OLT) | 85176290, 85172990 | XGS-PON (10G DS – 10G US ) (including ONT and OLT) | 60 | 40 |

| | | | | | |
|---|---|---|---|---|---|
| 15 | SDH/ PDH Cross Connects | 85176290 | SDH/ PDH Cross Connects (STM : 1/4/16/64; E1/E3/DS3; Ethernet interfaces) | 60 | 40 |
| 16 | Small Size Radio Sub System | 85176290 | Micro 2G BTS | 60 | 40 |
| 17 | LTE/ LTE-R Based Mobile Systems, with its various derivatives | 85176290, 85176990 | Macro eNode B, as per TEC ENB GR (TDD/FDD) | 60 | 40 |
| | | | Micro eNodeB, as per TEC ENB GR (TDD/FDD) | 60 | 40 |
| | | | Pico eNodeB, as per TEC ENB GR (TDD/FDD) | 60 | 40 |
| | | | Home Base Station/ Femto | 60 | 40 |
| | | | EPC | 60 | 40 |
| | | | 4G NIB Small cell | 60 | 40 |
| 18 | Wi-Fi based broadband wireless access systems -indoor | 85176290, 85176990 | Indoor AP (802.11 ax MIMO, 2.4 & 5 GHz bands) | 55 | 35 |
| | | | Indoor AP (802.11 ac MIMO, 2.4 & 5 GHz bands) | 55 | 35 |
| 19 | Wi-Fi based broadband wireless access systems -Outdoor | 85176290, 85176990 | Outdoor AP (802.11ac - MIMO 2.4 and 5 GHz bands) - IP67 Rated | 55 | 35 |
| | | | Outdoor AP (802.11ax MIMO, 2.4 & 5 GHz bands) | 55 | 35 |
| 20 | Wi-Fi Access Controller (with interoperability and multi-vendor AP support) | 85176290 | Type 1: <= 2000 AP support | 55 | 35 |
| | | | Type 2: upto 5000 AP support | 55 | 35 |
| 21 | Authentication, Authorization and Accounting(AAA) Server | 85176290 | AAA Block (Radius) | 50 | 35 |
| | | | AAA Block (Radius/ Diameter) | 50 | 35 |
| 22 | Radio systems (IP/ Hybrid) | 85176290 | Radio systems (IP/ Hybrid) (5 GHz band - License Exempt band) | 55 | 35 |
| 23 | Software Defined Radio, Cognitive Radio systems | 85176290 | Ruggedised handheld, Ruggedised or non-ruggedised vehicle mounts, P2P OR P2MP or Mobile adhoc topology, Unlicensed band operation | 55 | 35 |
| 24 | Repeaters (RF/RF-over-Optical), IBS and Distributed Antenna systems (indoor / outdoor) | 85176290, 85177100 | Repeaters (RF/RF-over-Optical), IBS and Distributed Antenna systems (indoor / outdoor) including Active & Passive Accessories | 60 | 40 |
| 25 | VSAT Terminal Subsystem – ODUs/ | 85176290, 85256091 | Antenna | 50 | 25 |
| 26 | VSAT Hub Subsystems | 85256091 | NMS H/W & S/W | 50 | 25 |
| | | | Antenna (>=7m) and accessories etc. | 50 | 25 |
| 27 | Satellite Phones(S Bands) | 85176990 | Both Voice and Data (upto 9.6 Kbps) | 50 | 25 |
| 28 | Disaster communication Systems etc., including backpack satellite products (S Band) | 85176990 | Portable Terminals Voice and Data (2 Mbps UL) | 50 | 25 |
| 29 | Satellite based Systems, terminals including location, resources tracking (L, S and Ku, Ka bands) | 85176990 | Two way MSS Data Terminals (Satellite Receivers with location data) S - Band (Satellite IoT devices for various applications i.e. | 50 | 25 |

| | | | | | |
|---|---|---|---|---|---|
| | | | position tracking, messaging etc.) | | |
| | | | One Way Receivers MSS Data Terminals (Satellite Transmitters & Receivers - one way) S – Band (Simplex / Half-duplex, Mobile Satellite Service (MSS) terminal, Satellite IoT devices) | 50 | 25 |
| 30 | Telecom Network Management systems (NMS) with its various derivatives | 85176290 | | 65 | 50 |
| 31 | Optical Fibre | 9001000 | Single Mode | 50 | 0 |
| 32 | Optical Fiber Cable | 85447090 | Optical Fiber Cable (UG & OH) | 55 | 0 |
| 33 | Telecom Power System (Including Solar Power) | 85176990 | UPS, Power Plant, Invertor (Including Solar Power) 0.5-1500 KVA/ Power Plant: 1-2000 KVA (Modular) | 55 | 30 |
| 34 | Telecom Batteries (Lead Acid) | 85176990 | Lead Acid up to 5000 AH (Including VRLA) | 55 | 30 |
| 35 | IP Audio/ Video phones / Adaptor | 85176990 | IP Audio/ Video phones / Adaptor | 50 | 15 |
| 36 | IP/ Internet Set-top Box | 85176990 | IP/ Internet Set-top Box | 55 | 35 |

MLC%- Minimum Local Content as a percentage of total Bill of Material (cost of production) to qualify as Make in India Telecom Products, Services or Works.

**TABLE-B**

**Main Inputs /stages for manufacture of telecom products & conditions for the inputs to be qualified as Local Content**

| **Main Inputs /stages for manufacture of telecom products *** | **Conditions to be met for the inputs to be qualified as Local Content** |
|---|---|
| 1) Design<br>a) Hardware design<br>b) Software Design & Development | The maximum Local Content (LC) percentage for Design which can be claimed by a Local manufacturer for the telecom products based on in-house/in country R&D costs incurred/amortized to create IPR in India are as per **Table-A (last column)** subject to additional conditions that:<br>a) The Intellectual Property Right (IPR) reside in India for Hardware Design; and<br>b) The Copyright is in India for the software Design & Development. |
| 2) Components<br>a) Integrated chips (ICs)- Processor, Memory etc.<br>b) Active components – Transistors, Diodes etc.<br>c) Passive Components – Resistors, Capacitors, Inductors etc. | Should be Manufactured in India |
| 3) PCB Fabrication | Should be Manufactured in India |
| 4) Cables/Chassis etc.<br>a) Chassis<br>b) Cables<br>c) Racks<br>d) Heat sinks<br>e) Enclosures | Should be Manufactured in India |
| 5) RF Components/Subsystem<br>a) Duplexers/Filters | Should be Manufactured in India |

| | |
|---|---|
| b) Antenna | |
| 6) Assembly/Integration/Testing# | The upper ceiling limit of Domestic Local Content (LC) for Assembly/ Integration/ Testing in respect of the telecom products listed in **Table-A** would be 10% of the total product Bill of Material. |
| * The product may include some/all of the input/stage as mentioned above. While calculating the local content only those inputs/stages will be considered which are relevant in the manufacturing of the telecom product.<br><br>#In case a system or subsystem is merely assembled / integrated / tested, then actual Local Content shall be taken as up to 10% of the cost of system / subsystem. | |

**Form 1**

**Format for Self-Certification regarding Local Content (LC) for Telecom Product, Services or Works to be submitted on non-judicial stamp paper of the value Rs. 100/-**

**Date:**

I__ _____**S/o, D/o, W/o,** Resident of _____ do hereby solemnly affirm and declare as under:

That I agree to abide by the terms and conditions of Department of Telecommunications, Government of India issued vide Notification No:_____ dated_____.

That the information furnished hereinafter is correct to the best of my knowledge and belief and I undertake to produce relevant records before the procuring entity or any other authority so nominated by the Department of Telecommunications, Government of India for the purpose of assessing the LC.

That the LC for all inputs which constitute the said Telecom Product/Services/Works has been verified by me and I am responsible for the correctness of the claims made therein.

That in the event of the LC of the Telecom Product/Services/Works mentioned herein is found to be incorrect and not meeting the prescribed LC norms, based on the assessment of an authority so nominated by the Department of Telecommunications, Government of India, **I and my Statutory auditor or cost auditor (if applicable) will be liable for actions as specified in Clause (9) of the DPIIT PPP-MII Order dated 19.07.2024 for all incorrect/false facts and figures.**

I agree to maintain detailed breakup / information (separately for each product) to substantiate my claim for LC in the Company's record for a period of 2 years and shall make this available for verification to any authority. I shall also maintain records of local content pertaining to items bought from other domestic manufacturers / traders.

[Please provide following information]

i Name and details of the local supplier (Registered Office, Manufacturing unit location, nature of legal entity)
ii. Date on which this certificate is issued
iii. Telecom Product/Services/Works for which the certificate is produced
iv. Procuring agency to whom the certificate is furnished
v. Percentage of LC claimed
vi. Name and contact details of the unit of the manufacturer
vii. Sale Price of the product
viii. Ex-Factory Price of the product
ix. Freight, insurance and handling
x. Total Bill of Material
xi. List and total cost value of inputs used for manufacture of the Telecom product/Services/Works
xii. List and total cost of inputs which are locally sourced. Please attach LC certificates from local suppliers, if the input is not produced in-house.
xiii. List and cost of inputs which are imported, directly or indirectly

I hereby certify that, having read all the provisions of the above order and principles / basis of calculations, the local content calculation does not include the following:

a. Imported items sourced locally from resellers/distributors.

b. The license fees / royalties paid/ technical charges paid out of India

c. Procurement / supply of repackaged / refurbished/rebranded imported products

I hereby also certify to the best of my knowledge and belief that all the particulars furnished above are correct and complete. I agree to comply with the terms and conditions of the DPIIT PPP-MII order dated 19.07.2024 and DoT PPP-MII Notification dated……..

**I understand that any incorrect declaration regarding the local content or failure to substantiate the claim of LC will result in penalties as specified in Clause (9) of the DPIIT PPP-MII Order dated 19.07.2024.**

I further certify and take personal responsibility that I have applied my mind to the calculations and principles of LC as specified in this order and I shall, having declared the LC shall not seek recourse to change it on any ground. Any changes made by me on any grounds in a bid in LC after bid submission shall make my bid non-responsive and I shall hold myself liable for civil/criminal action arising out of any such change. I understand and agree that any such post bid change in LC content shall also be a valid ground for blacklisting of the firm from future contracts/bids.

**Signature:**

**Name:**

**Designation: CEO/MD**

**Address:**

**Email Address:**

**Mobile No.:**

**Place:**

**Date:**

**List of Acronyms used in the notification**

| Sl. No. | Acronyms | Expansion |
|---|---|---|
| 1. | AAA | Authentication Authorization & Accounting |
| 2. | AMC | Annual Maintenance contract |
| 3. | AP | Access Point |
| 4. | BBU | Base Band Unit |
| 5. | BIS | Bureau of Indian Standard |
| 6. | B-RAS | Broadband Remote Access Server |
| 7. | BTS | Base Transceiver Station |
| 8. | CDOT | Centre for Development of Telematics |
| 9. | CMC | Comprehensive Maintenance Contract |
| 10. | CPE | Customer Premise Equipment |
| 11. | CS | Central Scheme |
| 12. | CSR | Cell Site Router |
| 13. | CSS | Central Sector Scheme |
| 14. | CWDM | Coarse Wavelength Division Multiplexing |
| 15. | DIPP | Department of Industrial Policy and Promotion |
| 16. | DoT | Department of Telecommunications |
| 17. | DPIIT | Department for Promotion of Industry and Internal Trade |
| 18. | DSL | Digital Subscriber Line |
| 19. | DSLAM | Digital Subscriber Line Access Multiplexer |
| 20. | DWDM | Dense Wavelength Division Multiplexing |
| 21. | e-node B (ENB) | Evolved node B |
| 22. | EPC | Engineering Procurement Construction |
| 23. | FDD | Frequency Division Duplexing |
| 24. | gNB | Next Generation Node B |
| 25. | GFR | General Financial Rules |
| 26. | GPON | Gigabit Passive Optical Network |
| 27. | GR | Generic Requirements |
| 28. | GSM | Global System for Mobile |
| 29. | HDSL | High bit-rate Digital Subscriber Line |

| | | |
|---|---|---|
| 30. | IBS | Integrated Building System |
| 31. | IC | Integrated Chip |
| 32. | IMS | IP Multimedia Subsystem |
| 33. | IOT | Internet of Things |
| 34. | IP | Internet Protocol |
| 35. | IPR | Intellectual Property Right |
| 36. | IR | Interface Requirement |
| 37. | LAN | Local Area Network |
| 38. | L-2 | Layer Two |
| 39. | L-3 | Layer Three |
| 40. | LC | Local Content |
| 41. | Li-ion | Lithium-ion |
| 42. | LTE | Long Term Evolution |
| 43. | LTE-R | Long Term Evolution-Railway |
| 44. | MIMO | Multiple Input Multiple Output |
| 45. | MLC | Minimum Local Content |
| 46. | MPLS | Multi-protocol Label Switching |
| 47. | MPLS-TP | Multiprotocol Label Switching-Transport Profile |
| 48. | MSS | Mobile Satellite Service |
| 49. | MUX | Multiplexer |
| 50. | NFV | Network Function Virtualization |
| 51. | NG-PON2 | Next Generation Gigabit Passive Optical Network 2 |
| 52. | NIB | Network in Box |
| 53. | NMS | Network Management System |
| 54. | OADM | Optical Add-Drop Multiplexer |
| 55. | ODU | Outdoor Unit |
| 56. | OLT | Optical Line Terminal |
| 57. | ONT | Optical Network Terminal |
| 58. | OTN | Optical Transport Network |
| 59. | P2P | Point to Point |
| 60. | P2MP | Point to Multi Point |
| 61. | PABX | Private Auto Branch Exchange |
| 62. | PBX | Private Branch Exchange |
| 63. | PCB | Printed Circuit Board |
| 64. | PDH | Plesiochronous Digital Hierarchy |
| 65. | PMI | Preference to Make in India |
| 66. | PTN | Packet Transport Network |
| 67. | PoC | Proof of Concept |
| 68. | PoE | Power over Ethernet |
| 69. | PPP-MII | Public Procurement (Preference to Make in India) |
| 70. | PTN | Packet Transport Network |
| 71. | ROADM | Reconfigurable Optical Add-Drop Multiplexer |
| 72. | R&D | Research and Development |
| 73. | RF | Radio Frequency |
| 74. | S-HDSL | Single pair High speed Digital Subscriber Line |
| 75. | SDH | Synchronous Digital Hierarchy |
| 76. | SDN | Software Defined Network |
| 77. | SD-WAN | Software Defined - Wide Area Network |

Page 246 of 4391 : B957-TENDER DOC-B957-300-16-43-MR-T-3001 : Rev. A

| | | |
|---|---|---|
| 78. | STM | Synchronous Transport Module |
| 79. | TDD | Time Division Duplexing |
| 80. | TDM | Time Division Multiplexing |
| 81. | TEC | Telecommunication Engineering Centre |
| 82. | TEPC | Telecom Export Promotion Council |
| 83. | UCS | Unified Communication System |
| 84. | UL | Unified License |
| 85. | USOF | Universal Service Obligation Fund |
| 86. | UTM | Unified Threat Management |
| 87. | VRLA | Valve Regulated Lead Acid |
| 88. | VSAT | Very Small Aperture Terminal |
| 89. | Wi-Fi | Wireless Fidelity |
| 90. | XG-PON | 10 Gigabit Passive Optical Network |
| 91. | XGS-PON | 10 Gigabit Symmetrical Passive Optical Network |

ASHOK KUMAR JAIN, Dy. Director General

Uploaded by Dte. of Printing at Government of India Press, Ring Road, Mayapuri, New Delhi-110064
and Published by the Controller of Publications, Delhi-110054.

SARVESH KUMAR SRIVASTAVA Digitally signed by SARVESH KUMAR SRIVASTAVA Date: 2024.10.22 21:17:02 +05'30'

**No.: FP-20013/24/2017-FP-PNG (E-17013)**
**Government of India**
**Ministry of Petroleum and Natural Gas**
**(Flagship Programme Cell)**
****

Shastri Bhawan, New Delhi
Dated 21st August, 2024

To

1. Chairman, IOCL
2. C&MD, ONGC/ BPCL/ HPCL/ OIL/ GAIL/ EIL/ Balmer Lawrie
3. Managing Director, CPCL/ NRL/ MRPL/ BCPL/ OVL
4. DG, DGH
5. DG, PPAC
6. Secretary, OIDB
7. ED, OISD
8. ED, CHT
9. Director, RGIPT/ IIPE
10. Secretary, PNGRB
11. CEO & MD, ISPRL

**Subject: Revised Public Procurement (Preference to Make in India) Order, 2017- regarding**

Sir/ Madam,

I am directed to forward revised Public Procurement (Preference to Make in India) Order, 2017 dated 19.7.2024 issued by Department for Promotion of Industries and internal Trade (DPIIT), for information and necessary action.

Yours faithfully

Kala 21/8/24
(Kala)
Under Secretary to the Govt. of India
Tel.: 011-23381029

Encl.: as above

**Copy to:**

a. PPS/ PS to Secretary, P&NG
b. PPS/ PS to AS&FA/ AS, MoPNG
c. PPS/ PS to JS (G)/ JS(M&OR)/ JS (GP)/ JS (IC)/ JS (IFD)/ DDG, MoPNG

No. P-45021/2/2017-PP (BE-II)-Part(4)Vol.II
Government of India
Ministry of Commerce and Industry
Department for Promotion of Industry and Internal Trade
(Public Procurement Section)

Vanijya Bhawan, New Delhi
Dated: 19 July,2024

To

All Central Ministries/Departments/CPSUs/All concerned

# ORDER

**Subject: Public Procurement (Preference to Make in India), Order 2017– Revision; regarding.**

**Department for Promotion of Industry and Internal Trade, in partial modification [Paras 2, 3, 5, 10 & 13] of Order No.P-45021/2/2017-B.E.-II dated 15.6.2017 as amended by Order No.P-45021/2/2017-B.E.-II dated 28.05.2018, Order No.P-45021/2/2017-B.E.-II dated 29.05.2019, Order No.P-45021/2/2017-B.E.-II dated 04.06.2020 and Order No.P-45021/2/2017-B.E.-II dated 16.09.2020 hereby issues the revised 'Public Procurement (Preference to Make in India), Order 2017" dated 19.07.2024 effective with immediate effect.**

**Whereas** it is the policy of the Government of India to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment, and

**Whereas** procurement by the Government is substantial in amount and can contribute towards this policy objective, and

**Whereas** local content can be increased through partnerships, cooperation with local companies, establishing production units in India or Joint Ventures (JV) with Indian suppliers, increasing the participation of local employees in services and training them,

**Now therefore the following Order is issued:**

1. This Order is issued pursuant to Rule 153 (iii) of the General Financial Rules 2017.
2. **Definitions**: For the purposes of this Order:
   *'Local content'* means the amount of value added in India which shall, unless otherwise prescribed by the Nodal Ministry, be the total value of the item procured (excluding net domestic indirect taxes) minus the value of imported content in the item (including all customs duties) as a proportion of the total value, in percent.

***Explanatory notes for calculation of local content given above***

a. Imported items sourced locally from resellers/distributors shall be excluded from calculation of local content.
b. The license fees/royalties paid/ technical charges paid out of India shall be excluded from local content calculation.

c. Procurement/Supply of repackaged/refurbished/rebranded imported products as understood commonly shall be treated as reselling of imported products and shall be excluded from calculation of local content. The definition of repackaged/refurbished/rebranded imported products is as follows;

'Refurbishing' means repair or reconditioning of an imported product does not amount to manufacture because no new goods come into existence.

'Repackaging' means repacking of imported goods from bulk pack to smaller packs would not ordinarily amount to manufacture of a new item.

'Rebranding' means relabeling or renaming or change in symbol or logo/makes or corporate image of a company/organization/ firm for an imported product would amount to rebranding.

d. To ensure that imported items sourced locally from resellers/distributors are excluded from calculation of local content, procuring entities to obtain from bidders, the cost of such locally-sourced imported items (Inclusive of taxes) along with break-up on license/royalties paid/technical expertise cost etc. sourced from outside India. For items sold by bidder as reseller, OEM certificate for country of origin to be submitted.

e. For contracts involving supply of multiple items, weighted average of all items to be taken while calculating the local content.

'*Class-I local supplier*' means a supplier or service provider, whose goods, services or works offered for procurement, meets the minimum local content as prescribed for 'Class-I local supplier' under this Order.

'*Class-II local supplier*' means a supplier or service provider, whose goods, services or works offered for procurement, meets the minimum local content as prescribed for 'Class-II local supplier' but less than that prescribed for 'Class-I local supplier' under this Order.

'*Non - Local supplier*' means a supplier or service provider, whose goods, services or works offered for procurement, has local content less than that prescribed for 'Class-II local supplier' under this Order.

'*L1*' means the lowest tender or lowest bid or the lowest quotation received in a tender, bidding process or other procurement solicitation as adjudged in the evaluation process as per the tender or other procurement solicitation.

'*Margin of purchase preference*' means the maximum extent to which the price quoted by a "Class-I local supplier" may be above the L1 for the purpose of purchase preference.

'*Nodal Ministry*' means the Ministry or Department identified pursuant to this order in respect of a particular item of goods or services or works.

'*Procuring entity*' means a Ministry or department or attached or subordinate office of, or autonomous body controlled by, the Government of India and includes Government companies as defined in the Companies Act.

*'Works'* means all works as per Rule 130 of GFR- 2017, and will also include *'turnkey works'*.

**2A. *Special treatment for items covered under PLI Scheme***

The manufacturers manufacturing an item under PLI scheme shall be treated as deemed Class II local supplier for that item unless they have minimum local content equal to or higher than that notified for Class-I local supplier for that item, provided the manufacturer has received incentive from the concerned PLI Ministry for the item. The above shall be applicable for the specific time period only, as notified by concerned PLI Ministry.

**3. Eligibility of 'Class-I local supplier'/ 'Class-II local supplier'/ 'Non-local suppliers' for different types of procurement**

(a) In procurement of all goods, services or works in respect of which the Nodal Ministry / Department has communicated that there is sufficient local capacity and local competition, only 'Class-I local supplier', as defined under the Order, shall be eligible to bid irrespective of purchase value.

(b) Only 'Class-I local supplier' and 'Class-II local supplier', as defined under the Order, shall be eligible to bid in procurement undertaken by procuring entities, except when Global tender enquiry has been issued. In global tender enquiries, 'Non-local suppliers' shall also be eligible to bid along with 'Class-I local suppliers' and 'Class-II local suppliers'. In procurement of all goods, services or works, not covered by sub-para 3(a) above, and with estimated value of purchases less than Rs. 200 Crore, in accordance with Rule 161(iv) of GFR, 2017, Global tender enquiry shall not be issued except with the approval of competent authority as designated by Department of Expenditure.

(c) For the purpose of this Order, works includes Engineering, Procurement and Construction (EPC) contracts and services include System Integrator (SI) contracts.

**3.1 Mandatory sourcing of items, with sufficient local capacity and competition, from Class-I local suppliers in SI/EPC/Turnkey Contracts/Service Tenders**

a. The items, notified as having sufficient local capacity and competition, shall mandatory be sourced from Class-I local suppliers in SI/EPC/Turnkey Contracts/ Services tenders. This provision will be applicable only for those items which have been notified by the Nodal Ministry as Class I i.e. having sufficient local capacity and competition, with specific HSN codes."

b. Notwithstanding above, if in any project, it is considered that it is not practically feasible to source such items from Class I local suppliers, it may take relaxation from such stipulation with the approval of Secretary of the administrative Ministry/ Department concerned or with the approval of the Competent Authority specified by the Administrative Ministry/Department, on case-specific basis.

**3A. Purchase Preference**

(a) Subject to the provisions of this Order and to any specific instructions issued by the Nodal Ministry or in pursuance of this Order, purchase preference shall be given to 'Class-I local supplier' in procurement undertaken by procuring entities in the manner specified here under.

(b) In the procurement of goods or works, which are covered by para 3(b)

above and which are divisible in nature, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

i. Among all qualified bids, the lowest bid will be termed as L1. If L1 is 'Class-I local supplier', the contract for full quantity will be awarded to L1.
ii. If L1 bid is not a 'Class-I local supplier', 50% of the order quantity shall be awarded to L1. Thereafter, the lowest bidder among the 'Class-I local supplier' will be invited to match the L1 price for the remaining 50% quantity subject to the Class-I local supplier's quoted price falling within the margin of purchase preference, and contract for that quantity shall be awarded to such 'Class-I local supplier' subject to matching the L1 price. In case such lowest eligible 'Class-I local supplier' fails to match the L1 price or accepts less than the offered quantity, the next higher 'Class-I local supplier' within the margin of purchase preference shall be invited to match the L1 price for remaining quantity and so on, and contract shall be awarded accordingly. In case some quantity is still left uncovered on Class-I local suppliers, then such balance quantity may also be ordered on the L1 bidder.

(c) In the procurement of goods or works, which are covered by para 3(b) above and which are not divisible in nature, and in procurement of services where the bid is evaluated on price alone, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

i. Among all qualified bids, the lowest bid will be termed as L1. If L1 is Class -I local supplier', the contract will be awarded to L1.
ii. If L1 is not 'Class-I local supplier', the lowest bidder among the 'Class-I local supplier', will be invited to match the L1 price subject to Class-I local supplier's quoted price falling within the margin of purchase preference, and the contract shall be awarded to such 'Class-I local supplier' subject to matching the L1 price.
iii. In case such lowest eligible 'Class-I local supplier' fails to match the L1 price, the 'Class-I local supplier' with the next higher bid within the margin of purchase preference shall be invited to match the L1 price and so on and contract shall be awarded accordingly. In case none of the 'Class-I local supplier' within the margin of purchase preference matches the L1 price, the contract may be awarded to the L1 bidder.

(d) "Class-II local supplier" will not get purchase preference in any procurement, undertaken by procuring entities.

**3B. Applicability in tenders where contract is to be awarded to multiple bidders-** In tenders where contract is awarded to multiple bidders subject to matching of L1 rates or otherwise, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

a. In case there is sufficient local capacity and competition for the item to be procured, as notified by the nodal Ministry, only Class I local suppliers shall be eligible to bid. As such, the multiple suppliers, who would be awarded the contract, should be all and only 'Class I Local suppliers'.
b. In other cases, 'Class II local suppliers' and 'Non local suppliers' may also participate in the bidding process along with 'Class I Local suppliers' as per provisions of this Order.
c. If 'Class I Local suppliers' qualify for award of contract for at least

Signature Not Verified
Digitally signed by ARITRA DE
Date: 2026.05.18 16:41:22 IST
Location: eProcure-EPROC